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# **32**

# SH7619 Group

# Hardware Manual

Renesas 32-Bit RISC **Microcomputer** SuperHTM RISC engine Family / SH7619 Series

> SH7619 R4S76190 R4S76191

**Renesas Electronics** www renesas com

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### **General Precautions on Handling of Product**

- 1. Treatment of NC Pins
- Note: Do not connect anything to the NC pins. The NC (not connected) pins are either not connected to any of the internal circuitry or are used as test pins or to reduce noise. If something is connected to the NC pins, the operation of the LSI is not guaranteed.
- 2. Treatment of Unused Input Pins
- Note: Fix all unused input pins to high or low level. Generally, the input pins of CMOS products are high-impedance input pins. If unused pins are in their open states, intermediate levels are induced by noise in the vicinity, a passthrough current flows internally, and a malfunction may occur.
- 3. Processing before Initialization
- Note: When power is first supplied, the product's state is undefined. The states of internal circuits are undefined until full power is supplied throughout the chip and a low level is input on the reset pin. During the period where the states are undefined, the register settings and the output state of each pin are also undefined. Design your system so that it does not malfunction because of processing while it is in this undefined state. For those products which have a reset function, reset the LSI immediately after the power supply has been turned on.
- 4. Prohibition of Access to Undefined or Reserved Addresses
- Note: Access to undefined or reserved addresses is prohibited. The undefined or reserved addresses may be used to expand functions, or test registers may have been be allocated to these addresses. Do not access these registers; the system's operation is not guaranteed if they are accessed.



## Configuration of This Manual

This manual comprises the following items:

- 1. General Precautions on Handling of Product
- 2. Configuration of This Manual
- 3. Preface
- 4. Contents
- 5. Overview
- 6. Description of Functional Modules
	- CPU and System-Control Modules
	- On-Chip Peripheral Modules

The configuration of the functional description of each module differs according to the module. However, the generic style includes the following items:

- i) Feature
- ii) Input/Output Pin
- iii) Register Description
- iv) Operation
- v) Usage Note

When designing an application system that includes this LSI, take notes into account. Each section includes notes in relation to the descriptions given, and usage notes are given, as required, as the final part of each section.

- 7. List of Registers
- 8. Electrical Characteristics
- 9. Appendix

10. Main Revisions and Additions in this Edition (only for revised versions)

The list of revisions is a summary of points that have been revised or added to earlier versions. This does not include all of the revised contents. For details, see the actual locations in this manual.

11. Index



## Preface

The SH7619 Group RISC (Reduced Instruction Set Computer) microcomputers include a Renesas Technology-original RISC CPU as its core, and the peripheral functions required to configure a system.

- Target Users: This manual was written for users who will be using the SH7619 in the design of application systems. Target users are expected to understand the fundamentals of electrical circuits, logical circuits, and microcomputers.
- Objective: This manual was written to explain the hardware functions and electrical characteristics of the SH7619 to the target users. Refer to the SH-1/SH-2/SH-DSP Software Manual for a detailed description of the instruction set.

Notes on reading this manual:

- In order to understand the overall functions of the chip Read the manual according to the contents. This manual can be roughly categorized into parts on the CPU, system control functions, peripheral functions and electrical characteristics.
- In order to understand the details of the CPU's functions Read the SH-1/SH-2/SH-DSP Software Manual.
- In order to understand the details of a register when its name is known The addresses, bits, and initial values of the registers are summarized in section 24, List of Registers.
	- Examples: Register name: The following notation is used for cases when the same or a similar function, e.g. 16-bit timer pulse unit or serial communication interface, is implemented on more than one channel:  $XXX_N (XXX)$  is the register name and N is the channel number) Bit order: The MSB is on the left and the LSB is on the right. Number notation: Binary is B'xxxx, hexadecimal is H'xxxx, decimal is xxxx. Signal notation: An overbar is added to a low-active signal: xxxx

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## Figures





#### **Section 11 Ethernet Controller (EtherC)**







#### **Section 15 Serial Communication Interface with FIFO (SCIF)**













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## Tables





#### **Section 7 Bus State Controller (BSC)**






### **Section 25 Electrical Characteristics**







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# Section 1 Overview

This LSI is a CMOS single-chip microcontroller that integrates a Renesas Technology original RISC (Reduced Instruction Set Computer) CPU core with peripheral functions required for an Ethernet system.

The CPU of this LSI has a RISC (Reduced Instruction Set Computer) type instruction set. The CPU basically operates at a rate of one instruction per cycle, offering a great improvement in instruction execution speed. In addition, the 32-bit internal architecture provides improved data processing power. With this CPU, it has become possible to assemble low-cost and highperformance/high-functionality systems even for applications such as realtime control, which could not previously be handled by microcontrollers because of their high-speed processing requirements.

This LSI is equipped with an Ethernet controller that includes a media access controller (MAC) conforming to the IEEE802.3u standard and a physical layer transceiver (PHY), enabling 10/100 Mbps LAN connection. As the equipped Ethernet controller also includes a media independent interface (MII) standard unit, a PHY LSI can be externally connected.

In addition, this LSI provides on-chip peripheral functions necessary for system configuration, such as cache memory, RAM, a direct memory access controller (DMAC), timers, a serial communication interface with FIFO (SCIF), a serial IO with FIFO (SIOF), a host interface (HFI), an interrupt controller (INTC), and I/O ports.

The external memory access support function of this LSI enables direct connection to various types of memory, such as standard memory, SDRAM, and PCMCIA. This greatly reduces system cost.



## **1.1 Features**

The features of this LSI are listed in table 1.1.

#### **Table 1.1 Features of SH7619**















## **1.2 Block Diagram**

Figure 1.1 is a block diagram of this LSI.



**Figure 1.1 Block Diagram** 



## **1.3 Pin Assignments**



**Figure 1.2 Pin Assignments** 

## **1.4 Pin Functions**

#### **Table 1.2 Pin Functions**

**Classifi-**



























Notes Fix all unused pins that have no weak keeper circuit to high or low level. Unused pins that internally have weak keeper circuit need not to be fixed to high or low level. The weak keeper is a circuit that is included in I/O pins and fixes the input pins to high or low when I/O pins are not driven from outside.

\* Magic Packet is the trademark of Advanced Micro Devices, Inc.





### **Table 1.3 Pin Features**



















# Section 2 CPU

## **2.1 Features**

- General registers:  $32$ -bit register  $\times 16$
- Basic instructions: 62
- Addressing modes: 11 Register direct (Rn) Register indirect (@Rn) Post-increment register indirect (@Rn+) Pre-decrement register indirect (@-Rn) Register indirect with displacement (@disp:4, Rn) Index register indirect (@R0, Rn) GBR indirect with displacement (@disp:8, GBR) Index GBR indirect (@R0, GBR) PC relative with displacement (@disp:8, PC) PC relative (disp:8/disp:12/Rn) Immediate (#imm:8)

## **2.2 Register Configuration**

There are three types of registers: general registers (32-bit  $\times$  16), control registers (32-bit  $\times$  3), and system registers  $(32-bit \times 4)$ .





#### **Figure 2.1 CPU Internal Register Configuration**

#### **2.2.1 General Registers (Rn)**

There are sixteen 32-bit general registers (Rn), designated R0 to R15. The general registers are used for data processing and address calculation. R0 is also used as an index register. With a number of instructions, R0 is the only register that can be used. R15 is used as a hardware stack pointer (SP). In exception handling, R15 is used for accessing the stack to save or restore the status register (SR) and program counter (PC) values.

#### **2.2.2 Control Registers**

There are three 32-bit control registers, designated status register (SR), global base register (GBR), and vector base register (VBR). SR indicates a processing state. GBR is used as a base address in GBR indirect addressing mode for data transfer of on-chip peripheral module registers. VBR is used as a base address of the exception handling (including interrupts) vector table.



Status register (SR)





Global-base register (GBR)

This register indicates a base address in GBR indirect addressing mode. The GBR indirect addressing mode is used for data transfer of the on-chip peripheral module registers and logic operations.

• Vector-base register (VBR)

This register indicates the base address of the exception handling vector table.

#### **2.2.3 System Registers**

There are four 32-bit system registers, designated two multiply and accumulate registers (MACH and MACL), a procedure register (PR), and program counter (PC).

- Multiply and accumulate registers (MAC) This register stores the results of multiplication and multiply-and-accumulate operation.
- Procedure register (PR)

This register stores the return-destination address from subroutine procedures.

• Program counter (PC)

The PC indicates the point which is four bytes (two instructions) after the current execution instruction.

#### **2.2.4 Initial Values of Registers**

Table 2.1 lists the initial values of registers after a reset.

**Table 2.1 Initial Values of Registers** 

Type of register	<b>Register</b>	<b>Default</b>
General register	<b>R0 to R14</b>	Undefined
	R <sub>15</sub> (SP)	SP value set in the exception handling vector table
Control register	<b>SR</b>	13 to 10: 1111 (H'F)
		Reserved bits: 0
		Other bits: Undefined
	<b>GBR</b>	Undefined
	<b>VBR</b>	H'00000000
System register	MACH, MACL, PR	Undefined
	РC	PC value set in the exception handling vector table



## **2.3 Data Formats**

#### **2.3.1 Register Data Format**

The size of register operands is always longwords (32 bits). When loading byte (8 bits) or word (16 bits) data in memory into a register, the data is sign-extended to longword and stored in the register.



**Figure 2.2 Register Data Format** 

#### **2.3.2 Memory Data Formats**

Memory data formats are classified into byte, word, and longword.

Byte data can be accessed from any address. If word data starting from boundary other than 2n or longword data starting from a boundary other than 4n is accessed, an address error will occur. In such cases, the data accessed cannot be guaranteed. See figure 2.3.



**Figure 2.3 Memory Data Format** 

Either big endian and little endian formats can be selected according to the mode pin setting at a reset. For details on mode pin settings, see section 7, Bus State Controller (BSC).

#### **2.3.3 Immediate Data Formats**

Immediate data of eight bits is placed in the instruction code.

For the MOV, ADD, and CMP/EQ instructions, the immediate data is sign-extended to longword and then calculated. For the TST, AND, OR, and XOR instructions, the immediate data is zeroextended to longword and then calculated. Thus, if the immediate data is used for the AND instruction, the upper 24 bits in the destination register are always cleared.

The immediate data of word or longword is not placed in the instruction code. It is placed in a table in memory. The table in memory is accessed by the MOV immediate data instruction in PC relative addressing mode with displacement.

## **2.4 Features of Instructions**

### **2.4.1 RISC Type**

The instructions are RISC-type instructions with the following features:

**Fixed 16-Bit Length:** All instructions have a fixed length of 16 bits. This improves program code efficiency.

**One Instruction per Cycle:** Since pipelining is used, basic instructions can be executed in one cycle. One cycle is 25ns with 40 MHz operation.

**Data Size:** The basic data size for operations is longword. Byte, word, or longword can be selected as the memory access size. Byte or word data in memory is sign-extended to longword and then calculated. Immediate data is sign-extended to longword for arithmetic operations or zero-extended to longword size for logical operations.

#### **Table 2.2 Word Data Sign Extension**



Note:  $*$  Immediate data is accessed by @(disp, PC).

**Load/Store Architecture:** Basic operations are executed between registers. In operations involving memory, data is first loaded into a register (load/store architecture). However, bit manipulation instructions such as AND are executed directly in memory.

**Delayed Branching:** Unconditional branch instructions mean the delayed branch instructions. With a delayed branch instruction, the branch is made after execution of the instruction immediately following the delayed branch instruction. This minimizes disruption of the pipeline when a branch is made. The conditional branch instructions have two types of instructions: conditional branch instructions and delayed branch instructions.



#### **Table 2.3 Delayed Branch Instructions**

**Multiply/Multiply-and-Accumulate Operations:**  $A \times 16 \rightarrow 32$  multiply operation is executed in one to two cycles, and a  $16 \times 16 + 64 \rightarrow 64$  multiply-and-accumulate operation in two to three cycles. A  $32 \times 32 \rightarrow 64$  multiply operation and a  $32 \times 32 + 64 \rightarrow 64$  multiply-andaccumulate operation are each executed in two to four cycles.

**T Bit:** The result of a comparison is indicated by the T bit in SR, and a conditional branch is performed according to whether the result is True or False. Processing speed has been improved by keeping the number of instructions that modify the T bit to a minimum.

#### **Table 2.4 T Bit**



**Immediate Data:** 8-bit immediate data is placed in the instruction code. Word and longword immediate data is not placed in the instruction code. It is placed in a table in memory. The table in memory is accessed with the MOV immediate data instruction using PC relative addressing mode with displacement.



#### **Table 2.5 Access to Immediate Data**

Note:  $*$  Immediate data is accessed by @(disp, PC).

**Absolute Addresses:** When data is accessed by absolute address, place the absolute address value in a table in memory beforehand. The absolute address value is transferred to a register using the method whereby immediate data is loaded when an instruction is executed, and the data is accessed using the register indirect addressing mode.

#### **Table 2.6 Access to Absolute Address**



Note: \* Immediate data is referenced by @(disp,PC).

**16-Bit/32-Bit Displacement:** When data is accessed using the 16- or 32-bit displacement addressing mode, the displacement value is placed in a table in memory beforehand. Using the method whereby immediate data is loaded when an instruction is executed, this value is transferred to a register and the data is accessed using index register indirect addressing mode.



#### **Table 2.7 Access with Displacement**

Note: \* Immediate data is referenced by @(disp,PC).

#### **2.4.2 Addressing Modes**

Table 2.8 lists addressing modes and effective address calculation methods.

#### **Table 2.8 Addressing Modes and Effective Addresses**










#### **2.4.3 Instruction Formats**

This section describes the instruction formats, and the meaning of the source and destination operands. The meaning of the operands depends on the instruction code. The following symbols are used in the table.

- xxxx: Instruction code
- mmmm: Source register
- nnnn: Destination register
- iiii: Immediate data
- dddd: Displacement



## **Table 2.9 Instruction Formats**











Note:  $*$  In multiply and accumulate instructions, nnnn is the source register.

# **2.5 Instruction Set**

### **2.5.1 Instruction Set by Type**

Table 2.10 lists the instructions classified by type.

## **Table 2.10 Instruction Types**











The instruction code, operation, and execution cycles of the instructions are listed in the following tables, classified by type.



Notes: 1. The table shows the minimum number of execution states. In practice, the number of instruction execution states will be increased in cases such as the following:

- When there is contention between an instruction fetch and a data access
- When the destination register of a load instruction (memory  $\rightarrow$  register) is also used by the following instruction

2. Scaled  $(x1, x2, or x4)$  according to the instruction operand size, etc. For details, see SH-1/SH-2/SH-DSP Software Manual.



## • Data Transfer Instructions









• Arithmetic Operation Instructions





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## • Shift Instructions



#### • Branch Instructions





Note: \* One cycle when the branch is not executed.

#### • System Control Instructions







Note: \* Number of execution cycles until this LSI enters sleep mode.

About the number of execution cycles:

 The table lists the minimum number of execution cycles. In practice, the number of execution cycles will be increased depending on the conditions such as:

- When there is a conflict between instruction fetch and data access
- When the destination register of a load instruction (memory  $\rightarrow$  register) is also used by the instruction immediately after the load instruction.

# **2.6 Processing States**

#### **2.6.1 State Transition**

The CPU has the four processing states: reset, exception handling, program execution, and powerdown. Figure 2.4 shows the CPU state transition. Note that some products do not support the manual reset function and the MRES pin.



**Figure 2.4 CPU State Transition** 



Reset state

The CPU is reset. When the RES pin is driven low, the CPU enters the power-on reset state. When the RES pin is high and MRES pin is low, the CPU enters the manual reset state.

Exception handling state

This state is a transitional state in which the CPU processing state changes due to a request for exception handling such as a reset or an interrupt.

When a reset occurs, the execution start address as the initial value of the program counter (PC) and the initial value of the stack pointer (SP) are fetched from the exception handling vector table. Then, a branch is made for the start address to execute a program.

When an interrupt occurs, the PC and status register (SR) are saved in the stack area pointed to by SP. The start address of an exception handling routine is fetched from the exception handling vector table and a branch to the address is made to execute a program.

Then the processing state enters the program execution state.

• Program execution state

The CPU executes programs sequentially.

Power-down state

The CPU stops to reduce power consumption. The SLEEP instruction makes the CPU enter sleep mode or software standby mode.



# Section 3 Cache

## **3.1 Features**

- Capacity: 16 kbytes
- Structure: Instructions/data unified, 4-way set associative
- Line size: 16 bytes
- Number of entries: 256 entries/way in 16-kbyte mode
- Write method: Write-back/write-through is selectable
- Replacement method: Least-recently-used (LRU) algorithm

## **3.1.1 Cache Structure**

The cache holds both instructions and data and employs a 4-way set associative system. It is composed of four ways (banks), and each of which is divided into an address section and a data section. Each of the address and data sections is divided into 256 entries. The data of an entry is called a line. Each line consists of 16 bytes (4 bytes  $\times$  4). The data capacity per way is 4 kbytes (16 bytes  $\times$  256 entries), with a total of 16 kbytes in the cache (4 ways).

Figure 3.1 shows the cache structure.



**Figure 3.1 Cache Structure** 

**Address Array:** The V bit indicates whether or not the entry data is valid. When the V bit is 1, data is valid; when 0, data is not valid. The U bit indicates whether or not the entry has been written to in write-back mode. When the U bit is 1, the entry has been written to; when 0, it has not. The tag address is composed of 22 bits (address bits 31 to 10) used for comparison during cache searches.

In this LSI, the upper three bits of 32 address bits are used as shadow bits (see section 7, Bus State Controller (BSC)), therefore, the upper three bits of the tag address are cleared to 0.

The V and U bits are initialized to 0 by a power-on reset. The tag address is not initialized by a power-on reset.

**Data Array:** Holds 16-byte instruction and data. Entries are registered in the cache in line units (16 bytes). The data array is not initialized by a power-on reset.

**LRU:** With the 4-way set associative system, up to four instructions or data with the same entry address can be registered in the cache. When an entry is registered, LRU shows which of the four ways it is registered in. There are six LRU bits, controlled by hardware. The least-recently-used (LRU) algorithm is used to select the way.

When a cache miss occurs, six LRU bits indicate the way to be replaced. If a bit pattern other than those listed in table 3.1 is set in the LRU bits by software, the cache will not function correctly. When changing the LRU bits by software, set one of the patterns listed in table 3.1.

The LRU bits are initialized to 000000 by a power-on reset.





### **3.1.2 Divided Areas and Cache**

A 4-G byte address space is divided into five areas with the architecture of this LSI. The cache access methods can be specified for each area. Table 3.2 lists the correspondence between the divided areas and cache.

#### **Table 3.2 Correspondence between Divided Areas and Cache**





# **3.2 Register Descriptions**

The cache has the following registers. For details on register addresses and register states during each process, refer to section 24, List of Registers.

• Cache control register 1 (CCR1)

## **3.2.1 Cache Control Register 1 (CCR1)**

The cache is enabled or disabled by the CE bit in CCR1. CCR1 also has the CF bit (which invalidates all cache entries), and the WT and CB bits (which select either write-through mode or write-back mode). Programs that change the contents of CCR1 should be placed in the address space that is not cached.





## **3.3 Operation**

#### **3.3.1 Searching Cache**

If the cache is enabled (the CE bit in CCR1 is set to 1), whenever an instruction or data in H'00000000 to H'7FFFFFFF, H'8000000 to H'9FFFFFFF, and H'C0000000 to H'DFFFFFFF is accessed, the cache will be searched to see if the desired instruction or data is in the cache. Figure 3.2 illustrates the method by which the cache is searched.

Entries are selected using bits 11 to 4 of the memory access address and the tag address of that entry is read. The address comparison is performed on all four ways. When the comparison shows a match and the selected entry is valid  $(V = 1)$ , a cache hit occurs. When the comparison does not show a match or the selected entry is not valid  $(V = 0)$ , a cache miss occurs. Figure 3.2 shows a hit on way 1.





**Figure 3.2 Cache Search Scheme** 

#### **3.3.2 Read Access**

**Read Hit:** In a read access, instructions and data are transferred from the cache to the CPU. The LRU bits are updated so that they point to the most recently hit way.

**Read Miss:** An external bus cycle starts and the entry is updated. The way to be replaced is shown in table 3.1. Data is updated in units of 16 bytes by updating the entry. When the desired instruction or data is loaded from external memory to the cache, the instruction or data is transferred to the CPU in parallel. When it is loaded to the cache, the U bit is cleared to 0, the V bit is set to 1, the LRU bits are updated so that they point to the most recently hit way. When the U bit of the entry which is to be replaced by entry updating in write-back mode is 1, the cacheupdate cycle starts after the entry is transferred to the write-back buffer. After the cache completes its update cycle, the write-back buffer writes the entry back to the memory. Transfer is in 16-byte units.

#### **3.3.3 Write Access**

**Write Hit:** In a write access in write-back mode, the data is written to the cache and no external memory write cycle is generated. The U bit of the entry that has been written to is set to 1, and the LRU bits are updated to indicate that the hit way is the most recently hit way. In write-through mode, the data is written to the cache and an external memory write cycle is generated. The U bit of the entry that has been written to is not updated, and the LRU bits are updated to indicate that the hit way is the most recently hit way.

**Write Miss:** In write-back mode, an external write cycle starts when a write miss occurs, and the entry is updated. The way to be replaced is shown in table 3.1. When the U bit of the entry which is to be replaced by entry updating is 1, the cache-update cycle starts after the entry has been transferred to the write-back buffer. Data is written to the cache and the U bit and the V bit are set to 1. The LRU bits are updated to indicate that the replaced way is the most recently updated way. After the cache has completed its update cycle, the write-back buffer writes the entry back to the memory. Transfer is in 16-byte units. In write-through mode, no write to cache occurs in a write miss; the write is only to the external memory.

#### **3.3.4 Write-Back Buffer**

When the U bit of the entry to be replaced in write-back mode is 1, the entry must be written back to the external memory. To increase performance, the entry to be replaced is first transferred to the write-back buffer and fetching of new entries to the cache takes priority over writing back to the external memory. After the fetching of new entries to the cache completes, the write-back buffer writes the entry back to the external memory. During the write-back cycles, the cache can be accessed. The write-back buffer can hold one line of cache data (16 bytes) and its physical address. Figure 3.3 shows the configuration of the write-back buffer.



**Figure 3.3 Write-Back Buffer Configuration** 

#### **3.3.5 Coherency of Cache and External Memory**

Coherency between the cache and the external memory must be ensured by software. When memory shared by this LSI and another device is allocated to a cacheable address space, invalidate and write back the cache by accessing the memory-mapped cache, as required. Memory that is shared by the CPU, DMAC, and E-DMAC of this LSI should also be handled in this way.



# **3.4 Memory-Mapped Cache**

To allow software management of the cache, cache contents can be read from or written to by the MOV instructions. The address array is allocated to addresses H'F0000000 to H'F0FFFFFF, and the data array to addresses H'F1000000 to H'F1FFFFFF. The address array and data array must be accessed in longwords, and instruction fetches cannot be performed.

## **3.4.1 Address Array**

The address array is allocated to H'F0000000 to H'F0FFFFFF. To access an address array, the 32 bit address field (for read/write accesses) and 32-bit data field (for write accesses) must be specified. The address field specifies information for selecting the entry to be accessed; the data field specifies the tag address, V bit, U bit, and LRU bits to be written to the address array.

In the address field, specify the entry address for selecting the entry, W for selecting the way, A for enabling or disabling the associative operation, and H'F0 for indicating address array access. As for W, 00 indicates way 0, 01 indicates way 1, 10 indicates way 2, and 11 indicates way 3.

In the data field, specify the tag address, LRU bits, U bit, and V bit. Always clear the upper three bits (bits 31 to 29) of the tag address to 0. Figure 3.4 shows the address and data formats. The following three operations are available in the address array.

**Address-Array Read:** Read the tag address, LRU bits, U bit, and V bit for the entry that corresponds to the entry address and way specified by the address field of the read instruction. In reading, the associative operation is not performed, regardless of whether the associative bit (A bit) specified in the address is 1 or 0.

**Address-Array Write (Non-Associative Operation):** Write the tag address, LRU bits, U bit, and V bit, specified by the data field of the write instruction, to the entry that corresponds to the entry address and way as specified by the address field of the write instruction. Ensure that the associative bit (A bit) in the address field is set to 0. When writing to a cache line for which the U  $bit = 1$  and the V bit  $= 1$ , write the contents of the cache line back to memory, then write the tag address, LRU bits, U bit, and V bit specified by the data field of the write instruction. When 0 is written to the V bit, 0 must also be written to the U bit for that entry.



**Address-Array Write (Associative Operation):** When writing with the associative bit (A bit) of the address field set to 1, the addresses in the four ways for the entry specified by the address field of the write instruction are compared with the tag address that is specified by the data field of the write instruction. Write the U bit and the V bit specified by the data field of the write instruction to the entry of the way that has a hit. However, the tag address and LRU bits remain unchanged. When there is no way that has a hit, nothing is written and there is no operation. This function is used to invalidate a specific entry in the cache. When the U bit of the entry that has had a hit is 1 at this time, writing back should be performed. However, when 0 is written to the V bit, 0 must also be written to the U bit of that entry.

#### **3.4.2 Data Array**

The data array is allocated to H'F1000000 to H'F1FFFFFF. To access a data array, the 32-bit address field (for read/write accesses) and 32-bit data field (for write accesses) must be specified. The address field specifies information for selecting the entry to be accessed; the data field specifies the longword data to be written to the data array.

In the address field, specify the entry address for selecting the entry, L for indicating the longword position within the (16-byte) line, W for selecting the way, and H'F1 for indicating data array access. As for L, 00 indicates longword 0, 01 indicates longword 1, 10 indicates longword 2, and 11 indicates longword 3. As for W, 00 indicates way 0, 01 indicates way 1, 10 indicates way 2, and 11 indicates way 3.

Since access size of the data array is fixed at longword, bits 1 and 0 of the address field should be set to 00.

Figure 3.4 shows the address and data formats.

The following two operations on the data array are available. The information in the address array is not affected by these operations.

**Data-Array Read:** Read the data specified by L of the address field, from the entry that corresponds to the entry address and the way that is specified by the address field.

**Data-Array Write:** Write the longword data specified by the data field, to the position specified by L of the address field, in the entry that corresponds to the entry address and the way specified by the address field.





**Figure 3.4 Specifying Address and Data for Memory-Mapped Cache Access** 



#### **3.4.3 Usage Examples**

**Invalidating Specific Entries:** Specific cache entries can be invalidated by writing 0 to the entry's V bit in the memory-mapped cache access. When the A bit is 1, the tag address specified by the write data is compared to the tag address within the cache selected by the entry address, and the V bit and U bit specified by the write data are written when a match is found. If no match is found, there is no operation. When the V bit of an entry in the address array is set to 0, the entry is written back if the entry's U bit is 1. In the example shown below, R0 specifies the write data and R1 specifies the address.

```
; R0=H'01100010; VPN=B'0000 0001 0001 0000 0000 00, U=0, V=0 
; R1=H'F0000088; address array access, entry=B'00001000, A=1 
; 
MOV.L R0,@R1
```
**Reading Data of Specific Entry:** The data section of a specific entry can be read from by the memory-mapped cache access. The longword indicated in the data field of the data array in figure 3.4 is read into the register. In the example shown below, R0 specifies the address and R1 shows what is read.

```
; R0=H'F100004C; data array access, entry=B'00000100 
; Way = 0, longword address = 3 
; 
MOV.L @R0,R1 ; Longword 3 is read.
```




# Section 4 U Memory

This LSI has on-chip U memory which can be used to store instructions and data.

## **4.1 Features**

Features of the U Memory are shown below.

- Size 16 kbytes
- Address H'E55F\_C000 to H'E55F\_FFFF
- Priority

The U memory can be accessed from the I bus by the DMAC and E-DMAC and from the L bus by the CPU. In the event of simultaneous accesses from different buses, the accesses are processed according to the priority. The priority is: I bus > L bus.

# **4.2 Usage Notes**

In sleep mode, the U memory cannot be accessed by the DMAC and E-DMAC.





# Section 5 Exception Handling

## **5.1 Overview**

## **5.1.1 Types of Exception Handling and Priority**

Exception handling is started by four sources: resets, address errors, interrupts and instructions and have the priority, as shown in table 5.1. When several exceptions are detected at once, they are processed according to the priority.

<b>Exception</b>	<b>Exception Source</b>		<b>Priority</b>
Reset	Power-on reset		High
	H-UDI reset		
Interrupt	User break (break before instruction execution)		
Address error	CPU address error (instruction fetch)		
Instruction	General illegal instructions (undefined code)		
	Illegal slot instruction (undefined code placed immediately after a delayed branch instruction <sup>*1</sup> or instruction that changes the PC value $*^2$ )		
	Trap instruction (TRAPA instruction)		
Address error	CPU address error (data access)		
Interrupt	User break (break after instruction execution or operand break)		
	<b>NMI</b>		
	H-UDI		
	<b>IRQ</b>		
	On-chip peripheral modules	Watchdog timer (WDT)	Low
		Ether controller (EtherC and E-DMAC)	
		Compare match timer 0 and 1 (CMT0 and CMT1)	
		Serial communication interface with FIFO (SCIF0, SCIF1, and SCIF2)	
		Host interface (HIF)	

**Table 5.1 Types of Exceptions and Priority** 





Notes: 1. Delayed branch instructions: JMP, JSR, BRA, BSR, RTS, RTE, BF/S, BT/S, BSRF, and BRAF.

 2. Instructions that change the PC value: JMP, JSR, BRA, BSR, RTS, RTE, BT, BF, TRAPA, BF/S, BT/S, BSRF, BRAF, LDC Rm,SR, LDC.L @Rm+,SR.

#### **5.1.2 Exception Handling Operations**

The exceptions are detected and the exception handling starts according to the timing shown in table 5.2.





When exception handling starts, the CPU operates

**Exception Handling Triggered by Reset:** The initial values of the program counter (PC) and stack pointer (SP) are fetched from the exception handling vector table (PC from the address H'A0000000 and SP from the address H'A0000004). For details, see section 5.1.3, Exception Handling Vector Table. H'00000000 is then written to the vector base register (VBR), and H'F (B'1111) is written to the interrupt mask bits (I3 to I0) in the status register (SR). The program starts from the PC address fetched from the exception handling vector table.
**Exception Handling Triggered by Address Error, Interrupt, and Instruction:** SR and PC are saved to the stack indicated by R15. For interrupt exception handling, the interrupt priority level is written to the interrupt mask bits (I3 to I0) in SR. For address error and instruction exception handling, bits I3 to I0 are not affected. The start address is then fetched from the exception handling vector table and the program starts from that address.

## **5.1.3 Exception Handling Vector Table**

Before exception handling starts, the exception handling vector table must be set in memory. The exception handling vector table stores the start addresses of exception handling routines. (The reset exception handling table holds the initial values of PC and SP.)

All exception sources are given different vector numbers and vector table address offsets. The vector table addresses are calculated from these vector numbers and vector table address offsets. During exception handling, the start addresses of the exception handling routines are fetched from the exception handling vector table that is indicated by this vector table address.

Table 5.3 shows the vector numbers and vector table address offsets. Table 5.4 shows how vector table addresses are calculated.



#### **Table 5.3 Vector Numbers and Vector Table Address Offsets**





Note: \* For details on the vector numbers and vector table address offsets of on-chip peripheral module interrupts, see table 6.2, Interrupt Exception Handling Vectors and Priorities in section 6, Interrupt Controller (INTC).

#### **Table 5.4 Calculating Exception Handling Vector Table Addresses**



Notes: 1. VBR: Vector base register

- 2. Vector table address offset: See table 5.3.
- 3. Vector number: See table 5.3.

# **5.2 Resets**

#### **5.2.1 Types of Resets**

Resets have priority over any exception source. As table 5.5 shows, a power-on reset initializes all modules in this LSI.

#### **Table 5.5 Reset Status**



#### **5.2.2 Power-On Reset**

**Power-On Reset by** RES **Pin:** When the RES pin is driven low, this LSI enters the power-on reset state. To reliably reset this LSI, the RES pin should be kept low for at least the oscillation settling time when applying the power or when in standby mode (when the clock is halted) or at least 20 tcyc when the clock is operating. During the power-on reset state, CPU internal states and all registers of on-chip peripheral modules are initialized.

In the power-on reset state, power-on reset exception handling starts when driving the RES pin high after driving the pin low for the given time. The CPU operates as follows:

- 1. The initial value (execution start address) of the program counter (PC) is fetched from the exception handling vector table.
- 2. The initial value of the stack pointer (SP) is fetched from the exception handling vector table.
- 3. The vector base register (VBR) is cleared to H'00000000 and the interrupt mask bits (I3 to I0) of the status register (SR) are set to H'F (B'1111).
- 4. The values fetched from the exception handling vector table are set in PC and SP, then the program starts.

Be certain to always perform power-on reset exception handling when turning the system power on.



**Power-On Reset by WDT:** When TCNT of the WDT overflows while a setting is made so that a power-on reset can be generated in watchdog timer mode of the WDT, this LSI enters the poweron reset state.

If a reset caused by the signal input on the RES pin and a reset caused by a WDT overflow occur simultaneously, the RES pin reset has priority, and the WOVF bit in RSTCSR is cleared to 0. When the power-on reset exception handling caused by the WDT is started, the CPU operates as follows:

- 1. The initial value (execution start address) of the program counter (PC) is fetched from the exception handling vector table.
- 2. The initial value of the stack pointer (SP) is fetched from the exception handling vector table.
- 3. The vector base register (VBR) is cleared to H'00000000 and the interrupt mask bits (I3 to I0) of the status register (SR) are set to H'F (B'1111).
- 4. The values fetched from the exception handling vector table are set in the PC and SP, then the program starts.

## **5.2.3 H-UDI Reset**

The H-UDI reset is generated by issuing the H-UDI reset assert command. The CPU operation is described below. For details, see section 21, User Debugging Interface (H-UDI).

- 1. The initial value (execution start address) of the program counter (PC) is fetched from the exception handling vector table.
- 2. The initial value of the stack pointer (SP) is fetched from the exception handling vector table.
- 3. The vector base register (VBR) is cleared to H'00000000 and the interrupt mask bits (I3 to I0) in the status register (SR) are set to H'F (B'1111).
- 4. The values fetched from the exception handling vector table are set in PC and SP, then the program starts.

# **5.3 Address Errors**

# **5.3.1 Address Error Sources**

Address errors occur when instructions are fetched or data is read from or written to, as shown in table 5.6.

## **Table 5.6 Bus Cycles and Address Errors**



#### **Bus Cycle**

# **5.3.2 Address Error Exception Source**

When an address error exception is generated, the bus cycle which caused the address error ends, the current instruction finishes, and then the address error exception handling starts. The CPU operates as follows:

- 1. The status register (SR) is saved to the stack.
- 2. The program counter (PC) is saved to the stack. The PC value to be saved is the start address of the instruction which caused an address error exception. When the instruction that caused the exception is placed in the delay slot, the address of the delayed branch instruction which is placed immediately before the delay slot.
- 3. The start address of the exception handling routine is fetched from the exception handling vector table that corresponds to the generated address error, and the program starts executing from that address. This branch is not a delayed branch.



# **5.4 Interrupts**

#### **5.4.1 Interrupt Sources**

Table 5.7 shows the sources that start the interrupt exception handling. They are NMI, user break, H-UDI, IRQ, and on-chip peripheral modules.

#### **Table 5.7 Interrupt Sources**



All interrupt sources are given different vector numbers and vector table address offsets. For details on vector numbers and vector table address offsets, see table 6.2, Interrupt Exception Handling Vectors and Priorities in section 6, Interrupt Controller (INTC).



# **5.4.2 Interrupt Priority**

The interrupt priority is predetermined. When multiple interrupts occur simultaneously (overlapped interruptions), the interrupt controller (INTC) determines their relative priorities and starts the exception handling according to the results.

The priority of interrupts is expressed as priority levels 0 to 16, with priority 0 the lowest and priority 16 the highest. The NMI interrupt has priority 16 and cannot be masked, so it is always accepted. The priority level of the user break interrupt and H-UDI is 15. IRQ interrupt and on-chip peripheral module interrupt priority levels can be set freely using the interrupt priority level setting registers A to G (IPRA to IPRG) of the INTC as shown in table 5.8. The priority levels that can be set are 0 to 15. Level 16 cannot be set. For details on IPRA to IPRG, see section 6.3.4, Interrupt Priority Registers A to G (IPRA to IPRG).



## **Table 5.8 Interrupt Priority**

# **5.4.3 Interrupt Exception Handling**

When an interrupt occurs, the interrupt controller (INTC) ascertains its priority level. NMI is always accepted, but other interrupts are only accepted if they have a priority level higher than the priority level set in the interrupt mask bits (I3 to I0) of the status register (SR).

When an interrupt is accepted, exception handling begins. In interrupt exception handling, the CPU saves SR and the program counter (PC) to the stack. The priority level of the accepted interrupt is written to bits I3 to I0 in SR. Although the priority level of the NMI is 16, the value set in bits I3 to I0 is H'F (level 15). Next, the start address of the exception handling routine is fetched from the exception handling vector table for the accepted interrupt, and program execution branches to that address and the program starts. For details on the interrupt exception handling, see section 6.6, Interrupt Operation.



# **5.5 Exceptions Triggered by Instructions**

#### **5.5.1 Types of Exceptions Triggered by Instructions**

Exception handling can be triggered by the trap instruction, illegal slot instructions, and general illegal instructions, as shown in table 5.9.

#### **Table 5.9 Types of Exceptions Triggered by Instructions**



H'FFFF are decoded.

#### **5.5.2 Trap Instructions**

When a TRAPA instruction is executed, the trap instruction exception handling starts. The CPU operates as follows:

- 1. The status register (SR) is saved to the stack.
- 2. The program counter (PC) is saved to the stack. The PC value saved is the start address of the instruction to be executed after the TRAPA instruction.
- 3. The CPU reads the start address of the exception handling routine from the exception handling vector table that corresponds to the vector number specified in the TRAPA instruction, program execution branches to that address, and then the program starts. This branch is not a delayed branch.



#### **5.5.3 Illegal Slot Instructions**

An instruction placed immediately after a delayed branch instruction is called "instruction placed in a delay slot". When the instruction placed in the delay slot is an undefined code, illegal slot exception handling starts after the undefined code is decoded. Illegal slot exception handling also starts when an instruction that changes the program counter (PC) value is placed in a delay slot and the instruction is decoded. The CPU handles an illegal slot instruction as follows:

- 1. The status register (SR) is saved to the stack.
- 2. The program counter (PC) is saved to the stack. The PC value saved is the target address of the delayed branch instruction immediately before the undefined code or the instruction that rewrites the PC.
- 3. The start address of the exception handling routine is fetched from the exception handling vector table that corresponds to the exception that occurred. Program execution branches to that address and the program starts. This branch is not a delayed branch.

#### **5.5.4 General Illegal Instructions**

When an undefined code placed anywhere other than immediately after a delayed branch instruction (i.e., in a delay slot) is decoded, general illegal instruction exception handling starts. The CPU handles the general illegal instructions in the same procedures as in the illegal slot instructions. Unlike processing of illegal slot instructions, however, the program counter value that is stacked is the start address of the undefined code.



# **5.6 Cases when Exceptions are Accepted**

When an exception other than resets occurs during decoding the instruction placed in a delay slot or immediately after an interrupt disabled instruction, it may not be accepted and be held shown in table 5.10. In this case, when an instruction which accepts an interrupt request is decoded, the exception is accepted.





Notes: 1. Interrupt disabled instructions: LDC, LDC.L, STC, STC.L, LDS, LDS.L, STS, and STS.L

- 2. An exception is accepted before the execution of a delayed branch instruction. However, when an address error or a slot illegal instruction exception occurs in the delay slot of the RTE instruction, correct operation is not guaranteed.
- 3. An exception is accepted after a delayed branch (between instructions in the delay slot and the branch destination).
- 4. An exception is accepted after the execution of the next instruction of an interrupt disabled instruction (before the execution two instructions after an interrupt disabled instruction).

# **5.7 Stack States after Exception Handling Ends**

The stack states after exception handling ends are shown in table 5.11.

## **Table 5.11 Stack Status after Exception Handling Ends**









# **5.8 Usage Notes**

## **5.8.1 Value of Stack Pointer (SP)**

The SP value must always be a multiple of 4. If it is not, an address error will occur when the stack is accessed during exception handling.

## **5.8.2 Value of Vector Base Register (VBR)**

The VBR value must always be a multiple of 4. If it is not, an address error will occur when the stack is accessed during exception handling.

# **5.8.3 Address Errors Caused by Stacking for Address Error Exception Handling**

When the SP value is not a multiple of 4, an address error will occur when stacking for exception handling (interrupts, etc.) and address error exception handling will start after the first exception handling is ended. Address errors will also occur in the stacking for this address error exception handling. To ensure that address error exception handling does not go into an endless loop, no address errors are accepted at that point. This allows program control to be passed to the handling routine for address error exception and enables error processing.

When an address error occurs during exception handling stacking, the stacking bus cycle (write) is executed. When stacking the SR and PC values, the SP values for both are subtracted by 4, therefore, the SP value is still not a multiple of 4 after the stacking. The address value output during stacking is the SP value whose lower two bits are cleared to 0. So the write data stacked is undefined.

# **5.8.4 Notes on Slot Illegal Instruction Exception Handling**

Some specifications on slot illegal instruction exception handling in this LSI differ from those of the conventional SH2.

- Conventional SH2: Instructions LDC Rm, SR and LDC.L @Rm+, SR are not subject to the slot illegal instructions.
- This LSI: Instructions LDC Rm,SR and LDC.L @Rm+,SR are subject to the slot illegal instructions.

The supporting status on our software products regarding this note is as follows:



## **Compiler**

This instruction is not allocated in the delay slot in the compiler V.4 and its subsequent versions.

# **Real-time OS for** µ**ITRON specifications**

1. HI7000/4, HI-SH7

This instruction does not exist in the delay slot within the OS.

2. HI7000

This instruction is in part allocated to the delay slot within the OS, which may cause the slot illegal instruction exception handling in this LSI.

3. Others

The slot illegal instruction exception handling may be generated in this LSI in a case where the instruction is described in assembler or when the middleware of the object is introduced.

Note that a check-up program (checker) to pick up this instruction is available on our website. Download and utilize this checker as needed.



# Section 6 Interrupt Controller (INTC)

The interrupt controller (INTC) ascertains the priority of interrupt sources and controls interrupt requests to the CPU.

# **6.1 Features**

• 16 levels of interrupt priority

Figure 6.1 shows a block diagram of the INTC.





**Figure 6.1 INTC Block Diagram** 

RENESAS

# **6.2 Input/Output Pins**

Table 6.1 shows the INTC pin configuration.

#### **Table 6.1 Pin Configuration**



# **6.3 Register Descriptions**

The interrupt controller has the following registers. For details on the addresses of these registers and the states of these registers in each processing state, see section 24, List of Registers.

- Interrupt control register 0 (ICR0)
- IRO control register (IROCR)
- IRO status register (IROSR)
- Interrupt priority register A (IPRA)
- Interrupt priority register B (IPRB)
- Interrupt priority register C (IPRC)
- Interrupt priority register D (IPRD)
- Interrupt priority register E (IPRE)
- Interrupt priority register F (IPRF)
- Interrupt priority register G (IPRG)



## **6.3.1 Interrupt Control Register 0 (ICR0)**

ICR0 is a 16-bit register that sets the input signal detection mode of the external interrupt input pin NMI and indicates the input signal level on the NMI pin.





## **6.3.2 IRQ Control Register (IRQCR)**

IRQCR is a 16-bit register that sets the input signal detection mode of the external interrupt input pins IRQ0 to IRQ7.











# **6.3.3 IRQ Status register (IRQSR)**

IRQSR is a 16-bit register that indicates the states of the external interrupt input pins IRQ0 to IRQ7 and the status of interrupt request.















#### **6.3.4 Interrupt Priority Registers A to G (IPRA to IPRG)**

Interrupt priority registers are seven 16-bit readable/writable registers that set priority levels from 0 to 15 for interrupts except NMI. For the correspondence between interrupt request sources and IPR, refer to table 6.2, Interrupt Exception Handling Vectors and Priorities. Each of the corresponding interrupt priority ranks are established by setting a value from H'0 to H'F in each of the four-bit groups 15 to 12, 11 to 8, 7 to 4 and 3 to 0. Reserved bits that are not assigned should be set H'0 (B'0000).









Note: Name in the tables above is represented by a general name. Name in the list of register is, on the other hand, represented by a module name.

# **6.4 Interrupt Sources**

#### **6.4.1 External Interrupts**

There are five types of interrupt sources: User break, NMI, H-UDI, IRQ, and on-chip peripheral modules. Individual interrupts are given priority levels (0 to 16, with 0 the lowest and 15 the highest). Giving an interrupt a priority level of 0 masks it.

**NMI Interrupt:** The NMI interrupt is given a priority level of 16 and is always accepted. An NMI interrupt is detected at the edge of the pins. Use the NMI edge select bit (NMIE) in interrupt control register 0 (ICR0) to select either the rising or falling edge. In the NMI interrupt exception handler, the interrupt mask level bits (I3 to I0) in the status register (SR) are set to level 15.



**IRQ7 to IRQ0 Interrupts:** IRQ interrupts are requested by input from pins IRQ0 to IRQ7. Use the IRQ sense select bits (IRQ71S to IRQ 01S and IRQ70S to IRQ00S) in the IRQ control register (IRQCR) to select the detection mode from low level detection, falling edge detection, rising edge detection, and both edge detection for each pin. The priority level can be set from 0 to 15 for each pin using the interrupt priority registers A and B (IPRA and IPRB).

In the case that the low level detection is selected, an interrupt request signal is sent to the INTC while the IRQ pin is driven low. The interrupt request signal stops to be sent to the INTC when the IRQ pin becomes high. It is possible to confirm that an interrupt is requested by reading the IRQ flags (IRQ7F to IRQ0F) in the IRQ status register (IRQSR).

In the case that the edge detection is selected, an interrupt request signal is sent to the INTC when the following change on the IRQ pin is detected: from high to low in falling edge detection mode, from low to high in rising edge detection mode, and from low to high or from high to low in both edge detection mode. The IRQ interrupt request by detecting the change on the pin is held until the interrupt request is accepted. It is possible to confirm that an IRQ interrupt request has been detected by reading the IRQ flags (IRQ7F to IRQ0F) in the IRQ status register (IRQSR). An IRQ interrupt request by detecting the change on the pin can be withdrawn by writing 0 to an IRQ flag after reading 1.

In the IRQ interrupt exception handling, the interrupt mask bits (I3 to I0) in the status register (SR) are set to the priority level value of the accepted IRQ interrupt. Figure 6.2 shows the block diagram of the IRQ7 to IRQ0 interrupts.



**Figure 6.2 Block Diagram of IRQ7 to IRQ0 Interrupts Control** 

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#### **6.4.2 On-Chip Peripheral Module Interrupts**

On-chip peripheral module interrupts are interrupts generated by the following on-chip peripheral modules.

Since a different interrupt vector is allocated to each interrupt source, the exception handling routine does not have to decide which interrupt has occurred. Priority levels between 0 and 15 can be allocated to individual on-chip peripheral modules in interrupt priority registers C to G (IPRC to IPRG). On-chip peripheral module interrupt exception handling sets the interrupt mask level bits (I3 to I0) in the status register (SR) to the priority level value of the on-chip peripheral module interrupt that was accepted.

#### **6.4.3 User Break Interrupt**

A user break interrupt has a priority level of 15, and occurs when the break condition set in the user break controller (UBC) is satisfied. User break interrupt requests are detected by edge and are held until accepted. User break interrupt exception handling sets the interrupt mask level bits (I3 to I0) in the status register (SR) to level 15. For more details on the user break interrupt, see section 20, User Break Controller (UBC).

#### **6.4.4 H-UDI Interrupt**

User debugging interface (H-UDI) interrupt has a priority level of 15, and occurs when an H-UDI interrupt instruction is serially input. H-UDI interrupt requests are detected by edge and are held until accepted. H-UDI exception handling sets the interrupt mask level bits (I3-I0) in the status register (SR) to level 15. For more details on the H-UDI interrupt, see section 21, User Debugging Interface (H-UDI).



# **6.5 Interrupt Exception Handling Vector Table**

Table 6.2 lists interrupt sources, their vector numbers, vector table address offsets, and interrupt priorities.

Individual interrupt sources are allocated to different vector numbers and vector table address offsets. Vector table addresses are calculated from the vector numbers and vector table address offsets. For interrupt exception handling, the start address of the exception handling routine is fetched from the vector table address in the vector table. For the details on calculation of vector table addresses, see table 5.4, Calculating Exception Handling Vector Table Addresses in section 5, Exception Handling.

IRQ interrupts and on-chip peripheral module interrupt priorities can be set freely between 0 and 15 for each pin or module by setting interrupt priority registers A to G (IPRA to IPRG). However, when interrupt sources whose priority levels are allocated with the same IPR are requested, the interrupt of the smaller vector number has priority. This priority cannot be changed. Priority levels of IRQ interrupts and on-chip peripheral module interrupts are initialized to level 0 at a power-on reset. If the same priority level is allocated to two or more interrupt sources and interrupts from those sources occur simultaneously, they are processed by the default priority order shown in table 6.2.



#### **Table 6.2 Interrupt Exception Handling Vectors and Priorities**





# **6.6 Interrupt Operation**

#### **6.6.1 Interrupt Sequence**

The sequence of interrupt operations is explained below. Figure 6.3 is a flowchart of the operations.

- 1. The interrupt request sources send interrupt request signals to the interrupt controller.
- 2. The interrupt controller selects the highest priority interrupt from interrupt requests sent, according to the priority levels set in interrupt priority level setting registers A to G (IPRA to IPRG). Interrupts that have lower-priority than that of the selected interrupt are ignored\*. If interrupts that have the same priority level or interrupts within a same module occur simultaneously, the interrupt with the highest priority is selected according to the priority shown in table 6.2.
- 3. The interrupt controller compares the priority level of the selected interrupt request with the interrupt mask bits (I3 to I0) in the status register (SR) of the CPU. If the priority level of the selected request is equal to or less than the level set in bits I3 to I0, the request is ignored. If the priority level of the selected request is higher than the level in bits I3 to I0, the interrupt controller accepts the request and sends an interrupt request signal to the CPU.
- 4. The CPU detects the interrupt request sent from the interrupt controller in the decode stage of an instruction to be executed. Instead of executing the decoded instruction, the CPU starts interrupt exception handling.
- 5. SR and PC are saved onto the stack.
- 6. The priority level of the accepted interrupt is copied to bits (I3 to I0) in SR.
- 7. The CPU reads the start address of the exception handling routine from the exception vector table for the accepted interrupt, branches to that address, and starts executing the program. This branch is not a delayed branch.
- Note: \* Interrupt requests that are designated as edge-detect type are held pending until the interrupt requests are accepted. IRQ interrupts, however, can be cancelled by accessing the IRQ status register (IRQSR). Interrupts held pending due to edge detection are cleared by a power-on reset or an H-UDI reset.





**Figure 6.3 Interrupt Sequence Flowchart** 



# **6.6.2 Stack after Interrupt Exception Handling**

Figure 6.4 shows the stack after interrupt exception handling.



## **Figure 6.4 Stack after Interrupt Exception Handling**

# **6.7 Interrupt Response Time**

Table 6.3 lists the interrupt response time, which is the time from the occurrence of an interrupt request until the interrupt exception handling starts and fetching of the first instruction of the interrupt handling routine begins.




### **Table 6.3 Interrupt Response Time**

m4: Fetch first instruction of interrupt service routine





# Section 7 Bus State Controller (BSC)

The bus state controller (BSC) outputs control signals for various types of memory that is connected to the external address space and external devices. The BSC functions enable this LSI to connect directly with SRAM, SDRAM, and other memory storage devices, and external devices.

# **7.1 Features**

The BSC has the following features.

- External address space
	- A maximum 32 or 64 Mbytes for each of the areas, CS0, CS3, CS4, CS5B, and CS6B, totally 256 Mbytes (divided into five areas)
	- A maximum 64 Mbytes for each of the six areas, CS0, CS3, CS4, CS5, and CS6, totally 320 Mbytes (divided into five areas)
	- Can specify the normal space interface, byte-selection SRAM, SDRAM, PCMCIA for each address space
	- Can select the data bus width (8, 16, or 32 bits) for each address space. (The CS0 data bus width can only be selected from 8 or 16 bits.)
	- Can control the insertion of wait cycles for each address space
	- Can control the insertion of wait cycles for each read access and write access
	- Can control the insertion of idle cycles in the consecutive access for five cases independently: read-write (in same space/different space), read-read (in same space/different space), or the first cycle is a write access
- Normal space interface
	- Supports the interface that can directly connect to the SRAM
- SDRAM interface
	- Can connect directly to SDRAM in area 3
	- Multiplex output for row address/column address
	- Efficient access by single read/single write
	- High-speed access by bank-active mode
	- Supports auto-refreshing and self-refreshing



- Byte-selection SRAM interface
	- Can connect directly to byte-selection SRAM
- PCMCIA direct interface
	- Supports IC memory cards and I/O card interfaces defined in the JEIDA specifications Ver 4.2 (PCMCIA2.1 Rev 2.1)
	- Controls the insertion of wait cycles by software
	- Supports the bus sizing function of the I/O bus width (only in little endian mode)
- Refresh function
	- Supports the auto-refreshing and self-refreshing functions
	- Specifies the refresh interval by setting the refresh counter and clock selection
	- Can execute consecutive refresh cycles by specifying the refresh counts  $(1, 2, 4, 6, 0r 8)$





The block diagram of the BSC is shown in figure 7.1.



# **7.2 Input/Output Pins**

table 7.1 lists the pin configuration of the BSC.

### **Table 7.1 Pin Configuration**





Note: \* As pins A25 to A16 act as general I/O ports immediately after a power-on reset, pull-up or pull-down these pins outside the LSI as needed.

# **7.3 Area Overview**

### **7.3.1 Area Division**

The architecture of this LSI has 32-bit address space. The upper three address bits divide the space into areas P0 to P4, and the cache access methods can be specified for each area. For details, see section 3, Cache. Each area indicated by the remaining 29 bits is divided into ten areas (five areas are reserved) when address map 1 is selected or eight areas (three areas are reserved) when address map 2 is selected. The address map is selected by the MAP bit in CMNCR. The BSC controls the areas indicated by the 29 bits.

As listed in tables 7.2 and 7.3, memory can be connected directly to five physical areas of this LSI, and the chip select signals (CS0, CS3, CS4, CS5B, and CS6B) are output for each area. CS0 is asserted during area 0 access.



### **7.3.2 Shadow Area**

Areas 0, 3, 4, 5B, and 6B are divided by decoding physical address bits A28 to A25, which correspond to areas 000 to 111. Address bits 31 to 29 are ignored. This means that the range of area 0 addresses, for example, is H'00000000 to H'03FFFFFF, and its corresponding shadow space is the address space in P1 to P3 areas obtained by adding to it H'20000000  $\times$  n (n = 1 to 6).

The address range for area 7 is H'1C000000 to H'1FFFFFFF. The address space H'1C000000 + H'20000000  $\times$  n to H'1FFFFFFF + H'20000000  $\times$  n (n = 0 to 6) corresponding to the area 7 shadow spaces are reserved, so do not use it.

Area P4 (HE0000000 to HEFFFFFFF) is an I/O area and is allocated to internal register addresses. Therefore, area P4 does not become shadow space.



**Figure 7.2 Address Space** 

### **7.3.3 Address Map**

The external address space has a capacity of 256 Mbytes and is divided into five areas. Types of memory to be connected and the data bus width are specified for individual areas. The address map for the external address space is shown in table 7.2.



## **Table 7.2 Address Map 1 (CMNCR.MAP = 0)**

Note: \* Do not access the reserved area. If the reserved area is accessed, the correct operation cannot be guaranteed.

### **Table 7.3 Address Map 2 (CMNCR.MAP = 1)**







Notes: 1. Do not access the reserved area. If the reserved area is accessed, the correct operation cannot be guaranteed.

 2. For area 5, CS5BBCR and CS5BWCR are enabled. For area 6, CS6BBCR and CS6BWCR are enabled.

### **7.3.4 Area 0 Memory Type and Memory Bus Width**

The memory bus width in this LSI can be set for each area. In area 0, the bus width is selected from 8 bits and 16 bits at a power-on reset by the external pin setting. The bus width of other areas is set by the register. The correspondence between the memory type, external pin (MD3), and bus width is listed in table 7.4.

### **Table 7.4 Correspondence between External Pin (MD3), Memory Type, and Bus Width for CS0**



#### **7.3.5 Data Alignment**

This LSI supports the big endian and little endian methods of data alignment. The data alignment is specified using the external pin (MD5) at a power-on reset as shown in table 7.5.

### **Table 7.5 Correspondence between External Pin (MD5) and Endians**



# **7.4 Register Descriptions**

The BSC has the following registers. For the addresses and access size for these registers, see section 24, List of Registers.

Do not access spaces other than CS0 until setting the memory interfaces is complete.

- Common control register (CMNCR)
- CS0 space bus control register for area 0 (CS0BCR)
- CS3 space bus control register for area 3 (CS3BCR)
- CS4 space bus control register for area 4 (CS4BCR)
- CS5B space bus control register for area 5B (CS5BBCR)
- CS6B space bus control register for area 6B (CS6BBCR)
- CS0 space wait control register for area 0 (CS0WCR)
- CS3 space wait control register for area 3 (CS3WCR)
- CS4 space wait control register for area 4 (CS4WCR)
- CS5B space wait control register for area 5B (CS5BWCR)
- CS6B space wait control register for area 6B (CS6BWCR)
- SDRAM control register (SDCR)
- Refresh timer control/status register (RTCSR)
- Refresh timer counter (RTCNT)
- Refresh time constant register (RTCOR)



### **7.4.1 Common Control Register (CMNCR)**

CMNCR is a 32-bit register that controls the common items for each area. Do not access external memory other than area 0 until setting CMNCR is complete.





Note: \* The external pin (MD5) state for specifying endian is sampled at a power-on reset. When big endian is specified, this bit is read as 0 and when little endian is specified, this bit is read as 1.

### **7.4.2 CSn Space Bus Control Register (CSnBCR) (n = 0, 2, 3, 4, 5B, 6B)**

CSnBCR specifies the type of memory connected to each space, data-bus width of each space, and the number of wait cycles between access cycles.

Do not access external memory other than area 0 until setting CSnBCR is completed.

















### **7.4.3 CSn Space Wait Control Register (CSnWCR) (n = 0, 3, 4, 5B, 6B)**

CSnWCR specifies various wait cycles for memory accesses. The bit configuration of this register varies as shown below according to the memory type (TYPE3, TYPE2, TYPE1, or TYPE0) specified by the CSn space bus control register (CSnBCR). Specify CSnWCR before accessing the target area. Specify CSnBCR first, then specify CSnWCR.

#### **Normal Space, Byte-Selection SRAM:**

• CS0WCR







### • CS3WCR





### • CS4WCR











### • CS5BWCR







### • CS6BWCR







### **SDRAM:**

• CS3WCR









### **PCMCIA:**

### • CS5BWCR, CS6BWCR













### **7.4.4 SDRAM Control Register (SDCR)**

SDCR specifies the method to refresh and access SDRAM, and the types of SDRAMs to be connected.





### **7.4.5 Refresh Timer Control/Status Register (RTCSR)**

RTCSR specifies various items about refresh for SDRAM.

When RTCSR is written to, the upper 16 bits of the write data must be H'A55A to cancel write protection.










#### **7.4.6 Refresh Timer Counter (RTCNT)**

RTCNT is an 8-bit counter that increments using the clock selected by bits CKS2 to CKS0 in RTCSR. When RTCNT matches RTCOR, RTCNT is cleared to 0. The value in RTCNT returns to 0 after counting up to 255. When RTCNT is written to, the upper 16 bits of the write data must be H'A55A to cancel write protection.



#### **7.4.7 Refresh Time Constant Register (RTCOR)**

RTCOR is an 8-bit register. When RTCOR matches RTCNT, the CMF bit in RTCSR is set to 1 and RTCNT is cleared to 0. When the RFSH bit in SDCR is 1, a memory refresh request is issued. The request is maintained until the refresh operation is performed. If the request is not processed when the next matching occurs, the previous request is ignored.

When the RTCOR is written to, the upper 16 bits of the write data must be H'A55A to cancel write protection.





## **7.5 Operation**

#### **7.5.1 Endian/Access Size and Data Alignment**

This LSI supports big endian, in which the most significant byte (MSByte) of multiple byte data is stored in the lower address, and little endian, in which the least significant byte (LSByte) of multiple byte data is stored in the lower address. Endian is specified at a power-on reset by the external pin (MD5). When pin MD5 is driven low at a power-on reset, the endian will become big endian and when pin MD5 is driven high at a power-on reset, the endian will become little endian.

Three data bus widths (8, 16, and 32 bits) are available for normal memory and byte-selection SRAM. Two data bus widths (16 and 32 bits) are available for SDRAM. Two data bus widths (8 and 16 bits) are available for PCMCIA interface. Data alignment is performed in accordance with the data bus width of the device and endian. This also means that when longword data is read from a byte-width device, the read operation must be done four times. In this LSI, data alignment and conversion of data length is performed automatically between the respective interfaces.

Tables 7.6 to 7.11 show the relationship between endian, device data width, and access unit.



#### **Table 7.6 32-Bit External Device/Big Endian Access and Data Alignment**





## **Table 7.7 16-Bit External Device/Big Endian Access and Data Alignment**





## **Table 7.8 8-Bit External Device/Big Endian Access and Data Alignment**





## **Table 7.9 32-Bit External Device/Big Endian Access and Data Alignment**





## **Table 7.10 16-Bit External Device/Little Endian Access and Data Alignment**





## **Table 7.11 8-Bit External Device/Little Endian Access and Data Alignment**

#### **7.5.2 Normal Space Interface**

**Basic Timing:** For access to a normal space, this LSI uses strobe signal output in consideration of the fact that mainly static RAM will be directly connected. When using SRAM with a byteselection pin, see section 7.5.6, Byte-Selection SRAM Interface. Figure 7.3 shows the basic timings of normal space access. A no-wait normal access is completed in two cycles. The BS signal is asserted for one cycle to indicate the start of a bus cycle.



**Figure 7.3 Normal Space Basic Access Timing (No-Wait Access)** 

There is no output signal which informs external devices of the access size when reading. Although the least significant bit of the address indicates the correct address when the access starts, 16-bit data is always read from a 16-bit device. When writing, only the  $\overline{WEn}$  ( $\overline{BEn}$ ) signal for the byte to be written to is asserted.

When buffers are placed on the data bus, the RD signal should be used to control the buffers. The  $RD/\overline{WR}$  signal indicates the same state as a read cycle (driven high) when no access has been

carried out. Therefore, care must be taken when controlling the buffers with the  $RD/\overline{WR}$  signal, to avoid data conflict.

Figures 7.4 and 7.5 show the basic timings of normal space consecutive access. If the WM bit in CSnWCR is cleared to 0, a Tnop cycle is inserted to check the external wait (figure 7.4). If the WM bit in CSnWCR is set to 1, an external wait request is ignored and no Tnop cycle is inserted (figure 7.5).



**Figure 7.4 Consecutive Access to Normal Space (1): Bus Width = 16 bits, Longword Access, CSnWCR.WM = 0 (Access Wait = 0, Cycle Wait = 0)** 

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**Figure 7.5 Consecutive Access to Normal Space (2): Bus Width = 16 bits, Longword Access, CSnWCR.WM = 1 (Access Wait = 0, Cycle Wait = 0)** 







**Figure 7.6 Example of 32-Bit Data-Width SRAM Connection** 

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**Figure 7.7 Example of 16-Bit Data-Width SRAM Connection** 



**Figure 7.8 Example of 8-Bit Data-Width SRAM Connection** 



## **7.5.3 Access Wait Control**

Wait cycle insertion on a normal space access can be controlled by the settings of bits WR3 to WR0 in CSnWCR. It is possible for areas 4, 5A, and 5B to insert wait cycles independently in read access and in write access. The areas other than 4, 5A, and 5B have the same access wait for read cycle and write cycle. The specified number of Tw cycles is inserted as wait cycles in a normal space access shown in figure 7.9.



**Figure 7.9 Wait Timing for Normal Space Access (Software Wait Only)** 

When the WM bit in CSnWCR is cleared to 0, the external wait signal (WAIT) is also sampled. The  $\overline{WAIT}$  pin sampling is shown in figure 7.10. In this example, two wait cycles are inserted as software wait. The WAIT signal is sampled at the falling edge of the CKIO signal in the cycle immediately before the T2 cycle (T1 or Tw cycle).



Figure 7.10 Wait Cycle Timing for Normal Space Access (Wait cycle Insertion using  $\overline{WAIT}$ )



## **7.5.4 Extension of Chip Select (**CSn**) Assertion Period**

The number of cycles from  $\overline{CSn}$  assertion to  $\overline{RD}$  and  $\overline{WEn}$  ( $\overline{BEn}$ ) assertion can be specified by setting bits SW1 and SW0 in CSnWCR. The number of cycles from RD and WEn (BEn) negation to  $\overline{CSn}$  negation can be specified by setting bits HW1 and HW0. Therefore, a flexible interface to an external device can be obtained. Figure 7.11 shows an example. A Th cycle and a Tf cycle are added before and after a normal cycle, respectively. In these cycles, RD and WEn (BEn) are not asserted, while other signals are asserted. The data output is prolonged to the Tf cycle, and this prolongation is useful for devices with slow writing operations.



**Figure 7.11 Example of Timing when** CSn **Assertion Period is Extended** 

## **7.5.5 SDRAM Interface**

**SDRAM Direct Connection:** The SDRAM that can be connected to this LSI is a product that has 11/12/13 bits of row address, 8/9/10 bits of column address, 4 or less banks, and uses the A10 pin for setting precharge mode in read and write command cycles.

The control signals for direct connection of SDRAM are  $\overline{RAS}$ ,  $\overline{CAS}$ , RD/WR, DOMUU, DOMUL, DOMLU, DOMLL, CKE, and CS3. Signals other than CKE are valid when CS3 is asserted. SDRAM can be connected to area 2. The data bus width of the area that is connected to SDRAM can be set to 16 bits or 32 bits.

Burst read/single write (burst length 1) and burst read/burst write (burst length 1) are supported as the SDRAM operating mode.

Commands for SDRAM can be specified by  $\overline{RAS}$ ,  $\overline{CAS}$ ,  $\overline{RAN}$ , and specific address signals. These commands are shown below.

- NOP
- Auto-refreshing (REF)
- Self-refreshing (SELF)
- All banks precharge (PALL)
- Specified bank precharge (PRE)
- Bank active (ACTV)
- Read (READ)
- Read with precharge (READA)
- Write (WRIT)
- Write with precharge (WRITA)
- Write mode register (MRS)

The byte to be accessed is specified by DQMUU, DQMUL, DQMLU and DQMLL. Reading or writing is performed for a byte whose corresponding DQMxx is low. For details on the relationship between DQMxx and the byte to be accessed, refer to section 7.5.1, Endian/Access Size and Data Alignment.





Figures 7.12 and 7.13 show an example of the connection of the SDRAM with the LSI.

**Figure 7.12 Example of 32-Bit Data-Width SDRAM Connection** 



**Figure 7.13 Example of 16-Bit Data-Width SDRAM Connection** 

**Address Multiplexing:** An address multiplexing is specified so that SDRAM can be connected without external multiplexing circuitry according to the setting of bits BSZ1 and BSZ0 in CSnBCR, AnROW1 and AnROW0 and AnCOL1 AnCOL0 in SDCR. Tables 7.12 to 7.17 show the relationship between those settings and the bits output on the address pins. Do not specify those bits in the manner other than this table, otherwise the operation of this LSI is not guaranteed. A25 to A18 are not multiplexed and the original values of address are always output on these pins.

When the data bus width is 16 bits  $(BSZ[1:0] = B'10)$ , pin A0 of SDRAM specifies a word address. Therefore, connect this A0 pin of SDRAM to pin A1 of this LSI; pin A1 pin of SDRAM to pin A2 of this LSI, and so on. When the data bus width is 32 bits  $(BSZ[1:0] = B'11)$ , pin A0 of SDRAM specifies a long word address. Therefore, connect this A0 pin of SDRAM to pin A2 of this LSI; pin A1 pin of SDRAM to pin A3 of this LSI, and so on.



## **Table 7.12 Relationship between Register Settings (BSZ[1:0], A3ROW[1:0], and A3COL[1:0]) and Address Multiplex Output (1)**





Notes: 1. L/H is a bit used in the command specification; it is fixed low or high according to the access mode.

- 2. Bank address specification
- 3. Applicable only to a 64-Mbit product

#### **Table 7.13 Relationship between Register Settings (BSZ[1:0], A3ROW[1:0], and A3COL[1:0]) and Address Multiplex Output (2)**





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access mode.

2. Bank address specification

#### **Table 7.14 Relationship between Register Settings (BSZ[1:0], A3ROW[1:0], and A3COL[1:0]) and Address Multiplex Output (3)**



One 512-Mbit product (4 Mwords x 32 bits x 4 banks, 9-bit column product)

Two 256-Mbit products (4 Mwords x 16 bits x 4 banks, 9-bit column product)

Notes: 1. L/H is a bit used in the command specification; it is fixed low or high according to the access mode.

2. Bank address specification

#### **Table 7.15 Relationship between Register Settings (BSZ[1:0], A3ROW[1:0], and A3COL[1:0]) and Address Multiplex Output (4)**





Notes: 1. L/H is a bit used in the command specification; it is fixed low or high according to the access mode.

2. Bank address specification

## **Table 7.16 Relationship between Register Settings (BSZ[1:0], A3ROW[1:0], and A3COL[1:0]) and Address Multiplex Output (5)**







Notes: 1. L/H is a bit used in the command specification; it is fixed low or high according to the access mode.

2. Bank address specification

#### **Table 7.17 Relationship between Register Settings (BSZ[1:0], A3ROW[1:0], and A3COL[1:0]) and Address Multiplex Output (6)**







Notes: 1. L/H is a bit used in the command specification; it is fixed low or high according to the access mode.

2. Bank address specification

**Burst Read:** A burst read occurs in the following cases with this LSI.

- 1. Access size in reading is larger than data bus width.
- 2. 16-byte transfer in cache miss.
- 3. 16-byte transfer by DMAC and E-DMAC (access to non-cacheable area)

This LSI always accesses the SDRAM with burst length 1. For example, read access of burst length 1 is performed consecutively four times to read 16-byte consecutive data from the SDRAM that is connected to a 32-bit data bus. The number of bursts in this access is four.



<b>Bus Width</b>	<b>Access Size</b>	<b>Number of Bursts</b>
16 bits	8 bits	
	16 bits	
	32 bits	2
	16 bytes	8
32 bits	8 bits	
	16 bits	
	32 bits	
	16 bytes	4

Table 7.18 shows the relationship between the access size and the number of bursts.

**Table 7.18 Relationship between Access Size and Number of Bursts** 

Figures 7.14 and 7.15 show timing charts in burst read. In burst read, the ACTV command is output in the Tr cycle, the READ command is issued in the Tc1, Tc2, and Tc3 cycles, the READA command is issued in the Tc4 cycle, and the read data is latched at the rising edge of the external clock (CKIO) in the Td1 to Td4 cycles. The Tap cycle is used to wait for the completion of an auto-precharge induced by the READ command in the SDRAM. In the Tap cycle, a new command will not be issued to the same bank. However, other banks can be accessed. The number of Tap cycles is specified by bits WTRP1 and WTRP0 in CS3WCR.

In this LSI, wait cycles can be inserted by specifying bits in CSnWCR to connect the SDRAM with variable frequencies. Figure 7.15 shows an example in which wait cycles are inserted. The number of cycles from the Tr cycle where the ACTV command is output to the Tc1 cycle where the READA command is output can be specified using bits WTRCD1 and WTRCD0 in CS3WCR. When bits WTRCD1 and WTRCD0 is set to one cycle or more, a Trw cycle where the NOP command is issued is inserted between the Tr cycle and Tc1 cycle. The number of cycles from the Tc1 cycle where the READA command is output to the Td1 cycle where the read data is latched can be specified by bits A3CL1 and A3CL0 bits in CS3WCR in CS3WCR. This number of cycles corresponds to the synchronous DRAM CAS latency. The CAS latency for the synchronous DRAM is normally defined as up to three cycles. However, the CAS latency in this LSI can be specified as one to four cycles. This CAS latency can be achieved by connecting a latch circuit between this LSI and the synchronous DRAM.







**Figure 7.14 Burst Read Basic Timing (Auto Precharge)** 





**Figure 7.15 Burst Read Wait Specification Timing (Auto Precharge)** 



**Single Read:** A read access ends in one cycle when data exists in non-cacheable area and the data bus width is larger than or equal to access size. Since the burst length is set to 1 in synchronous DRAM burst read/single write mode, only the required data is output. Consequently, no unnecessary bus cycles are generated even when a cache-through area is accessed.

Figure 7.16 shows the single read basic timing.



**Figure 7.16 Basic Timing for Single Read (Auto Precharge)** 

**Burst Write:** A burst write occurs in the following cases in this LSI.

- 1. Access size in writing is larger than data bus width.
- 2. Write-back of the cache
- 3. 16-byte transfer by DMAC and E-DMAC (access to non-cacheable area)

This LSI always accesses SDRAM with burst length 1. For example, write access of burst length 1 is performed consecutively four times to write 16-byte consecutive data to the SDRAM that is connected to a 32-bit data bus. The relationship between the access size and the number of bursts is shown in table 7.18.

Figure 7.17 shows a timing chart for burst writes. In burst write, the ACTV command is output in the Tr cycle, the WRIT command is issued in the Tc1, Tc2, and Tc3 cycles, and the WRITA command is issued to execute an auto-precharge in the Tc4 cycle. In the write cycle, the write data is output simultaneously with the write command. After the write command with the autoprecharge is output, the Trw1 cycle that waits for the auto-precharge initiation is followed by the Tap cycle that waits for completion of the auto-precharge induced by the WRITA command in the SDRAM. In the Tap cycle, a new command will not be issued to the same bank. However, other CS areas and other banks can be accessed. The number of Trw1 cycles is specified by bits TRWL1 and TRWL0 in CS3WCR. The number of Tap cycles is specified by bits WTRP1 and WTRP0 in CS3WCR.



**Figure 7.17 Basic Timing for Burst Write (Auto Precharge)** 



**Single Write:** A write access ends in one cycle when data is written in non-cacheable area and the data bus width is larger than or equal to access size.

Figure 7.18 shows the single write basic timing.



**Figure 7.18 Basic Timing for Single Write (Auto-Precharge)** 

**Bank Active:** The synchronous DRAM bank function is used to support high-speed accesses to the same row address. When the BACTV bit in SDCR is 1, accesses are performed using commands without auto-precharge (READ or WRIT). This function is called bank-active function.

When a bank-active function is used, precharging is not performed when the access ends. When accessing the same row address in the same bank, it is possible to issue the READ or WRIT command immediately, without issuing an ACTV command. Since synchronous DRAM is internally divided into several banks, it is possible to keep one row address in each bank activated. If the next access is to a different row address, a PRE command is first issued to precharge the relevant bank, then when precharging is completed, the access is performed by issuing an ACTV command followed by a READ or WRIT command. If this is followed by an access to a different row address, the access time will be longer because of the precharging performed after the access request is issued. The number of cycles between issuance of the PRE command and the ACTV command is determined by bits WTRP1 and WTRP0 in CSnWCR.

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In a write access, when an auto-precharge is performed, a command cannot be issued to the same bank for a period of Trwl + Tap cycles after issuance of the WRITA command. When bank active mode is used, READ or WRIT command can be issued successively if the row address is the same. The number of cycles can thus be reduced by Trwl + Tap cycles for each write.

There is a limit on tRAS, the time for placing each bank in the active state. If there is no guarantee that another row address will be accessed within the period in which this value is maintained by program execution, it is necessary to set auto-refreshing and set the refresh cycle to no more than the maximum value of tRAS.

A burst read cycle without auto-precharge is shown in figure 7.19, a burst read cycle for the same row address in figure 7.20, and a burst read cycle for different row addresses in figure 7.21. Likewise, a single write cycle without auto-precharge is shown in figure 7.22, a single write cycle for the same row address in figure 7.23, and a single write cycle for different row addresses in figure 7.24.

In figure 7.20, a Tnop cycle in which no operation is performed is inserted before the Tc cycle that issues the READ command. The Tnop cycle is inserted to secure two cycles of CAS latency for the DQMxx signal that specifies which byte data is read from SDRAM. If the CAS latency is specified as two cycles or more, the Tnop cycle is not inserted because the two cycles of latency can be secured even if the DQMxx signal is asserted after the Tc cycle.

When bank active mode is set, if only accesses to the respective banks in the area 3 are considered, as long as accesses to the same row address continue, the operation starts with the cycle in figure 7.19 or 7.22, followed by repetition of the cycle in figure 7.20 or 7.23. An access to a different area during this time has no effect. When a different row address is accessed in the bank active state, the bus cycle shown in figure 7.21 or 7.24 is executed instead of that in figure 7.20 or 7.23. In bank active mode, too, all banks become inactive after a refresh cycle.





**Figure 7.19 Burst Read Timing (No Auto Precharge)** 

Section 7 Bus State Controller (BSC)




**Figure 7.20 Burst Read Timing (Bank Active, Same Row Address)** 







**Figure 7.21 Burst Read Timing (Bank Active, Different Row Addresses)** 





**Figure 7.22 Single Write Timing (No Auto Precharge)** 





**Figure 7.23 Single Write Timing (Bank Active, Same Row Address)** 





**Figure 7.24 Single Write Timing (Bank Active, Different Row Addresses)** 

**Refreshing:** This LSI has a function for controlling synchronous DRAM refreshing. Autorefreshing can be performed by clearing the RMODE bit to 0 and setting the RFSH bit to 1 in SDCR. A consecutive refreshing can be performed by setting bits RRC2 to RRC0 in RTCSR. If synchronous DRAM is not accessed for a long period, self-refreshing mode, in which the power consumption for data retention is low, can be activated by setting both the RMODE bit and the RFSH bit to 1.

1. Auto-refreshing

Refreshing is performed at intervals determined by the input clock selected by bits CKS2 to CKS0 in RTCSR, and the value set by in RTCOR. The value of bits CKS[2:0] in RTCOR should be set so as to satisfy the given refresh interval for the synchronous DRAM used. First make the settings for RTCOR, RTCNT, and the RMODE, then make the CKS[2:0] and RRC[2:0] settings. When the clock is selected by bits CKS[2:0], RTCNT starts counting up from the value at that time. The RTCNT value is constantly compared with the RTCOR value, and if the two values are the same, a refresh request is generated and an auto-refreshing is performed for the number of times specified by the RRC[2:0]. At the same time, RTCNT is cleared to 0 and the count-up is restarted.



Figure 7.25 shows the auto-refreshing cycle timing. After starting the auto-refreshing, PALL command is issued in the Tp cycle to make all the banks to precharged state from active state when some bank is being precharged. Then the REF command is issued in the Trr cycle after inserting idle cycles of which number is specified by bits WTRP1 and WTRP0 in CSnWCR. A new command is not issued for the duration of the number of cycles specified by bits WTRC1 and WTRC0 in CSnWCR after the Trr cycle. Bits WTRC1 and WTRC0 in CSnWCR must be set so as to satisfy the SDRAM refreshing cycle time (tRC). A Tpw cycle is inserted between the Tp cycle and Trr cycle when the setting of bits WTRP1 and WTRP0 in CSnWCR is longer than or equal to two cycles.



**Figure 7.25 Auto-Refreshing Timing** 

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### 2. Self-refreshing

When self-refreshing mode is selected, the refresh timing and refresh addresses are generated within the synchronous DRAM. Self-refreshing is activated by setting both the RMODE bit and the RFSH bit in SDCR to 1. After starting the self-refreshing, the PALL command is issued in the Tp cycle after the completion of pre-charging the bank. The SELF command is then issued after inserting idle cycles of which the number is specified by bits WTRP1 and WTRP0 in CSnWSR. Synchronous DRAM cannot be accessed while self-refreshing. Selfrefreshing mode is cleared by clearing the RMODE bit to 0. After self-refreshing mode has been cleared, command issuance is disabled for the number of cycles specified by bits WTRC1 and WTRC0 in CSnWCR.

Self-refreshing timing is shown in figure 7.26. Settings must be made immediately after clearing self-refreshing mode so that auto-refreshing is performed at the correct intervals. When self-refreshing is activated from the auto-refreshing mode, only clearing the RMODE bit to 1 resumes auto-refreshing mode. If it takes long time to start the auto-refreshing, setting RTCNT to the value of  $RTCOR - 1$  starts the auto-refreshing immediately.

After self-refreshing has been set, the self-refreshing mode continues even in standby mode, and is maintained even after recovery from standby mode by an interrupt.

Since the BSC registers are initialized at a power-on reset, the self-refreshing mode is cleared.





**Figure 7.26 Self-Refreshing Timing** 

**Relationship between Refresh Requests and Bus Cycles:** If a refresh request occurs during bus cycle execution, the refresh cycle must wait for the bus cycle to be completed.

If a new refresh request occurs while the previous refresh request is not performed, the previous refresh request is deleted. To refresh correctly, a bus cycle longer than the refresh interval or the bus busy must be prevented.

**Power-On Sequence:** In order to use synchronous DRAM, mode setting must first be performed after turning the power on. To perform synchronous DRAM initialization correctly, the BSC registers must first be set, followed by writing to the synchronous DRAM mode register. When writing to the synchronous DRAM mode register, the address signal value at that time is latched by a combination of the CSn, RAS, CAS, and RD/WR signals. If the value to be set is X, write to the address of H'F8FD5000  $+ X$  in words. In this operation, the data is ignored. To set burst read/single write, burst read/burst write, CAS latency 2 to 3, wrap type = sequential, and burst length 1 supported by the LSI, arbitrary data is written to the addresses shown in table 7.19 in bytes. In this case, 0s are output at the external address pins of A12 or later.

#### **Table 7.19 Access Address for SDRAM Mode Register Write**



• Burst read/single write (burst length 1)

• Burst read/burst write (burst length 1)



Mode register setting timing is shown in figure 7.27. The PALL command (all bank precharge command) is firstly issued. The REF command (auto-refreshing command) is then issued eight times. The MRS command (mode register write command) is finally issued. Idle cycles, of which number is specified by bits WTRP1 and WTRP0 in CSnWCR, are inserted between the PALL and the first REF commands. Idle cycles, of which number is specified by bits WTRC1 and WTRC0 in CSnWCR, are inserted between the REF and REF commands, and between the 8th REF and MRS commands. In addition, one or more idle cycles are inserted between the MRS and the next command.

It is necessary to keep idle time of certain cycles for SDRAM before issuing the PALL command after turning the power on. Refer the manual of the SDRAM for the idle time to be needed. When the pulse width of the reset signal is longer then the idle time, mode register setting can be started immediately after the reset, but care should be taken when the pulse width of the reset signal is shorter than the idle time.







**Figure 7.27 Write Timing for SDRAM Mode Register (Based on JEDEC)** 

# **7.5.6 Byte-Selection SRAM Interface**

The byte-selection SRAM interface is for access to SRAM which has a byte-selection pin (WEn (BEn)). This interface is used to access to SRAM which has 16-bit data pins and upper and lower byte selection pins, such as UB and LB.

When the BAS bit in CSnWCR is cleared to 0 (initial value), the write access timing of the byteselection SRAM interface is the same as that for the normal space interface. While in read access of a byte-selection SRAM interface, the byte-selection signal is output from the WEn (BEn) pin, which is different from that for the normal space interface. The basic access timing is shown in figure 7.28. In write access, data is written to the memory according to the timing of the byteselection pin (WEn (BEn)). For details, refer to the data sheet for the corresponding memory.

If the BAS bit in CSnWCR is set to 1, the  $\overline{WEn}$  ( $\overline{BEn}$ ) pin and RD/ $\overline{WR}$  pin timings change. The basic access timing is shown in figure 7.29. In write access, data is written to the memory according to the timing of the write enable pin (RD/WR). The data hold timing from RD/WR negation to data write must be secured by setting bits HW1 to HW0 in CSnWCR. Figure 7.30 shows the access timing when a software wait is specified.



**Figure 7.28 Basic Access Timing for Byte-Selection SRAM (BAS = 0)** 







**Figure 7.29 Basic Access Timing for Byte-Selection SRAM (BAS = 1)** 





**Figure 7.30 Wait Timing for Byte-Selection SRAM (BAS = 1) (Software Wait Only)** 







**Figure 7.31 Example of Connection with 32-Bit Data-Width Byte-Selection SRAM** 



**Figure 7.32 Example of Connection with 16-Bit Data-Width Byte-Selection SRAM** 

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## **7.5.7 PCMCIA Interface**

With this LSI, if address map 2 is selected using the MAP bit in CMNCR, the PCMCIA interface can be specified in areas 5 and 6. Areas 5 and 6 in the physical space can be used for the IC memory card and I/O card interface defined in the JEIDA specifications version 4.2 (PCMCIA2.1 Rev. 2.1) by specifying bits TYPE3 to TYPE0 in CSnBCR ( $n = 5B$  and  $6B$ ) to B'0101. In addition, bits SA1 and SA0 in CSnWCR ( $n = 5B$  and 6B) assign the upper or lower 32 Mbytes of each area to an IC memory card or I/O card interface. For example, if bits SA1 and SA0 in CS5BWCR are set to 1 and cleared to 0, respectively, the upper 32 Mbytes and the lower 32 Mbytes of area 5B are used as an IC memory card interface and I/O card interface, respectively.

When the PCMCIA interface is used, the bus size must be specified as 8 bits or 16 bits using bits BSZ1 and BSZ0 in CS5BBCR or CS6BBCR.

Figure 7.33 shows an example of a connection between this LSI and the PCMCIA card. To enable insertion and removal of the PCMCIA card with the system power turned on, tri-state buffers must be connected between the LSI and the PCMCIA card.

In the JEIDA and PCMCIA standards, operation in big endian mode is not clearly defined. Consequently, the provided PCMCIA interface in big endian mode is available only for this LSI.







**Figure 7.33 Example of PCMCIA Interface Connection** 



**Basic Timing for Memory Card Interface:** Figure 7.34 shows the basic timing of the PCMCIA IC memory card interface. If areas 5 and 6 in the physical space are specified as the PCMCIA interface, accessing the common memory areas in areas 5 and 6 automatically accesses with the IC memory card interface. If the external bus frequency (CKIO) increases, the setup times and hold times for the address pins (A25 to A0), card enable signals (CE1A, CE2A, CE1B, CE2B), and write data (D15 to D0) to the RD and WE signals become insufficient. To prevent this error, this LSI can specify the setup times and hold times for areas 5 and 6 in the physical space independently, using CS5BWCR and CS6BWCR. In the PCMCIA interface, as in the normal space interface, a software wait or hardware wait can be inserted using the WAIT pin. Figure 7.35 shows the PCMCIA memory bus wait timing.



**Figure 7.34 Basic Access Timing for PCMCIA Memory Card Interface** 







**Figure 7.35 Wait Timing for PCMCIA Memory Card Interface (TED[3:0] = B'0010, TEH[3:0] = B'0001, Software Wait = 1, Hardware Wait = 1)** 

When 32 Mbytes of the memory space are used as an IC memory card interface, a port is used to generate the REG signal that switches between the common memory and attribute memory. When the memory space used for the IC memory card interface is 16 Mbytes or less, pin A24 can be used as the  $\overline{\text{REG}}$  signal by allocating 16-Mbyte memory space to each the common memory space and the attribute memory space.





**Figure 7.36 Example of PCMCIA Space Assignment (CS5BWCR.SA[1:0] = B'10, CS6BWCR.SA[1:0] = B'10)** 

**Basic Timing for I/O Card Interface:** Figures 7.37 and 7.38 show the basic timings for the PCMCIA I/O card interface.

The I/O card and IC memory card interfaces are specified by an address to be accessed. When area 5 of the physical space is specified as the PCMCIA and both bits SA1 and SA0 in CS5BWCR are set to 1, the I/O card interface can automatically be specified by accessing the physical addresses from H'16000000 to H'17FFFFFF and from H'14000000 to H'15FFFFFF. When area 6 of the physical space is specified as the PCMCIA and both bits SA1 and SA0 in CS6BWCR are set to 1, the I/O card interface can automatically be specified by accessing the physical addresses from H'1A000000 to H'1BFFFFFF and from H'18000000 to H'19FFFFFF.

Note that areas to be accessed as the PCMCIA I/O card must be non-cached (space P2).

If the PCMCIA card is accessed as an I/O card in little endian mode, dynamic bus sizing for the I/O bus can be achieved using the IOIS16 signal. If the IOIS16 signal is driven high in a word-size I/O bus cycle while the bus width of area 6 is specified as 16 bits, the bus width is recognized as 8 bits and data is accessed twice in units of eight bits in the I/O bus cycle to be executed.



The IOIS16 signal is sampled at the falling edge of the CKIO signal in the Tpci0, Tpci0w, and Tpci1 cycles when bits TED3 to TED0 are specified as 1.5 cycles or more, and is reflected in the CE2 signal 1.5 cycles after the CKIO sampling point. Bits TED3 to TED0 must be specified appropriately to satisfy the setup time of the PC card from ICIORD and ICIOWR to CEn.

Figure 7.39 shows the dynamic bus sizing basic timing.

Note that the  $\overline{IOIS16}$  signal is not supported in big endian mode. In the big endian mode, the IOIS16 signal must be fixed low.



**Figure 7.37 Basic Timing for PCMCIA I/O Card Interface** 



**Figure 7.38 Wait Timing for PCMCIA I/O Card Interface (TED[3:0] = B'0010, TEH[3:0] = B'0001, Software Wait = 1, Hardware Wait = 1)** 



**Figure 7.39 Timing for Dynamic Bus Sizing of PCMCIA I/O Card Interface (TED[3:0] = B'0010, TEH[3:0] = B'0001, Software Waits = 3)** 



### **7.5.8 Wait between Access Cycles**

Data output in the previous cycle may conflict with that in the next cycle because the buffer-off timing of devices with slow access speed cannot be operated to satisfy the higher operating frequency of LSIs. As a result of these conflict, the reliability of the device is low and malfunctions may occur. This LSI has a function that avoids data conflicts by inserting wait cycles between consecutive access cycles.

The number of wait cycles between access cycles can be set by bits IWW1 and IWW0, bits IWRWD1 and IWRWD0, bits IWRWS1 and IWRWS0, bits IWRRD1 and IWRRD0, and bits IWRRS1 and IWRRS0 in CSnBCR. The conditions for setting the wait cycles between access cycles (idle cycles) are shown below.

- 1. Consecutive accesses are write-read or write-write
- 2. Consecutive accesses are read-write for different areas
- 3. Consecutive accesses are read-write for the same area
- 4. Consecutive accesses are read-read for different areas
- 5. Consecutive accesses are read-read for the same area

### **7.5.9 Others**

**Reset:** The bus state controller (BSC) can be initialized completely only by a power-on reset. At power-on reset, all signals are negated and output buffers are turned off regardless of the bus cycle state. All control registers are initialized. In standby mode and sleep mode, control registers of the BSC are not initialized.

Some flash memories may stipulate a minimum time from reset release to the first access. To ensure this minimum time, the BSC supports a 7-bit counter (RWTCNT). At a power-on reset, the RWTCNT contents are cleared to 0. After a power-on reset, RWTCNT is counted up in synchronization with the CKIO signal and an external access will not be generated until RWTCNT is counted up to H'007F.

**Access from the Site of the LSI Internal Bus Master:** There are three types of LSI internal buses: a cache bus, internal bus, and peripheral bus. The CPU and cache memory are connected to the cache bus. Internal bus masters other than the CPU and BSC are connected to the internal bus. Low-speed peripheral modules are connected to the peripheral bus. Internal memory other than the cache memory and debugging modules such as the UBC are connected to both the cache bus and internal bus. Access from the cache bus to the internal bus is enabled but access from the internal bus to the cache bus is disabled. This gives rise to the following problems.



Internal bus masters other than the CPU such as the DMAC and E-DMAC can access on-chip memory other than the cache memory but cannot access the cache memory. If an on-chip bus master other than the CPU writes data to an external memory other than the cache, the contents of the external memory may differ from that of the cache memory. To prevent this problem, if the external memory whose contents is cached is written by an on-chip bus master other than the CPU, the corresponding cache memory should be purged by software.

If the CPU initiates read access for the cache, the cache is searched. If the cache stores data, the CPU latches the data and completes the read access. If the cache does not store data, the CPU performs four consecutive longword read cycles to perform cache fill operations via the internal bus. If a cache miss occurs in byte or word operand access or at a branch to an odd word boundary  $(4n + 2)$ , the CPU performs four consecutive longword accesses to perform a cache fill operation on the external interface. For a cache-through area, the CPU performs access according to the actual access addresses. For an instruction fetch to an even word boundary (4n), the CPU performs longword access. For an instruction fetch to an odd word boundary  $(4n + 2)$ , the CPU performs word access.

For a read cycle of a cache-through area or an on-chip peripheral module, the read cycle is first accepted and then read cycle is initiated. The read data is sent to the CPU via the cache bus.

In a write cycle for the cache area, the write cycle operation differs according to the cache write methods.

In write-back mode, the cache is first searched. If data is detected at the address corresponding to the cache, the data is then re-written to the cache. In the actual memory, data will not be re-written until data in the corresponding address is re-written. If data is not detected at the address corresponding to the cache, the cache is updated. In this case, data to be updated is first saved to the internal buffer, 16-byte data including the data corresponding to the address is then read, and data in the corresponding access of the cache is finally updated. Following these operations, a write-back cycle for the saved 16-byte data is executed.

In write-through mode, the cache is first searched. If data is detected at the address corresponding to the cache, the data is re-written to the cache simultaneously with the actual write via the internal bus. If data is not detected at the address corresponding to the cache, the cache is not updated but an actual write is performed via the internal bus.

Since the BSC incorporates a 1-stage write buffer, the BSC can execute an access via the internal bus before the previous external bus cycle is completed in a write cycle. If the on-chip module is read or written after the external low-speed memory is written, the on-chip module can be accessed before the completion of the external low-speed memory write cycle.



In read cycles, the CPU is placed in the wait cycle until read operation has been completed. To continue the process after the data write to the device has been completed, perform a dummy read to the same address to check for completion of the write before the next process to be executed.

The write buffer of the BSC functions in the same way for an access by a bus master other than the CPU such as the DMAC or E-DMAC. Accordingly, to perform dual address DMA transfers, the next read cycle is initiated before the previous write cycle is completed. Note, however, that if both the DMA source and destination addresses exist in external memory space, the next write cycle will not be initiated until the previous write cycle is completed.

**On-Chip Peripheral Module Access:** To access an on-chip module register, two or more peripheral module clock (Pφ) cycles are required. Care must be taken in system design.



# Section 8 Clock Pulse Generator (CPG)

This LSI has a clock pulse generator (CPG) that generates an internal clock (Iφ), a peripheral clock  $(P\phi)$ , a bus clock  $(B\phi)$ , and a clock  $(M\phi)$  for the on-chip IEEE802.3-PHY (physical layer device, hereinafter called PHY). The CPG consists of an oscillator, PLL circuits, and divider circuits.

# **8.1 Features**

• Four clock modes

Selection of four clock modes depending on the frequency of a clock source and whether a crystal resonator or external clock input is in use.

• Four clocks generated independently

An internal clock  $(I\phi)$  for the CPU and cache; a peripheral clock  $(P\phi)$  for the on-chip peripheral modules; a bus clock ( $B\phi = CKIO$ ) for the external bus interface; and a clock ( $M\phi$ ) for the on-chip PHY.

• Frequency change function

Frequencies of the internal clock, peripheral clock, and clock for the PHY can be changed independently using the PLL circuit and divider circuit within the CPG. Frequencies are changed by software using the frequency control register (FRQCR) and PHY clock frequency control register (MCLKCR) settings.

• Power-down mode control

The clock can be stopped in sleep mode and software standby mode and specific modules can be stopped using the module standby function.



A block diagram of the CPG is shown in figure 8.1.



**Figure 8.1 Block Diagram of CPG** 



The clock pulse generator blocks function as follows:

**PLL Circuit 1:** PLL circuit 1 leaves the input clock frequency from the PLL circuit 2 unchanged or doubles it. The multiplication ratio is set by the frequency control register. The phase of the rising edge of the internal clock is controlled so that it will match the phase of the rising edge of the CKIO pin.

**PLL Circuit 2:** PLL circuit 2 doubles or quadruples the clock frequency input from the crystal oscillator or the EXTAL pin. The multiplication ratio is fixed for each clock operating mode. The clock operating mode is set with pins MD0, MD1, or MD2.

**Crystal Oscillator:** The crystal oscillator is an oscillator circuit when a crystal resonator is connected to the XTAL and EXTAL pins. The crystal oscillator can be used by setting the clock operating mode.

**Divider 1:** Divider 1 generates clocks with the frequencies used by the internal clock, peripheral clock, and bus clock. The frequency output as the internal clock is always the same as that of the devider1 output. The frequency output as the bus clock is automatically selected so that it is the same as the frequency of the CKIO signal according to the multiplication ratio of PLL circuit 1. The frequencies can be 1, 1/2, or 1/4 times the output frequency of PLL circuit 1, as long as it stays at or above the frequency of the CKIO pin. The division ratio is set in the frequency control register.

**Divider 2:** Divider 2 generates a clock that is supplied to the on-chip PHY. Divider 2 must output 25-MHz frequency for the on-chip PHY that requires 25-MHz clock. The output clock of divider 2 can be 1, 1/2, 1/4, or 1/5 times the output frequency of PLL circuit 1. The division ratio is set in the PHY clock frequency control register.

**Clock Frequency Control Circuit:** The clock frequency control circuit controls the clock frequency using pins MD0, MD1, and MD2, the frequency control register, and PHY clock frequency control register.

**Standby Control Circuit:** The standby control circuit controls the state of the on-chip oscillator circuit and other modules during clock switching and in software standby mode.

**Frequency Control Register:** The frequency control register has control bits assigned for the following functions: clock output/non-output from the CKIO pin, the frequency multiplication ratio of PLL circuit 1, and the frequency division ratio of the peripheral clock.

**Standby Control Register:** The standby control register has bits for controlling the power-down modes. For details, see section 10, Power-Down Modes.

**PHY Clock Frequency Control Register:** The PHY clock frequency control register sets the frequency division ratio of the PHY clock.

# **8.2 Input/Output Pins**

Table 8.1 shows the CPG pin configuration.



Clock output pin CKIO Output Outputs an external clock.

### **Table 8.1 Pin Configuration**

Note:  $*$  The values of these mode control pins are sampled only at a power-on reset or in a software standby with the MDCHG bit in STBCR to 1. This can prevent the erroneous operation of this LSI.

# **8.3 Clock Operating Modes**

Table 8.2 shows the relationship between the mode control pins (MD2 to MD0) combinations and the clock operating modes. Table 8.3 shows the usable frequency ranges in the clock operating modes and the frequency range of the input clock.

#### **Table 8.2 Mode Control Pins and Clock Operating Modes**



**Mode 1:** The frequency of the external clock input from the EXTAL pin is quadrupled by PLL circuit 2, and then the clock is supplied to this LSI. Since the input clock frequency ranging 10 MHz to 15.625 MHz can be used, the CKIO frequency ranges from 40 MHz to 62.5 MHz.

**Mode 2:** The frequency of the on-chip crystal oscillator output is quadrupled by PLL circuit 2, and then the clock is supplied to this LSI. Since the crystal resonator frequency ranging 10 MHz to 15.625 MHz can be used, the CKIO frequency ranges from 40 MHz to 62.5 MHz.

**Mode 5:** The frequency of the external clock from the EXTAL pin is doubled by PLL circuit 2, and then the clock is supplied to this LSI. Since the input clock frequency ranging 10 MHz to 25 MHz, the CKIO frequency ranges from 20 MHz to 50 MHz.

**Mode 6:** The frequency of the on-chip crystal oscillator output is doubled by PLL circuit 2, and then the clock is supplied to the LSI. Since the crystal oscillation frequency ranging 10 MHz to 25 MHz can be used, the CKIO frequency ranges from 20 MHz to 50 MHz.





Note:  $*$  Input clock is assumed to be 1.



### **Cautions:**

- 1. The internal clock frequency is the product of the frequency of the CKIO pin and the frequency multiplication ratio of PLL circuit 1.
- 2. The peripheral clock frequency is the product of the frequency of the CKIO pin, the frequency multiplication ratio of PLL circuit 1, and the division ratio of divider 1. Do not set the peripheral clock frequency lower than the CKIO pin frequency.
- 3. The PHY clock frequency is the product of the frequency of the CKIO pin, the frequency multiplication ratio of PLL circuit 1, and the division ratio of divider 2.
- 4.  $\times$ 1,  $\times$ 1/2, or  $\times$ 1/4 can be used as the division ratio of divider 1. This is set by the frequency control register.
- 5. The division ratio of divider 2 is selected from  $\times$ 1,  $\times$ 1/2,  $\times$ 1/4, or  $\times$ 1/5. This is set by the PHY clock frequency control register.
- 6. The output frequency of PLL circuit 1 is the product of the frequency of the CKIO pin and the multiplication ratio of PLL circuit 1. It is set by the frequency control register.
- 7. The bus clock frequency is always set to be equal to the frequency of the CKIO pin.
- 8. The clock mode, the FRQCR register value, and the frequency of the input clock should be decided to satisfy the range of operating frequency specified in section 25, Electrical Characteristics, with referring to table 8.3.

# **8.4 Register Descriptions**

The CPG has the following registers.

For details on the addresses of these registers and the states of these registers in each processing state, see section 24, List of Registers.

- Frequency control register (FRQCR)
- PHY clock frequency control register (MCLKCR)

# **8.4.1 Frequency Control Register (FRQCR)**

FRQCR is a 16-bit readable/writable register that specifies whether a clock is output from the CKIO pin in standby mode, the frequency multiplication ratio of PLL circuit 1, and the frequency division ratio of the peripheral clock. Only word access can be used on FRQCR.

FRQCR is initialized by a power-on reset due to the external input signal. However, it is not initialized by a power-on reset due to a WDT overflow.







### **8.4.2 PHY Clock Frequency Control Register (MCLKCR)**

MCLKCR is an 8-bit readable/writable register. This register must be written to in words. The upper byte of the word data must be H'5A and the lower byte is the write data.



#### **8.4.3 Usage Notes**

- MCLKCR is used only to generate clocks for the on-chip PHY. However, dedicated clocks input from the CK\_PHY pin can be used instead of Mφ, which is set by MCLKCR as clocks for the on-chip PHY.
- When changing the contents of MCLKCR or FRQCR, make sure that the on-chip PHY is in the reset state. Otherwise, a hazard may be temporarily generated on Mφ output. To use Mφ as clocks for the on-chip PHY, assert the module reset of the on-chip PHY after the contents of MCLKCR or FRQCR have been changed.



# **8.5 Changing Frequency**

The internal clock frequency can be changed by changing the multiplication ratio of PLL circuit 1. The peripheral clock frequency can be changed either by changing the multiplication ratio of PLL circuit 1 or by changing the division ratio of divider 1. All of these are controlled by software through the frequency control register. The methods are described below.

### **8.5.1 Changing Multiplication Ratio**

The PLL lock time must be preserved when the multiplication ratio of PLL circuit 1 is changed. The on-chip WDT counts for preserving the PLL lock time.

- 1. In the initial state, the multiplication ratio of PLL circuit 1 is 1.
- 2. Set a value that satisfies the given PLL lock time in the WDT and stop the WDT. The following must be set.
	- TME bit in WTCSR  $= 0$ : WDT stops
	- Bits CKS2 to CKS0 in WTCSR: Division ratio of WDT count clock
	- WTCNT: Initial counter value
- 3. Set the desired value in bits STC2 to STC0 while the MDCHG bit in STBCR is 0. The division ratio can also be set in bits PFC2 to PFC0.
- 4. This LSI pauses internally and the WDT starts incrementing. The internal and peripheral clocks both stop and only the WDT is supplied with the clock. The clock will continue to be output on the CKIO pin.
- 5. Supply of the specified clock starts at a WDT count overflow, and this LSI starts operating again. The WDT stops after it overflows.
- Notes: 1. When the MDCHG bit in STBCR is set to 1, changing the FRQCR value has no effect on the operation immediately. For details, see section 8.5.3, Changing Clock Operating Mode.
	- 2. The multiplication ratio should be changed after completion of the operation, if the onchip peripheral module is operating. The internal and peripheral clocks are stopped during the multiplication ratio is changed. The communication error may occur by the peripheral module communicating to the external IC, and the time error may occur by the timer unit (except the WDT). The edge detection of external interrupts (NMI and IRQ7 to IRQ0) cannot be performed.



### **8.5.2 Changing Division Ratio**

The WDT will not count unless the multiplication ratio is changed simultaneously.

- 1. In the initial state, PFC2 to  $PFC0 = 011$ .
- 2. Set the desired values in bits PFC2 to PFC0 while the MDCHG bit in STBCR is 0. The values that can be set are limited by the clock mode and the multiplication ratio of PLL circuit 1. Note that if the wrong value is set, this LSI will malfunction.
- 3. The clock is immediately changed to the new division ratio.
- Note: When the MDCHG bit in STBCR is set to 1, changing the FRQCR value has no effect on the operation immediately. For details, see section 8.5.3, Changing Clock Operating Mode.

## **8.5.3 Changing Clock Operating Mode**

The values of the mode control pins (MD2 to MD0) that define a clock operating mode are fetched at a power-on reset and software standby while the MDCHG bit in STBCR is set to 1 register.

Even if changing the FRQCR with the MDCHG bit set to 1, the clock mode cannot immediately be changed to the specified clock mode. This change can be reflected as a multiplication ratio or a division ratio after leaving software standby mode to change operating modes. Reducing the PLL settling time without changing again the multiplication ratio after the operating mode changing is possible by the use of this.

The procedures for the mode change using software standby mode are described below.

- 1. Set bits MD2 to MD0 to the desired clock operating mode.
- 2. Set both the STBY and MDCHG bits in STBCR to 1.
- 3. Set the adequate value to the WDT so that the given oscillation settling time can be satisfied. Then stop the WDT.
- 4. Set FRQCR to the desired mode. Set bits STC2 to STC0 to the desired multiplication ratio. At this time, a division ratio can be set in bits PFC2 to PFC0. During the operation before the mode change, the clock cannot be changed to the specified clock.
- 5. Enter software standby mode using the SLEEP instruction.
- 6. Leave software standby mode using an interrupt.
- 7. After leaving software standby mode, this LSI starts the operation with the value of FRQCR that has been set before the mode change.



- Notes: 1. Pins MD2 to MD0 should be set during the operation before the mode change or during software standby mode before requesting an interrupt.
	- 2. Clear the STBY bit in STBCR in the exception handling routine for the interrupt in step 6. Otherwise, software standby mode is entered again. For details, see section 10.5.2, Canceling Software Standby Mode.
	- 3. Once bits STC2 to STC0 are changed, the clock is not switched to the specified clock even if only bits PFC2 to PFC0 are changed. When bits STC2 to STC0 are changed after the MDCHG bit has been set to 1, the FRQCR setting must not be made until the clock mode is changed.


# **8.6 Notes on Board Design**

**Note on Using an External Crystal Resonator:** Place the crystal resonator, capacitors CL1 and CL2, and feedback resistor R1 as close to the XTAL and EXTAL pins as possible. In addition, to minimize induction and thus obtain oscillation at the correct frequency, the capacitors to be attached to the resonator must be grounded to the same ground. Do not bring wiring patterns close to these components.





**Notes on Using External Clocks:** When external clocks are input from the EXTAL pin, leave the XTAL pin open. In order to prevent a malfunction due to the reflection noise caused in a signal line which connected to XTAL pin, cut this signal line as short as possible.

**Notes on Bypass Capacitor:** A multilayer ceramic capacitor must be inserted for each pair of Vss and Vcc as a bypass capacitor. The bypass capacitor must be inserted as close as possible to the power supply pins of the LSI. Note that the capacitance and frequency characteristics of the bypass capacitor must be appropriate for the operating frequency of the LSI.

- Digital power supply pairs for internal logic A7-B7, E2-E1, E13-E12, H4-H3, K12-K13, M10-N10
- Power supply pairs for input and output A1-B1, A9-B9, B15-B14, H14-H15, K1-K2, R7-P7, P13-P14
- Power supply pairs for PLL N15-N14, R15-P15
- Analog power supply pairs for PHY N4-(N3, AP3), P4-P5
- No ground available that can be paired with R5 (Vcc3A)



**Notes on Using a PLL Oscillator Circuit:** In the Vcc and Vss connection pattern for the PLL, signal lines from the board power supply pins must be as short as possible and pattern width must be as wide as possible to reduce inductive interference.

Since the analog power supply pins of the PLL are sensitive to the noise, the system may malfunction due to inductive interference at the other power supply pins. To prevent such malfunction, the analog power supply pin Vcc and digital power supply pin VccQ should not supply the same resources on the board if at all possible.



**Figure 8.3 Note on Using a PLL Oscillator Circuit** 



# Section 9 Watchdog Timer (WDT)

This LSI includes the watchdog timer (WDT) that can reset this LSI by the overflow of the counter when the value of the counter has not been updated because of a system runaway.

The WDT is a single-channel timer that uses a peripheral clock as an input and counts the clock settling time when leaving software standby mode and temporary standby state, such as frequency changes. It can also be used as an interval timer.

## **9.1 Features**

The WDT has the following features:

- Can be used to ensure the clock settling time. The WDT can be used when leaving software standby mode and the temporary standby state which occur when the clock frequency is changed.
- Can switch between watchdog timer mode and interval timer mode.
- Internal resets in watchdog timer mode Internal resets are generated when the counter overflows.
- Interrupts are generated in interval timer mode Interval timer interrupts are generated when the counter overflows.
- Choice of eight counter input clocks Eight clocks  $(x)$  to  $x/4096$ ) that are obtained by dividing the peripheral clock can be chosen.



Figures 9.1 is a block diagram of the WDT.



**Figure 9.1 Block Diagram of WDT** 



# **9.2 Register Descriptions**

The WDT has the following two registers. For details on the addresses of these registers and the states of these registers in each processing state, see section 24, List of Registers.

- Watchdog timer counter (WTCNT)
- Watchdog timer control/status register (WTCSR)

## **9.2.1 Watchdog Timer Counter (WTCNT)**

WTCNT is an 8-bit readable/writable register that increments on the selected clock. When an overflow occurs, it generates a reset in watchdog timer mode and an interrupt in interval time mode. WTCNT is not initialized by an internal power-on reset due to the WDT overflow. WTCNT is initialized to H'00 by a power-on reset input to the pin and an H-UDI reset.

Use a word access to write to WTCNT, with H'5A in the upper byte. Use a byte access to read WTCNT.

Note: The writing method for WTCNT differs from other registers so that the WTCNT value cannot be changed accidentally. For details, see section 9.2.3, Notes on Register Access.

## **9.2.2 Watchdog Timer Control/Status Register (WTCSR)**

WTCSR is an 8-bit readable/writable register composed of bits to select the clock used for the counting, bits to select the timer mode and overflow flags, and enable bits.

WTCSR holds its value in the internal reset state due to the WDT overflow. WTCSR is initialized to H'00 by a power-on reset input to the pin and an H-UDI reset. To use it for counting the clock settling time when leaving software standby mode, WTCSR holds its value after a counter overflow.

Use a word access to write to WTCSR, with H'A5 in the upper byte. Use a byte access to read WTCSR.

Note: The writing method for WTCNT differs from other registers so that the WTCNT value cannot be changed accidentally. For details, see section 9.2.3, Notes on Register Access.







#### **9.2.3 Notes on Register Access**

The watchdog timer counter (WTCNT) and watchdog timer control/status register (WTCSR) are more difficult to write to than other registers. The procedure for writing to these registers is given below.

**Writing to WTCNT and WTCSR:** These registers must be written by a word transfer instruction. They cannot be written by a byte or longword transfer instruction. When writing to WTCNT, set the upper byte to H'5A and transfer the lower byte as the write data, as shown in figure 9.2. When writing to WTCSR, set the upper byte to H'A5 and transfer the lower byte as the write data. This transfer procedure writes the lower byte data to WTCNT or WTCSR.







# **9.3 WDT Operation**

#### **9.3.1 Canceling Software Standbys**

The WDT can be used to cancel software standby mode with an NMI interrupt or external interrupt (IRQ). The procedure is described below. (The WDT does not run when resets are used for canceling, so keep the RES pin low until the clock stabilizes.)

- 1. Before transition to software standby mode, always clear the TME bit in WTCSR to 0. When the TME bit is 1, an erroneous reset or interval timer interrupt may be generated when the count overflows.
- 2. Set the type of count clock used in the CKS2 to CKS0 bits in WTCSR and the initial values for the counter in WTCNT. These values should ensure that the time till count overflow is longer than the clock oscillation settling time.
- 3. Move to software standby mode by executing a SLEEP instruction to stop the clock.
- 4. The WDT starts counting by detecting the change of input levels of the NMI or IRQ pin.
- 5. When the WDT count overflows, the CPG starts supplying the clock and the processor resumes operation. The WOVF flag in WTCSR is not set when this happens.
- 6. Since the WDT continues counting from H'00, set the STBY bit in STBCR to 0 in the interrupt processing program and this will stop the WDT to count. When the STBY bit remains 1, the LSI again enters software standby mode when the WDT has counted up to H'80. This software standby mode can be canceled by a power-on reset.



#### **9.3.2 Changing Frequency**

To change the multiplication ratio of PLL circuit 1, use the WDT. When changing the frequency only by switching the divider, do not use the WDT.

- 1. Before changing the frequency, always clear the TME bit in WTCSR to 0. When the TME bit is 1, an erroneous reset or interval timer interrupt may be generated when the count overflows.
- 2. Set the type of count clock used in the CKS2 to CKS0 bits in WTCSR and the initial values for the counter in WTCNT. These values should ensure that the time till count overflow is longer than the clock oscillation settling time.
- 3. When bits STC2 to STC0 in the frequency control register (FRQCR) is written, the processor stops temporarily. The WDT starts counting.
- 4. When the WDT count overflows, the CPG resumes supplying the clock and the processor resumes operation. The WOVF flag in WTCSR is not set when this happens.
- 5. WTCNT stops at the value of H'00.
- 6. Before changing WTCNT after the execution of the frequency change instruction, always confirm that the value of WTCNT is H'00 by reading WTCNT.

#### **9.3.3 Using Watchdog Timer Mode**

- 1. Set the WT/IT bit in WTCSR to 1, set the type of count clock in bits CKS2 to CKS0, and set the initial value of the counter in WTCNT.
- 2. Set the TME bit in WTCSR to 1 to start the count in watchdog timer mode.
- 3. While operating in watchdog timer mode, rewrite the counter periodically to H'00 to prevent the counter from overflowing.
- 4. When the counter overflows, the WDT sets the WOVF flag in WTCSR to 1 and generates a power-on reset. WTCNT then resumes counting.



### **9.3.4 Using Interval Timer Mode**

When operating in interval timer mode, interval timer interrupts are generated at every overflow of the counter. This enables interrupts to be generated at set periods.

- 1. Clear the WT/IT bit in WTCSR to 0, set the type of count clock in the CKS2 to CKS0 bits, and set the initial value of the counter in WTCNT.
- 2. Set the TME bit in WTCSR to 1 to start the count in interval timer mode.
- 3. When the WTCNT overflows, the WDT sets the IOVF flag in WTCSR to 1 and an interval timer interrupt request is sent to the INTC. The WTCNT then resumes counting.

# **9.4 Usage Notes**

Pay attention to the following points when using the WDT.

While using the WDT in interval mode, no overflow occurs by the H'00 immediately after writing H'FF to WDTCNT. (IOVF in WTCSR is not set.)

The overflow occurs at the point when the count reaches H'00 after one cycle.

This phenomenon does not occur when the WDT is used in watchdog timer mode.



# Section 10 Power-Down Modes

This LSI supports the following power-down modes: sleep mode, software standby mode, module standby mode.

# **10.1 Features**

Supports sleep mode, software standby mode, and module standby

## **10.1.1 Types of Power-Down Modes**

This LSI has the following power-down modes.

- Sleep mode
- Software standby mode
- Module standby mode (cache, U-memory, UBC, H-UDI, and on-chip peripheral modules)

Table 10.1 shows the methods to make a transition from the program execution state, as well as the CPU and peripheral module states in each mode and the procedures for canceling each mode.

#### **Table 10.1 States of Power-Down Modes**





# **10.2 Input/Output Pins**

Table 10.2 lists the pins used for the power-down modes.

#### **Table 10.2 Pin Configuration**



# **10.3 Register Descriptions**

There are following registers used for the power-down modes. For details on the addresses of these registers and the states of these registers in each processing state, see section 24, List of Registers.

- Standby control register (STBCR)
- Standby control register 2 (STBCR2)
- Standby control register 3 (STBCR3)
- Standby control register 4 (STBCR4)



#### **10.3.1 Standby Control Register (STBCR)**

STBCR is an 8-bit readable/writable register that specifies the state of the power-down mode.





#### **10.3.2 Standby Control Register 2 (STBCR2)**

STBCR2 is an 8-bit readable/writable register that controls the operation of modules in powerdown mode.





#### **10.3.3 Standby Control Register 3 (STBCR3)**

STBCR3 is an 8-bit readable/writable register that controls the operation of modules in powerdown mode.







#### **10.3.4 Standby Control Register 4 (STBCR4)**

STBCR4 is an 8-bit readable/writable register that controls the operation of modules in powerdown mode.





### **10.4 Sleep Mode**

#### **10.4.1 Transition to Sleep Mode**

Executing the SLEEP instruction when the STBY bit in STBCR is 0 causes a transition from the program execution state to sleep mode. Although the CPU halts immediately after executing the SLEEP instruction, the contents of its internal registers remain unchanged. The on-chip peripheral modules continue to operate in sleep mode and the clock continues to be output to the CKIO pin.

#### **10.4.2 Canceling Sleep Mode**

Sleep mode is canceled by an interrupt other than a user break (NMI, H-UDI, IRQ, and on-chip peripheral module) or a reset.

**Canceling with Interrupt:** When a user-break, NMI, H-UDI, IRQ, or on-chip peripheral module interrupt occurs, sleep mode is canceled and interrupt exception handling is executed. When the priority level of an IRQ or on-chip peripheral module interrupt is lower than the interrupt mask level set in the status register (SR) of the CPU, an interrupt request is not accepted preventing sleep mode from being canceled.

**Canceling with Reset: S**leep mode is canceled by a power-on reset or an H-UDI reset.



# **10.5 Software Standby Mode**

#### **10.5.1 Transition to Software Standby Mode**

This LSI switches from a program execution state to software standby mode by executing the SLEEP instruction when the STBY bit in STBCR is 1. In software standby mode, not only the CPU but also the clock and on-chip peripheral modules halt. The clock output from the CKIO pin also halts.

The contents of the CPU and cache registers remain unchanged. Some registers of on-chip peripheral modules are, however, initialized. Table 10.3 lists the states of on-chip peripheral modules registers in software standby mode.



#### **Table 10.3 Register States in Software Standby Mode**

Note: \* For details, see section 22, Ethernet Physical Layer Transceiver (PHY).

The procedure for switching to software standby mode is as follows:

- 1. Clear the TME bit in the timer control register (WTCSR) of the WDT to 0 to stop the WDT.
- 2. Set the timer counter (WTCNT) of the WDT to 0 and bits CKS2 to CKS0 in WTCSR to appropriate values to secure the specified oscillation settling time.
- 3. After setting the STBY bit in STBCR to 1, execute the SLEEP instruction.
- 4. Software standby mode is entered and the clocks within this LSI are halted.

#### **10.5.2 Canceling Software Standby Mode**

Software standby mode is canceled by interrupts (NMI, IRQ) or a reset.

**Canceling with Interrupt:** The WDT can be used for hot starts. When an NMI or IRQ interrupt is detected, the clock will be supplied to the entire LSI and software standby mode will be canceled after the time set in the timer control/status register of the WDT has elapsed. Interrupt exception handling is then executed. After the branch to the interrupt handling routine, clear the STBY bit in STBCR. WTCNT stops automatically. If the STBY bit is not cleared, WTCNT continues operation and a transition is made to software standby mode\* when it reaches H'80. This function prevents data destruction due to the voltage rise by an unstable power supply voltage.

IRQ cancels the software standby mode when the input condition matches the specified detect condition while the IRQn1S and IRQn0S bits in IRQCR are not B'00 (settings other than the low level detection). When the priority level of an IRQ interrupt is lower than the interrupt mask level set in the status register (SR) of the CPU, the execution of the instruction following the SLEEP instruction starts again after the cancellation of software standby mode. When the priority level of an IRQ interrupt is higher than the interrupt mask level set in the status register (SR) of the CPU, IRQ interrupt exception handling is executed after the cancellation of software standby mode.

Note: \* This software standby mode can be canceled only by a power-on reset.





**Figure 10.1 Canceling Standby Mode with STBY Bit in STBCR** 

**Canceling with Reset:** Software standby mode is canceled by a power-on reset. Keep the RES pin low until the clock oscillation settles. The internal clock will continue to be output to the CKIO pin.

# **10.6 Module Standby Mode**

## **10.6.1 Transition to Module Standby Mode**

Setting the MSTP bits in the standby control registers (STBCR2 to STBCR4) to 1 halts the supply of clocks to the corresponding on-chip peripheral modules. This function can be used to reduce the power consumption in normal mode.

In module standby mode, the states of the external pins of the on-chip peripheral modules change depending on the on-chip peripheral module and port settings. Almost all of the registers retain its previous state.

## **10.6.2 Canceling Module Standby Function**

The module standby function can be canceled by clearing the MSTP bits in STBCR2 to STBCR4 to 0, or by a power-on reset.



# Section 11 Ethernet Controller (EtherC)

This LSI has an on-chip Ethernet controller (EtherC) conforming to the Ethernet or the IEEE802.3 MAC (Media Access Control) layer standard. Connecting a physical-layer LSI (PHY-LSI) complying with this standard enables the Ethernet controller (EtherC) to perform transmission and reception of Ethernet/IEEE802.3 frames. This LSI has one MAC layer interface.

The Ethernet controller is connected to the direct memory access controller for Ethernet controller (E-DMAC) inside this LSI, and carries out high-speed data transfer to and from the memory.

Figure 11.1 shows a configuration of the EtherC.

# **11.1 Features**

- Transmission and reception of Ethernet/IEEE802.3 frames
- Supports 10/100 Mbps receive/transfer
- Supports full-duplex and half-duplex modes
- Conforms to IEEE802.3u standard MII (Media Independent Interface)
- Magic Packet detection and Wake-On-LAN (WOL) signal output
- Conforms to IEEE802.3x flow control





**Figure 11.1 Configuration of EtherC** 



# **11.2 Input/Output Pins**

Table 11.1 lists the pin configuration of the EtherC.

#### **Table 11.1 Pin Configuration**







Note: \* MII signal conforming to IEEE802.3u



# **11.3 Register Description**

The EtherC has the following registers. For details on addresses and access sizes of registers, see section 24, List of Registers.

### **MAC Layer Interface Control Registers:**

- EtherC mode register (ECMR)
- EtherC status register (ECSR)
- EtherC interrupt permission register (ECSIPR)
- PHY interface register (PIR)
- MAC address high register (MAHR)
- MAC address low register (MALR)
- Receive frame length register (RFLR)
- PHY status register (PSR)
- Transmit retry over counter register (TROCR)
- Delayed collision detect counter register (CDCR)
- Lost carrier counter register (LCCR)
- Carrier not detect counter register (CNDCR)
- CRC error frame counter register (CEFCR)
- Frame receive error counter register (FRECR)
- Too-short frame receive counter register (TSFRCR)
- Too-long frame receive counter register (TLFRCR)
- Residual-bit frame counter register (RFCR)
- Multicast address frame counter register (MAFCR)
- IPG register (IPGR)
- Automatic PAUSE frame set register (APR)
- Manual PAUSE frame set register (MPR)
- PAUSE frame retransfer count set register (TPAUSER)



### **11.3.1 EtherC Mode Register (ECMR)**

ECMR is a 32-bit readable/writable register and specifies the operating mode of the Ethernet controller. The settings in this register are normally made in the initialization process following a reset.

The operating mode setting must not be changed while the transmitting and receiving functions are enabled. To switch the operating mode, return the EtherC and E-DMAC to their initial states by means of the SWR bit in EDMR before making settings again.











#### **11.3.2 EtherC Status Register (ECSR)**

ECSR is a 32-bit readable/writable register and indicates the status in the EtherC. This status can be notified to the CPU by interrupts. When 1 is written to the PSRTO, LCHNG, MPD, and ICD, the corresponding flags can be cleared. Writing 0 does not affect the flag. For bits that generate interrupt, the interrupt can be enabled or disabled according to the corresponding bit in ECSIPR.











#### **11.3.3 EtherC Interrupt Permission Register (ECSIPR)**

ECSIPR is a 32-bit readable/writable register that enables or disables the interrupt sources indicated by ECSR. Each bit can disable or enable interrupts corresponding to the bits in ECSR.





# **11.3.4 PHY Interface Register (PIR)**

PIR is a 32-bit readable/writable register that provides a means of accessing the PHY registers via the MII.





#### **11.3.5 MAC Address High Register (MAHR)**

MAHR is a 32 -bit readable/writable register that specifies the upper 32 bits of the 48-bit MAC address. The settings in this register are normally made in the initialization process after a reset. The MAC address setting must not be changed while the transmitting and receiving functions are enabled. To switch the MAC address setting, return the EtherC and E-DMAC to their initial states by means of the SWR bit in EDMR before making settings again.



#### **11.3.6 MAC Address Low Register (MALR)**

MALR is a 32-bit readable/writable register that specifies the lower 16 bits of the 48-bit MAC address. The settings in this register are normally made in the initialization process after a reset. The MAC address setting must not be changed while the transmitting and receiving functions are enabled. To switch the MAC address setting, return the EtherC and E-DMAC to their initial states by means of the SWR bit in EDMR before making settings again.





#### **11.3.7 Receive Frame Length Register (RFLR)**

RFLR is a 32-bit readable/writable register and it specifies the maximum frame length (in bytes) that can be received by this LSI. The settings in this register must not be changed while the receiving function is enabled.



#### **11.3.8 PHY Status Register (PSR)**



PSR is a read-only register that can read interface signals from the PHY.

#### **11.3.9 Transmit Retry Over Counter Register (TROCR)**

TROCR is a 32-bit counter that indicates the number of frames that were unable to be transmitted in 16 transmission attempts including the retransfer. When 16 transmission attempts have failed, TROCR is incremented by 1. When the value in this register reaches H'FFFFFFFF, the count is halted. The counter value is cleared to 0 by a write to this register with any value.





#### **11.3.10 Delayed Collision Detect Counter Register (CDCR)**

CDCR is a 32-bit counter that indicates the number of delayed collisions on all lines from a start of transmission. When the value in this register reaches H'FFFFFFFF, count-up is halted. The counter value is cleared to 0 by a write to this register with any value.



#### **11.3.11 Lost Carrier Counter Register (LCCR)**

LCCR is a 32-bit counter that indicates the number of times the carrier was lost during data transmission. When the value in this register reaches H'FFFFFFFF, the count is halted. The counter value is cleared to 0 by writing to this register with any value.



#### **11.3.12 Carrier Not Detect Counter Register (CNDCR)**

CNDCR is a 32-bit counter that indicates the number of times the carrier could not be detected while the preamble was being sent. When the value in this register reaches H'FFFFFFFFFFFFFF. is halted. The counter value is cleared to 0 by a write to this register with any value.


# **11.3.13 CRC Error Frame Counter Register (CEFCR)**

CEFCR is a 32-bit counter that indicates the number of times a frame with a CRC error was received. When the value in this register reaches H'FFFFFFFF, the count is halted. The counter value is cleared to 0 by a write to this register with any value.



#### **11.3.14 Frame Receive Error Counter Register (FRECR)**

FRECR is a 32-bit counter that indicates the number of frames input from the PHY for which a receive error was indicated by the RX-ER pin. FRECR is incremented each time the RX-ER pin becomes active. When the value in this register reaches H'FFFFFFFF, the count is halted. The counter value is cleared to 0 by a write to this register with any value.



#### **11.3.15 Too-Short Frame Receive Counter Register (TSFRCR)**

TSFRCR is a 32-bit counter that indicates the number of frames of fewer than 64 bytes that have been received. When the value in this register reaches H'FFFFFFFF, the count is halted. The counter value is cleared to 0 by a write to this register with any value.





# **11.3.16 Too-Long Frame Receive Counter Register (TLFRCR)**

TLFRCR is a 32-bit counter that indicates the number of frames received with a length exceeding the value specified by the receive frame length register (RFLR). When the value in this register reaches H'FFFFFFFF, the count is halted. TLFRCR is not incremented when a frame containing residual bits is received. In this case, the reception of the frame is indicated in the residual-bit frame counter register (RFCR). The counter value is cleared to 0 by a write to this register with any value.



# **11.3.17 Residual-Bit Frame Counter Register (RFCR)**

RFCR is a 32-bit counter that indicates the number of frames received containing residual bits (less than an 8-bit unit). When the value in this register reaches H'FFFFFFFF, the count is halted. The counter value is cleared to 0 by a write to this register with any value.



# **11.3.18 Multicast Address Frame Counter Register (MAFCR)**

MAFCR is a 32-bit counter that indicates the number of frames received with a specified multicast address. When the value in this register reaches H'FFFFFFFF, the count is halted. The counter value is cleared to 0 by a write to this register with any value.



# **11.3.19 IPG Register (IPGR)**

IPGR sets the IPG (Inter Packet Gap). This register must not be changed while the transmitting and receiving functions of the EtherC mode register (ECMR) are enabled. (For details, refer to section 11.4.6, Operation by IPG Setting.)



#### **11.3.20 Automatic PAUSE Frame Set Register (APR)**

APR sets the TIME parameter value of the automatic PAUSE frame. When transmitting the automatic PAUSE frame, the value set in this register is used as the TIME parameter of the PAUSE frame.





# **11.3.21 Manual PAUSE Frame Set Register (MPR)**

MPR sets the TIME parameter value of the manual PAUSE frame. When transmitting the manual PAUSE frame, the value set to this register is used as the TIME parameter of the PAUSE frame.



#### **11.3.22 PAUSE Frame Retransfer Count Set Register (TPAUSER)**

TPAUSER sets the upper limit of the number of times of the PAUSE frame retransfer. TPAUSER must not be changed while the transmitting function is enabled.



# **11.4 Operation**

The overview of the Ethernet controller (EtherC) are shown below. The EtherC transmits and receives PAUSE frames conforming to the Ethernet/IEEE802.3x frames.

# **11.4.1 Transmission**

The EtherC transmitter assembles the transmit data on the frame and outputs to MII when there is a transmit request from the E-DMAC. The data transmitted via the MII is transmitted to the lines by PHY-LSI. Figure 11.3 shows the state transition of the EtherC transmitter.





# **Figure 11.2 EtherC Transmitter State Transitions**

- 1. When the transmit enable (TE) bit is set, the transmitter enters the transmit idle state.
- 2. When a transmit request is issued by the transmit E-DMAC, the EtherC sends the preamble after a transmission delay equivalent to the frame interval time. If full-duplex transfer is selected, which does not require carrier detection, the preamble is sent as soon as a transmit request is issued by the E-DMAC.
- 3. The transmitter sends the SFD, data, and CRC sequentially. At the end of transmission, the transmit E-DMAC generates a transmission complete interrupt (TC). If a collision or the carrier-not-detected state occurs during data transmission, these are reported as interrupt sources.
- 4. After waiting for the frame interval time, the transmitter enters the idle state, and if there is more transmit data, continues transmitting.

#### **11.4.2 Reception**

The EtherC receiver separates the frame data (MII into preamble, SFD, DA (destination address), SA (Source address), type/length, Data, and CRC data) and outputs DA, SA, type/length, Data to the E-DMAC. Figure 11.3 shows the state transitions of the EtherC receiver.



**Figure 11.3 EtherC Receiver State Transmissions** 

- 1. When the receive enable (RE) bit is set, the receiver enters the receive idle state.
- 2. When an SFD (start frame delimiter) is detected after a receive packet preamble, the receiver starts receive processing. Discards a frame with an invalid pattern.
- 3. In normal mode, if the destination address matches the receiver's own address, or if broadcast or multicast transmission or promiscuou**s** mode is specified, the receiver starts data reception.
- 4. Following data reception from the MII, the receiver carries out a CRC check. The result is indicated as a status bit in the descriptor after the frame data has been written to memory. Reports an error status in the case of an abnormality.
- 5. After one frame has been received, if the receive enable bit is set  $(RE = 1)$  in the EtherC mode register, the receiver prepares to receive the next frame.

# **11.4.3 MII Frame Timing**

Each MII Frame timing is shown in figure 11.4.



**Figure 11.4 (1) MII Frame Transmit Timing (Normal Transmission)** 



**Figure 11.4 (2) MII Frame Transmit Timing (Collision)** 





**Figure 11.4 (3) MII Frame Transmit Timing (Transmit Error)** 













## **11.4.4 Accessing MII Registers**

MII registers in the PHY are accessed via this LSI's PHY interface register (PIR). Connection is made as a serial interface in accordance with the MII frame format specified in IEEE802.3u.

**MII Management Frame Format:** The format of an MII management frame is shown in figure 11.8. To access an MII register, a management frame is implemented by the program in accordance with the procedures shown in MII Register Access Procedure.



#### **Figure 11.5 MII Management Frame Format**



**MII Register Access Procedure:** The program accesses MII registers via the PHY interface register (PIR). Access is implemented by a combination of 1-bit-unit data write, 1-bit-unit data read, bus release, and independent bus release. Figure 11.9 shows the MII register access timing. The timing will differ depending on the PHY type.



**Figure 11.6 (1) 1-Bit Data Write Flowchart** 





**Figure 11.6 (2) Bus Release Flowchart (TA in Read in Figure 11.5)** 



**Figure 11.6 (3) 1-Bit Data Read Flowchart** 

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**Figure 11.6 (4) Independent Bus Release Flowchart (IDLE in Write in Figure 11.5)** 

# **11.4.5 Magic Packet Detection**

The EtherC has a Magic Packet detection function. This function provides a Wake-On-LAN (WOL) facility that activates various peripheral devices connected to a LAN from the host device or other source. This makes it possible to construct a system in which a peripheral device receives a Magic Packet sent from the host device or other source, and activates itself. When the Magic Packet is detected, data is stored in the FIFO of the E-DMAC by the broadcast packet that has received data previously and the EtherC is notified of the receiving status. To return to normal operation from the interrupt processing, initialize the EtherC and E-DMAC by using the SWR bit in the E-DMAC mode register (EDMR).

With a Magic Packet, reception is performed regardless of the destination address. As a result, this function is valid, and the WOL pin enabled, only in the case of a match with the destination address specified by the format in the Magic Packet. Further information on Magic Packets can be found in the technical documentation published by AMD Corporation.

The procedure for using the WOL function with this LSI is as follows.

- 1. Disable interrupt source output by means of the various interrupt enable/mask registers.
- 2. Set the Magic Packet detection enable bit (MPDE) in the EtherC mode register (ECMR).
- 3. Set the Magic Packet detection interrupt enable bit (MPDIP) in the EtherC interrupt enable register (ECSIPR) to the enable setting.
- 4. If necessary, set the CPU operating mode to sleep mode or set supporting functions to module standby mode.
- 5. When a Magic Packet is detected, an interrupt is sent to the CPU. The WOL pin notifies peripheral LSIs that the Magic Packet has been detected.





# **11.4.6 Operation by IPG Setting**

The EtherC has a function to change the non-transmission period IPG (Inter Packet Gap) between transmit frames. By changing the set values of the IPG setting register (IPGR), the transmission efficiency can be raised and lowered from the standard value. IPG settings are prescribed in IEEE802.3 standards. When changing settings, adequately check that the respective devices can operate smoothly on the same network.



**Figure 11.7 Changing IPG and Transmission Efficiency** 

# **11.4.7 Flow Control**

The EtherC supports flow control functions conforming to IEEE802.3x in full-duplex operations. Flow control can be applied to both receive and transmit operations. The methods for transmitting PAUSE frames when controlling flow are as follows:

**Automatic PAUSE Frame Transmission:** For receive frames, PAUSE frames are automatically transmitted when the number of data in the receive FIFO (included in E-DMAC) reaches the value set in the flow control FIFO threshold register (FCFTR) of the E-DMAC. The TIME parameter included in the PAUSE frame at this time is set by the automatic PAUSE frame setting register (APR). The automatic PAUSE frame transmission is repeated until the number of data in the receive FIFO becomes less than the FCFTR setting as the receive data is read from the FIFO.

The upper limit of the number of retransfers of the PAUSE frame can also be set by the automatic PAUSE frame retransfer count set register (TPAUSER). In this case, PAUSE frame transmission is repeated until the number of data becomes FCFTR value set or below, or the number of transmits reaches the value set by TPAUSER. The automatic PAUSE frame transmission is enabled when the TXF bit in the EtherC mode register (ECMR) is 1.

**Manual PAUSE Frame Transmission:** PAUSE frames are transmitted by directives from the software. When writing the Timer value to the manual PAUSE frame set register (MPR), manual PAUSE frame transmission is started. With this method, PAUSE frame transmission is carried out only once.

**PAUSE Frame Reception:** The next frame is not transmitted until the time indicated by the Timer value elapses after receiving a PAUSE frame. However, the transmission of the current frame is continued. A received PAUSE frame is valid only when the RXF bit in the EtherC mode register (ECMR) is set to 1.

# **11.5 Connection to PHY-LSI**

Figure 11.8 shows the example of connection to a DP83846AVHG by National Semiconductor Corporation.



**Figure 11.8 Example of Connection to DP83846AVHG** 



# **11.6 Usage Notes**

• Conditions for Setting LCHNG Bit

Even if the level of the signal input to the LNKSTA pin is not changed, the LCHNG bit in ECSR may be set. It may happen when the pin function is changed from port to LNKSTA by PCCRH2 of the PFC or when a software reset caused by the SWR bit in EDMR is cleared while the LNKSTA pin is being driven high.

This is because the LNKSTA signal is internally fixed low when the pin functions as a port or during the software reset state regardless of the external pin level.

Clear the LCHNG bit before setting the LCHNGIP bit in ECSIPR not to request a LINK signal changed interrupt accidentally.

• Flow Control Defect 1

Once a PAUSE frame is received while the receiving flow control is enabled in full-duplex mode (the RXF bit in ECMR  $= 1$ ), each time when the local station receives a normal unicast frame (non-PAUSE frame without a CRC error), the TIME parameter specified by the PAUSE frame that has been previously received is incorrectly applied. As a result, unnecessary waiting time is generated to slow down the transmission throughput. The TIME parameter value is maintained until another PAUSE frame is received.

This defect can be prevented if the destination station supports the function to transmit the 0 time PAUSE frame as the same as this LSI does. Enable the use of 0 time PAUSE frame in this LSI (the ZPF bit in ECMR  $= 1$ ) before the 0 time PAUSE frame is received from the destination station. This clears the TIME parameter incorrectly maintained in the EtherC and prevents the unnecessary waiting time for transmission to be generated.

Note: This defect may be generated only in the R4S76190. In the R4S76191, the defect has been corrected.



• Flow Control Defect 2

When a PAUSE period is generated while the transmitting/receiving flow control is enabled in full-duplex mode (the TXF/RXF bit in ECMR  $= 1$ ), non-PAUSE frames are waited for transmission (this is a normal operation) whereas PAUSE frames are incorrectly waited for transmission. The transmission of non-PAUSE frames in a PAUSE period is prohibited, though the transmission of PAUSE frames is enabled in IEEE802.3.

When a PAUSE period is generated by the request from the destination station (that is, a PAUSE frame is received from the destination station), the load of the destination station is high and that of the local station is not so high. Therefore, the transmission of PAUSE frames during this period is less likely to happen. The ratio that this defect actually affects the operation in this LSI is rather low.

Note: This defect may be generated only in the R4S76190. In the R4S76191, the defect has been corrected.





# Section 12 Ethernet Controller Direct Memory Access Controller (E-DMAC)

This LSI includes a direct memory access controller (E-DMAC) directly connected to the Ethernet controller (EtherC). A large proportion of buffer management is controlled by the E-DMAC itself using descriptors. This lightens the load on the CPU and enables efficient control of data transfer.

Figure 12.1 shows the configuration of the E-DMAC, and the descriptors and transmit/receive buffers in memory.

# **12.1 Features**

The E-DMAC has the following features:

- The load on the CPU is reduced by means of a descriptor management system
- Transmit/receive frame status information is indicated in descriptors
- Achieves efficient system bus utilization through the use of block transfer (16-byte units)
- Supports single-frame/multi-buffer operation



**Figure 12.1 Configuration of E-DMAC, and Descriptors and Buffers** 



# **12.2 Register Descriptions**

The E-DMAC has the following registers. For addresses and access sizes of these registers, see section 24, List of Registers.

- E-DMAC mode register (EDMR)
- E-DMAC transmit request register (EDTRR)
- E-DMAC receive request register (EDRRR)
- Transmit descriptor list address register (TDLAR)
- Receive descriptor list address register (RDLAR)
- EtherC/E-DMAC status register (EESR)
- EtherC/E-DMAC status interrupt permission register (EESIPR)
- Transmit/receive status copy enable register (TRSCER)
- Receive missed-frame counter register (RMFCR)
- Transmit FIFO threshold register (TFTR)
- FIFO depth register (FDR)
- Receiving method control register (RMCR)
- E-DMAC operation control register (EDOCR)
- Receive buffer write address register (RBWAR)
- Receive descriptor fetch address register (RDFAR)
- Transmit buffer read address register (TBRAR)
- Transmit descriptor fetch address register (TDFAR)
- Flow control FIFO threshold register (FCFTR)
- Transmit interrupt register (TRIMD)



# **12.2.1 E-DMAC Mode Register (EDMR)**

EDMR is a 32-bit readable/writable register that specifies the operating mode of the E-DMAC. The settings in this register are normally made in the initialization process following a reset. If the EtherC and E-DMAC are initialized by means of this register during data transmission, abnormal data may be sent onto the line. Operating mode settings must not be changed while the transmit and receive functions are enabled. To change the operating mode, the EtherC and E-DMAC modules are got into at their initial state by means of the software reset bit (SWR) in this register, then make new settings. It takes 64 cycles of the internal bus clock Bφ to initialize the EtherC and E-DMAC. Therefore, registers of the EtherC and E-DMAC should be accessed after 64 cycles of the internal bus clock Bφ has elapsed.







# **12.2.2 E-DMAC Transmit Request Register (EDTRR)**

The EDTRR is a 32-bit readable/writable register that issues transmit directives to the E-DMAC. When transmission of one frame is completed, the next descriptor is read. If the transmit descriptor active bit in this descriptor has the "active" setting, transmission is continued. If the transmit descriptor active bit has the "inactive" setting, the TR bit is cleared and operation of the transmit DMAC is halted.



# **12.2.3 E-DMAC Receive Request Register (EDRRR)**

EDRRR is a 32-bit readable/writable register that issues receive directives to the E-DMAC. When the receive request bit is set, the E-DMAC reads the relevant receive descriptor. If the receive descriptor active bit in the descriptor has the "active" setting, the E-DMAC prepares for a receive request from the EtherC. When one receive buffer of data has been received, the E-DMAC reads the next descriptor and prepares to receive the next frame. If the receive descriptor active bit in the descriptor has the "inactive" setting, the RR bit is cleared and operation of the receive DMAC is halted.



Note: \* If the receive function is disabled during frame reception, write-back is not performed successfully to the receive descriptor. Following pointers to read a receive descriptor become abnormal and the E-DMAC cannot operate successfully. In this case, to make the E-DMAC reception enabled again, execute a software reset by the SWR bit in EDMR. To make the E-DMAC reception disabled without executing a software reset, set the RE bit in ECMR. Next, after the E\_DMAC has completed the reception and write-back to the receive descriptor has been confirmed, disable the receive function of this register.



# **12.2.4 Transmit Descriptor List Address Register (TDLAR)**

TDLAR is a 32-bit readable/writable register that specifies the start address of the transmit descriptor list. Descriptors have a boundary configuration in accordance with the descriptor length indicated by the DL bit in EDMR. This register must not be written to during transmission. Modifications to this register should only be made while transmission is disabled by the TR bit  $(= 0)$  in the E-DMAC transmit request register (EDTRR).



# **12.2.5 Receive Descriptor List Address Register (RDLAR)**

RDLAR is a 32-bit readable/writable register that specifies the start address of the receive descriptor list. Descriptors have a boundary configuration in accordance with the descriptor length indicated by the DL bit in EDMR. This register must not be written to during reception. Modifications to this register should only be made while reception is disabled by the RR bit  $(= 0)$ in the E-DMAC Receive Request Register (EDRRR).



# **12.2.6 EtherC/E-DMAC Status Register (EESR)**

EESR is a 32-bit readable/writable register that shows communications status information on the E-DMAC in combination with the EtherC. The information in this register is reported in the form of interrupts. Individual bits are cleared by writing 1 (however, bit 22 (ECI) is a read-only bit and not to be cleared by writing 1) and are not affected by writing 0. Each interrupt source can also be masked by means of the corresponding bit in the EtherC/E-DMAC status interrupt permission register (EESIPR).

The interrupts generated by this register are EINT0. For interrupt priority, see section 6.5, Interrupt Exception Handling Vector Table.

















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# **12.2.7 EtherC/E-DMAC Status Interrupt Permission Register (EESIPR)**

EESIPR is a 32-bit readable/writable register that enables interrupts corresponding to individual bits in the EtherC/E-DMAC status register (EESR). An interrupt is enabled by writing 1 to the corresponding bit. In the initial state, interrupts are not enabled.









# **12.2.8 Transmit/Receive Status Copy Enable Register (TRSCER)**

TRSCER specifies whether or not transmit and receive status information reported by bits in the EtherC/E-DMAC status register is to be indicated in bits TFS26 to TFS0 and RFS26 to RFS0 in the corresponding descriptor. Bits in this register correspond to bits 11 to 0 in the EtherC/E-DMAC status register (EESR). When a bit is cleared to 0, the transmit status (bits 11 to 8 in EESR) is indicated in bits TFS3 to TFS0 in the transmit descriptor, and the receive status (bits 7 to 0 in EESR) is indicated in bits RFS7 to RFS0 of the receive descriptor. When a bit is set to 1, the occurrence of the corresponding interrupt is not indicated in the descriptor. After this LSI is reset, all bits are cleared to 0.







# **12.2.9 Receive Missed-Frame Counter Register (RMFCR)**

RMFCR is a 16-bit counter that indicates the number of frames missed (discarded, and not transferred to the receive buffer) during reception. When the receive FIFO overflows, the receive frames in the FIFO are discarded. The number of frames discarded at this time is counted. When the value in this register reaches H'FFFF, counting-up is halted. When this register is read, the counter value is cleared to 0. Write operations to this register have no effect.





# **12.2.10 Transmit FIFO Threshold Register (TFTR)**

TFTR is a 32-bit readable/writable register that specifies the transmit FIFO threshold at which the first transmission is started. The actual threshold is 4 times the set value. The EtherC starts transmission when the amount of data in the transmit FIFO exceeds the number of bytes specified by this register, when the transmit FIFO is full, or when 1-frame write is executed. When setting this register, do so in the transmission-halt state.



Note: When starting transmission before one frame of data write has completed, take care the generation of the underflow.

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# **12.2.11 FIFO Depth Register (FDR)**

FDR is a 32-bit readable/writable register that specifies the depth of the transmit and receive FIFOs.





### **12.2.12 Receiving Method Control Register (RMCR)**

RMCR is a 32-bit readable/writable register that specifies the control method for the RR bit in EDRRR when a frame is received. This register must be set during the receiving-halt state.





# **12.2.13 E-DMAC Operation Control Register (EDOCR)**

EDOCR is a 32-bit readable/writable register that specifies the control methods used in E-DMAC operation.





## **12.2.14 Receiving-Buffer Write Address Register (RBWAR)**

RBWAR stores the address of data to be written in the receiving buffer when the E-DMAC writes data to the receiving buffer. Which addresses in the receiving buffer are processed by the E-DMAC can be recognized by monitoring addresses displayed in this register. The address that the E-DMAC is actually processing may be different from the value read from this register.



#### **12.2.15 Receiving-Descriptor Fetch Address Register (RDFAR)**

RDFAR stores the descriptor start address that is required when the E-DMAC fetches descriptor information from the receiving descriptor. Which receiving descriptor information is used for processing by the E-DMAC can be recognized by monitoring addresses displayed in this register. The address from which the E-DMAC is actually fetching a descriptor may be different from the value read from this register.



#### **12.2.16 Transmission-Buffer Read Address Register (TBRAR)**

TBRAR stores the address of the transmission buffer when the E-DMAC reads data from the transmission buffer. Which addresses in the transmission buffer are processed by the E-DMAC can be recognized by monitoring addresses displayed in this register. The address from which the E-DMAC is actually reading in the buffer may be different from the value read from this register.



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### **12.2.17 Transmission-Descriptor Fetch Address Register (TDFAR)**

TDFAR stores the descriptor start address that is required when the E-DMAC fetches descriptor information from the transmission descriptor. Which transmission descriptor information is used for processing by the E-DMAC can be recognized by monitoring addresses displayed in this register. The address from which the E-DMAC is actually fetching a descriptor may be different from the value read from this register.



### **12.2.18 Flow Control FIFO Threshold Register (FCFTR)**

FCFTR is a 32-bit readable/writable register that sets the flow control of the EtherC (setting the threshold on automatic PAUSE transmission). The threshold can be specified by the depth of the receive FIFO data (RFD2 to RFD0) and the number of receive frames (RFF2 to RFF0). The condition to start the flow control is decided by taking OR operation on the two thresholds. Therefore, the flow control by the two thresholds is independently started.

When flow control is performed according to the RFD bits setting, if the setting is the same as the depth of the receive FIFO specified by the FIFO depth register (FDR), flow control is started when the remaining FIFO is (FIFO data  $-64$ ) bytes. For instance, when RFD in FDR = 1 and RFD in FCFTR = 1, flow control is started when  $(512 - 64)$  bytes of data is stored in the receive FIFO. The value set in the RFD bits in this register should be equal to or less than those in FDR.







#### **12.2.19 Transmit Interrupt Register (TRIMD)**

TRIMD is a 32-bit readable/writable register that specifies whether or not to notify write-back completion for each frame using the TWB bit in EESR and an interrupt on transmit operations.



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# **12.3 Operation**

The E-DMAC is connected to the EtherC, and performs efficient transfer of transmit/receive data between the EtherC and memory (buffers) without the intervention of the CPU. The E-DMAC itself reads control information, including buffer pointers called descriptors, relating to the buffers. The E-DMAC reads transmit data from the transmit buffer and writes receive data to the receive buffer in accordance with this control information. By setting up a number of consecutive descriptors (a descriptor list), it is possible to execute transmission and reception continuously.

# **12.3.1 Descriptor List and Data Buffers**

Before starting transmission/reception, the communication program creates transmit and receive descriptor lists in memory. The start addresses of these lists are then set in the transmit and receive descriptor list start address registers.

The descriptor start address must be aligned so that it matches the address boundary according to the descriptor length set by the E-DMAC mode register (EDMR). The transmit buffer start address can be aligned with a byte, a word, and a longword boundary.

# **(1) Transmit Descriptor**

Figure 12.2 shows the relationship between a transmit descriptor and the transmit buffer. According to the specification in this descriptor, the relationship between the transmit frame and transmit buffer can be defined as one frame/one buffer or one frame/multi-buffer.





**Figure 12.2 Relationship between Transmit Descriptor and Transmit Buffer** 



# **(a) Transmit Descriptor 0 (TD0)**

TD0 indicates the transmit frame status. The CPU and E-DMAC use TD0 to report the frame transmission status.







#### **(b) Transmit Descriptor 1 (TD1)**

TD1 specifies the transmit buffer length (maximum 64 kbytes).

**Initial** 



### **(c) Transmit Descriptor 2 (TD2)**

TD2 specifies the 32-bit transmit buffer start address. The transmit buffer start address setting can be aligned with a byte, a word, or a longword boundary.



## **(2) Receive Descriptor**

Figure 12.3 shows the relationship between a receive descriptor and the receive buffer. In frame reception, the E-DMAC performs data rewriting up to a receive buffer 16-byte boundary, regardless of the receive frame length. Finally, the actual receive frame length is reported in the lower 16 bits of RD1 in the descriptor. Data transfer to the receive buffer is performed automatically by the E-DMAC to give a one frame/one buffer or one frame/multi-buffer configuration according to the size of one received frame.



**Figure 12.3 Relationship between Receive Descriptor and Receive Buffer** 



# **(a) Receive Descriptor 0 (RD0)**

RD0 indicates the receive frame status. The CPU and E-DMAC use RD0 to report the frame receive status.















#### **(b) Receive Descriptor 1 (RD1)**

RD1 specifies the receive buffer length (maximum 64 kbytes).

**Initial** 



#### **(c) Receive Descriptor 2 (RD2)**

RD2 specifies the 32-bit receive buffer start address. The receive buffer start address must be aligned with a longword boundary. However, when SDRAM is connected, it must be aligned with a 16-byte boundary.

#### **12.3.2 Transmission**

When the transmit function is enabled and the transmit request bit (TR) is set in the E-DMAC transmit request register (EDTRR), the E-DMAC reads the descriptor used last time from the transmit descriptor list (in the initial state, the descriptor indicated by the transmission descriptor start address register (TDLAR)). If the setting of the TACT bit in the read descriptor is active, the E-DMAC reads transmit frame data sequentially from the transmit buffer start address specified by TD2, and transfers it to the EtherC. The EtherC creates a transmit frame and starts transmission to the MII. After DMA transfer of data equivalent to the buffer length specified in the descriptor, the following processing is carried out according to the TFP value.



1. TFP =  $00$  or  $01$  (frame continuation):

Descriptor write-back is performed after DMA transfer.

2. TFP =  $01$  or 11 (frame end):

Descriptor write-back is performed after completion of frame transmission.

The E-DMAC continues reading descriptors and transmitting frames as long as the setting of the TACT bit in the read descriptors is "active." When a descriptor with an "inactive" TACT bit is read, the E-DMAC resets the transmit request bit (TR) in the transmit register and ends transmit processing (EDTRR).





# **12.3.3 Reception**

When the receive function is enabled and the CPU sets the receive request bit (RR) in the E-DMAC receive request register (EDRRR), the E-DMAC reads the descriptor following the previously used one from the receive descriptor list (in the initial state, the descriptor indicated by the transmission descriptor start address register (TDLAR)), and then enters the receive-standby state. If the setting of the RACT bit is "active" and an own-address frame is received, the E-DMAC transfers the frame to the receive buffer specified by RD2. If the data length of the received frame is greater than the buffer length given by RD1, the E-DMAC performs write-back to the descriptor when the buffer is full (RFP = 10 or 00), then reads the next descriptor. The E-DMAC then continues to transfer data to the receive buffer specified by the new RD2. When frame reception is completed, or if frame reception is suspended because of a certain kind of error, the E-DMAC performs write-back to the relevant descriptor (RFP = 11 or 01), and then ends the receive processing. The E-DMAC then reads the next descriptor and enters the receive-standby state again.

To receive frames continuously, the receive enable control bit (RNC) must be set to 1 in the receive control register (RCR). After initialization, this bit is cleared to 0.





**Figure 12.5 Sample Reception Flowchart** 



# **12.3.4 Multi-Buffer Frame Transmit/Receive Processing**

# **Multi-Buffer Frame Transmit Processing**

If an error occurs during multi-buffer frame transmission, the processing shown in figure 12.6 is carried out by the E-DMAC.

Where the transmit descriptor is shown as inactive (TACT bit  $= 0$ ) in the figure, buffer data has already been transmitted normally, and where the transmit descriptor is shown as active (TACT bit = 1), buffer data has not been transmitted. If a frame transmit error occurs in the first descriptor part where the transmit descriptor is active (TACT bit  $= 1$ ), transmission is halted, and the TACT bit cleared to 0, immediately. The next descriptor is then read, and the position within the transmit frame is determined on the basis of bits TFP1 and TFP0 (continuing [B'00] or end [B'01]). In the case of a continuing descriptor, the TACT bit is cleared to 0, only, and the next descriptor is read immediately. If the descriptor is the final descriptor, not only is the TACT bit cleared to 0, but write-back is also performed to the TFE and TFS bits at the same time. Data in the buffer is not transmitted between the occurrence of an error and write-back to the final descriptor. If error interrupts are enabled in the EtherC/E-DMAC status interrupt permission register (EESIPR), an interrupt is generated immediately after the final descriptor write-back.



**Figure 12.6 E-DMAC Operation after Transmit Error** 

#### **Multi-Buffer Frame Receive Processing**

If an error occurs during multi-buffer frame reception, the processing shown in figure 12.7 is carried out by the E-DMAC.

Where the receive descriptor is shown as inactive  $(RACT bit = 0)$  in the figure, buffer data has already been received normally, and where the receive descriptor is shown as active (RACT bit  $=$ 1), this indicates a buffer for which reception has not yet been performed. If a frame receive error occurs in the first descriptor part where the RACT bit  $= 1$  in the figure, reception is halted immediately and a status write-back to the descriptor is performed.

If error interrupts are enabled in the EtherC/E-DMAC status interrupt permission register (EESIPR), an interrupt is generated immediately after the write-back. If there is a new frame receive request, reception is continued from the buffer after that in which the error occurred.



**Figure 12.7 E-DMAC Operation after Receive Error** 



# **12.4 Usage Notes**

#### **12.4.1 Usage Notes on SH-Ether EtherC/E-DMAC Status Register (EESR)**

When the status bits in EESR of the on-chip E-DMAC of the SH-Ether chip are used as interrupt sources, setting of the interrupt source may fail if software writes a 1 to the corresponding status bit in EESR to clear the bit and this coincides with setting of the status interrupt source in EESR by the EtherC or E-DMAC. Figure 12.8 shows an example of timing in the case where setting of the interrupt source in EESR has failed.

- (a) In this example, both the reception interrupt and transmission interrupt sources of EESR are used. Firstly, reception interrupt source A from the EtherC or E-DMAC sets bit A in EESR and an interrupt is generated.
- (b) The interrupt handler writes 1 to bit A to clear it.
- (c) If clearing of bit A by writing of a 1 and generation of the transmission-interrupt source B signal by the EtherC or E-DMAC take place simultaneously, bit A will be cleared but the status bit for transmission-interrupt source B in EESR might not be set.



**Figure 12.8 Timing of the Case where Setting of the Interrupt Source Bit in EESR by the E-DMAC Fails** 

#### **(1) Countermeasure**

This problem does not occur with all of the bits in EESR. The description applies to some bits but not others. Table 12.1 shows whether the problem can occur with the individual bits and whether the state of the individual interrupt source is reflected in the descriptor.

# **Table 12.1 EESR Bits for which This Problem can Occur and Reflection of Interrupt Sources in the Descriptor**









"Yes": Setting of this interrupt source bit can fail.

"No": Setting of this interrupt source bit does not fail.

Take the following countermeasures for bits where the problem can arise.

- Bit 30 (TWB): Write-back complete interrupt source bit in EESR may not be set. Check the TACT bit in the transmit descriptor.  $TACT = 0$  indicates that the transmission is complete.
- Bit 26 (TABT): Transmit abort detection interrupt source bit in EESR may not be set. Since the state of the interrupt source is written back to the relevant descriptor, check the transmit descriptor (TD0) to confirm the error status.
- Bit 24 (RFCOF): Receive frame counter overflow interrupt source bit in EESR may not be set. However, even if the software is not notified of the interrupt despite the frame counter having overflowed, the upper layer (e.g. TCP/IP) can recognize the error because this LSI discards the frame. After departure from the overflow state, storage in the receive FIFO proceeds normally from the head of the next frame. Therefore, no problem with the system arises.
- Bit 21 (TC): Frame transmission complete interrupt source bit in EESR may not be set. For transmission-related processing, either procedure (a) or (b) given below is effective.
	- (a) Transmission processing without interrupt handling of the frame transmission complete interrupt
		- 1. Prepare multiple transmit descriptors so that multiple frames can be transmitted.
		- 2. After setting the transmit descriptors, set bit 0 (TR) in the E-DMAC transmit request register (EDTRR) to start transmission.
		- 3. Before setting the next frame for transmission in the descriptor (when a transmission task arises), check the TACT bit of the corresponding transmit descriptor.
		- 4. If the TACT bit is clear, set the frame for transmission in the corresponding transmit descriptor and set the TR bit in EDTRR to start transmission. If the TACT bit is set to 1, do not set the transmit descriptor until the next timing.
	- (b) For systems where completion of the transmission of each frame must be confirmed (that is, set frame for transmission  $\rightarrow$  initiate transmission  $\rightarrow$  complete frame transmission  $\rightarrow$ set the next frame for transmission  $\rightarrow$  ...)
		- 1. Check the TACT bit in the last descriptor of the frame for transmission and confirm that  $TACT = 0$ , which means that the transmission was completed.



- Bit 19 (TFUF): Transmit FIFO underflow interrupt source bit in EESR may not be set. When this bit is used as an interrupt source but is not set when it should be, the software is not notified of the interrupt. However, the upper layer will recognize the error in the form of an underflow of the transmit FIFO.
- Bit 16 (RFOF): Receive FIFO overflow interrupt source bit in EESR may not be set. Since the state of the interrupt source is written back to the relevant descriptor, check the receive descriptor (RD0) to confirm the error status.
- Bit 11 (CND), bit 10 (DLC), bit 9 (CD), bit 8 (TRO): The interrupt source bits in EESR for the carrier not detected, loss of carrier detected, delayed collision detected, and transmit retry over interrupts may not be set.

However, since the states of the interrupt sources are written back to the relevant descriptor, check the transmit descriptor (TD0) to confirm the error status.

# **(2) Example of a countermeasure when the software configuration is based on the frame transmit complete interrupt**

The following descriptions are of sample countermeasures for cases when software processing is based on the frame transmit complete interrupt (bit 21 (TC) in EESR).

If the TC interrupt source bit (bit 21) in EESR is not set on completion of transmission, the system will continue to wait for the TC interrupt, leading to stoppage of transmission. This situation arises when the interrupt handler writes a 1 to clear the bit. The sample method given as case (a) below takes the above possibility into account and avoids the problem by monitoring the transmit descriptor in interrupt processing for interrupts other than the TC interrupt.

The sample method given as case (b) below avoids the above problem by setting a timeout limit for retry processing when multiple transmit descriptors are in use.

Note: The countermeasure should be the one that best suits the structure of your driver and other software.



# **(a) Countermeasure by monitoring of the transmit descriptor in the processing of interrupts other than the frame transmit complete (TC) interrupt**

- 1. Prepare multiple transmit descriptors so that multiple frames can be transmitted.
- 2. Provide a "condition flag" for use in step 5 and by interrupt handlers, and then turn off this flag.

This flag serves as a condition flag into which the TACT bits of transmit descriptors are read out.

- 3. After setting the frame for transmission in the first descriptor, start transmission by setting bit 0 (TR) in the E-DMAC transmit request register (EDTRR).
- 4. Before setting the next frame for transmission in the transmit descriptor (when another transmission task arises), check the TACT bit in the corresponding transmit descriptor.
- 5. If the TACT bit is clear, set the frame for transmission in the corresponding transmit descriptor and start transmission by setting the TR bit in EDTRR. If the TACT bit is set to 1, turn on the condition flag and make an OS service call (e.g. to acquire the semaphore) to place the transmission task in the waiting state.

Note: Before setting the TR bit in EDTRR, always read the TR bit and make sure that  $TR = 0$ .

- 6. Wait until the transmission task leaves the waiting state. There are two conditions for making the OS service call (e.g. returning the semaphore) from the interrupt handler to take the task out of the waiting state.
	- Generation of a TC interrupt
	- Generation of an interrupt other than the TC interrupt while the condition flag is on and TACT = 0. Elimination of unwanted processing by checking the TACT bit is only possible when the condition flag is on. The condition flag should be turned off after the task has left the waiting state.
- 7. When the transmission task has left the waiting state and entered execution, set the transmit frame in the corresponding transmit descriptor and then set the TR bit in EDTRR to start transmission.





**Figure 12.9 Countermeasure by Monitoring the Transmit Descriptor in Processing of Interrupts Other than the Frame Transmit Complete (TC) Interrupt** 



## **(b) Countermeasure by adding timeout processing**

- 1. Prepare multiple transmit descriptors so that multiple frames can be transmitted.
- 2. After setting the descriptors, set bit 0 (TR) in the E-DMAC transmit request register (EDTRR) to start transmission.
- 3. Before setting the next frame for transmission in the transmit descriptor (when a transmission task arises), check the TACT bit in the corresponding transmit descriptor.
- 4. If the TACT bit is clear, set the frame for transmission in the corresponding transmit descriptor and set the TR bit in EDTRR to start transmission. If the TACT bit is set to 1, place the transmission task in a waiting state by making an OS service call of a routine with a timeout function (e.g. acquire a semaphore that has a timeout).

Note: Before setting the TR bit in EDTRR, always read the TR bit and make sure that  $TR = 0$ .

- 5. When the transmission task has left the waiting state and entered the execution state within the time limit, set the frame for transmission in the corresponding transmit descriptor and then set the TR bit in EDTRR to start transmission. Taking the transmission task out of the waiting state should be done by the interrupt handler when the TC interrupt is generated.
- 6. When the timeout limit is reached, check the TACT bit in the corresponding transmit descriptor. If the TACT bit is clear, set the frame for transmission in the corresponding transmit descriptor and set the TR bit in EDTRR to start transmission. If the TACT bit is set to 1, place the transmission task in a waiting state by making an OS service call of a routine with a timeout function, or execute a software reset to initialize all of the modules associated with Ethernet functionality.





**Figure 12.10 Method of Adding Timeout Processing** 

# **12.4.2 Usage Notes on SH-Ether Transmit-FIFO Underflow**

In the transmission operation of the on-chip E-DMAC of the SH-Ether, if the E-DMAC cannot acquire bus-mastership due to occupancy of the bus by a bus master other than the E-DMAC, data are not writable to the transmit FIFO and an underflow occurs. The expected operation from that point is as follows: on obtaining the bus mastership, the E-DMAC resumes transmission of the remaining data for transmission; on completion of the DMA transfer, it writes back to the corresponding descriptor, and then fetches the next transmit descriptor. However, if the size of the transmit FIFO set by the FIFO depth register (FDR)  $\leq$  maximum frame length for transmission (1518 bytes), the E-DMAC may stop operating even if the transmit request bit (TR) in the E-DMAC transmit request register (EDTRR) is set to 1, according to the relationship between the length of the remaining frame data and the value of the transmit FIFO pointer.

The relationship between the stoppage of E-DMAC operation and the state of the transmit FIFO is shown below.

The data for transmission, which are placed in external memory (transmit buffer), are DMAtransferred by the E-DMAC to the transmit FIFO and output from the MII pin via the EtherC module. The transmit FIFO write pointer (WP) is used when the E-DMAC writes the data for transmission to the transmit FIFO, and the transmit FIFO read pointer (RP) is used when the EtherC module reads the data for transmission from the transmit FIFO.

- 1. After a software reset, the transmit FIFO will have been initialized, and WP and RP will hold the minimum and maximum values, respectively, of the transmit FIFO capacity.
- 2. When the E-DMAC starts DMA transfer, WP is incremented when the data for transmission are written to the transmit FIFO. On the other hand, RP is incremented when the data written to the transmit FIFO are read out by the EtherC module.
- Note: The transmit FIFO only stores the data of a single frame that is being processed. It does not store data extending over multiple frames. This means that the E-DMAC does not transfer the next frame to the transmit FIFO until the data of the frame being processed are read from the transmit FIFO.
- 3. If the E-DMAC fails to get the bus mastership for a system-related reason, the DMA transfer does not proceed and a transmit underflow occurs ( $WP = RP <$  frame length). Read access to the transmit FIFO by the EtherC is then terminated and RP is initialized (to the maximum value of the size of the transmit FIFO).
- 4. On again acquiring the bus mastership, the E-DMAC resumes DMA transfer of the remaining data of the frame. However, if the transmit FIFO becomes full despite a failure to write all of the remaining frame data from the point when the transmit FIFO underflowed, the E-DMAC waits for the transmit FIFO to become empty before transferring further remaining data.

However, as stated in step 3, the read access to the transmit FIFO by the EtherC module will have been terminated, and the E-DMAC thus stops operating with the transmit FIFO full. In short, this problem arises when [initial value of  $RP - WP$  value  $\lt$  length of remaining frame data] at the point of the transmit underflow.



**Figure 12.11 Operation when E-DMAC Stops and the Transmit FIFO** 

#### **(1) Countermeasure**

This problem occurs under this condition: size of transmit FIFO set in the FIFO depth register (FDR)  $\leq$  maximum length of frame for transmission (1518bytes).

To release the E-DMAC from the stopped state due to this problem, execute a software reset to initialize both the E-DMAC and EtherC modules.

Specific countermeasures are given below. An example for the case where the software does not use TC interrupts in transmission processing is given as (2), and an example for the case with TC interrupt-driven software is given as (3). Both methods require the addition of timeout processing with a maximum specified time as the timeout limit, and are based on the countermeasures explained in section 12.4.1, Usage Notes on SH-Ether EtherC/E-DMAC Status Register (EESR).

The constant specified time corresponds to the timeout limit stated in section 12.4.1, Usage Notes on SH-Ether EtherC/E-DMAC Status Register (EESR). The maximum specified time should be set with reference to the maximum times taking retry processing into consideration, as given in table 12.2. Derive n, the number of repetitions of the constant specified time, from this maximum specified time. If transfer takes more than the maximum specified time, this indicates that the E-DMAC has stopped due to a transmission underflow. In this case, execute a software reset to initialize the EtherC and E-DMAC modules. Since the receiving side will also be initialized by the software reset, the receiving side may require processing in a higher-level layer (e.g. TCP/IP).

Note: The countermeasure should be the one that best suits the structure of your driver and other software.

# **(2) Countermeasure for the case where the software handles transmission without the aid of TC interrupts**

The countermeasure described under (a), Processing transmission without handling of the frame transmission complete (TC) interrupt, below, is based on the method explained in the description of bit 21 in (1) Countermeasure of section 12.4.1, Usage Notes on SH-Ether EtherC/E-DMAC Status Register (EESR).



# **(a) Processing transmission without handling of the frame transmission complete (TC) interrupt**

- 1. Make initial settings for the timer.
- 2. Prepare multiple transmit descriptors so that multiple frames can be transmitted.
- 3. After setting the transmit descriptors, start transmission by setting bit 0 (TR) in the E-DMAC transmit request register (EDTRR).
- 4. Before setting the next frame for transmission in the transmit descriptor (when a transmission task arises), check the TACT bit in the corresponding transmit descriptor.
- 5. If the TACT bit is clear, set the frame for transmission in the corresponding transmit descriptor and start transmission by setting the TR bit in EDTRR. If the TACT bit is set to 1, set counter i to 0 (counter i is the variable that indicates the number of repetitions of the timer operation to measure the specified constant period).
- 6. Start counting by the timer.
- 7. When the specified constant period has elapsed, stop the timer counter and check the TACT bit in the corresponding transmit descriptor.
- 8. If the TACT bit is clear, set the frame for transmission in the corresponding transmit descriptor and set the TR bit in EDTRR to start transmission. If the TACT bit is set to 1, increment counter i.
- 9. While the TACT bit is found to be 1 in step 8 and the value of counter i is less than n, repeat steps 6 to 8 until the maximum specified time is reached (the maximum specified time should be set with reference to the maximum times in consideration of retry processing given in table 12.2, and from this maximum specified time, determine n, the number of repetitions of the specified constant period; n is determined by the user with reference to table 12.2). If counter i reaches or exceeds n, the maximum specified time has elapsed and we can judge that the E-DMAC has stopped due to a transmit underflow. Initialize the EtherC and E-DMAC modules by setting the software-reset bit SWR in the E-DMAC mode register (EDMR). After re-making initial settings for the Ethernet module, initialize the transmit/receive descriptors and transmit/receive buffers.





**Figure 12.12 Processing Transmission without Handling of the TC Interrupt** 

## **(3) Countermeasure for the case of TC interrupt-driven software**

The sample countermeasure for the case of TC interrupt-driven software shown below is the addition of timeout processing within the limit imposed by the maximum specified time. This is based on the method explained in (b) Countermeasure by adding timeout processing in section 12.4.1, Usage Notes on SH-Ether EtherC/E-DMAC Status Register (EESR).

The maximum specified time should be set with reference to the maximum times in consideration of retry processing (table 12.2). From this maximum specified time, determine n, the number of calls of the OS service routine with a timeout function.

# **(b) Countermeasure as the addition of timeout processing within the limit imposed by the maximum specified time**

- 1. Prepare multiple transmit descriptors so that multiple frames can be transmitted.
- 2. After setting the transmit descriptors, start transmission by setting bit 0 (TR) in the E-DMAC transmit request register (EDTRR).
- 3. Before setting the next frame for transmission in the transmit descriptor (when a transmission task arises), check the TACT bit in the transmit descriptor.
- 4. If the TACT bit is clear, set the frame for transmission in the corresponding transmit descriptor and start transmission by setting the TR bit in EDTRR. If the TACT bit is set to 1, set counter i to 0 (counter i is the variable that indicates the number of calls of the OS service routine with a timeout function). Then, place the transmission task in a waiting state by calling the OS routine (e.g. acquire a semaphore that has a timeout limit).

Note: Before setting the TR bit in EDTRR, always read the TR bit and make sure that  $TR = 0$ .

- 5. When the transmission task has left the waiting state and entered the execution state within the specified constant period, set the frame for transmission in the corresponding transmit descriptor and then set the TR bit in EDTRR to start transmission. The transmission task should be taken out of the waiting state by the interrupt handler initiated by generation of the TC interrupt.
- 6. If the transmission task has not left the waiting state within the specified constant period, increment counter i. Then, if  $i < n$ , check the TACT bit in the corresponding transmit descriptor. The value for counting, n, is determined by the user with reference to table 12.2.
- 7. If the TACT bit is clear, set the frame for transmission in the corresponding transmit descriptor and set the TR bit in EDTRR to start transmission. If the TACT bit is set to 1, return the transmission task to the waiting state by calling an OS service routine that has a timeout function, and then repeat steps 5 and 6.


8. If counter i reaches or exceeds n, the maximum specified time has elapsed and we can judge that the E-DMAC has stopped due to a transmit underflow. Initialize the EtherC and E-DMAC modules by setting the software-reset bit SWR in the E-DMAC mode register (EDMR). After re-making initial settings for the Ethernet module, initialize the transmit/receive descriptors and transmit/receive buffers.





**Figure 12.13 Countermeasure for the Case with TC Interrupt-Driven Software: Addition of Timeout Processing within the Limit Imposed by the Maximum Specified Time** 

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#### **Table 12.2 Reference Values for Maximum Specified Time**

Note: The maximum specified time refers to the maximum time taken to transmit a single frame or the maximum time for flow control for a single frame.





# Section 13 Direct Memory Access Controller (DMAC)

This LSI includes the direct memory access controller (DMAC).

The DMAC can be used in place of the CPU to perform high-speed transfers between external devices that have DACK (transfer request acknowledge signal), external memory, on-chip memory, memory-mapped external devices, and on-chip peripheral modules.

## **13.1 Features**

- Four channels (two channels can receive an external request)
- 4-Gbyte physical address space
- Data transfer unit is selectable: Byte, word (2 bytes), longword (4 bytes), and 16 bytes  $(longword \times 4)$
- Maximum transfer count: 16,777,216 transfers
- Address mode: Dual address mode or single address mode can be selected.
- Transfer requests:

External request, on-chip peripheral module request, or auto request can be selected.

The following modules can issue an on-chip peripheral module request.

SCIF0, SCIF1, SCIF2, and SIOF0

• Selectable bus modes:

Cycle steal mode (normal mode and intermittent mode) or burst mode can be selected.

• Selectable channel priority levels:

The channel priority levels are selectable between fixed mode and round-robin mode.

- Interrupt request: An interrupt request can be generated to the CPU after transfers end by the specified counts.
- External request detection: There are following four types of DREQ input detection.
	- Low level detection
	- High level detection
	- Rising edge detection
	- Falling edge detection
- Transfer request acknowledge signal:

Active levels for DACK and TEND can be set independently.





Figure 13.1 shows the block diagram of the DMAC.

**Figure 13.1 Block Diagram of DMAC** 

## **13.2 Input/Output Pins**

The external pins for the DMAC are described below. Table 13.1 lists the configuration of the pins that are connected to external bus. The DMAC has pins for 2 channels (channels 0 and 1) for external bus use.

### **Table 13.1 Pin Configuration**





## **13.3 Register Descriptions**

The DMAC has the following registers. See section 24, List of Registers, for the addresses of these registers and the state of them in each processing status. The SAR for channel 0 is expressed such as SAR\_0.

## **Channel 0:**

- DMA source address register  $0$  (SAR  $0$ )
- DMA destination address register\_0 (DAR\_0)
- DMA transfer count register\_0 (DMATCR\_0)
- DMA channel control register\_0 (CHCR\_0)

## **Channel 1:**

- DMA source address register 1 (SAR 1)
- DMA destination address register 1 (DAR\_1)
- DMA transfer count register\_1 (DMATCR\_1)
- DMA channel control register \_1 (CHCR\_1)

## **Channel 2:**

- DMA source address register 2 (SAR 2)
- DMA destination address register 2 (DAR 2)
- DMA transfer count register 2 (DMATCR 2)
- DMA channel control register 2 (CHCR 2)

## **Channel 3:**

- DMA source address register\_3 (SAR\_3)
- DMA destination address register\_3 (DAR\_3)
- DMA transfer count register\_3 (DMATCR\_3)
- DMA channel control register\_3 (CHCR\_3)

## **Common:**

- DMA operation register (DMAOR)
- DMA extended resource selector 0 (DMARS0)
- DMA extended resource selector 1 (DMARS1)

## **13.3.1 DMA Source Address Registers 0 to 3 (SAR\_0 to SAR\_3)**

SAR are 32-bit readable/writable registers that specify the source address of a DMA transfer. During a DMA transfer, these registers indicate the next source address. When the data is transferred from an external device with the DACK in single address mode, the SAR is ignored.

To transfer data in 16 bits or in 32 bits, specify the address with 16-bit or 32-bit address boundary. When transferring data in 16-byte units, a 16-byte boundary must be set for the source address value. The initial value is undefined.

### **13.3.2 DMA Destination Address Registers 0 to 3 (DAR\_0 to DAR\_3)**

DAR are 32-bit readable/writable registers that specify the destination address of a DMA transfer. During a DMA transfer, these registers indicate the next destination address. When the data is transferred from an external device with the DACK in single address mode, the DAR is ignored.

To transfer data in 16 bits or in 32 bits, specify the address with 16-bit or 32-bit address boundary. When transferring data in 16-byte units, a 16-byte boundary must be set for the destination address value. The initial value is undefined.

## **13.3.3 DMA Transfer Count Registers 0 to 3 (DMATCR\_0 to DMATCR\_3)**

DMATCR are 32-bit readable/writable registers that specify the DMA transfer count. The number of transfers is 1 when the setting is H'00000001, 16,777,215 when H'00FFFFFF is set, and 16,777,216 (the maximum) when H'00000000 is set. During a DMA transfer, these registers indicate the remaining transfer count.

The upper eight bits of DMATCR are always read as 0, and the write value should always be 0. To transfer data in 16 bytes, one 16-byte transfer (128 bits) counts one. The initial value is undefined.



## **13.3.4 DMA Channel Control Registers 0 to 3 (CHCR\_0 to CHCR\_3)**

CHCR are 32-bit readable/writable registers that control the DMA transfer mode.















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Note: \* Writing 0 is possible to clear the flag.

## [Notice]

About the TE bit (Transfer End Flag) of DMA Channel Control Registers (CHCR) in DMAC;

Just when a flag is set to 1, if the flag is read, the read data will be 0, but the internal state will be the same as reading 1.

In that case, if the flag is written 0, the flag will be cleared as 0, because the internal state is the same as reading 1.

## [Workaround]

In the case of using a flag of DMAC, to protect unintended bit clear to 0, please write it as following.

(1) In the case of intended bit clear, please write 0 after reading 1 to the flag.

(2) In the other cases, please write 1 to the flag.

If the flag is not used, it is no problem to write 0 to flag (in the case of intended bit clear, write 0 after reading 1 to the flag).



## **13.3.5 DMA Operation Register (DMAOR)**

DMAOR is a 16-bit readable/writable register that specifies the priority level of channels at the DMA transfer. This register shows the DMA transfer status.





Note: \* Writing 0 is possible to clear the flag.



## [Notice]

About the AE bit (Address Error Flag) and the NMIF bit (NMIF Flag) of DMA Operation Register (DMAOR) in DMAC;

Just when a flag is set to 1, if the flag is read, the read data will be 0, but the internal state will be the same as reading 1.

In that case, if the flag is written 0, the flag will be cleared as 0, because the internal state is the same as reading 1.

## [Workaround]

In the case of using a flag of DMAC, to protect unintended bit clear to 0, please write it as following.

(1) In the case of intended bit clear, please write 0 after reading 1 to the flag.

(2) In the other cases, please write 1 to the flag.

If the flag is not used, it is no problem to write 0 to flag (in the case of intended bit clear, write 0 after reading 1 to the flag).

If an interrupt is generated by the flag and the flag causing the interrupt is read in an interrupt handler routine, this case does not apply to the foregoing notice. However if there is a possibility that another flag bit in the register is set at the timing of reading the register, please follow the workaround described above.



## **13.3.6 DMA Extended Resource Selectors 0 and 1 (DMARS0 and DMARS1)**

DMARS are 16-bit readable/writable registers that specify the DMA transfer request sources from peripheral modules in each channel. DMARS0 specifies the sources for channels 0 and 1, and DMARS1 specifies the sources for channels 2 and 3. This register can set the transfer request of SCIF0, SCIF1, SCIF2, and SIOF0.

When MID/RID other than the values listed in table 13.2 is set, the operation of this LSI is not guaranteed. The transfer request from DMARS is valid only when the resource select bits (RS3 to RS0) has been set to B'1000 for CHCR\_0 to CHCR\_3 registers. Otherwise, even if DMARS has been set, transfer request source is not accepted.



## • DMARS0



#### • DMARS1



## **Table 13.2 Transfer Request Sources**



## **13.4 Operation**

When there is a DMA transfer request, the DMAC starts the transfer according to the predetermined channel priority; when the transfer end conditions are satisfied, it ends the transfer. Transfers can be requested in three modes: auto request, external request, and on-chip peripheral module request. In bus mode, burst mode or cycle steal mode can be selected.

## **13.4.1 DMA Transfer Flow**

After the DMA source address registers (SAR), DMA destination address registers (DAR), DMA transfer count registers (DMATCR), DMA channel control registers (CHCR), DMA operation register (DMAOR), and DMA extended resource selectors (DMARS) are set, the DMAC transfers data according to the following procedure:

- 1. Checks to see if transfer is enabled (DE = 1, DME = 1, TE = 0, AE = 0, NMIF = 0)
- 2. When a transfer request occurs while transfer is enabled, the DMAC transfers one transfer unit of data (depending on the TS0 and TS1 settings). In auto request mode, the transfer begins automatically when the DE bit and DME bit are set to 1. The DMATCR value will be decremented for each transfer. The actual transfer flows vary by address mode and bus mode.
- 3. When the specified number of transfer have been completed (when DMATCR reaches 0), the transfer ends normally. If the IE bit in CHCR is set to 1 at this time, a DEI interrupt is sent to the CPU.
- 4. When an address error or an NMI interrupt is generated, the transfer is aborted. Transfers are also aborted when the DE bit in CHCR or the DME bit in DMAOR is changed to 0.



Figure 13.2 shows a flowchart of this procedure.



**Figure 13.2 DMA Transfer Flowchart** 

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## **13.4.2 DMA Transfer Requests**

DMA transfer requests are basically generated in either the data transfer source or destination, but they can also be generated by external devices or on-chip peripheral modules that are neither the source nor the destination. Transfers can be requested in three modes: auto request, external request, and on-chip peripheral module request. The request mode is selected in the RS3 to RS0 bits in DMARS0 and DMARS 1.

**Auto-Request Mode:** When there is no transfer request signal from an external source, as in a memory-to-memory transfer or a transfer between memory and an on-chip peripheral module unable to request a transfer, auto-request mode allows the DMAC to automatically generate a transfer request signal internally. When the DE bits in CHCR and the DME bit in DMAOR are set to 1, the transfer begins so long as the AE and NMIF bits in DMAOR are all 0.

**External Request Mode:** In this mode, a transfer is performed at the request signals (DREQ0 and DREQ1) of an external device. This mode is valid only in channel 0 and channel 1. Choose one of the modes shown in table 13.3 according to the application system. When this mode is selected, if the DMA transfer is enabled (DE = 1, DME = 1, TE = 0, AE = 0, NMIF = 0), a transfer is performed upon a request at the DREQ input.





Choose to detect DREQ by either the edge or level of the signal input with the DL bit and DS bit in CHCR\_0 and CHCR\_1 as shown in table 13.4. The source of the transfer request does not have to be the data transfer source or destination.



### **Table 13.4 Selecting External Request Detection with DL, DS Bits**



**CHCR\_0 or CHCR\_1** 

When DREQ is accepted, the DREQ pin becomes request accept disabled state. After issuing acknowledge signal DACK for the accepted DREQ, the DREQ pin again becomes request accept enabled state.

When DREQ is used by level detection, there are following two cases by the timing to detect the next DREQ after outputting DACK.

- Overrun 0: Transfer is aborted after the same number of transfer has been performed as requests.
- Overrun 1: Transfer is aborted after transfers have been performed for (the number of requests plus 1) times.

The DO bit in CHCR selects this overrun 0 or overrun 1.

### **Table 13.5 Selecting External Request Detection with DO Bit**

### **CHCR\_0 or CHCR\_1**



**On-Chip Peripheral Module Request Mode:** In this mode, a transfer is performed at the transfer request signal of an on-chip peripheral module. Transfer request signals comprise the transmit data empty transfer request and receive data full transfer request from the SCIF0, SCIF1, SCIF2, and SIOF0 set by DMARS0 and DMARS 1.

When this mode is selected, if the DMA transfer is enabled ( $DE = 1$ ,  $DME = 1$ ,  $TE = 0$ ,  $AE = 0$ ,  $NMIF = 0$ , a transfer is performed upon the input of a transfer request signal.

When a transmit data empty transfer request of the SCIF0 is set as the transfer request, the transfer destination must be the SCIF0's transmit data register. Likewise, when receive data full transfer request of the SCIF0 is set as the transfer request, the transfer source must be the SCIF0's receive data register. These conditions also apply to the SCIF1, SCIF2, and SIOF0.

The number of the receive FIFO triggers can be set as a transfer request depending on an on-chip peripheral module. Data needs to be read after the DMA transfer is ended, because data may be remained in the receive FIFO when the receive FIFO trigger condition is not satisfied.

<b>CHCR</b>	<b>DMARS</b>		<b>DMA Transfer</b>				
RS[3:0]	MID	<b>RID</b>	Request <b>Source</b>	<b>DMA Transfer</b> <b>Request Signal</b>	Source	<b>Destination</b>	<b>Bus</b> Mode
1000	001000	01	<b>SCIF0</b> transmitter	TXI0 (transmit FIFO data empty interrupt)	Any	SCFTDR0	Cycle steal
		10	<b>SCIF0</b> receiver	RXI0 (receive FIFO data full interrupt)	SCFRDR0	Any	Cycle steal
	001001	01	SCIF <sub>1</sub> transmitter	TXI1 (transmit FIFO data empty interrupt)	Any	SCFTDR0	Cycle steal
		10	SCIF <sub>1</sub> receiver	RXI1 (receive FIFO data full interrupt)	SCFRDR1	Any	Cycle steal
	001010	01	SCIF <sub>2</sub> transmitter	TXI2 (transmit FIFO data empty interrupt)	Any	SCFTDR2	Cycle steal
		10	SCIF <sub>2</sub> receiver	RXI2 (receive FIFO data full interrupt)	SCFRDR2	Any	Cycle steal
	010100	01	SIOF <sub>0</sub> transmitter	TXI0 (transmit FIFO data empty interrupt)	Any	SITDR <sub>0</sub>	Cycle steal
		10	SIOF <sub>0</sub> receiver	RXI0 (receive FIFO data full interrupt)	SIRDR0	Any	Cycle steal

**Table 13.6 Selecting On-Chip Peripheral Module Request Modes with RS3 to RS0 Bits** 

## **13.4.3 Channel Priority**

When the DMAC receives simultaneous transfer requests on two or more channels, it transfers data according to a predetermined priority. Two modes (fixed mode and round-robin mode) are selected by the PR1 and PR0 bits in DMAOR.

**Fixed Mode:** In this mode, the priority levels among the channels remain fixed. There are two kinds of fixed modes as follows:

- $CH0 > CH1 > CH2 > CH3$
- $CH0 > CH2 > CH3 > CH1$

These are selected by the PR1 and the PR0 bits in DMAOR.



**Round-Robin Mode:** In round-robin mode each time data of one transfer unit (word, byte, longword, or 16-byte unit) is transferred on one channel, the priority is rotated. The channel on which the transfer was just finished rotates to the bottom of the priority. The round-robin mode operation is shown in figure 13.3. The priority of round-robin mode is  $CH0 > CH1 > CH2 > CH3$ immediately after a reset. When round-robin mode is specified, the same bus mode, either cycle steal mode or burst mode, must be specified for all of the channels.



### **Figure 13.3 Round-Robin Mode**



Figure 13.4 shows how the priority changes when channel 0 and channel 3 transfers are requested simultaneously and a channel 1 transfer is requested during the channel 0 transfer. The DMAC operates as follows:

- 1. Transfer requests are generated simultaneously to channels 0 and 3.
- 2. Channel 0 has a higher priority, so the channel 0 transfer begins first (channel 3 waits for transfer).
- 3. A channel 1 transfer request occurs during the channel 0 transfer (channels 1 and 3 are both waiting)
- 4. When the channel 0 transfer ends, channel 0 becomes lowest priority.
- 5. At this point, channel 1 has a higher priority than channel 3, so the channel 1 transfer begins (channel 3 waits for transfer).
- 6. When the channel 1 transfer ends, channel 1 becomes lowest priority.
- 7. The channel 3 transfer begins.
- 8. When the channel 3 transfer ends, channels 3 and 2 shift downward in priority so that channel 3 becomes the lowest priority.



**Figure 13.4 Changes in Channel Priority in Round-Robin Mode** 



## **13.4.4 DMA Transfer Types**

DMA transfer has two types; single address mode transfer and dual address mode transfer. They depend on the number of bus cycles of access to source and destination. A data transfer timing depends on the bus mode, which has cycle steal mode and burst mode. The DMAC supports the transfers shown in table 13.7.

#### **Table 13.7 Supported DMA Transfers**



Notes: 1. Dual: Dual address mode

2. Single: Single address mode

 3. For on-chip peripheral modules, 16-byte transfer is available only by registers which can be accessed in longword units.

## **Address Modes:**

• Dual Address Mode

In dual address mode, both the transfer source and destination are accessed by an address. The source and destination can be located externally or internally.

DMA transfer requires two bus cycles because data is read from the transfer source in a data read cycle and written to the transfer destination in a data write cycle. At this time, transfer data is temporarily stored in the DMAC. In the transfer between external memories as shown in figure 13.5, data is read to the DMAC from one external memory in a data read cycle, and then that data is written to the other external memory in a write cycle.



**Figure 13.5 Data Flow of Dual Address Mode** 

Auto request, external request, and on-chip peripheral module request are available for the transfer request. DACK can be output in read cycle or write cycle in dual address mode. The channel control register (CHCR) can specify whether the DACK is output in read cycle or write cycle.



Figure 13.6 shows an example of DMA transfer timing in dual address mode.

**Figure 13.6 Example of DMA Transfer Timing in Dual Mode (Source: Ordinary Memory, Destination: Ordinary Memory)** 

• Single Address Mode

In single address mode, either the transfer source or transfer destination peripheral device is accessed (selected) by means of the DACK signal, and the other device is accessed by an address. In this mode, the DMAC performs one DMA transfer in one bus cycle, accessing one of the external devices by outputting the DACK transfer request acknowledge signal to it, and at the same time outputting an address to the other device involved in the transfer. For example, in the case of transfer between external memory and an external device with DACK shown in figure 13.7, when the external device outputs data to the data bus, that data is written to the external memory in the same bus cycle.



**Figure 13.7 Data Flow in Single Address Mode** 

Two kinds of transfer are possible in single address mode: (1) transfer between an external device with DACK and a memory-mapped external device, and (2) transfer between an external device with DACK and external memory. In both cases, only the external request signal (DREQ) is used for transfer requests.





Figure 13.8 shows an example of DMA transfer timing in single address mode.

**Figure 13.8 Example of DMA Transfer Timing in Single Address Mode** 

**Bus Modes:** There are two bus modes: cycle steal mode and burst mode. Select the mode in the TB bits in the channel control register (CHCR).

- Cycle-Steal Mode
	- Normal mode

In cycle-steal normal mode, the bus mastership is given to another bus master after a onetransfer-unit (byte, word, longword, or 16-byte unit) DMA transfer. When another transfer request occurs, the bus mastership is obtained from the other bus master and a transfer is performed for one transfer unit. When that transfer ends, the bus mastership is passed to the other bus master. This is repeated until the transfer end conditions are satisfied.

In cycle-steal normal mode, transfer areas are not affected regardless of settings of the transfer request source, transfer source, and transfer destination.

Figure 13.9 shows an example of DMA transfer timing in cycle-steal normal mode. Transfer conditions shown in the figure are:

- Dual address mode
- DREQ low level detection



## **Figure 13.9 DMA Transfer Example in Cycle-Steal Normal Mode (Dual Address, DREQ Low Level Detection)**

Intermittent mode 16 and intermittent mode 64

In intermittent mode of cycle steal, the DMAC returns the bus mastership to other bus master whenever a unit of transfer (byte, word, longword, or 16-byte unit) is complete. If the next transfer request occurs after that, the DMAC gets the bus mastership from other bus master after waiting for 16 or 64 clocks in Bφ count. The DMAC then transfers data of one unit and returns the bus mastership to other bus master. These operations are repeated until the transfer end condition is satisfied. It is thus possible to make lower the ratio of bus occupation by DMA transfer than cycle-steal normal mode.

When the DMAC gets again the bus mastership, DMA transfer can be postponed in case of entry updating due to cache miss.

This intermittent mode can be used for all transfer section; transfer request source, transfer source, and transfer destination. The bus modes, however, must be cycle steal mode in all channels.



Figure 13.10 shows an example of DMA transfer timing in cycle steal intermittent mode. Transfer conditions shown in the figure are:

- Dual address mode
- DREQ low level detection



**Figure 13.10 Example of DMA Transfer in Cycle Steal Intermittent Mode (Dual Address, DREQ Low Level Detection)** 

• Burst Mode

In burst mode, once the DMAC obtains the bus mastership, the transfer is performed continuously without releasing the bus mastership until the transfer end condition is satisfied. In external request mode with level detection of the DREQ pin, however, when the DREQ pin is not active, the bus mastership passes to the other bus master after the DMAC transfer request that has already been accepted ends, even if the transfer end conditions have not been satisfied.

Burst mode cannot be used when the on-chip peripheral module is the transfer request source.

Figure 13.11 shows DMA transfer timing in burst mode.





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**Relationship between Request Modes and Bus Modes by DMA Transfer Category:** Table

13.8 shows the relationship between request modes and bus modes by DMA transfer category.





B: Burst mode, C: Cycle steal mode

Notes: 1. External requests and auto requests are all available.

- 2. External requests, auto requests, and on-chip peripheral module requests are all available. However, for on-chip peripheral module requests, the request source register must be designated as the transfer source or the transfer destination.
- 3. Access size permitted for the on-chip peripheral module register functioning as the transfer source or transfer destination.
- 4. If the transfer request is an external request, channels 0 and 1 are only available.



**Bus Mode and Channel Priority:** When the priority is set in fixed mode (CH0 > CH1), even though channel 1 is transferring in burst mode, if there is a transfer request to channel 0 which has a higher priority, the transfer of channel 0 will begin immediately.

At this time, if channel 0 is also operating in burst mode, the channel 1 transfer will continue when the channel 0 transfer with a higher priority has completely finished.

If channel 0 is operating in cycle steal mode, immediately after channel 0 with a higher priority completes the transfer of one transfer unit, the channel 1 transfer will begin again without releasing the bus mastership. Transfer will then switch between the two in the order of channel 0, channel 1, channel 0, and channel 1. For the bus state, the CPU cycle after cycle steal mode transfer finishes is replaced with a burst mode transfer cycle (hereafter referred to as burst mode high-priority execution).

This example is illustrated in figure 13.12. If there are channels with conflicting burst transfers, transfer for the channel with the highest priority is performed first.

In DMA transfer for more than one channel, the DMAC does not give the bus mastership to the bus master until all conflicting burst transfers have finished.



**Figure 13.12 Bus State when Multiple Channels are Operating** 

In round-robin mode, the priority changes according to the specifications shown in figure 13.3. Note that a channel operating in cycle steal mode cannot be handled together with a channel operating in burst mode.


# **13.4.5 Number of Bus Cycle States and DREQ Pin Sampling Timing**

**Number of Bus Cycle States:** When the DMAC is the bus master, the number of bus cycle states is controlled by the bus state controller (BSC) in the same way as when the CPU is the bus master. For details, see section 7, Bus State Controller (BSC).

DREQ **Pin Sampling Timing:** Figures 13.13, 13.14, 13.15, and 13.16 show the sample timing of the DREQ input in each bus mode, respectively.



**Figure 13.13 Example of DREQ Input Detection in Cycle Steal Mode Edge Detection** 



**Figure 13.14 Example of DREQ Input Detection in Cycle Steal Mode Level Detection** 





**Figure 13.15 Example of DREQ Input Detection in Burst Mode Edge Detection** 



**Figure 13.16 Example of DREQ Input Detection in Burst Mode Level Detection** 



**Figure 13.17 Example of DMA Transfer End in Cycle Steal Mode Level Detection** 

When an 8-bit or 16-bit external device is accessed in longword units, or when an 8-bit external device is accessed in word units, the DACK output is divided because of the data alignment. This example is illustrated in figure 13.18.





**Figure 13.18 Example of BSC Ordinary Memory Access (No Wait, Idle Cycle 1, Longword Access to 16-Bit Device)** 



# **13.5 Usage Notes**

Pay attentions to the following notes when the DMAC is used.

# **13.5.1 Notes on DACK Pin Output**

When burst mode and cycle steal mode are simultaneously set in two or more channels, an additional DACK may be asserted at the end of burst transfer. This phenomenon will occur when all of the conditions described below are satisfied.

- 1. When the DMA transfer is simultaneously performed in two or more channels support both burst mode and cycle steal mode
- 2. When the channel to be used in burst mode is set to dual address mode, and DACK is output in data write cycle
- 3. When the DMAC cannot obtain the bus mastership consecutively even though a transfer demand of cycle steal has been received after the completion of burst transfer

This phenomenon is avoided by taking either of three measures shown below.

• Measure 1

After confirming the completion of burst transfer (TE bit  $= 1$ ), perform the DMA transfer of other cycle steal mode

Measure 2

The channel to be used in burst mode should not be set to output DACK in data write cycle

• Measure 3

When the DMA transfer is simultaneously performed in two or more channels, set all of the channels to burst mode or cycle steal mode



# **13.5.2 Notes On DREQ Sampling When DACK is Divided in External Access**

#### **(1) Error Phenomenon**

When the DACK output is divided in an external access, DREQ may be sampled twice at maximum in the external access.

#### **(2) Error Conditions and Phenomenon**

Conditions: The DACK output is divided in an external access when:

- 16-byte access,
- 32-bit access to the 8-bit space,
- 16-bit access to the 8-bit space, or
- 32-bit access to the 16-bit space

is performed with either of the following idle cycle settings made:

- Idle cycles between write-write cycles (IWW =  $01$  or more)
- Idle cycles between read-read cycles in the same spaces (IWRRS =  $01$  or more)
- External wait mask specification ( $WM = 0$ ).

In addition to the above conditions, the following conditions are included depending on the detection method of DREQ.

- For DREQ level detection: only write access
- For DREQ edge detection: both write access and read access

Phenomenon: The detection timings of the DREQ pin in the above access are shown in figures 13.19 to 13.22.



**Figure 13.19 Example of DREQ Input Detection in Cycle Steal Mode Edge Detection When DACK is Divided to 4 by Idle Cycles** 





**Figure 13.20 Example of DREQ Input Detection in Cycle Steal Mode Edge Detection When DACK is Divided to 2 by Idle Cycles** 



**Figure 13.21 Example of DREQ Input Detection in Cycle Steal Mode Level Detection When DACK is Divided to 4 by Idle Cycles** 





**Figure 13.22 Example of DREQ Input Detection in Cycle Steal Mode Level Detection When DACK is Divided to 2 by Idle Cycles** 

# **(3) Notes**

For the external access described in (2) above, note the following.

- 1. When the DREQ edge is detected, input one DREQ edge at maximum in the bus cycle.
- 2. When the DREQ level is detected in overrun 0, negate the DREQ input in the bus cycle after the detection of the first DACK output negation and before the second DACK output negation.
- 3. When the DREQ level is detected in overrun 1, negate DREQ input after the detection of the first DACK output assertion and before the second DACK output assertion.



# **13.5.3 Other Notes**

- 1. Before making a transition to standby mode, either wait until DMA transfer finishes or suspend DMA transfer.
- 2. If an on-chip peripheral module whose clock supply is to be stopped by the module standby function is performing DMA transfer, either wait until DMA transfer finishes or suspend DMA transfer before making a transition to module standby mode.
- 3. Do not write to SAR, DAR, DMATCR, or DMARS during DMA transfer.

# **Concerning Above Notes 1 and 2:**

DMA transfer end can be confirmed by checking whether the TE bit in CHCR is set to 1.

To suspend DMA transfer, clear the DE bit in CHCR to 0.





# Section 14 Compare Match Timer (CMT)

This LSI has an on-chip compare match timer (CMT) consisting of a 2-channel 16-bit timer. The CMT has a16-bit counter, and can generate interrupts at set intervals.

# **14.1 Features**

CMT has the following features.

- Selection of four counter input clocks Any of four internal clocks (Pφ/8, Pφ/32, Pφ/128, and Pφ/512) can be selected independently for each channel.
- Interrupt request on compare match
- When not in use, CMT can be stopped by halting its clock supply to reduce power consumption.

Figure 14.1 shows a block diagram of CMT.



**Figure 14.1 Block Diagram of Compare Match Timer** 

# **14.2 Register Descriptions**

The CMT has the following registers.

- Compare match timer start register (CMSTR)
- Compare match timer control/status register\_0 (CMCSR\_0)
- Compare match counter\_0 (CMCNT\_0)
- Compare match constant register\_0 (CMCOR\_0)
- Compare match timer start register 1 (CMSTR 1)
- Compare match timer control/status register 1 (CMCSR 1)
- Compare match counter 1 (CMCNT\_1)
- Compare match constant register\_1 (CMCOR\_1)

# **14.2.1 Compare Match Timer Start Register (CMSTR)**

CMSTR is a 16-bit register that selects whether compare match counter (CMCNT) operates or is stopped.



CMSTR is initialized to H'0000 by a power-on reset and a transition to standby mode.

#### **14.2.2 Compare Match Timer Control/Status Register (CMCSR)**

CMCSR is a 16-bit register that indicates compare match generation, enables interrupts and selects the counter input clock.



CMCSR is initialized to H'0000 by a power-on reset and a transition to standby mode.





Note: \* Only 0 can be written, to clear the flag.

## **14.2.3 Compare Match Counter (CMCNT)**

CMCNT is a 16-bit register used as an up-counter. When the counter input clock is selected with bits CKS1 and CKS0 in CMCSR and the STR bit in CMSTR is set to 1, CMCNT starts counting using the selected clock.

When the value in CMCNT and the value in compare match constant register (CMCOR) match, CMCNT is cleared to H'0000 and the CMF flag in CMCSR is set to 1.

CMCNT is initialized to H'0000 by a power-on reset and a transition to standby mode.

#### **14.2.4 Compare Match Constant Register (CMCOR)**

CMCOR is a 16-bit register that sets the interval up to a compare match with CMCNT.

CMCOR is initialized to H'FFFF by a power-on reset and is initialized to H'FFFF in standby mode.



# **14.3 Operation**

# **14.3.1 Interval Count Operation**

When an internal clock is selected with bits CKS1 and CKS0 in CMCSR and the STR bit in CMSTR is set to 1, CMCNT starts incrementing using the selected clock. When the values in CMCNT and CMCOR match, CMCNT is cleared to H'0000 and the CMF flag in CMCSR is set to 1. When the CMIE bit in CMCSR is set to 1, a compare match interrupt (CMI) is requested. CMCNT then starts counting up again from H'0000.

Figure 14.2 shows the operation of the compare match counter.



**Figure 14.2 Counter Operation** 

# **14.3.2 CMCNT Count Timing**

One of four internal clocks (Pφ/8, Pφ/32, Pφ/128, and Pφ/512) obtained by dividing the Pφ clock can be selected with bits CKS1 and CKS0 in CMCSR. Figure 14.3 shows the timing.



**Figure 14.3 Count Timing** 



# **14.4 Interrupts**

#### **14.4.1 Interrupt Sources**

The CMT has channels and each of them to which a different vector address is allocated has compare match interrupt. When both the interrupt request flag (CMF) and interrupt enable bit (CMIE) are set to 1, the corresponding interrupt request is output. When the interrupt is used to activate a CPU interrupt, the priority of channels can be changed by the interrupt controller settings. For details, see section 6, Interrupt Controller (INTC).

# **14.4.2 Timing of Setting Compare Match Flag**

When CMCOR and CMCNT match, a compare match signal is generated and the CMF bit in CMCSR is set to 1. The compare match signal is generated in the last cycle in which the values match (when the CMCNT value is updated to H'0000). That is, after a match between CMCOR and CMCNT, the compare match signal is not generated until the next CMCNT counter clock input. Figure 14.4 shows the timing of CMF bit setting.



**Figure 14.4 Timing of CMF Setting** 

# **14.4.3 Timing of Clearing Compare Match Flag**

The CMF bit in CMCSR is cleared by reading 1 from this bit, then writing 0.

# **14.5 Usage Notes**

#### **14.5.1 Conflict between Write and Compare-Match Processes of CMCNT**

When the compare match signal is generated in the T2 cycle while writing to CMCNT, clearing CMCNT has priority over writing to it. In this case, CMCNT is not written to. Figure 14.5 shows the timing to clear the CMCNT counter.



**Figure 14.5 Conflict between Write and Compare-Match Processes of CMCNT** 



# **14.5.2 Conflict between Word-Write and Count-Up Processes of CMCNT**

Even when the count-up occurs in the T2 cycle while writing to CMCNT in words, the writing has priority over the count-up. In this case, the count-up is not performed. Figure 14.6 shows the timing to write to CMCNT in words.



**Figure 14.6 Conflict between Word-Write and Count-Up Processes of CMCNT** 



## **14.5.3 Conflict between Byte-Write and Count-Up Processes of CMCNT**

Even when the count-up occurs in the T2 cycle while writing to CMCNT in bytes, the byte-writing has priority over the count-up. In this case, the count-up is not performed. The byte data on another side, which is not written to, is also not counted and the previous contents remain. Figure 14.7 shows the timing when the count-up occurs in the T2 cycle while writing to CMCNT in bytes.



**Figure 14.7 Conflict between Byte-Write and Count-Up Processes of CMCNT** 

# **14.5.4 Conflict between Write Processes to CMCNT with the Counting Stopped and CMCOR**

Writing the same value to CMCNT with the counting stopped and CMCOR is prohibited. If written, the CMF flag in CMCSR is set to 1 and CMCNT is cleared to H'0000.





# Section 15 Serial Communication Interface with FIFO (SCIF)

# **15.1 Overview**

This LSI has a three-channel serial communication interface with FIFO (SCIF) that supports both asynchronous and clock synchronous serial communication. It also has 16-stage FIFO registers for both transmission and reception independently for each channel that enable this LSI to perform efficient high-speed continuous communication.

# **15.1.1 Features**

- Asynchronous serial communication:
	- $\overline{\phantom{C}}$  Serial data communication is performed by start-stop in character units. The SCIF can communicate with a universal asynchronous receiver/transmitter (UART), an asynchronous communication interface adapter (ACIA), or any other communications chip that employs a standard asynchronous serial system. There are eight selectable serial data communication formats.
	- Data length: 7 or 8 bits
	- Stop bit length: 1 or 2 bits
	- Parity: Even, odd, or none
	- Receive error detection: Parity, framing, and overrun errors
	- Break detection: Break is detected when a framing error is followed by at least one frame at the space 0 level (low level). It is also detected by reading the RxD level directly from the port data register when a framing error occurs.
- Synchronous mode:
	- Serial data communication is synchronized with a clock signal. The SCIF can communicate with other chips having a synchronous communication function. There is one serial data communication format.
	- Data length: 8 bits
	- Receive error detection: Overrun errors
- Full duplex communication: The transmitting and receiving sections are independent, so the SCIF can transmit and receive simultaneously. Both sections use 16-stage FIFO buffering, so high-speed continuous data transfer is possible in both the transmit and receive directions.
- On-chip baud rate generator with selectable bit rates



- Internal or external transmit/receive clock source: From either baud rate generator (internal) or SCK pin (external)
- Four types of interrupts: Transmit-FIFO-data-empty, break, receive-FIFO-data-full, and receive-error interrupts are requested independently.
- When the SCIF is not in use, it can be stopped by halting the clock supplied to it, saving power.
- In asynchronous, on-chip modem control functions  $(\overline{RTS})$  and  $\overline{CTS})$  (only for channel 1 and channel 0).
- The number of data in the transmit and receive FIFO registers and the number of receive errors of the receive data in the receive FIFO register can be ascertained.
- A time-out error (DR) can be detected when receiving in asynchronous mode.





Figure 15.1 shows a block diagram of the SCIF for each channel.

**Figure 15.1 Block Diagram of SCIF** 



# **15.2 Pin Configuration**

The SCIF has the serial pins summarized in table 15.1.

# **Table 15.1 SCIF Pins**





# **15.3 Register Description**

The SCIF has the following registers. These registers specify the data format and bit rate, and control the transmitter and receiver sections.

- Receive FIFO data register 0 (SCFRDR 0)
- Transmit FIFO data register\_0 (SCFTDR\_0)
- Serial mode register\_0 (SCSMR\_0)
- Serial control register\_0 (SCSCR\_0)
- Serial status register\_0 (SCFSR\_0)
- Bit rate register\_0 (SCBRR\_0)
- FIFO control register\_0 (SCFCR\_0)
- FIFO data count register\_0 (SCFDR\_0)
- Serial port register\_0 (SCSPTR\_0)
- Line status register\_0 (SCLSR\_0)
- Receive FIFO data register\_1 (SCFRDR\_1)
- Transmit FIFO data register\_1 (SCFTDR\_1)
- Serial mode register\_1 (SCSMR\_1)
- Serial control register\_1 (SCSCR\_1)
- Serial status register\_1 (SCFSR\_1)
- Bit rate register\_1 (SCBRR\_1)
- FIFO control register\_1 (SCFCR\_1)
- FIFO data count register\_1 (SCFDR\_1)
- Serial port register\_1 (SCSPTR\_1)
- Line status register\_1 (SCLSR\_1)
- Receive FIFO data register\_2 (SCFRDR\_2)
- Transmit FIFO data register\_2 (SCFTDR\_2)
- Serial mode register\_2 (SCSMR\_2)
- Serial control register\_2 (SCSCR\_2)
- Serial status register\_2 (SCFSR\_2)
- Bit rate register\_2 (SCBRR\_2)
- FIFO control register\_2 (SCFCR\_2)
- FIFO data count register\_2 (SCFDR\_2)
- Serial port register\_2 (SCSPTR\_2)
- Line status register\_2 (SCLSR\_2)



# **15.3.1 Receive Shift Register (SCRSR)**

SCRSR receives serial data. Data input at the RxD pin is loaded into SCRSR in the order received, LSB (bit 0) first, converting the data to parallel form. When one byte has been received, it is automatically transferred to SCFRDR, the receive FIFO data register. The CPU cannot read or write to SCRSR directly.

## **15.3.2 Receive FIFO Data Register (SCFRDR)**

SCFRDR is a 16-stage 8-bit FIFO register that stores serial receive data. The SCIF completes the reception of one byte of serial data by moving the received data from the receive shift register (SCRSR) into SCFRDR for storage. Continuous reception is possible until 16 bytes are stored.

The CPU can read but not write to SCFRDR. If data is read when there is no receive data in the SCFRDR, the value is undefined. When this register is full of receive data, subsequent serial data is lost.

SCFRDR is initialized to undefined value by a power-on reset.



#### **15.3.3 Transmit Shift Register (SCTSR)**

SCTSR transmits serial data. The SCIF loads transmit data from the transmit FIFO data register (SCFTDR) into SCTSR, then transmits the data serially from the TxD pin, LSB (bit 0) first. After transmitting one data byte, the SCIF automatically loads the next transmit data from SCFTDR into SCTSR and starts transmitting again. The CPU cannot read or write to SCTSR directly.



# **15.3.4 Transmit FIFO Data Register (SCFTDR)**

SCFTDR is a 16-stage 8-bit FIFO register that stores data for serial transmission. When the SCIF detects that the transmit shift register (SCTSR) is empty, it moves transmit data written in the SCFTDR into SCTSR and starts serial transmission. Continuous serial transmission is performed until there is no transmit data left in SCFTDR. SCFTDR can always be written to by the CPU.

When SCFTDR is full of transmit data (16 bytes), no more data can be written. If writing of new data is attempted, the data is ignored.

SCFTDR is initialized to undefined value by a power-on reset.



# **15.3.5 Serial Mode Register (SCSMR)**

SCSMR is a 16-bit register that specifies the SCIF serial communication format and selects the clock source for the baud rate generator.

The CPU can always read and write to SCSMR. SCSMR is initialized to H'0000 by a power-on reset.











## **15.3.6 Serial Control Register (SCSCR)**

SCSCR is a 16-bit register that operates the SCIF transmitter/receiver, enables/disables interrupt requests, and selects the transmit/receive clock source. The CPU can always read and write to SCSCR. SCSCR is initialized to H'0000 by a power-on reset.















# **15.3.7 Serial Status Register (SCFSR)**

SCFSR is a 16-bit register. The upper 8 bits indicate the number of receives errors in the SCFRDR data, and the lower 8 bits indicate the status flag indicating SCIF operating state.

The CPU can always read and write to SCFSR, but cannot write 1 to the status flags (ER, TEND, TDFE, BRK, RDF, and DR). These flags can be cleared to 0 only if they have first been read (after being set to 1). Bits 3 (FER) and 2 (PER) are read-only bits that cannot be written. SCFSR is initialized to H'0060 by a power-on reset.




























Note: \* The only value that can be written is 0 to clear the flag.



## **15.3.8 Bit Rate Register (SCBRR)**

SCBRR is an 8-bit register that, together with the baud rate generator clock source selected by the CKS1 and CKS0 bits in the serial mode register (SCSMR), determines the serial transmit/receive bit rate.

The CPU can always read and write to SCBRR. SCBRR is initialized to H'FF by a power-on reset. Each channel has independent baud rate generator control, so different values can be set in three channels.

The SCBRR setting is calculated as follows:

• Asynchronous mode:

$$
N = \frac{P\varphi}{64 \times 2^{2n-1} \times B} \times 10^6 - 1
$$

Synchronous mode:

$$
N = \frac{P\phi}{8 \times 2^{2n-1} \times B} \times 10^6 - 1
$$

- B: Bit rate (bits/s)
- N: SCBRR setting for baud rate generator  $(0 \le N \le 255)$ (The setting value should satisfy the electrical characteristics.)
- Pφ: Operating frequency for peripheral modules (MHz)
- n: Baud rate generator clock source  $(n = 0, 1, 2, 3)$  (for the clock sources and values of n, see table 15.2.)





## **Table 15.2 SCSMR Settings**

$$
Error (%) = \left\{ \frac{P\phi \times 10^6}{(N + 1) \times B \times 64^{2n-1} \times 2} \cdot 1 \right\} \times 100
$$

Table 15.3 lists examples of SCBRR settings in asynchronous mode, and table 15.4 lists examples of SCBRR settings in synchronous mode.

	$P\phi$ (MHz)											
		5			6		6.144					
Bit Rate (bits/s) n		N	Error (%)	n	N	Error (%)	n	N	Error $(\%)$			
110	2	88	$-0.25$	2	106	$-0.44$	2	108	0.08			
150	2	64	0.16	2	77	0.16	2	79	0.00			
300	1	129	0.16	1	155	0.16	1	159	0.00			
600	1	64	0.16	1	77	0.16	1	79	0.00			
1200	0	129	0.16	0	155	0.16	0	159	0.00			
2400	0	64	0.16	0	77	0.16	0	79	0.00			
4800	0	32	$-1.36$	0	38	0.16	0	39	0.00			
9600	0	15	1.73	0	19	$-2.34$	0	19	0.00			
19200	$\Omega$	7	1.73	0	9	$-2.34$	0	9	0.00			
31250	0	$\overline{4}$	0.00	0	5	0.00	0	5	2.40			
38400	0	3	1.73	0	4	$-2.34$	0	4	0.00			

**Table 15.3 Bit Rates and SCBRR Settings in Asynchronous Mode** 







## **P**φ **(MHz)**



	T \											
		16		19.6608				20		24		
<b>Bit Rate</b> (bits/s)	n	N	Error $(\%)$	n	N	Error (%)	n	N	Error $(\%)$	n	N	Error $(\%)$
110	3	70	0.03	3	86	0.31	3	88	$-0.25$	3	106	$-0.44$
150	2	207	0.16	2	255	0.00	3	64	0.16	3	77	0.16
300	$\overline{c}$	103	0.16	$\overline{c}$	127	0.00	$\overline{c}$	129	0.16	$\overline{c}$	155	0.16
600	1	207	0.16	1	255	0.00	2	64	0.16	2	77	0.16
1200	1	103	0.16	1	127	0.00	1	129	0.16	1	155	0.16
2400	0	207	0.16	0	255	0.00	1	64	0.16	1	77	0.16
4800	0	103	0.16	0	127	0.00	0	129	0.16	0	155	0.16
9600	0	51	0.16	$\Omega$	63	0.00	0	64	0.16	$\Omega$	77	0.16
19200	0	25	0.16	0	31	0.00	0	32	$-1.36$	0	38	0.16
31250	0	15	0.00	0	19	$-1.70$	0	19	0.00	0	23	0.00
38400	0	12	0.16	0	15	0.00	0	15	1.73	0	19	$-2.34$

 **P**φ **(MHz)** 

#### **P**φ **(MHz)**



Note: Settings with an error of 1% or less are recommended.





## **Table 15.4 Bit Rates and SCBRR Settings in Synchronous Mode**

[Legend]

Blank: No setting possible

-: Setting possible, but error occurs

\*: Continuous transmission/reception is disabled.

Note: Settings with an error of 1% or less are recommended.



Table 15.5 indicates the maximum bit rates in asynchronous mode when the baud rate generator is used. Tables 15.6 and 15.7 list the maximum rates for external clock input.



## **Table 15.5 Maximum Bit Rates for Various Frequencies with Baud Rate Generator (Asynchronous Mode)**





## **Table 15.6 Maximum Bit Rates with External Clock Input (Asynchronous Mode)**

### **Table 15.7 Maximum Bit Rates with External Clock Input (Synchronous Mode)**



## **15.3.9 FIFO Control Register (SCFCR)**

SCFCR is a 16-bit register that resets the number of data in the transmit and receive FIFO registers, sets the trigger data number, and contains an enable bit for loop-back testing. SCFCR can always be read and written to by the CPU. It is initialized to H'0000 by a power-on reset.











## **15.3.10 FIFO Data Count Register (SCFDR)**

SCFDR is a 16-bit register which indicates the number of data stored in the transmit FIFO data register (SCFTDR) and the receive FIFO data register (SCFRDR). It indicates the number of transmit data in SCFTDR with the upper eight bits, and the number of receive data in SCFRDR with the lower eight bits. SCFDR can always be read from by the CPU. SCFDR is initialized to H'0000 by a power on reset.



## **15.3.11 Serial Port Register (SCSPTR)**

SCSPTR is a 16-bit register that controls input/output and data for the pins multiplexed to the SCIF function. Bits 7 and 6 can control the  $\overline{RTS}$  pin, bits 5 and 4 can control the  $\overline{CTS}$  pin, and bits 3 and 2 can control the SCK pin. Bits 1 and 0 can be used to read the input data from the RxD pin and to output data to the TxD pin, so they control break of serial transfer. In addition to descriptions of individual bits shown below, see section 15.6, Serial Port Register (SCSPTR) and SCIF Pins.

SCSPTR can always be read from or written to by the CPU. Bits 7, 5, 3, and 1 in SCSPTR are initialized by a power-on reset.













Note:  $*$  This bit is read as an undefined value and the setting value is 0.



## **15.3.12 Line Status Register (SCLSR)**

SCLSR is a 16-bit readable/writable register which can always be read from and written to by the CPU. However, a 1 cannot be written to the ORER flag. This flag can be cleared to 0 only if it has first been read (after being set to 1). SCLSR is initialized to H'0000 by a power-on reset.



Note: \* The only value that can be written is 0 to clear the flag.



# **15.4 Operation**

### **15.4.1 Overview**

For serial communication, the SCIF has an asynchronous mode in which characters are synchronized individually, and a synchronous mode in which communication is synchronized with clock pulses. The SCIF has a 16-byte FIFO buffer for both transmit and receive operations, reducing the overhead of the CPU, and enabling continuous high-speed communication. Moreover, it has  $\overline{RTS}$  and  $\overline{CTS}$  signals as modem control signals (for channels 0 and 1). The transmission format is selected in the serial mode register (SCSMR), which is shown in table 15.8. The SCIF clock source is selected by the combination of the CKE1 and CKE0 bits in the serial control register (SCSCR), which is shown in table 15.9.

### **Asynchronous Mode:**

- Data length is selectable: 7 or 8 bits.
- Parity bit is selectable. So is the stop bit length (1 or 2 bits). The combination of the preceding selections constitutes the communication format and character length.
- In receiving, it is possible to detect framing errors, parity errors, receive FIFO data full, overrun errors, receive data ready, and breaks.
- The number of stored data bytes is indicated for both the transmit and receive FIFO registers.
- An internal or external clock can be selected as the SCIF clock source.
	- When an internal clock is selected, the SCIF operates using the on-chip baud rate generator.
	- When an external clock is selected, the external clock input must have a frequency 16 times the bit rate. (The on-chip baud rate generator is not used.)

### **Synchronous Mode:**

- The transmission/reception format has a fixed 8-bit data length.
- In receiving, it is possible to detect overrun errors (ORER).
- An internal or external clock can be selected as the SCIF clock source.
	- When an internal clock is selected, the SCIF operates using the on-chip baud rate generator, and outputs a serial clock signal to external devices.
	- When an external clock is selected, the SCIF operates on the input serial clock. The onchip baud rate generator is not used.





Note: \* : Don't care

## **Table 15.9 SCSMR and SCSCR Settings and SCIF Clock Source Selection**



Note: \* : Don't care

## **15.4.2 Operation in Asynchronous Mode**

In asynchronous mode, each transmitted or received character begins with a start bit and ends with a stop bit. Serial communication is synchronized one character at a time.

The transmitting and receiving sections of the SCIF are independent, so full duplex communication is possible. The transmitter and receiver are 16-byte FIFO buffered, so data can be written and read while transmitting and receiving are in progress, enabling continuous transmitting and receiving.

Figure 15.2 shows the general format of asynchronous serial communication. In asynchronous serial communication, the communication line is normally held in the mark (high) state. The SCIF monitors the line and starts serial communication when the line goes to the space (low) state, indicating a start bit. One serial character consists of a start bit (low), data (LSB first), parity bit (high or low), and stop bit (high), in that order.

When receiving in asynchronous mode, the SCIF synchronizes at the falling edge of the start bit. The SCIF samples each data bit on the eighth pulse of a clock with a frequency 16 times the bit rate. Receive data is latched at the center of each bit.



**Figure 15.2 Example of Data Format in Asynchronous Communication (8-Bit Data with Parity and Two Stop Bits)** 

**Transmit/Receive Formats:** Table 15.10 lists the eight communication formats that can be selected in asynchronous mode. The format is selected by settings in the serial mode register (SCSMR).

	<b>SCSMR Bits</b>		Serial Transmit/Receive Format and Frame Length											
		CHR PE STOP	1	$\mathbf{2}$	3	4	5	6	7	8	9	10	11	12
$\Omega$	0	0	<b>START</b>					8-bit data				<b>STOP</b>		
$\Omega$	0	1	<b>START</b>					8-bit data					STOP STOP	
$\Omega$	1	0	<b>START</b>					8-bit data				P	<b>STOP</b>	
$\Omega$	1	1	<b>START</b>					8-bit data				P	STOP STOP	
1	0	0	<b>START</b>				7-bit data				STOP <sup>1</sup>			
1	$\mathbf 0$	1	<b>START</b>				7-bit data					STOP STOP		
$\mathbf{1}$	1	0	<b>START</b>				7-bit data				P	<b>STOP</b>		
1		1	<b>START</b>				7-bit data				P		STOP STOP	

**Table 15.10 Serial Communication Formats (Asynchronous Mode)** 

[Legend]

START: Start bit

STOP: Stop bit

P: Parity bit

**Clock:** An internal clock generated by the on-chip baud rate generator or an external clock input from the SCK pin can be selected as the SCIF transmit/receive clock. The clock source is selected by the  $C/\overline{A}$  bit in the serial mode register (SCSMR) and bits CKE1 and CKE0 in the serial control register (SCSCR) (table 15.9).

When an external clock is input at the SCK pin, it must have a frequency equal to 16 times the desired bit rate.

When the SCIF operates on an internal clock, it can output a clock signal at the SCK pin. The frequency of this output clock is equal to 16 times the desired bit rate.



### **Transmitting and Receiving Data: SCIF Initialization (Asynchronous Mode):**

Before transmitting or receiving, clear the TE and RE bits to 0 in the serial control register (SCSCR), then initialize the SCIF as follows.

When changing the operation mode or the communication format, always clear the TE and RE bits to 0 before following the procedure given below. Clearing TE to 0 initializes the transmit shift register (SCTSR). Clearing TE and RE to 0, however, does not initialize the serial status register (SCFSR), transmit FIFO data register (SCFTDR), or receive FIFO data register (SCFRDR), which retain their previous contents. Clear TE to 0 after all transmit data has been transmitted and the TEND flag in the SCFSR is set. The TE bit can be cleared to 0 during transmission, but the transmit data goes to the Mark state after the bit is cleared to 0. Set the TFRST bit in SCFCR to 1 and reset SCFTDR before TE is set again to start transmission.

When an external clock is used, the clock should not be stopped during initialization or subsequent operation. SCIF operation becomes unreliable if the clock is stopped.







**Figure 15.3 Sample Flowchart for SCIF Initialization** 



## **Transmitting Serial Data (Asynchronous Mode)**

Figure 15.4 shows a sample flowchart for serial transmission.

Use the following procedure for serial data transmission after enabling the SCIF for transmission.





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In serial transmission, the SCIF operates as described below.

- 1. When data is written into the transmit FIFO data register (SCFTDR), the SCIF transfers the data from SCFTDR to the transmit shift register (SCTSR) and starts transmitting. Confirm that the TDFE flag in the serial status register (SCFSR) is set to 1 before writing transmit data to SCFTDR. The number of data bytes that can be written is (16 – transmit trigger setting).
- 2. When data is transferred from SCFTDR to SCTSR and transmission is started, consecutive transmit operations are performed until there is no transmit data left in SCFTDR. When the number of transmit data bytes in SCFTDR falls below the transmit trigger number set in the FIFO control register (SCFCR), the TDFE flag is set. If the TIE bit in the serial control register (SCSR) is set to 1 at this time, a transmit-FIFO-data-empty interrupt (TXI) request is generated.

The serial transmit data is sent from the TxD pin in the following order.

- A. Start bit: One-bit 0 is output.
- B. Transmit data: 8-bit or 7-bit data is output in LSB-first order.
- C. Parity bit: One parity bit (even or odd parity) is output. (A format in which a parity bit is not output can also be selected.)
- D. Stop bit(s): One or two 1 bits (stop bits) are output.
- E. Mark state: 1 is output continuously until the start bit that starts the next transmission is sent.
- 3. The SCIF checks the SCFTDR transmit data at the timing for sending the stop bit. If data is present, the data is transferred from SCFTDR to SCTSR, the stop bit is sent, and then serial transmission of the next frame is started. If there is no transmit data, the TEND flag in SCFSR is set to 1, the stop bit is sent, and then the line goes to the mark state in which 1 is output continuously.





Figure 15.5 shows an example of the operation for transmission.

## **Figure 15.5 Example of Transmit Operation (8-Bit Data, Parity, One Stop Bit)**

4. When modem control is enabled, transmission can be stopped and restarted in accordance with the  $\overline{\text{CTS}}$  input value. When  $\overline{\text{CTS}}$  is set to 1, if transmission is in progress, the line goes to the mark state after transmission of one frame. When  $\overline{\text{CTS}}$  is set to 0, the next transmit data is output starting from the start bit.

Figure 15.6 shows an example of the operation when modem control is used (only for channel 0).



**Figure 15.6 Example of Operation Using Modem Control (**CTS**)** 

### **Receiving Serial Data (Asynchronous Mode):**

Figures 15.7 and 15.8 show a sample flowchart for serial reception.

Use the following procedure for serial data reception after enabling the SCIF for reception.



**Figure 15.7 Sample Flowchart for Receiving Serial Data (1)** 





**Figure 15.8 Sample Flowchart for Receiving Serial Data (2)** 

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In serial reception, the SCIF operates as described below.

- 1. The SCIF monitors the transmission line, and if a 0 start bit is detected, performs internal synchronization and starts reception.
- 2. The received data is stored in SCRSR in LSB-to-MSB order.
- 3. The parity bit and stop bit are received. After receiving these bits, the SCIF carries out the following checks.
	- A. Stop bit check: The SCIF checks whether the stop bit is 1. If there are two stop bits, only the first is checked.
	- B. The SCIF checks whether receive data can be transferred from the receive shift register (SCRSR) to SCFRDR.
	- C. Overrun check: The SCIF checks that the ORER flag is 0, indicating that the overrun error has not occurred.
	- D. Break check: The SCIF checks that the BRK flag is 0, indicating that the break state is not set.

If all the above checks are passed, the receive data is stored in SCFRDR.

Note: When a parity error or a framing error occurs, reception is not suspended.

4. If the RIE bit in SCSCR is set to 1 when the RDF or DR flag changes to 1, a receive-FIFOdata-full interrupt (RXI) request is generated. If the RIE bit or the REIE bit in SCSCR is set to 1 when the ER flag changes to 1, a receive-error interrupt (ERI) request is generated. If the RIE bit or the REIE bit in SCSCR is set to 1 when the BRK or ORER flag changes to 1, a break reception interrupt (BRI) request is generated.





Figure 15.9 shows an example of the operation for reception.



5. When modem control is enabled, the  $\overline{RTS}$  signal is output depending on the empty status of SCFRDR. When  $\overline{RTS}$  is 0, reception is possible. When  $\overline{RTS}$  is 1, this indicates that the SCFRDR is full and no extra data can be received. (Only for channel 0 and channel 1) Figure 15.10 shows an example of the operation when modem control is used.



**Figure 15.10 Example of Operation Using Modem Control (**RTS**)** 

## **15.4.3 Synchronous Mode**

In synchronous mode, the SCIF transmits and receives data in synchronization with clock pulses. This mode is suitable for high-speed serial communication.

The SCIF transmitter and receiver are independent, so full-duplex communication is possible while sharing the same clock. The transmitter and receiver are also 16-byte FIFO buffered, so continuous transmitting or receiving is possible by reading or writing data while transmitting or receiving is in progress.

Figure 15.11 shows the general format in synchronous serial communication.





In synchronous serial communication, each data bit is output on the communication line from one falling edge of the serial clock to the next. Data is guaranteed valid at the rising edge of the serial clock. In each character, the serial data bits are transmitted in order from the LSB (first) to the MSB (last). After output of the MSB, the communication line remains in the state of the MSB. In synchronous mode, the SCIF transmits data by synchronizing with the falling edge of the serial clock, and receives data by synchronizing with the rising edge of the serial clock.



**Communication Format:** The data length is fixed at eight bits. No parity bit can be added.

**Clock:** An internal clock generated by the on-chip baud rate generator or an external clock input from the SCK pin can be selected as the SCIF transmit/receive clock.

When the SCIF operates on an internal clock, it outputs the clock signal at the SCK pin. Eight clock pulses are output per transmitted or received character. When the SCIF is not transmitting or receiving, the clock signal remains in the high state. When only receiving, the clock signal outputs while the RE bit of SCSCR is 1 and the number of data in receive FIFO is less than the receive FIFO data trigger number. In this case,  $8 \times (16 + 1) = 136$  pulses of synchronous clock are output. To perform reception of n characters of data, select an external clock as the clock source. If an internal clock should be used, set  $RE = 1$  and  $TE = 1$  and receive n characters of data simultaneously with the transmission of n characters of dummy data.

**Transmitting and Receiving Data SCIF Initialization (Synchronous Mode):** Before transmitting, receiving, or changing the mode or communication format, the software must clear the TE and RE bits to 0 in the serial control register (SCSCR), then initialize the SCIF. Clearing TE to 0 initializes the transmit shift register (SCTSR). Clearing RE to 0, however, does not initialize the RDF, PER, FER, and ORER flags and receive data register (SCRDR), which retain their previous contents.

Figure 15.12 shows a sample flowchart for initializing the SCIF.




**Figure 15.12 Sample Flowchart for SCIF Initialization** 



**Transmitting Serial Data (Synchronous Mode):** Figure 15.13 shows a sample flowchart for transmitting serial data.



**Figure 15.13 Sample Flowchart for Transmitting Serial Data** 



#### **In transmitting serial data, the SCIF operates as follows:**

- 1. When data is written into the transmit FIFO data register (SCFTDR), the SCIF transfers the data from SCFTDR to the transmit shift register (SCTSR) and starts transmitting. Confirm that the TDFE flag in the serial status register (SCFSR) is set to 1 before writing transmit data to SCFTDR. The number of data bytes that can be written is (16 – transmit trigger setting).
- 2. When data is transferred from SCFTDR to SCTSR and transmission is started, consecutive transmit operations are performed until there is no transmit data left in SCFTDR. When the number of transmit data bytes in SCFTDR falls below the transmit trigger number set in the FIFO control register (SCFCR), the TDFE flag is set. If the TIE bit in the serial control register (SCSR) is set to 1 at this time, a transmit-FIFO-data-empty interrupt (TXI) request is generated.

If clock output mode is selected, the SCIF outputs eight synchronous clock pulses. If an external clock source is selected, the SCIF outputs data in synchronization with the input clock. Data is output from the TxD pin in order from the LSB (bit 0) to the MSB (bit 7).

- 3. The SCIF checks the SCFTDR transmit data at the timing for sending the MSB (bit 7). If data is present, the data is transferred from SCFTDR to SCTSR, the MSB (bit 7) is sent, and then serial transmission of the next frame is started. If there is no transmit data, the TEND flag in SCFSR is set to 1, the MSB (bit 7) is sent, and then the TxD pin holds the states.
- 4. After the end of serial transmission, the SCK pin is held in the high state.

Figure 15.14 shows an example of SCIF transmit operation.



**Figure 15.14 Example of SCIF Transmit Operation** 



**Receiving Serial Data (Synchronous Mode):** Figure 15.15 and 15.16 show a sample flowchart for receiving serial data. When switching from asynchronous mode to synchronous mode without SCIF initialization, make sure that ORER, PER, and FER are cleared to 0.



**Figure 15.15 Sample Flowchart for Receiving Serial Data (1)** 



**Figure 15.16 Sample Flowchart for Receiving Serial Data (2)** 

#### **In receiving, the SCIF operates as follows:**

- 1. The SCIF synchronizes with serial clock input or output and initializes internally.
- 2. Receive data is shifted into SCRSR in order from the LSB to the MSB. After receiving the data, the SCIF checks the receive data can be loaded from SCRSR into SCFRDR or not. If this check is passed, the SCIF stores the received data in SCFRDR. If the check is not passed (overrun error is detected), further reception is prevented.
- 3. After setting RDF to 1, if the receive-data-full interrupt enable bit (RIE) is set to 1 in SCSCR, the SCIF requests a receive-data-full interrupt (RXI). If the ORER bit is set to 1 and the RIE bit or REIE bit in SCSCR is also set to 1, the SCIF requests a break interrupt (BRI).



Figure 15.17 shows an example of SCIF receive operation.

**Figure 15.17 Example of SCIF Receive Operation** 



### **Transmitting and Receiving Serial Data Simultaneously (Synchronous Mode):** Figure 15.18

shows a sample flowchart for transmitting and receiving serial data simultaneously.



**Figure 15.18 Sample Flowchart for Transmitting/Receiving Serial Data** 

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## **15.5 SCIF Interrupts**

The SCIF has four interrupt sources: transmit-FIFO-data-empty (TXI), receive-error (ERI), receive-data-full (RXI), and break (BRI).

Table 15.11 shows the interrupt sources and their order of priority. The interrupt sources are enabled or disabled by means of the TIE, RIE, and REIE bits in SCSCR. A separate interrupt request is sent to the interrupt controller for each of these interrupt sources.

When TXI request is enabled by TIE bit and the TDFE flag in the serial status register (SCFSR) is set to 1, a TXI interrupt request is generated.

When RXI request is enabled by RIE bit and the RDF or DR flag in SCFSR is set to 1, an RXI interrupt request is generated. The RXI interrupt request caused by DR flag is generated only in asynchronous mode.

When BRI request is enabled by RIE bit or REIE bit and the BRK flag in SCFSR or ORER flag in SCLSR is set to 1, a BRI interrupt request is generated.

When ERI request is enabled by RIE bit or REIE bit and the ER flag in SCFCR is set to 1, an ERI interrupt request is generated.

When the RIE bit is set to 0 and the REIE bit is set to 1, SCIF request ERI interrupt and BRI interrupt without requesting RXI interrupt.

The TXI interrupt indicates that transmit data can be written, and the RXI interrupt indicates that there is receive data in SCFRDR.

#### **Table 15.11 SCIF Interrupt Sources**





### **15.6 Serial Port Register (SCSPTR) and SCIF Pins**

The relationship between SCSPTR and the SCIF pins is shown in figures 15.19 to 15.23.



**Figure 15.19 RTSIO Bit, RTSDT Bit, and** RTS **Pin** 





**Figure 15.20 CTSIO Bit, CTSDT Bit, and** CTS **Pin** 







**Figure 15.21 SCKIO Bit, SCKDT Bit, and SCK Pin** 



**Figure 15.22 SPBIO Bit, SPBDT Bit, and TxD Pin** 

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**Figure 15.23 SPBDT Bit and RxD Pin** 



### **15.7 Usage Notes**

Note the following when using the SCIF.

1. SCFTDR Writing and TDFE Flag

The TDFE flag in the serial status register (SCFSR) is set when the number of transmit data bytes written in the transmit FIFO data register (SCFTDR) has fallen below the transmit trigger number set by bits TTRG1 and TTRG0 in the FIFO control register (SCFCR). After TDFE is set, transmit data up to the number of empty bytes in SCFTDR can be written, allowing efficient continuous transmission.

However, if the number of data bytes written in SCFTDR is equal to or less than the transmit trigger number, the TDFE flag will be set to 1 again after being read as 1 and cleared to 0. TDFE clearing should therefore be carried out when SCFTDR contains more than the transmit trigger number of transmit data bytes.

The number of transmit data bytes in SCFTDR can be found from the upper 8 bits of the FIFO data count register (SCFDR).

2. SCFRDR Reading and RDF Flag

The RDF flag in the serial status register (SCFSR) is set when the number of receive data bytes in the receive FIFO data register (SCFRDR) has become equal to or greater than the receive trigger number set by bits RTRG1 and RTRG0 in the FIFO control register (SCFCR). After RDF is set, receive data equivalent to the trigger number can be read from SCFRDR, allowing efficient continuous reception.

However, if the number of data bytes in SCFRDR is equal to or greater than the trigger number, the RDF flag will be set to 1 again if it is cleared to 0. RDF should therefore be cleared to 0 after being read as 1 after all the receive data has been read.

The number of receive data bytes in SCFRDR can be found from the lower 8 bits of the FIFO data count register (SCFDR).

3. Break Detection and Processing

Break signals can be detected by reading the RxD pin directly when a framing error (FER) is detected. In the break state the input from the RxD pin consists of all 0s, so the FER flag is set and the parity error flag (PER) may also be set. Note that, although transfer of receive data to SCFRDR is halted in the break state, the SCIF receiver continues to operate.



4. Sending a Break Signal

The I/O condition and level of the TxD pin are determined by the SPBIO and SPBDT bits in the serial port register (SCSPTR). This feature can be used to send a break signal.

Until TE bit is set to 1 (enabling transmission) after initializing, TxD pin does not work. During the period, mark status is performed by SPBDT bit. Therefore, the SPBIO and SPBDT bits should be set to 1 (high level output).

To send a break signal during serial transmission, clear the SPBDT bit to 0 (designating low level), then clear the TE bit to 0 (halting transmission). When the TE bit is cleared to 0, the transmitter is initialized regardless of the current transmission state, and 0 is output from the TxD pin.

5. Receive Data Sampling Timing and Receive Margin (Asynchronous Mode)

The SCIF operates on a base clock with a frequency of 16 times the transfer rate. In reception, the SCIF synchronizes internally with the fall of the start bit, which it samples on the base clock. Receive data is latched at the rising edge of the eighth base clock pulse. The timing is shown in figure 15.24.



**Figure 15.24 Receive Data Sampling Timing in Asynchronous Mode** 

The receive margin in asynchronous mode can therefore be expressed as shown in equation 1. **Equation 1:** 

$$
M = \left(0.5 - \frac{1}{2N}\right) = (L - 0.5) F - \frac{|D - 0.5|}{N} (1 + F) \right) \times 100\%
$$

Where:  $M:$  Receive margin  $(\%)$ 

N: Ratio of clock frequency to bit rate  $(N = 16)$ 

D: Clock duty cycle  $(D = 0$  to 1.0)

L: Frame length  $(L = 9$  to 12)

F: Absolute deviation of clock frequency

From equation 1, if  $F = 0$  and  $D = 0.5$ , the receive margin is 46.875%, as given by equation 2. **Equation 2:**

When  $D = 0.5$  and  $F = 0$ .

 $M = (0.5 - 1/(2 \times 16)) \times 100\%$  $= 46.875%$ 

This is a theoretical value. A reasonable margin to allow in system designs is 20% to 30%.

6. Prohibited Multiple Pin Allocation for Channel 1

Although signals SCK1, RxD1, and TxD1 can be respectively assigned to multiple pins of PD4 or PE20, PD3 or PE19, and PD2 or PE18, either of them must be selected. For example, if signal SCK1 is assigned to both pins PD4 and PE20, correct operation of the SCIF is not guaranteed.

7. Status of the TxD and RTS Pins When the TE Bit is Cleared

The TxDi  $(i = 0, 1, 2)$  and RTSj  $(i = 0, 1)$  pins usually function as output pins during serial communication. However, even if these functions are selected by the pin function controller (PFC), the internal weak keeper drives the pins to unstable levels as long as the TE bit in SCSCRi  $(i = 0, 1, 2)$  is cleared. To make these pins always function as output pins (regardless of the value of the TE bit), set SCSPTRi  $(i = 0, 1, 2)$  and PFC in the following order.

- a. Set the SPBIO and SPBDT bits in SCSPTRi  $(i = 0, 1, 2)$ . Set the RTSIO and RTSDT bits in SCSPTR<sub>j</sub>  $(i = 0, 1)$ .
- b. Select the TxDi  $(i = 0, 1, 2)$  and RTSj  $(i = 0, 1)$  pins with the PFC.
- 8. Interval from when the TE bit in SCSCR is Set to 1 until a Start Bit is Transmitted in Asynchronous Mode

In the SCIF included in former products, a start bit is transmitted after the internal equivalent to one frame. In the SCIF included in this product, however, a start bit is transmitted directly after the TE bit is set to 1.

9. Clear Timing of the FER or PER Bits when the DMAC Saves the Receive Data in Asynchronous Mode

The FER or PER bits in SCFSR are set when data including a framing error or parity error is received in asynchronous mode, whereas cleared when the corresponding data is read from SCFRDR. Therefore, when data with an error is received while the DMAC is set to save the receive data automatically, the receive-error interrupt is accepted after the DMAC reads the corresponding data. As a result, the CPU cannot check the FER or PER bits.

To prevent this defect, the RTRG[1:0] bits in SCFCR should be set to the higher number to delay the DMAC call timing. This enables the CPU to check the FER or PER bits in the receive-error interrupt routine, prior to the DMAC to read the error data.





# Section 16 Serial I/O with FIFO (SIOF)

This LSI includes a clock-synchronized serial I/O module with FIFO (SIOF) that comprises one channel. The SIOF can perform serial communication with a serial peripheral interface bus (SPI).

### **16.1 Features**

- Serial transfer
	- 16-stage 32-bit FIFOs (independent transmission and reception)
	- Supports 8-bit data/16-bit data/16-bit stereo audio input and output
	- MSB first for data transmission
	- Supports a maximum of 48-kHz sampling rate
	- Synchronization by either frame synchronization pulse or left/right channel switch
	- Supports CODEC control data interface
	- Connectable to linear, audio, or A-Law or µ-Law CODEC chip
	- Supports both master and slave modes
- Serial clock
	- $\overline{\phantom{a}}$  An external pin input or internal clock (P $\phi$ ) can be selected as the clock source.
- Interrupts: One type
- DMA transfer
	- Supports DMA transmission and reception by a transfer request for transmission and reception
- SPI mode
	- Fixed master mode can perform the full-duplex communication with the SPI slave devices continuously.
	- Selects the falling/rising edge of the SCK as data sampling.
	- Selects the clock phase of the SCK as a transmit timing.
	- Selects one slave device.
	- The length of transmit/receive data is fixed to 8 bits.



Figure 16.1 shows a block diagram of the SIOF.



**Figure 16.1 Block Diagram of SIOF** 



## **16.2 Input/Output Pins**

The pin configuration in this module is shown in table 16.1.

### **Table 16.1 Pin Configuration**



MOSI, and MISO.



### **16.3 Register Descriptions**

The SIOF has the following registers. For the addresses of these registers and the register states in each operating state, refer to section 24, List of Registers. In the register descriptions following this section, channel numbers are omitted.

### **Channel 0:**

- Mode register\_0 (SIMDR\_0)
- Control register\_0 (SICTR\_0)
- Transmit data register\_0 (SITDR\_0)
- Receive data register\_0 (SIRDR\_0)
- Transmit control data register\_0 (SITCR\_0)
- Receive control data register\_0 (SIRCR\_0)
- Status register\_0 (SISTR\_0)
- Interrupt enable register\_0 (SIIER\_0)
- FIFO control register\_0 (SIFCTR\_0)
- Clock select register\_0 (SISCR\_0)
- Transmit data assign register\_0 (SITDAR\_0)
- Receive data assign register\_0 (SIRDAR\_0)
- Control data assign register\_0 (SICDAR\_0)
- SPI control register\_0 (SPICR\_0)

### **16.3.1 Mode Register (SIMDR)**



SIMDR is a 16-bit readable/writable register that sets the SIOF operating mode.







#### **Table 16.2 Operation in Each Transfer Mode**



Note: \* The control data method is valid only when the FL3 to FL0 bits are specified as 1xxx. (x: Don't care.)



### **16.3.2 Control Register (SICTR)**

SICTR is a 16-bit readable/writable register that sets the SIOF operating state.









### **16.3.3 Transmit Data Register (SITDR)**

SITDR is a 32-bit write-only register that specifies the SIOF transmit data.

SITDR is initialized by the conditions specified in section 24, List of Registers, or by a transmit reset caused by the TXRST bit in SICTR.

SITDR is initialized in module stop mode.





### **16.3.4 Receive Data Register (SIRDR)**

SIRDR is a 32-bit read-only register that reads receive data of the SIOF. SIRDR stores data in the receive FIFO and is initialized to undefined value by the conditions specified in section 24, List of Registers, or by a receive reset caused by the RXRST bit in SICTR.





### **16.3.5 Transmit Control Data Register (SITCR)**

SITCR is a 32-bit readable/writable register that specifies transmit control data of the SIOF. SITCR can be specified only when the FL3 to FL0 bits in SIMDR are specified as 1xxx (x: Don't care.).

SITCR is initialized in module stop mode.





### **16.3.6 Receive Control Data Register (SIRCR)**

SIRCR is a 32-bit readable/writable register that stores receive control data of the SIOF. SIRCR can be specified only when the FL3 to FL0 bits in SIMDR are specified as 1xxx (x: Don't care.).





### **16.3.7 Status Register (SISTR)**

SISTR is a 16-bit read-only register that shows the SIOF state. Each bit in this register becomes an SIOF interrupt source when the corresponding bit in SIIER is set to 1.



SISTR is initialized in module stop mode.

**Initial** 


















### **16.3.8 Interrupt Enable Register (SIIER)**

SIIER is a 16-bit readable/writable register that enables the issue of SIOF interrupts. When each bit in this register is set to 1 and the corresponding bit in SISTR is set to 1, the SIOF issues an interrupt.









# **16.3.9 FIFO Control Register (SIFCTR)**

SIFCTR is a 16-bit readable/writable register that indicates the area available for the transmit/receive FIFO transfer.







### **16.3.10 Clock Select Register (SISCR)**

SISCR is a 16-bit readable/writable register that sets the serial clock generation conditions for the master clock. SISCR can be specified when the TRMD1 and TRMD0 bits in SIMDR are specified as B'10 or B'11.







# **16.3.11 Transmit Data Assign Register (SITDAR)**

SITDAR is a 16-bit readable/writable register that specifies the position of the transmit data in a frame (slot number).







# **16.3.12 Receive Data Assign Register (SIRDAR)**

SIRDAR is a 16-bit readable/writable register that specifies the position of the receive data in a frame (slot number).



# **16.3.13 Control Data Assign Register (SICDAR)**

SICDAR is a 16-bit readable/writable register that specifies the position of the control data in a frame (slot number). SICDAR can be specified only when the FL bit in SIMDR is specified as 1xxx (x: Don't care.).







# **16.3.14 SPI Control Register (SPICR)**

SPICR is a 16-bit readable/writable register that specifies the operating mode of the SPI.











# **16.4 Operation**

# **16.4.1 Serial Clocks**

**Master/Slave Modes:** The following two modes are available as the SIOF clock mode.

- Slave mode: SIOFSCK, SIOFSYNC input
- Master mode: SIOFSCK, SIOFSYNC output

**Baud Rate Generator:** In SIOF master mode, the baud rate generator (BRG) is used to generate the serial clock. The division ratio is from 1/1 to 1/1024.

Figure 16.2 shows connections for supply of the serial clock.



**Figure 16.2 Serial Clock Supply** 

Table 16.3 shows an example of serial clock frequency.

# **Table 16.3 SIOF Serial Clock Frequency**





# **16.4.2 Serial Timing**

**SIOFSYNC:** The SIOFSYNC is a frame synchronous signal. Depending on the transfer mode, it has the following functions.

- Synchronous pulse: 1-bit-width pulse indicating the start of the frame
- L/R: 1/2-frame-width pulse indicating the left-channel stereo data (L) in high level and the right-channel stereo data (R) in low level

Figure 16.3 shows the SIOFSYNC synchronization timing.



**Figure 16.3 Serial Data Synchronization Timing** 

**Transmit/Receive Timing:** The SIOFTxD transmit timing and SIOFRxD receive timing relative to the SIOFSCK can be set as the sampling timing in the following ways. The transmit/receive timing is set using the REDG bit in SIMDR.

- Falling-edge sampling
- Rising-edge sampling

Figure 16.4 shows the transmit/receive timing.



**Figure 16.4 SIOF Transmit/Receive Timing** 

# **16.4.3 Transfer Data Format**

The SIOF performs the following transfer.

- Transmit/receive data: Transfer of 8-bit data/16-bit data/16-bit stereo data
- Control data: Transfer of 16-bit data (uses the specific register as interface)

**Transfer Mode:** The SIOF supports the following four transfer modes as listed in table 16.4. The transfer mode can be specified by the TRMD1 and TRMD0 bits in SIMDR.







**Frame Length:** The length of the frame to be transferred by the SIOF is specified by the FL3 to FL0 bits in SIMDR. Table 16.5 shows the relationship between the FL3 to FL0 bit settings and frame length.



#### **Table 16.5 Frame Length**

Note: x: Don't care.

**Slot Position:** The SIOF can specify the position of transmit data, receive data, and control data in a frame (common to transmission and reception) by slot numbers. The slot number of each data is specified by the following registers.

- Transmit data: SITDAR
- Receive data: SIRDAR
- Control data: SICDAR

Only 16-bit data is valid for control data. In addition, control data is always assigned to the same slot number both in transmission and reception.



### **16.4.4 Register Allocation of Transfer Data**

**Transmit/Receive Data:** Writing and reading of transmit/receive data is performed for the following registers.

- Transmit data writing: SITDR (32-bit access)
- Receive data reading: SIRDR (32-bit access)

Figure 16.5 shows the transmit/receive data and the SITDR and SIRDR bit alignment.





Note: In the figure, only the shaded areas are transmitted or received as valid data. Data in unshaded areas is not transmitted or received.

Monaural or stereo can be specified for transmit data by the TDLE bit and TDRE bit in SITDAR. Monaural or stereo can be specified for receive data by the RDLE bit and RDRE bit in SIRDAR. To achieve left and right same audio output while stereo is specified for transmit data, specify the TLREP bit in SITDAR. Tables 16.6 and 16.7 show the audio mode specification for transmit data and that for receive data, respectively.



#### **Table 16.6 Audio Mode Specification for Transmit Data**



Note: x: Don't care

#### **Table 16.7 Audio Mode Specification for Receive Data**



Note: Left and right same audio mode is not supported in receive data. To execute monaural transmission or reception, use the left channel.

**Control Data:** Control data is written to or read from by the following registers.

- Transmit control data write: SITCR (32-bit access)
- Receive control data read: SIRCR (32-bit access)

Figure 16.6 shows the control data and bit alignment in SITCR and SIRCR.



**Figure 16.6 Control Data Bit Alignment** 

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The number of channels in control data is specified by the CD0E and CD1E bits in SICDAR. Table 16.8 shows the relationship between the number of channels in control data and bit settings.



#### **Table 16.8 Setting Number of Channels in Control Data**

Note: To use only one channel in control data, use channel 0.

#### **16.4.5 Control Data Interface**

Control data performs control command output to the CODEC and status input from the CODEC. The SIOF supports the following two control data interface methods.

- Control by slot position
- Control by secondary FS

Control data is valid only when data length is specified as 16 bits.

**Control by Slot Position (Master Mode 1, Slave Mode 1):** Control data is transferred for all frames transmitted or received by the SIOF by specifying the slot position of control data. This method can be used in both SIOF master and slave modes. Figure 16.7 shows an example of the control data interface timing by slot position control.



**Figure 16.7 Control Data Interface (Slot Position)** 

**Control by Secondary FS (Slave Mode 2):** The CODEC normally outputs the SIOFSYNC signal as synchronization pulse (FS). In this method, the CODEC outputs the secondary FS specific to the control data transfer after 1/2 frame time has been passed (not the normal FS output timing) to transmit or receive control data. This method is valid for SIOF slave mode. The following summarizes the control data interface procedure by the secondary FS.

- Transmit normal transmit data of  $LSB = 0$  (the SIOF forcibly clears 0).
- To execute control data transmission, send transmit data of  $LSB = 1$  (the SIOF forcibly set to 1 by writing SITCDR).
- The CODEC outputs the secondary FS.
- The SIOF transmits or receives (stores in SIRCDR) control data (data specified by SITCDR) synchronously with the secondary FS.

Figure 16.8 shows an example of the control data interface timing by the secondary FS.



**Figure 16.8 Control Data Interface (Secondary FS)** 



# **16.4.6 FIFO**

**Overview:** The transmit and receive FIFOs of the SIOF have the following features.

- 16-stage 32-bit FIFOs for transmission and reception
- The FIFO pointer can be updated in one read or write cycle regardless of access size of the CPU and DMAC. (One-stage 32-bit FIFO access cannot be divided into multiple accesses.)

**Transfer Request:** The transfer request of the FIFO can be issued to the CPU or DMAC as the following interrupt sources.

- FIFO transmit request: TDREQ (transmit interrupt source)
- FIFO receive request: RDREQ (receive interrupt source)

The request conditions for FIFO transmit or receive can be specified individually. The request conditions for the FIFO transmit and receive are specified by the TFWM2 to TFWM0 bits and RFWM2 to RFWM0 bits in SIFCTR, respectively. Tables 16.9 and 16.10 summarize the conditions specified by SIFCTR.

### **Table 16.9 Conditions to Issue Transmit Request**



#### **Table 16.10 Conditions to Issue Receive Request**





The number of stages of the FIFO is always sixteen even if the data area or empty area exceeds the FIFO size (the number of FIFOs). Accordingly, an overflow error or underflow error occurs if data area or empty area exceeds sixteen FIFO stages. The FIFO transmit or receive request is canceled when the above condition is not satisfied even if the FIFO is not empty or full.

**Number of FIFOs:** The number of FIFO stages used in transmission and reception is indicated by the following register.

- Transmit FIFO: The number of empty FIFO stages is indicated by the TFUA4 to TFUA0 bits in SIFCTR.
- Receive FIFO: The number of valid data stages is indicated by the RFUA4 to RFUA0 bits in SIFCTR.

The above indicate possible data numbers that can be transferred by the CPU or DMAC.



# **16.4.7 Transmit and Receive Procedures**

**Transmission/Reception and Transmission in Master Mode:** Figure 16.9 (1) shows an example of settings and operation for master mode transmission/reception. Figure 16.9 (2) shows an example of settings and operation for master mode transmission.





**Figure 16.9 (1) Transmission/Reception Operation in Master Mode (Example of Reception and Full-Duplex Transmission by the CPU with TDMAE=0)** 

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**Figure 16.9 (2) Transmission Operation in Master Mode (Example of Half-Duplex Transmission by the CPU with TDMAE=0)** 



**Reception in Master Mode:** Figure 16.10 shows an example of settings and operation for master mode reception.



**Figure 16.10 Example of Receive Operation in Master Mode** 

**Transmission in Slave Mode:** Figure 16.11 shows an example of settings and operation for slave mode transmission.



**Figure 16.11 Example of Transmit Operation in Slave Mode** 



**Reception in Slave Mode:** Figure 16.12 shows an example of settings and operation for slave mode reception.



**Figure 16.12 Example of Receive Operation in Slave Mode** 

**Transmit/Receive Reset:** The SIOF can separately reset the transmit and receive units by setting the following bits to 1.

- Transmit reset: TXRST bit in SICTR
- Receive reset: RXRST bit in SICTR

Table 16.11 shows the details of initialization upon transmit or receive reset.

<b>Type</b>	<b>Objects Initialized</b>
Transmit reset	<b>SITDR</b>
	Transmit FIFO write pointer and read pointer
	TCRDY, TFEMP, and TDREQ bits in SISTR
	<b>TXE bit in SICTR</b>
Receive reset	<b>SIRDR</b>
	Receive FIFO write pointer and read pointer
	RCRDY, RFFUL, and RDREQ bits in SISTR
	RXE bit in SICTR

**Table 16.11 Transmit and Receive Reset**

**Module Stop Mode:** The SIOF stops the transmit/receive operation in module stop mode. And all the registers in SIOF are retained.



### **16.4.8 Interrupts**

The SIOF has one type of interrupt.

**Interrupt Sources:** Interrupts can be issued by several sources. Each source is shown as an SIOF status in SISTR. Table 16.12 lists the SIOF interrupt sources.





Whether an interrupt is issued or not as the result of an interrupt source is determined by the SIIER settings. If an interrupt source is set to 1 and the corresponding bit in SIIER is set to 1, an SIOF interrupt is issued.

**Regarding Transmit and Receive Classification:** The transmit sources and receive sources are signals indicating the state; after being set, if the state changes, they are automatically cleared by the SIOF.

When the DMA transfer is used, a DMA transfer request is pulled low (0 level) for one cycle at the end of DMA transfer.

**Processing when Errors Occur:** On occurrence of each of the errors indicated as a status in SISTR, the SIOF performs the following operations.

- Transmit FIFO underflow (TFUDF) The immediately preceding transmit data is again transmitted.
- Transmit FIFO overflow (TFOVF) The contents of the transmit FIFO are protected, and the write operation causing the overflow is ignored.
- Receive FIFO overflow (RFOVF) Data causing the overflow is discarded and lost.
- Receive FIFO underflow (RFUDF) An undefined value is output on the bus.
- FS error (FSERR)

The internal counter is reset according to the FSYN signal in which an error occurs.

- Assign error (SAERR)
	- If the same slot is assigned to both serial data and control data, the slot is assigned to serial data.
	- If the same slot is assigned to two control data items, data cannot be transferred correctly.



### **16.4.9 Transmit and Receive Timing**

Examples of the SIOF serial transmission and reception are shown in figures 16.13 to 16.19.

**8-bit Monaural Data (1):** Synchronous pulse method, falling edge sampling, slot No.0 used for transmit and receive data, an frame length = 8 bits



**Figure 16.13 Transmit and Receive Timing (8-Bit Monaural Data (1))**

**8-bit Monaural Data (2):** Synchronous pulse method, falling edge sampling, slot No.0 used for transmit and receive data, and frame length = 16 bits



**Figure 16.14 Transmit and Receive Timing (8-Bit Monaural Data (2))**

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**16-bit Monaural Data (1):** Synchronous pulse method, falling edge sampling, slot No.0 used for transmit and receive data, and frame length  $= 64$  bits



**Figure 16.15 Transmit and Receive Timing (16-Bit Monaural Data (1))**

**16-bit Stereo Data (1):** L/R method, rising edge sampling, slot No.0 used for left channel data, slot No.1 used for right channel data, and frame length  $=$  32 bits



**Figure 16.16 Transmit and Receive Timing (16-Bit Stereo Data (1))**



**16-bit Stereo Data (2):** L/R method, rising edge sampling, slot No.0 used for left-channel transmit data, slot No.1 used for left-channel receive data, slot No.2 used for right-channel transmit data, slot No.3 used for right-channel receive data, and frame length = 64 bits



**Figure 16.17 Transmit and Receive Timing (16-Bit Stereo Data (2))**

**16-bit Stereo Data (3):** Synchronous pulse method, falling edge sampling, slot No.0 used for leftchannel data, slot No.1 used for right-channel data, slot No.2 used for control channel 0 data, slot No.3 used for control channel 1 data, and frame length = 128 bits



**Figure 16.18 Transmit and Receive Timing (16-Bit Stereo Data (3))**

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**16-bit Stereo Data (4):** Synchronous pulse method, falling edge sampling, slot No.0 used for leftchannel data, slot No.2 used for right-channel data, slot No.1 used for control channel 0 data, slot No.3 used for control channel 1 data, and frame length = 128 bits



**Figure 16.19 Transmit and Receive Timing (16-Bit Stereo Data (4))**

**Synchronization-Pulse Output Mode at End of Each Slot (SYNCAT Bit = 1):** Synchronous pulse method, falling edge sampling, slot No.0 used for left-channel data, slot No.1 used for rightchannel data, slot No.2 used for control channel 0 data, slot No.3 used for control channel 1 data, and frame length  $= 128$  bits

In this mode, valid data must be set to slot No. 0.



**Figure 16.20 Transmit and Receive Timing (16-Bit Stereo Data)**



### [Notes on Usage]

### 1. Defect in Frame Synchronous Signal (SYNC) Length

#### (a) Phenomena

With the SIOF Master Mode 2, in some case, the length of the SYNC signal in high level error occurs by changing the SYNC signal output condition from disabled (the FSE bit  $= 0$ ) to enabled (the FSE bit  $= 1$ ). In the above case, the SYNC signal rises before the correct timing and the length of the signal in high level will be 1 bit longer in the first frame than the value set in the SIMDR, whereas the error DOES NOT occur after second frame.



(Example): With the SIOF Master Mode 2, Frame Length = 32 bits

(b) Defect prevention

\*Please take following procedures (i) or (ii).

- (i) In the case of setting a data, please write a dummy data for the first frame and the valid data for other frames into the transmit FIFO, and set the destination stations to discard the data in the first frame.
- (ii) In the use of this product, please make your system composition that works correctly even in the case that the length of the SYNC signal will be 1 bit longer.
- 2. Resume Data Transmission with the SIOF Master Mode
- (a) Defect data transmission

With the SIOF master mode, in some case, the data is NOT transmitted correctly when the transmission operation is resumed after stopping the previous transmission operation by setting '0' to the TXE bit.


(b) Cause of the Defect

After the transmission, the SIOF will be reset and initialized by setting the TXE bit in the SICTR to '0' with the SIOF master mode 1/2. However, if that SIOF fails to be reset, the transmission will resume without the transmission module initialized and the defect mentioned above will occur.

(c) Defect prevention

Please change the setting of SCK temporarily to make reset the modules using the CK clock surely, specifically, whenever the TXE bit or the RXE bit in SICTR is set to  $\dot{0}$ , please take the procedures as follows;

(i) Set the  $P\phi$  as the master clock source.

(Set the MSSEL bit in SISCR to '1' (master clock =  $P\phi$ ).)

(ii) Set the master clock division ratio according with the count value of the prescalar of the baud rate generator as ×1/1.

(Set the bits BRPS[4:0] in SISCR to '0000' (as the master clock frequency  $\times$ 1/1)).

- (iii) Set the frequency division ratio for the output stage of the baud rate generator as  $\times 1/1$ . (Set the bits BRDV[2:0] in SISCR to '111' (as the prescalar output frequency  $\times$ 1/1).)
- (iv) Reset the transmission/reception operation.

(Set the TXRST bit (or RXST bit) in the SICTR to '1' (reset).)

(v) Set the value of SISCR for transmission/reception again, before start of next transmission/reception.



### **16.4.10 SPI Mode**

SPI-mode operation is selected for the SIOF by the setting in SPICR.

**Example of Configuration:** Figure 16.21 shows an example of the configuration for SPI-mode communications.





**SPI Operation:** The states of operation in SPI mode are described in terms of transmission and reception in table 16.13. In SPI mode, the data length is fixed to 8 bits and the values of the upper 8 bits of SITDR and SIRDR are the valid data for transmission and reception, respectively. Fixed master mode can perform the full-duplex communication with the SPI slave devices continuously. That is, 8-bit data is continuously transmitted/received, and resetting of transmit/receive operation by the TXRST or RXRST bit with  $SCK = P\phi$  controls the respective frames.



The shaded part is the data which is transmitted or received.



The only sources of interrupts that should be enabled in SPI-mode transfer are transmit data transfer request (TDREQ), transmit FIFO empty (TFEMP), receive-data transfer request (RDREQ), receive-FIFO full (RFFUL), and receive-FIFO overflow (RFOVF). Enabled or disabled states are selectable by the interrupt enable register (SIIER). Interrupts from other sources must be disabled at all times.

For the DMA transfer requests, the enabled sources are transmit-data DMA transfer request (TDMA) and receive-data DMA transfer request (RDMA). Enabled or disabled states are selectable by the interrupt enable register (SIIER).

In SPI mode, the baud rate is set by SISCR.

TXE	<b>RXE</b>	TDMAE	<b>RDMAE</b>	<b>SPI Transmit/Receive Operation</b>
0	0	Don't care	Don't care	Transmission/reception is disabled
0	1	0	1	<b>Half-Duplex Reception</b>
				The transmit FIFO does not operate and dummy data is transmitted from the MOSI. Data received at the MISO is stored in the receive FIFO and is transferred by using the DMA.
				Receive operation continues as long as RE bit = 1; the receive-FIFO overflow (RFOVF) status is set after the receive FIFO has become full and further receive data is ignored.
	$\Omega$	0	0	Half-Duplex Transmission
				The data in the transmit FIFO is transmitted from the MOSI. The receive FIFO does not operate, and data on the MISO is ignored. When the transmit FIFO becomes empty, the transmit operation is completed.
		1	0	Half-Duplex Transmission
				The data which has been transferred by using the DMA to the transmit FIFO is transmitted from the MOSI. The receive FIFO does not operate and data on the MISO is ignored. When the transmit FIFO becomes empty, the transmit operation is completed.

**Table 16.13 States of Transmit and Receive Operations in SPI Mode**





Note: In SPI mode, settings other than the above are prohibited.

In half-duplex reception (transmission is disabled), the value output from the MOSI can be controlled by the TXDIZ bit in SIMDR as follows.

 $TXDIZ = 0$ : Transmission is disabled, 1 is output on the MOSI.

TXDIZ = 1: Transmission is disabled, the MOSI is in the high-impedance state.

**Serial Clock Timing:** Timing on the data and clock lines in SPI mode is shown in figures 16.22 and 16.23. The user can select from four serial transfer formats, which differ according to the phase and polarity of the serial clock.



**Figure 16.22 SPI Data/Clock Timing 1 (CPHA = 0)**

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**Figure 16.23 SPI Data/Clock Timing 2 (CPHA = 1)** 



**Procedures for Transmission/Reception:** Shown in figures 16.24 to 16.27 are examples of settings for SPI transmission/reception along with the corresponding operations.

No.	Time chart	<b>SIOF Setting</b>	<b>SIOF Operation</b>
1	Start Set SISCR, SIFCTR, and SPICR.	Set the serial clock and threshold values for FIFO.	[Note] In SPI mode, registers SIMDR, SITDAR, SIRDAR, and SICDAR should be set to their initial values.
2	Set the SCKE bit in SICTR to 1.	Start baud rate generator operation.	[Note] Serial clock will not be output form the pin until communication is actually started.
3	Set the FSE bit in SICTR to 1. Set the TXE and RXE bits in SICTR to 1.* ------	Initialize the frame in the SIOF (ie, initialize the state of signal SS0), and enable transmission and reception.	[Note] Communication is actually started after SITDR has been written.
4	No TDREQ=1? Yes		
5	Set the SITDR register.	Set the data for transmission.	
6	Synchronously to SS0, output the contents of SITDR from MOSI and receive data from MISO. ,		Executes transmission and reception simultaneously. (Even when transmission is not necessary, dummy transmission must be performed. The output of dummy transmission can be masked by setting the pin function.)
7	No RDREQ=1? Yes		
8	Read the SIRDR register.	Read the received data.	
9	No Fransfer complete? Yes	Check SISTR.TFEMP (transmit FIFO empty) and ensure completion of communication by using a wait loop or other means. (Checking SISTR.TFEMP is enough to confirm the completion of simultaneous transmission and reception.)	
10	Clear the TXE and RXE bits in SICTR to 0.	Disable transmission and reception.	Transmission/reception end.
11	Clear the FSE bit in SICTR to 0.	To be prepared for the transmission/reception that is resumed later, set FSE = 0 to synchronize the frame in this LSI.	
12	Set BPRS = $00000$ and BRDV = 111 in the SISCR register. Apply a pulse to bits TxRST and RxRST in the SICTR register (0->1->0 input). Set the SISCR register to set the baud rate again.	To be prepared for the transmission/reception that is resumed later, initialize inside the baud rate generator.	
13	No Change communication mode <sup>2</sup> End Yes	If communication is not to be resumed (branching to No), no further setting is needed. To return to the same communication mode, go back to setting of FSE at step 3 of this flowchart.	
14	With FSE=0, TXE=0, and RXE=0 held, start setting other bits.	Go on to 'Start' of the corresponding flowchart.	

**Figure 16.24 SPI Transmission/Reception Operation (Example of Full-Duplex Transmission/Reception by the CPU with TDMAE = 0)**

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Note: \* For the case when interrupt generation on transmit FIFO underflow is enabled, set the TXE bit to 1 after setting data for transmission at step No.5.

# **Figure 16.25 SPI Transmission Operation (Example of Half-Duplex Transmission by the**   $CPU with TDMAE = 0)$



No.	<b>Time Chart</b>	SIOF/DMA Setting	SIOF/DMA Operation
1	<b>Start</b> Make settings for DMA.	Complete setting for DMA before making settings for the SIOF.	
2	Set SISCR, SIFCTR, SPICR, and SIIER.	Set the serial clock, threshold values for FIFO, and $TDMAE = 1$	[Note] In SPI mode, registers SIMDR, SITDAR, SIRDAR, and SICDAR should be set to their initial values.
3	Set the SCKE bit in SICTR to 1.	Start baud rate generator operation.	[Note] Serial clock will not be output form the pin until communication is actually started.
4	Set the FSE bit in SICTR to 1. Set the TXE bit in SICTR to 1.	Initialize the frame in the SIOF (ie, initialize the state of signal SS0), and enable transmission.	[Note] Communication is actually started after SITDR has been written.
5	No. TDREQ=1? Yes		
6	DMA transfer (Set the SITDR register.)	Set the data for transmission.	
7	Synchronously to SS0, output the contents of SITDR from MOSI.		Executes transmission.
8	No Transfer complete Yes	For example, in the DMA transfer end interrupt service routine, check SISTR.TFEMP (transmit FIFO empty) and ensure completion of communication by using a wait loop.	When the DMA transfr end interrupt is used, clear the IE bit in DMA.CHCRn before the execution returns from the interrupt service routine.
9	Clear the TXE bit in SICTR to 0.	Disable transmission.	Transmission ends.
10	Clear the FSE bit in SICTR to 0.	To be prepared for the transmission/reception that is resumed later, set FSE = 0 to synchronize the frame in this LSI.	
11	Set BPRS = $00000$ and BRDV = 111 in the SISCR register. Apply a pulse to bit TxRST in the SICTR register (0->1->0 input). Set the SISCR register to set the baud rate again.	To be prepared for the transmission/reception that is resumed later, initialize inside the baud rate generator.	
12	No Change ommunication mode? End Yes	If communication is not to be resumed (branching to No), no further setting is needed. To return to the same communication mode, go back to setting of FSE at step 4 of this flowchart.	
13	With FSE=0, TXE=0, and RXE=0 held, start setting other bits.	Go on to 'Start' of the corresponding flowchart.	

**Figure 16.26 SPI Transmission Operation (Example of Half-Duplex Transmission by DMA**  with  $TDMAE = 1$ )

No.	<b>Time Chart</b>	SIOF/DMA Setting	SIOF/DMA Operation
1	<b>Start</b> Make settings for DMA.	Complete setting for DMA before making settings for the SIOF.	
2	Set SISCR, SIFCTR, SPICR, and SIIER.	Set the serial clock, threshold values for FIFO, and $RDMAE = 1$	[Note] In SPI mode, registers SIMDR, SITDAR, SIRDAR, and SICDAR should be set to their initial values.
3	Set the SCKE bit in SICTR to 1.	Start baud rate generator operation.	[Note] Serial clock will not be output form the pin until communication is actually started.
4	Set the FSE bit in SICTR to 1. Set the RXE bit in SICTR to 1.	Initialize the frame in the SIOF (ie, initialize the state of signal SS0), and enable reception.	[Note] Communication is actually started after RXE = 1 has been set.
5	No RDREQ=1? Yes		
6	<b>DMA</b> transfer (Read from the SIRDR register.)	Read data from the SIRDR register.	
7	Synchronously to SS0, receive data from MISO.		Executes reception.
8	No ransfer complete? Yes	At the point when a DEI interrupt is generated, reception has already proceeded excessively. Therefore, read the necessary amount of data from FIFO and skip the remainder, or cancel by RxRST.	When the DMA transfr end interrupt is used, clear the IE bit in DMA.CHCRn before the execution returns from the interrupt service routine.
9	Clear the RXE bit in SICTR to 0.	Disable reception.	Reception ends.
10	Clear the FSE bit in SICTR to 0.	To be prepared for the transmission/reception that is resumed later, set FSE = 0 to synchronize the frame in this LSI.	
11	Set BPRS = $00000$ and BRDV = 111 in the SISCR register. Apply a pulse to bit RxRST in the SICTR register (0->1->0 input). Set the SISCR register to set the baud rate again.	To be prepared for the transmission/reception that is resumed later, initialize inside the baud rate generator.	
12	No Change ommunication mode <sup>2</sup> End Yes	If communication is not to be resumed (branching to No), no further setting is needed. To return to the same communication mode, go back to setting of FSE at step 4 of this flowchart.	
13	With FSE=0, TXE=0, and RXE=0 held, start setting other bits.	Go on to 'Start' of the corresponding flowchart.	

**Figure 16.27 SPI Reception Operation (Example of Half-Duplex Reception by DMA with**   $\text{RDMAE} = 1$ 





# Section 17 Host Interface (HIF)

This LSI incorporates a host interface (HIF) for use in high-speed transfer of data between external devices which cannot utilize the system bus.

The HIF allows external devices to read from and write to 2 kbytes (1 kbyte  $\times$  2 banks) of the onchip RAM exclusively for HIF use (HIFRAM) within this LSI, in 32-bit units. Interrupts issued to this LSI by an external device, interrupts sent from this LSI to the external device, and DMA transfer requests sent from this LSI to the external device are also supported. By using HIFRAM and these interrupt functions, software-based data transfer between external devices and this LSI becomes possible, and connection to external devices not releasing bus mastership is enabled.

Using HIFRAM, the HIF also supports HIF boot mode allowing this LSI to be booted.

# **17.1 Features**

The HIF has the following features.

- An external device can read from or write to HIFRAM in 32-bit units via the HIF pins (access in 8-bit or 16-bit units not allowed). The on-chip CPU can read from or write to HIFRAM in 8 bit, 16-bit, or 32-bit units, via the internal peripheral bus. The HIFRAM access mode can be specified as bank mode or non-bank mode.
- When an external device accesses HIFRAM via the HIF pins, automatic increment of addresses and the endian can be specified with the HIF internal registers.
- By writing to specific bits in the HIF internal registers from an external device, or by accessing the end address of HIFRAM from the external device, interrupts (internal interrupts) can be issued to the on-chip CPU. Conversely, by writing to specific bits in the HIF internal registers from the on-chip CPU, interrupts (external interrupts) or DMAC transfer requests can be sent from the on-chip CPU to the external device.
- There are seven interrupt source bits each for internal interrupts and external interrupts. Accordingly, software control of 128 different interrupts is possible, enabling high-speed data transfer using interrupts.
- In HIF boot mode, this LSI can be booted from HIFRAM by an external device storing the instruction code in HIFRAM.



Figure 17.1 shows a block diagram of the HIF.





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# **17.2 Input/Output Pins**

Table 17.1 shows the HIF pin configuration.

### **Table 17.1 Pin Configuration**





# **17.3 Parallel Access**

### **17.3.1 Operation**

The HIF can be accessed by combining the HIFCS, HIFRS, HIFWR, and HIFRD pins. Table 17.2 shows the correspondence between combinations of these signals and HIF operations.

<b>HIFCS</b>	<b>HIFRS</b>	<b>HIFWR</b>	<b>HIFRD</b>	<b>Operation</b>
	*	$\ast$	*	No operation (NOP)
				Read from register specified by HIFIDX[7:0]
				Write to register specified by HIFIDX[7:0]
				Read from status register (HIFGSR[7:0])
				Write to index register (HIFIDX[7:0])
	$\ast$			No operation (NOP)
	$\ast$			Setting prohibited

**Table 17.2 HIF Operations** 

[Legend]

\*: Don't care

### **17.3.2 Connection Method**

When connecting the HIF to an external device, a method like that shown in figure 17.2 should be used.



**Figure 17.2 HIF Connection Example** 

# **17.4 Register Descriptions**

The HIF has the following registers.

- HIF index register (HIFIDX)
- HIF general status register (HIFGSR)
- HIF status/control register (HIFSCR)
- HIF memory control register (HIFMCR)
- HIF internal interrupt control register (HIFIICR)
- HIF external interrupt control register (HIFEICR)
- HIF address register (HIFADR)
- HIF data register (HIFDATA)
- HIF boot control register (HIFBCR)
- HIFDREQ trigger register (HIFDTR)
- HIF bank interrupt control register (HIFBICR)

# **17.4.1 HIF Index Register (HIFIDX)**

HIFIDX is a 32-bit register used to specify the register read from or written to by an external device when the HIFRS pin is held low. HIFIDX can be only read by the on-chip CPU. HIFIDX can be only written to by an external device while the HIFRS pin is driven high.











Note: \* This bit can be only written to by an external device while the HIFRS pin is held high. It cannot be written to by the on-chip CPU.



### **17.4.2 HIF General Status Register (HIFGSR)**

HIFGSR is a 32-bit register, which can be freely used for handshaking between an external device connected to the HIF and the software of this LSI. HIFGSR can be read from and written to by the on-chip CPU. Reading from HIFGSR by an external device should be performed with the HIFRS pin high, or HIFGSR specified by bits REG5 to REG0 in HIFIDX and the HIFRS pin low. Writing to HIFGSR by an external device should be performed with HIFGSR specified by bits REG5 to REG0 in HIFIDX and the HIFRS pin low.



#### **17.4.3 HIF Status/Control Register (HIFSCR)**

HIFSCR is a 32-bit register used to control the HIFRAM access mode and endian setting. HIFSCR can be read from and written to by the on-chip CPU. Access to HIFSCR by an external device should be performed with HIFSCR specified by bits REG5 to REG0 in HIFIDX and the HIFRS pin low.









#### **17.4.4 HIF Memory Control Register (HIFMCR)**

HIFMCR is a 32-bit register used to control HIFRAM. HIFMCR can be only read by the on-chip CPU. Access to HIFMCR by an external device should be performed with HIFMCR specified by bits REG5 to REG0 in HIFIDX and the HIFRS pin low.







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setting of this bit.

### **17.4.5 HIF Internal Interrupt Control Register (HIFIICR)**

HIFIICR is a 32-bit register used to issue interrupts from an external device connected to the HIF to the on-chip CPU. Access to HIFIICR by an external device should be performed with HIFIICR specified by bits REG5 to REG0 in HIFIDX and the HIFRS pin low.



### **17.4.6 HIF External Interrupt Control Register (HIFEICR)**

HIFEICR is a 32-bit register used to issue interrupts to an external device connected to the HIF from this LSI. Access to HIFEICR by an external device should be performed with HIFEICR specified by bits REG5 to REG0 in HIFIDX and the HIFRS pin low.







### **17.4.7 HIF Address Register (HIFADR)**

HIFADR is a 32-bit register which indicates the address in HIFRAM to be accessed by an external device. When using the LOCK bit setting in HIFMCR to specify consecutive access of HIFRAM, auto-increment (+4) or auto-decrement (-4) of the address, according to the AI/AD bit setting in HIFMCR, is performed automatically, and HIFADR is updated. HIFADR can be only read by the on-chip CPU. Access to HIFADR by an external device should be performed with HIFADR specified by bits REG5 to REG0 in HIFIDX and the HIFRS pin low.



cannot be written to by the on-chip CPU.

### **17.4.8 HIF Data Register (HIFDATA)**

HIFDATA is a 32-bit register used to hold data to be written to HIFRAM and data read from HIFRAM for external device accesses. If HIFDATA is not used when accessing HIFRAM, it can be used for data transfer between an external device connected to the HIF and the on-chip CPU. HIFDATA can be read from and written to by the on-chip CPU. Access to HIFDATA by an external device should be performed with HIFDATA specified by bits REG5 to REG0 in HIFIDX and the HIFRS pin low.



#### **17.4.9 HIF Boot Control Register (HIFBCR)**

HIFBCR is a 32-bit register for exclusive control of an external device and the on-chip CPU regarding access of HIFRAM. HIFBCR can be only read by the on-chip CPU. Access to HIFBCR by an external device should be performed with HIFBCR specified by bits REG5 to REG0 in HIFIDX and the HIFRS pin low.







### **17.4.10 HIFDREQ Trigger Register (HIFDTR)**

HIFDTR is a 32-bit register. Writing to HIFDTR by the on-chip CPU asserts the HIFDREQ pin. HIFDTR cannot be accessed by an external device.





Notes: 1. This bit cannot be accessed by an external device. It can be accessed only by the onchip CPU.

2. Writing 0 to this bit by the on-chip CPU is ignored.

#### **17.4.11 HIF Bank Interrupt Control Register (HIFBICR)**

HIFBICR is a 32-bit register that controls HIF bank interrupts. HIFBICR cannot be accessed by an external device.







chip CPU.

2. Writing 1 to this bit by the on-chip CPU is ignored.



# **17.5 Memory Map**

Table 17.3 shows the memory map of HIFRAM.

#### **Table 17.3 Memory Map**



Notes: 1. Map for a single HIFRAM bank. Which bank is to be accessed by an external device or the on-chip CPU depends on the BMD and BSEL bits in HIFSCR. The mapping addresses are common between the banks.

 2. Note that in HIF boot mode, bank 0 is selected, and the first 1 kbyte in each of the following address ranges are also mapped: H'00000000 to H'01FFFFFF (first-half 32 Mbytes of area 0 in the P0 area), H'20000000 to H'21FFFFFF (first-half 32 Mbytes of area 0 in the P0 area), H'40000000 to H'41FFFFFF (first-half 32 Mbytes of area 0 in the P0 area), H'60000000 to H'61FFFFFF (first-half 32 Mbytes of area 0 in the P0 area), H'80000000 to H'81FFFFFF (first-half 32 Mbytes of area 0 in the P1 area), H'A0000000 to H'A1FFFFFF (first-half 32 Mbytes of area 0 in the P2 area), and H'C0000000 to H'C1FFFFFF (first-half 32 Mbytes of area 0 in the P3 area).

If an external device modifies HIFRAM when HIFRAM is accessed from the P0, P1, or P3 area with the cache enabled, coherency may not be ensured. When the cache is enabled, accessing HIFRAM from the P2 area is recommended.

In HIF boot mode, among the first-half 32 Mbytes of each area 0, access to the areas to which HIFRAM is not mapped is inhibited.

Even in HIF boot mode, the second-half 32 Mbytes of area 0, area 3, area 4, area 5B, area 5, area 6B, and area 6 are mapped to the external memory as normally.



# **17.6 Interface (Basic)**

Figure 17.3 shows the basic read/write sequence. HIF read is defined by the overlap period of the HIFRD low-level period and HIFCS low-level period, and HIF write is defined by the overlap period of the HIFWR low-level period and HIFCS low-level period. The HIFRS signal indicates whether this is normal access or index/status register access; low level indicates normal access and high level indicates index/status register access.



**Figure 17.3 Basic Timing for HIF Interface** 



# **17.7 Interface (Details)**

# **17.7.1 HIFIDX Write/HIFGSR Read**

Writing of HIFIDX and reading of HIFGSR are shown in figure 17.4.



**Figure 17.4 HIFIDX Write and HIFGSR Read** 

# **17.7.2 Reading/Writing of HIF Registers other than HIFIDX and HIFGSR**

As shown in figure 17.5, in reading and writing of HIF internal registers other than HIFIDX and HIFGSR, first HIFRS is held high and HIFIDX is written to in order to select the register to be accessed and the byte location. Then HIFRS is held low, and reading or writing of the register selected by HIFIDX is performed.



**Figure 17.5 HIF Register Settings** 



### **17.7.3 Consecutive Data Writing to HIFRAM by External Device**

Figure 17.6 shows the timing chart for consecutive data transfer from an external device to HIFRAM. As shown in this timing chart, by setting the start address and the data to be written first, consecutive data transfer can subsequently be performed.



**Figure 17.6 Consecutive Data Writing to HIFRAM** 

# **17.7.4 Consecutive Data Reading from HIFRAM to External Device**

Figure 17.7 shows the timing chart for consecutive data reading from HIFRAM to an external device. As this timing chart indicates, by setting the start address, data can subsequently be read out consecutively.





**Figure 17.7 Consecutive Data Reading from HIFRAM** 

# **17.8 External DMAC Interface**

Figures 17.8 to 17.11 show the HIFDREQ output timing. The start of the HIFDREQ assert synchronizes with the DTRG bit in HIFDTR being set to 1. The HIFDREQ negate timing and assert level are determined by the DMD and DPOL bits in HIFSCR, respectively.

When the external DMAC is specified to detect low level of the HIFDREQ signal, set  $DMD = 0$ and  $DPOL = 0$ . After writing 1 to the DTRG bit, the HIFDREQ signal remains low until low level is detected for both the HIFCS and HIFRS signals.

In this case, when the HIFDREQ signal is used, make sure that the setup time (HIFCS assertion to HIFRS settling) and the hold time (HIFRS hold to  $\overline{HIFCS}$  negate) are satisfied. If  $t_{HIFAS}$  and  $t_{HIFAH}$ stipulated in section 25.4.11, HIF Timing, are not satisfied, the HIFDREQ signal may be negated unintentionally.





**Figure 17.8 HIFDREQ Timing (When DMD = 0 and DPOL = 0)** 

When the external DMAC is specified to detect high level of the HIFDREQ signal, set  $DMD = 0$ and  $DPOL = 1$ . At the time the DPOL bit is set to 1, HIFDREQ becomes low. Then after writing 1 to the DTRG bit, HIFDREQ remains high until low level is detected for both the HIFCS and HIFRS signals.

In this case, when the HIFDREQ signal is used, make sure that the setup time (HIFCS assertion to HIFRS settling) and the hold time (HIFRS hold to  $\overline{HIFCS}$  negate) are satisfied. If  $t_{HIFAS}$  and  $t_{HIFAH}$ stipulated in section 25.4.11, HIF Timing, are not satisfied, the HIFDREQ signal may be negated unintentionally.



**Figure 17.9 HIFDREQ Timing (When DMD = 0 and DPOL = 1)** 

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When the external DMAC is specified to detect the falling edge of the HIFDREQ signal, set DMD  $= 1$  and DPOL  $= 0$ . After writing 1 to the DTRG bit, a low pulse of 32 peripheral clock cycles is generated at the HIFDREQ pin.



**Figure 17.10 HIFDREQ Timing (When DMD = 1 and DPOL = 0)** 

When the external DMAC is specified to detect the rising edge of the HIFDREQ signal, set DMD  $= 1$  and DPOL  $= 1$ . At the time the DPOL bit is set to 1, HIFDREQ becomes low. Then after writing 1 to the DTRG bit, a low pulse of 32 peripheral clock cycles is generated at the HIFDREQ pin.



**Figure 17.11 HIFDREQ Timing (When DMD = 1 and DPOL = 1)** 

When the external DMAC supports intermittent operating mode (block transfer mode), efficient data transfer can be implemented by using the HIFRAM consecutive access and bank functions.





# **Table 17.4 Consecutive Write Procedure to HIFRAM by External DMAC**


Hereafter No. 11 to 13 are repeated. When a register other than HIFDATA is accessed (except that HIFGSR read with HIFRS = low), HIFRAM consecutive write is interrupted, and No. 3 to 6 need to be done again.









Hereafter No. 12 to 14 are repeated. When a register other than HIFDATA is accessed (except that HIFGSR read with HIFRS = low), HIFRAM consecutive read is interrupted, and No. 3 to 5 need to be done again.

## **17.9 Alignment Control**

Tables 17.6 and 17.7 show the alignment control when an external device accesses the HIFDATA register, and the HIF registers other than the HIFDATA register, respectively.



#### **Table 17.6 HIFDATA Register Alignment for Access by an External Device**

#### **Table 17.7 HIF Registers (other than HIFDATA) Alignment for Access by an External Device**





# **17.10 Interface When External Device Power is Cut Off**

When the power supply of an external device interfacing with the HIF is cut off, intermediate levels may be applied to the HIF input pins or the HIF output pins may drive an external device not powered, thus causing the device to be damaged. The HIFEBL pin is provided to prevent this from happening. The system power monitor block controls the HIFEBL pin in synchronization with the cutoff of the external device power so that all HIF pins can be set to the high-impedance state. Figure 17.12 shows an image of high-impedance control of the HIF pins. Table 17.8 lists the input/output control for the HIF pins.



**Figure 17.12 Image of High-Impedance Control of HIF Pins by HIFEBL Pin** 



## **Table 17.8 Input/Output Control for HIF Pins**



Notes: 1. The pin also functions as an HIFEBL pin by setting the PFC registers.

2. The pin also functions as an HIF pin by setting the PFC registers.

When the HIF pin function is selected for the HIFEBL pin and this pin by setting the PFC registers, the input and/or output buffers are controlled according to the HIFEBL pin state.

When the HIF pin function is not selected for the HIFEBL pin and is selected for this pin by setting the PFC registers, the input and/or output buffers are always turned off. This setting is prohibited.

# Section 18 Pin Function Controller (PFC)

The pin function controller (PFC) consists of registers that select multiplexed pin functions and input/output directions. Tables 18.1 to 18.5 show the multiplexed pins in this LSI. Table 18.6 shows the pin functions in each operating mode.



#### **Table 18.1 List of Multiplexed Pins (Port A)**

#### **Table 18.2 List of Multiplexed Pins (Port B)**







## **Table 18.3 List of Multiplexed Pins (Port C)**







#### **Table 18.5 List of Multiplexed Pins (Port E)**



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## **Table 18.6 Pin Functions in Each Operating Mode**















# **18.1 Register Descriptions**

The PFC has the following registers. For details on the addresses of these registers and the states of these registers in each processing state, see section 24, List of Registers.

- Port A IO register H (PAIORH)
- Port A control register H1 (PACRH1)
- Port A control register H2 (PACRH2)
- Port B IO register L (PBIORL)
- Port B control register L1 (PBCRL1)
- Port B control register L2 (PBCRL2)
- Port C IO register H (PCIORH)
- Port C IO register L (PCIORL)
- Port C control register H2 (PCCRH2)
- Port C control register L1 (PCCRL1)
- Port C control register L2 (PCCRL2)
- Port D IO register L (PDIORL)
- Port D control register L2 (PDCRL2)
- Port E IO register H (PEIORH)
- Port E IO register L (PEIORL)
- Port E control register H1 (PECRH1)
- Port E control register H2 (PECRH2)
- Port E control register L1 (PECRL1)
- Port E control register L2 (PECRL2)



## **18.1.1 Port A IO Register H (PAIORH)**

PAIORH is a 16-bit readable/writable register that selects the input/output directions of the port A pins. Bits PA25IOR to PA16IOR correspond to pins PA25 to PA16 (the pin name abbreviations for multiplexed functions are omitted). PAIORH is enabled when a port A pin functions as a general input/output (PA25 to PA16), otherwise, disabled.

Setting a bit in PAIORH to 1 makes the corresponding pin function as an output and clearing a bit in PAIORH to 0 makes the pin function as an input.

Bits 15 to 10 in PAIORH are reserved. These bits are always read as 0. The write value should always be 0.

The initial value of PAIORH is H'0000.

#### **18.1.2 Port A Control Register H1 and H2 (PACRH1 and PACRH2)**

PACRH1 and PACRH2 are 16-bit readable/writable registers that select the pin functions for the multiplexed port A pins.

• PACRH1





#### • PACRH2







#### **18.1.3 Port B IO Register L (PBIORL)**

PBIORL is a 16-bit readable/writable register that selects the input/output directions of the port B pins. Bits PB13IOR to PB0IOR correspond to pins PB13 to PB00 (the pin name abbreviations for multiplexed functions are omitted). PBIORL is enabled when a port B pin functions as a general input/output (PB13 to PB00), otherwise, disabled.

Setting a bit in PBIORL to 1 makes the corresponding pin function as an output and clearing a bit in PBIORL to 0 makes the pin function as an input.

Bits 15 and 14 in PBIORL are reserved. These bits are always read as 0. The write value should always be 0.

The initial value of PAIBRL is H'0000.

#### **18.1.4 Port B Control Register L1 and L2 (PBCRL1 and PBCRL2)**

PBCRL1 and PBCRL2 are 16-bit readable/writable registers that select the pin functions for the multiplexed port B pins.

• PBCRL1









• PBCRL2









## **18.1.5 Port C IO Register H and L (PCIORH and PCIORL)**

PCIORH and PCIORL are 16-bit readable/writable registers that select the input/output directions of the port C pins. Bits PC20IOR to PC0IOR correspond to pins PC20 to PC00 (the pin name abbreviations for multiplexed functions are omitted). PCIORH is enabled when a port C pin functions as a general input/output (PC20 to PC16), otherwise, disabled. PCIORL is enabled when a port C pin functions as a general input/output (PC15 to PC00), otherwise, disabled.

Setting a bit in PCIORH and PCIORL to 1 makes the corresponding pin function as an output and clearing a bit in PCIORH and PCIORL to 0 makes the pin function as an input.

Bits 15 to 5 in PCIORH are reserved. These bits are always read as 0. The write value should always be 0.

The initial values of PCIORH and PCIORL are H'0000.

#### **18.1.6 Port C Control Register H2, L1, and L2 (PCCRH2, PCCRL1, and PCCRL2)**

PCCRH2, PCCRL1, and PCCRL2 are 16-bit readable/writable registers that select the pin functions for the multiplexed port C pins.

• PCCRH2







• PCCRL1









#### • PCCRL2









## **18.1.7 Port D IO Register L (PDIORL)**

PDIORL is a 16-bit readable/writable register that selects the input/output directions of the port D pins. Bits PD7IOR to PD0IOR correspond to pins PD7 to PD0 (the pin name abbreviations for multiplexed functions are omitted). PDIORL is enabled when a port C pin functions as a general input/output (PD7 to PD0), otherwise, disabled.

Setting a bit in PDIORL to 1 makes the corresponding pin function as an output and clearing a bit in PDIORL to 0 makes the pin function as an input.

Bits 15 to 8 in PDIORL are reserved. These bits are always read as 0. The write value should always be 0.

The initial value of PDIORL is H'0000.

#### **18.1.8 Port D Control Register L2 (PDCRL2)**

PDCRL2 is a 16-bit readable/writable register that selects the pin functions for the multiplexed port B pins.

• PDCRL2





#### **18.1.9 Port E IO Register H and L (PEIORH and PEIORL)**

PEIORH and PEIORL are 16-bit readable/writable registers that select the input/output directions of the port E pins. Bits PE24IOR to PE0IOR correspond to pins PE24 to PE00 (the pin name abbreviations for multiplexed functions are omitted). PEIORH is enabled when a port E pin functions as a general input/output (PE24 to PE16), otherwise, disabled. PEIORL is enabled when a port E pin functions as a general input/output (PE15 to PE00), otherwise, disabled.

Setting a bit in PEIORH and PEIORL to 1 makes the corresponding pin function as an output and clearing a bit in PEIORH and PEIORL to 0 makes the pin function as an input.

Bits 15 to 9 in PAIORH are reserved. These bits are always read as 0. The write value should always be 0.

The initial values of PEIORH and PEIORL are H'0000.

## **18.1.10 Port E Control Register H1, H2, L1, and L2 (PECRH1, PECRH2, PECRL1, and PECRL2)**

PECRH1, PECRH2, PECRL1, and PECRL2 are 16-bit readable/writable registers that select the pin functions for the multiplexed port E pins.

• PECRH1





#### • PECRH2





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• PECRL1






# • PECRL2











# **18.2 Notes on Usage**

## **18.2.1 Restriction in Using**

In the use of the pins listed in the following table, please set the data registers and also pin function controller (i.e. in the use of the output functions EXCEPT the function 1, please DO NOT change the initial value  $(= 0)$  in the data registers of that pins).

<b>Function 1</b> (Related Module)	<b>Function 2</b> (Related Module)	<b>Function 3</b> (Related Module)	<b>Function 4</b> (Related Module)
PD2 input/output (port)	IRQ2 input (INTC)	TxD1 output (SCIF)	DREQ0 input (DMAC)
PD4 input/output (port)	IRQ4 input (INTC)	SCK1 input/output (SCIF)	DACK0 output (DMAC)
PD5 input/output (port)	IRQ5 input (INTC)	TxD2 input/output (SCIF)	DREQ1 input (DMAC)

**Table 18.7 Pins restricted in using in SH7619** 

## **18.2.2 Details of Restriction**

For the logical specs of the output functions of the pins listed in the above table (i.e. logical sum of the value of the data register), when the data register of the pins is set to '1', the output of the pins will be FIXED to '1' (= High). For the initial value of that data register is '0', it DOES NOT cause any problems in the use of NOT writing any data at all after power-on-reset. In addition, the output is fixed to '1' (= High) in the use of writing '1' to the data register, it must be safe with the sets that have already worked without any problems UNLESS change the value of PFC, whereas input functions do work safety even in the function 1.





# Section 19 I/O Ports

This LSI has 26 ports (ports A, B, C, D, and E). Port A, port B, port C, port D, and port E are 10 bit, 14-bit, 21-bit, 8-bit, and 25-bit I/O port, respectively. The pins of each port are multiplexed with other functions. The pin function controller (PFC) handles the selection of multiplex pin functions. Each port has a data register to store data of pin.

# **19.1 Port A**

Port A of this LSI is an I/O port with ten pins as shown in figure 19.1.



**Figure 19.1 Port A** 

# **19.1.1 Register Description**

Port A is a 10-bit I/O port that has a following register. For details on the address of this register and the states of this register in each processing state, see section 24, List of Registers.

• Port A data register H (PADRH)

# **19.1.2 Port A Data Register H (PADRH)**

PADRH is a 16-bit readable/writable register which stores data for port A. Bits PA25DR to PA16DR correspond to pins PA25 to PA16. (Description of multiplexed functions is omitted.)



When the pin function is general output port, if the value is written to PADRH, the value is output from the pin; if PADRH is read, the value written to the register is directly read regardless of the pin state.

When the pin function is general input port, not the value of register but pin state is directly read if PADRH is read. Data can be written to PADRH but no effect on the pin state. Table 19.1 shows the reading/writing function of the port A data register H.



### **Table 19.1 Port A Data Register H (PADRH) Read/Write Operation**

• Bits 9 to 0 in PADRH



# **19.2 Port B**

Port B of this LSI is an I/O port with 14 pins as shown in figure 19.2.



**Figure 19.2 Port B** 

### **19.2.1 Register Description**

Port B is a 14-bit I/O port that has a following register. For details on the address of this register and the states of this register in each processing state, see section 24, List of Registers.

• Port B data register L (PBDRL)

## **19.2.2 Port B Data Register L (PBDRL)**

PBDRL is a 16-bit readable/writable register which stores data for port B. Bits PB13DR to PB0DR correspond to pins PB13 to PB00. (Description of multiplexed functions is omitted.)

When the pin function is general output port, if the value is written to PBDRL, the value is output from the pin; if PBDRL is read, the value written to the register is directly read regardless of the pin state.



When the pin function is general input port, not the value of register but pin state is directly read if PBDRL is read. Data can be written to PBDRL but no effect on the pin state. Table 19.2 shows the reading/writing function of the port B data register L.



### **Table 19.2 Port B Data Register L (PBDRL) Read/Write Operation**

• Bits 13 to 0 in PBDRL



# **19.3 Port C**

Port C of this LSI is an I/O port with 21 pins as shown in figure 19.3.



**Figure 19.3 Port C** 



### **19.3.1 Register Description**

Port C is a 21-bit I/O port that has the following registers. For details on the addresses of these registers and the states of these registers in each processing state, see section 24, List of Registers.

- Port C data register H (PCDRH)
- Port C data register L (PCDRL)

### **19.3.2 Port C Data Registers H and L (PCDRH and PCDRL)**

PCDRH and PCDRL are 16-bit readable/writable registers that stores data for port C. Bits PC20DR to PC0DR correspond to pins PC20 to PC00. (Description of multiplexed functions is omitted.)

When the pin function is general output port, if the value is written to PCDRH or PCDRL, the value is output from the pin; if PCDRH or PCDRL is read, the value written to the register is directly read regardless of the pin state.

When the pin function is general input port, not the value of register but pin state is directly read if PCDRH or PCDRL is read. Data can be written to PCDRH or PCDRL but no effect on the pin state. Table 19.3 shows the reading/writing function of the port C data registers H and L.



### • PCDRH

• PCDRL



# **Table 19.3 Port C Data Registers H and L (PCDRH and PCDRL) Read/Write Operation**

• Bits 4 to 0 in PCDRH and Bits 15 to 0 in PCDRL





# **19.4 Port D**

Port D of this LSI is an I/O port with eight pins as shown in figure 19.4.



**Figure 19.4 Port D** 

## **19.4.1 Register Description**

Port D is an 8-bit I/O port that has a following register. For details on the address of this register and the states of this register in each processing state, see section 24, List of Registers.

• Port D data register L (PDDRL)

## **19.4.2 Port D Data Register L (PDDRL)**

PDDRL is a 16-bit readable/writable register which stores data for port D. Bits PD7DR to PD0DR correspond to pins PD7 to PD0. (Description of multiplexed functions is omitted.)

When the pin function is general output port, if the value is written to PDDRL, the value is output from the pin; if PDDRL is read, the value written to the register is directly read regardless of the pin state.

When the pin function is general input port, not the value of register but pin state is directly read if PDDRL is read. Data can be written to PDDRL but no effect on the pin state. Table 19.4 shows the reading/writing function of the port D data register L.





# **Table 19.4 Port D Data Register L (PDDRL) Read/Write Operation**

• Bits 7 to 0 in PDDRL





# **19.5 Port E**

Port E of this LSI is an I/O port with 25 pins as shown in figure 19.5.

	PE00 (input/output)/HIFEBL (input)/SCK_SIO0 (input/output)
	PE01 (input/output)/HIFRDY (output)/SIOMCLK0 (input)
	PE02 (input/output)/HIFDREQ (output)/RXD_SIO0 (input)
	PE03 (input/output)/HIFMD (input)
	PE04 (input/output)/HIFINT (output)/TXD_SIO0 (output)
	PE05 (input/output)/HIFRD (input)
	PE06 (input/output)/HIFWR (input)/SIOFSYNC (input/output)
	PE07 (input/output)/HIFRS (input)
	PE08 (input/output)/HIFCS (input)
	PE09 (input/output)/HIFD00 (input/output)/D16 (input/output)
	PE10 (input/output)/HIFD01 (input/output)/D17 (input/output)
	PE11 (input/output)/HIFD02 (input/output)/D18 (input/output)
Port E	PE12 (input/output)/HIFD03 (input/output)/D19 (input/output)
	PE13 (input/output)/HIFD04 (input/output)/D20 (input/output)
	PE14 (input/output)/HIFD05 (input/output)/D21 (input/output)
	PE15 (input/output)/HIFD06 (input/output)/TxD0 (output)/D22 (input/output)
	PE16 (input/output)/HIFD07 (input/output)/RxD0 (input)/D23 (input/output)
	PE17 (input/output)/HIFD08 (input/output)/SCK0 (input/output)/D24 (input/output)
	PE18 (input/output)/HIFD09 (input/output)/TxD1 (output)/D25 (input/output)
	PE19 (input/output)/HIFD10 (input/output)/RxD1 (input)/D26 (input/output)
	PE20 (input/output)/HIFD11 (input/output)/SCK1 (input/output)/D27 (input/output)
	PE21 (input/output)/HIFD12 (input/output)/RTS0 (output)/D28 (input/output)
	PE22 (input/output)/HIFD13 (input/output)/CTS0 (input)/D29 (input/output)
	PE23 (input/output)/HIFD14 (input/output)/RTS1 (output)/D30 (input/output)

**Figure 19.5 Port E** 

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### **19.5.1 Register Description**

Port E is a 25-bit I/O port that has the following registers. For details on the addresses of these registers and the states of these registers in each processing state, see section 24, List of Registers.

- Port E data register H (PEDRH)
- Port E data register L (PEDRL)

### **19.5.2 Port E Data Registers H and L (PEDRH and PEDRL)**

PEDRH and PEDRL are 16-bit readable/writable registers that store data for port E. Bits PE24DR to PE0DR correspond to pins PE24 to PE00. (Description of multiplexed functions is omitted.)

When the pin function is general output port, if the value is written to PEDRH or PEDRL, the value is output from the pin; if PEDRH or PEDRL is read, the value written to the register is directly read regardless of the pin state.

When the pin function is general input port, not the value of register but pin state is directly read if PEDRH or PEDRL is read. Data can be written to PEDRH or PEDRL but no effect on the pin state. Table 19.5 shows the reading/writing function of the port E data registers H and L.



#### • PEDRH



• PEDRL



### **Table 19.5 Port E Data Registers H, L (PEDRH, PEDRL) Read/Write Operation**

• Bits 8 to 0 in PEDRH and Bits 15 to 0 in PEDRL



# **19.6 Usage Notes**

- 1. When pins that are multiplexed with general I/O is used as output pins for other functions, these pins work as general output pins for the period of  $1 \times t_{\text{pcyc}}$  synchronized with internal power-on reset by WDT overflow. For example, when the pin PB12/CS3 works as CS3 and the PB12DR bit in PBDRL is set to 0, the pin is driven low for the period of  $1 \times t_{PCYC}$  and may lead to memory malfunction. To prevent this, port registers that correspond to pins used for the strobe output must be set to strobe non-active level. This case does not apply to the power-on reset from the RES pin.
- 2. The weak keeper circuit is included in all pins except MD5, MD3, MD2, MD1, MD0, ASEMD, TESTMD, EXTAL, XTAL, TxP, TxM, RxP, RxM, EXRES1, and TSTBUSA. The weak keeper is a circuit, always operating while the power is on, that fixes the input in I/O pins to low or high when the pins are not driven from outside. Notes on processing the input pins are as follows:
	- When using pins having the weak keeper circuit as input pins and driving these pins to a certain level from outside, adjust the resistance of pull-up/pull-down resistors to let the weak keeper circuit keep the intended levels. (2 k $\Omega$  and 8 k $\Omega$  are recommended respectively.) The larger the resistance is, the longer the transition time is. In addition, a large resistance may fail to let the weak keeper circuit to keep the intended levels. Therefore, when the resistors adjusted comparatively large are used, ensure that any transition does not delay in the system.
	- While using the pins having the weak keeper circuit as input pins, if their levels do not matter, there is no need to deal with pins from outside.
	- MD5, MD3, MD2, MD1, MD0, ASEMD, and TESTMD.

Drive these to intended levels from outside. Since the weak keeper circuit is not included in those pins, comparatively large resistance in pull-up/pull-down resistors can be used.

## EXTAL, and XTAL

See section 8.6, Notes on Board Design in section 8, Clock Pulse Generator (CPG).

- 3. Since the HIFMD pin is not initially set to function as a general port pin, it must be pulled up or down externally to fix its state.
- 4. When using a multiplexed pin with a function not selected with its initial value (for example, using the PB12/CS3 pin, the initial function of which is PB12, as the CS3 pin), the pin must be pulled up or down externally at least after a reset until its pin function is selected by software to fix its state.





# Section 20 User Break Controller (UBC)

The user break controller (UBC) provides functions that simplify program debugging. These functions make it easy to design an effective self-monitoring debugger, enabling the chip to debug programs without using an in-circuit emulator. Break conditions that can be set in the UBC are instruction fetch or data read/write access, data size, data contents, address value, and stop timing in the case of instruction fetch.

# **20.1 Features**

The UBC has the following features:

The following break comparison conditions can be set.

Number of break channels: two channels (channels A and B)

User break can be requested as either the independent or sequential condition on channels A and B (sequential break: when channel A and channel B match with break conditions in the different bus cycles in that order, a break condition is satisfied).

Address (Compares addresses 32 bits):

Comparison bits are maskable in 1-bit units; user can mask addresses at lower 12 bits (4-k page), lower 10 bits (1-k page), or any size of page, etc.

One of the two address buses (L-bus address (LAB) and I-bus address (IAB)) can be selected.

— Data (only on channel B, 32-bit maskable)

One of the two data buses (logic data bus (LDB) and internal data bus (IDB)) can be selected.

- Bus cycle: Instruction fetch or data access
- Read/write
- Operand size: Byte, word, or longword
- User break interrupt is generated upon satisfying break conditions. A user-designed user-break condition interrupt exception processing routine can be run.
- In an instruction fetch cycle, it can be selected that a break is set before or after an instruction is executed.
- Maximum repeat times for the break condition (only for channel B):  $2^{12} 1$  times.
- Four pairs of branch source/destination buffers.



Figure 20.1 shows a block diagram of the UBC.



**Figure 20.1 Block Diagram of UBC** 

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# **20.2 Register Descriptions**

The user break controller has the following registers. For details on register addresses and access sizes, refer to section 24, List of Registers.

- Break address register A (BARA)
- Break address mask register A (BAMRA)
- Break bus cycle register A (BBRA)
- Break address register B (BARB)
- Break address mask register B (BAMRB)
- Break bus cycle register B (BBRB)
- Break data register B (BDRB)
- Break data mask register B (BDMRB)
- Break control register (BRCR)
- Execution times break register (BETR)
- Branch source register (BRSR)
- Branch destination register (BRDR)

# **20.2.1 Break Address Register A (BARA)**

BARA is a 32-bit readable/writable register. BARA specifies the address used for a break condition in channel A.





#### **20.2.2 Break Address Mask Register A (BAMRA)**

BAMRA is a 32-bit readable/writable register. BAMRA specifies bits masked in the break address specified by BARA.



### **20.2.3 Break Bus Cycle Register A (BBRA)**

Break bus cycle register A (BBRA) is a 16-bit readable/writable register, which specifies (1) L bus cycle or I bus cycle, (2) instruction fetch or data access, (3) read or write, and (4) operand size in the break conditions of channel A.





#### **20.2.4 Break Address Register B (BARB)**

BARB is a 32-bit readable/writable register. BARB specifies the address used for a break condition in channel B.



### **20.2.5 Break Address Mask Register B (BAMRB)**

BAMRB is a 32-bit readable/writable register. BAMRB specifies bits masked in the break address specified by BARB.



#### **20.2.6 Break Data Register B (BDRB)**

BDRB is a 32-bit readable/writable register. BDBR selects data used for a break condition in channel B.



Notes: 1. Specify an operated size when including the value of the data bus in the break condition.

 2. When the byte size is selected as a break condition, the same byte must be set in bits 15 to 8 and 7 to 0 in BDRB as the break data.



### **20.2.7 Break Data Mask Register B (BDMRB)**

BDMRB is a 32-bit readable/writable register. BDMRB specifies bits masked in the break data specified by BDRB.



Notes: 1. Specify an operated size when including the value of the data bus in the break condition.

 2. When the byte size is selected as a break condition, the same data must be set in bits 15 to 8 and 7 to 0 in BDRB as the break mask data.

## **20.2.8 Break Bus Cycle Register B (BBRB)**

Break bus cycle register B (BBRB) is a 16-bit readable/writable register, which specifies (1) L bus cycle or I bus cycle, (2) instruction fetch or data access, (3) read or write, and (4) operand size in the break conditions of channel B.







### **20.2.9 Break Control Register (BRCR)**

BRCR sets the following conditions:

- Channels A and B are used in two independent channel conditions or under the sequential condition.
- A break is set before or after instruction execution.
- Specify whether to include the number of execution times on channel B in comparison conditions.
- Specify whether to include data bus on channel B in comparison conditions.
- Enable PC trace.

The break control register (BRCR) is a 32-bit readable/writable register that has break conditions match flags and bits for setting a variety of break conditions.











### **20.2.10 Execution Times Break Register (BETR)**

BETR is a 16-bit readable/writable register. When the execution-times break condition of channel B is enabled, this register specifies the number of execution times to make the break. The maximum number is  $2^{12} - 1$  times. Every time the break condition is satisfied, BETR is decremented by 1. A break is issued when the break condition is satisfied after BETR becomes H'0001.



### **20.2.11 Branch Source Register (BRSR)**

BRSR is a 32-bit read-only register. BRSR stores bits 27 to 0 in the address of the branch source instruction. BRSR has the flag bit that is set to 1 when a branch occurs. This flag bit is cleared to 0 when BRSR is read, the setting to enable PC trace is made, or BRSR is initialized by a power-on reset. Other bits are not initialized by a power-on reset. The four BRSR registers have a queue structure and a stored register is shifted at every branch.





#### **20.2.12 Branch Destination Register (BRDR)**

BRDR is a 32-bit read-only register. BRDR stores bits 27 to 0 in the address of the branch destination instruction. BRDR has the flag bit that is set to 1 when a branch occurs. This flag bit is cleared to 0 when BRDR is read, the setting to enable PC trace is made, or BRDR is initialized by a power-on reset. Other bits are not initialized by a power-on reset. The four BRDR registers have a queue structure and a stored register is shifted at every branch.





# **20.3 Operation**

### **20.3.1 Flow of User Break Operation**

The flow from setting of break conditions to user break exception processing is described below:

- 1. The break addresses are set in the break address registers (BARA and BARB). The masked addresses are set in the break address mask registers (BAMRA and BAMRB). The break data is set in the break data register (BDRB). The masked data is set in the break data mask register (BDMRB). The bus break conditions are set in the break bus cycle registers (BBRA and BBRB). There are three control bit combinations in both BBRA and BBRB: bits to select Lbus cycle or I-bus cycle, bits to select instruction fetch or data access, and bits to select read or write. No user break will be generated if one of these combinations is set to B'00. The respective conditions are set in the bits of the break control register (BRCR). Make sure to set all registers related to breaks before setting BBRA/BBRB.
- 2. When the break conditions are satisfied, the UBC sends a user break request to the CPU and sets the L bus condition match flag (SCMFCA or SCMFCB) and the I bus condition match flag (SCMFDA or SCMFDB) for the appropriate channel.
- 3. The appropriate condition match flags (SCMFCA, SCMFDA, SCMFCB, and SCMFDB) can be used to check if the set conditions match or not. The matching of the conditions sets flags. Reset the flags by writing 0 before they are used again.
- 4. There is a chance that the data access break and its following instruction fetch break occur around the same time, there will be only one break request to the CPU, but these two break channel match flags could be both set.



### **20.3.2 Break on Instruction Fetch Cycle**

- 1. When L bus/instruction fetch/read/word or longword is set in the break bus cycle register (BBRA/BBRB), the break condition becomes the L bus instruction fetch cycle. Whether it breaks before or after the execution of the instruction can then be selected with the PCBA/PCBB bit of the break control register (BRCR) for the appropriate channel. If an instruction fetch cycle is set as a break condition, clear LSB in the break address register (BARA/BARB) to 0. A break cannot be generated as long as this bit is set to 1.
- 2. If the condition is matched while a break before execution is selected, a break is generated when it is confirmed that the instruction has been fetched and it will be executed. This means this feature cannot be used on instructions fetched by overrun (instructions fetched at a branch or during an interrupt transition, but not to be executed). When this kind of break is set in the delay slot of a delayed branch instruction, the break is generated immediately before the execution of the instruction that first accepts the break. Meanwhile, a break before the execution of the instruction in a delay slot and a break after the execution of the SLEEP instruction are also prohibited.
- 3. When a break after execution is selected, the instruction that matches the break condition is executed and then the break is generated prior to the execution of the next instruction. As with a break before execution, this cannot be used with overrun fetch instructions. When this kind of break is set for a delayed branch instruction, a break is not generated until the first instruction at which breaks are accepted.
- 4. When an instruction fetch cycle is set for channel B, the break data register B (BDRB) is ignored. There is thus no need to set break data for the break of the instruction fetch cycle.

### **20.3.3 Break on Data Access Cycle**

- The bus cycles in which L bus data access breaks occur are from instructions.
- The relationship between the data access cycle address and the comparison condition for each operand size is listed in table 20.1.



#### **Table 20.1 Data Access Cycle Addresses and Operand Size Comparison Conditions**



This means that when address H'00001003 is set in the break address register (BARA or BARB), for example, the bus cycle in which the break condition is satisfied is as follows (where other conditions are met).

- Longword access at H'00001000
- $-$  Word access at H'00001002
- Byte access at H'00001003
- When the data value is included in the break conditions on channel B:

When the data value is included in the break conditions, either longword, word, or byte is specified as the operand size of the break bus cycle registers (BBRA and BBRB). In this case, a break is generated when the address conditions and data conditions both match. To specify byte data for this case, set the same data in two bytes at bits 15 to 8 and bits 7 to 0 of the break data register B (BDRB) and break data mask register B (BDMRB). When word or byte is set, bits 31 to 16 of BDRB and BDMRB are ignored.

# **20.3.4 Sequential Break**

- By setting the SEQ bit in BRCR to 1, the sequential break is issued when a channel B break condition matches after a channel A break condition matches. A user break is not generated even if a channel B break condition matches before a channel A break condition matches. When channels A and B break conditions match at the same time, the sequential break is not issued. To clear the channel A condition match when a channel A condition match has occurred but a channel B condition match has not yet occurred in a sequential break specification, clear the SEQ bit in BRCR to 0.
- In sequential break specification, the L- or I-bus can be selected and the execution times break condition can be also specified. For example, when the execution times break condition is specified, the break is generated when a channel B condition matches with BETR = H'0001 after a channel A condition has matched.

# **20.3.5 Value of Saved Program Counter (PC)**

When a break occurs, PC is saved onto the stack. The PC value saved is as follows depending on the type of break.

When a break before execution is selected:

The value of the program counter (PC) saved is the address of the instruction that matches the break condition. The fetched instruction is not executed, and a break occurs before it.
• When a break after execution is selected:

The PC value saved is the address of the instruction to be executed following the instruction in which the break condition matches. The fetched instruction is executed, and a break occurs before the execution of the next instruction.

- When an address in a data access cycle is specified as a break condition: The PC value is the address of the instruction to be executed following the instruction that matched the break condition. The instruction that matched the condition is executed and the break occurs before the next instruction is executed.
- When an address and data in a data access cycle are specified as a break condition: The PC value is the start address of the instruction that follows the instruction already executed when break processing started. When a data value is added to the break conditions, the break will occur before the execution of an instruction that is within two instructions of the instruction that matched the break condition. Therefore, where the break will occur cannot be specified exactly.

#### **20.3.6 PC Trace**

- Setting PCTE in BRCR to 1 enables PC traces. When branch (branch instruction, and interrupt) is generated, the branch source address and branch destination address are stored in BRSR and BRDR, respectively.
- The branch source address has different values due to the kind of branch.
	- Branch instruction

The branch instruction address.

- Interrupt and exception
	- The address of the instruction in which the interrupt or exception was accepted. This address is equal to the return address saved onto the stack.

The start address of the interrupt or exception handling routine is stored in BRDR.

The TRAPA instruction belongs to interrupt and exception above.

• BRSR and BRDR have four pairs of queue structures. The top of queues is read first when the address stored in the PC trace register is read. BRSR and BRDR share the read pointer. Read BRSR and BRDR in order, the queue only shifts after BRDR is read. After switching the PCTE bit (in BRCR) off and on, the values in the queues are invalid.



## **20.3.7 Usage Examples**

#### **Break Condition Specified for L Bus Instruction Fetch Cycle:**

• Register specifications

BARA = H'00000404, BAMRA = H'00000000, BBRA = H'0054, BARB = H'00008010, BAMRB = H'00000006, BBRB = H'0054, BDRB = H'00000000, BDMRB = H'00000000, BRCR = H'00300400

Specified conditions: Channel A/channel B independent mode

Channel A

Address: H'00000404, Address mask: H'00000000

Bus cycle: L bus/instruction fetch (after instruction execution)/read (operand size is not included in the condition)

Channel B

Address: H'00008010, Address mask: H'00000006

Data: H'00000000, Data mask: H'00000000

Bus cycle: L bus/instruction fetch (before instruction execution)/read (operand size is not included in the condition)

A user break occurs after an instruction of address H'00000404 is executed or before instructions of addresses H'00008010 to H'00008016 are executed.

Register specifications

BARA = H'00037226, BAMRA = H'00000000, BBRA = H'0056, BARB = H'0003722E, BAMRB = H'00000000, BBRB = H'0056, BDRB = H'00000000, BDMRB = H'00000000, BRCR = H'00000008

Specified conditions: Channel A/channel B sequential mode

Channel A

Address: H'00037226, Address mask: H'00000000

Bus cycle: L bus/instruction fetch (before instruction execution)/read/word

Channel B

Address: H'0003722E, Address mask: H'00000000

Data: H'00000000, Data mask: H'00000000

Bus cycle: L bus/instruction fetch (before instruction execution)/read/word

After address H'00037226 is executed, a user break occurs before an instruction of address H'0003722E is executed.

• Register specifications

BARA = H'00027128, BAMRA = H'00000000, BBRA = H'005A, BARB = H'00031415, BAMRB = H'00000000, BBRB = H'0054, BDRB = H'00000000, BDMRB = H'00000000, BRCR = H'00300000

Specified conditions: Channel A/channel B independent mode

Channel A

Address: H'00027128, Address mask: H'00000000

- Bus cycle: L bus/instruction fetch (before instruction execution)/write/word
- The ASID check is not included.
- Channel B

Address: H'00031415, Address mask: H'00000000

Data: H'00000000, Data mask: H'00000000

Bus cycle: L bus/instruction fetch (before instruction execution)/read (operand size is not included in the condition)

On channel A, no user break occurs since instruction fetch is not a write cycle. On channel B, no user break occurs since instruction fetch is performed for an even address.

• Register specifications

```
BARA = H'00037226, BAMRA = H'00000000, BBRA = H'005A, BARB = H'0003722E, 
BAMRB = H'00000000, BBRB = H'0056, BDRB = H'00000000, BDMRB = H'00000000, 
BRCR = H'00000008
```
Specified conditions: Channel A/channel B sequential mode

Channel A

Address: H'00037226, Address mask: H'00000000

Bus cycle: L bus/instruction fetch (before instruction execution)/write/word

Channel B

Address: H'0003722E, Address mask: H'00000000

Data: H'00000000, Data mask: H'00000000

Bus cycle: L bus/instruction fetch (before instruction execution)/read/word

Since instruction fetch is not a write cycle on channel A, a sequential condition does not match. Therefore, no user break occurs.



• Register specifications

BARA = H'00000500, BAMRA = H'00000000, BBRA = H'0057, BARB = H'00001000, BAMRB = H'00000000, BBRB = H'0057, BDRB = H'00000000, BDMRB = H'00000000, BRCR = H'00300001, BETR = H'0005

Specified conditions: Channel A/channel B independent mode

Channel A

Address: H'00000500, Address mask: H'00000000

Bus cycle: L bus/instruction fetch (before instruction execution)/read/longword

The ASID check is not included.

Channel B

Address: H'00001000, Address mask: H'00000000

Data: H'00000000, Data mask: H'00000000

Bus cycle: L bus/instruction fetch (before instruction execution)/read/longword

The number of execution-times break enable (5 times)

On channel A, a user break occurs before an instruction of address H'00000500 is executed. On channel B, a user break occurs after the instruction of address H'00001000 are executed four times and before the fifth time.

• Register specifications

BARA = H'00008404, BAMRA = H'00000FFF, BBRA = H'0054, BARB = H'00008010, BAMRB = H'00000006, BBRB = H'0054, BDRB = H'00000000, BDMRB = H'00000000, BRCR = H'00000400

Specified conditions: Channel A/channel B independent mode

Channel A

Address: H'00008404, Address mask: H'00000FFF

Bus cycle: L bus/instruction fetch (after instruction execution)/read (operand size is not included in the condition)

Channel B

Address: H'00008010, Address mask: H'00000006

Data: H'00000000, Data mask: H'00000000

Bus cycle: L bus/instruction fetch (before instruction execution)/read (operand size is not included in the condition)

A user break occurs after an instruction of addresses H'00008000 to H'00008FFE is executed or before an instruction of addresses H'00008010 to H'00008016 is executed.

#### **Break Condition Specified for L Bus Data Access Cycle:**

• Register specifications

BARA = H'00123456, BAMRA = H'00000000, BBRA = H'0064, BARB = H'000ABCDE, BAMRB = H'000000FF, BBRB = H'006A, BDRB = H'0000A512, BDMRB = H'00000000, BRCR = H'00000080

Specified conditions: Channel A/channel B independent mode

Channel A

```
Address: H'00123456, Address mask: H'00000000, ASID = H'80
```
Bus cycle: L bus/data access/read (operand size is not included in the condition)

Channel B

Address: H'000ABCDE, Address mask: H'000000FF

Data: H'0000A512, Data mask: H'00000000

Bus cycle: L bus/data access/write/word

On channel A, a user break occurs with longword read from address H'00123454, word read from address H'00123456, or byte read from address H'00123456. On channel B, a user break occurs when word H'A512 is written in addresses H'000ABC00 to H'000ABCFE.

## **Break Condition Specified for I Bus Data Access Cycle:**

• Register specifications:

BARA = H'00314156, BAMRA = H'00000000, BBRA = H'0094, BARB = H'00055555, BAMRB = H'00000000, BBRB = H'00A9, BDRB = H'00007878, BDMRB = H'00000F0F, BRCR = H'00000080

Specified conditions: Channel A/channel B independent mode

Channel A

Address: H'00314156, Address mask: H'00000000, ASID = H'80

Bus cycle: I bus/instruction fetch/read (operand size is not included in the condition)

Channel B

Address: H'00055555, Address mask: H'00000000, ASID = H'70

Data: H'00000078, Data mask: H'0000000F

Bus cycle: I bus/data access/write/byte

On channel A, a user break occurs when instruction fetch is performed for address H'00314156 in the memory space.

On channel B, a user break occurs when the I bus writes byte data H'7\* in address H'00055555.



## **20.3.8 Notes**

- 1. The CPU reads from or writes to the UBC registers via the I bus. A desired break may not occur until the instruction to rewrite the UBC registers are executed and the actual values are reflected. In order to know the timing the UBC register is changed, read the last written register. Instructions after then are valid for the newly written register value.
- 2. UBC cannot monitor access to the L bus and I bus in the same channel.
- 3. Note on specification of sequential break:

A condition match occurs when a B-channel match occurs in a bus cycle after an A-channel match occurs in another bus cycle in sequential break setting. Therefore, no break occurs even if a bus cycle, in which an A-channel match and a channel B match occur simultaneously, is set.

- 4. When user breaks and other exceptions occur by the same instruction, they are handled according to the priority listed in table 5.1 of section 5, Exception Handling. When an exception with a higher priority is generated, no user break occurs.
	- A break before the execution of an instruction is accepted with a priority over other exceptions.
	- When a break after the execution of an instruction or a data access break occurs simultaneously with a re-execution-type exception with a higher priority (including a break before the execution of an instruction), the re-execution-type exception is accepted and the condition match flag is not set (however, there is an exception as explained in 5. of section 20.3.8, Notes). When the exception source of the re-execution type is cleared by exception handling and the same instruction is executed again and completed, the break is generated again and the flag is set.
	- When a break after the execution of an instruction or a data access break occurs simultaneously with a completion-type exception with a higher priority (TRAPA), no break occurs but the condition match flag is set.
- 5. Note on exception of 4. of section 20.3.8, Notes

When a break after the execution of an instruction or a data access break occurs during the execution of the instruction in which a CPU address error is generated by data access, the CPU address error has a priority over the break and occurs before the break. The condition match flag is also set at this time.

6. Note when a break occurs in the delay slot

When a break before the execution of an instruction is set to the delay slot instruction of the RTE instruction, the break does not occur before executing the branch destination of the RTE instruction.

7. User breaks are disabled during USB module standby mode. Do not read from or write to the UBC registers during USB module standby mode; the values are not guaranteed.

# Section 21 User Debugging Interface (H-UDI)

This LSI incorporates a user debugging interface (H-UDI) to provide a boundary scan function and emulator support.

This section describes the boundary scan function of the H-UDI. For details on emulator functions of the H-UDI, refer to the user's manual of the relevant emulator.

# **21.1 Features**

The H-UDI is a serial I/O interface which conforms to JTAG (Joint Test Action Group, IEEE Standard 1149.1 and IEEE Standard Test Access Port and Boundary-Scan Architecture) specifications.

The H-UDI in this LSI supports a boundary scan function, and is also used for emulator connection.

When using an emulator, H-UDI functions should not be used. Refer to the emulator manual for the method of connecting the emulator.

Figure 21.1 shows a block diagram of the H-UDI.



#### **Figure 21.1 Block Diagram of H-UDI**



# **21.2 Input/Output Pins**

Table 21.1 shows the pin configuration of the H-UDI.

## **Table 21.1 Pin Configuration**



# **21.3 Register Descriptions**

The H-UDI has the following registers. For details on the addresses of these registers and the states of these registers in each processing state, see section 24, List of Registers.

- Bypass register (SDBPR)
- Instruction register (SDIR)
- Boundary scan register (SDBSR)
- ID register (SDID)

# **21.3.1 Bypass Register (SDBPR)**

SDBPR is a 1-bit register that cannot be accessed by the CPU. When SDIR is set to the bypass mode, SDBPR is connected between H-UDI pins (TDI and TDO). The initial value is undefined.

# **21.3.2 Instruction Register (SDIR)**

SDIR is a 16-bit read-only register. This register is in JTAG IDCODE in its initial state. It is initialized by TRST assertion or in the TAP test-logic-reset state, and can be written to by the H-UDI irrespective of the CPU mode. Operation is not guaranteed if a reserved command is set in this register.





**Bits 15 to 8** 



#### **Table 21.2 H-UDI Commands**

### **21.3.3 Boundary Scan Register (SDBSR)**

SDBSR is a 333-bit shift register, located on the PAD, for controlling the input/output pins of this LSI. The initial value is undefined. This register cannot be accessed by the CPU.

Using the EXTEST, SAMPLE/PRELOAD, CLAMP, and HIGHZ commands, a boundary scan test conforming to the JTAG standard can be carried out. Table 21.3 shows the correspondence between this LSI's pins and boundary scan register bits.



Bit	<b>Pin Name</b>	VO.	<b>Bit</b>	<b>Pin Name</b>	VO.
	from TDI		303	PE02/HIFDREQ/RXD SIO0/-	IN
332	PD06/IRQ6/RxD2/DACK1	IN	302	PE01/HIFRDY/SIOMCLK0/-	IN
331	PD05/IRQ5/TxD2/DREQ1	IN	301	PE00/HIFEBL/SCK_SIO0/-	IN
330	PD04/IRQ4/SCK1/-	IN	300	PC17/MDC/-/-	IN
329	PD03/IRQ3/RxD1/DACK0	IN	299	PC16/MDIO/-/-	IN
328	PD02/IRQ2/TxD1/DREQ0	IN	298	<b>PC15/CRS/-/-</b>	IN
327	PD01/IRQ1/-/TEND1	IN	297	PC18/LNKSTA	IN
326	PD00/IRQ0/-/TEND0	IN	296	PD06/IRQ6/RxD2/DACK1	OUT
325	PE08/HIFCS	IN	295	PD05/IRQ5/TxD2/DREQ1	OUT
324	PE24/HIFD15/CTS1/D31	IN	294	PD04/IRQ4/SCK1/-	OUT
323	PE23/HIFD14/RTS1/D30	IN	293	PD03/IRQ3/RxD1/DACK0	OUT
322	PE22/HIFD13/CTS0/D29	IN	292	PD02/IRQ2/TxD1/DREQ0	OUT
321	PE21/HIFD12/RTS0/D28	IN	291	PD01/IRQ1/-/TEND1	OUT
320	PE20/HIFD11/SCK1/D27	IN	290	PD00/IRQ0/-/TEND0	<b>OUT</b>
319	PE19/HIFD10/RxD1/D26	IN	289	PE08/HIFCS	OUT
318	PE18/HIFD09/TxD1/D25	IN	288	PE24/HIFD15/CTS1/D31	OUT
317	PE17/HIFD08/SCK0/D24	IN	287	PE23/HIFD14/RTS1/D30	OUT
316	PE16/HIFD07/RxD0/D23	IN	286	PE22/HIFD13/CTS0/D29	OUT
315	PE15/HIFD06/TxD0/D22	IN	285	PE21/HIFD12/RTS0/D28	<b>OUT</b>
314	PE14/HIFD05/-/D21	IN	284	PE20/HIFD11/SCK1/D27	OUT
313	PE13/HIFD04/-/D20	IN	283	PE19/HIFD10/RxD1/D26	OUT
312	PE12/HIFD03/-/D19	IN	282	PE18/HIFD09/TxD1/D25	OUT
311	PE11/HIFD02/-/D18	IN	281	PE17/HIFD08/SCK0/D24	OUT
310	PE10/HIFD01/-/D17	IN	280	PE16/HIFD07/RxD0/D23	<b>OUT</b>
309	PE09/HIFD00/-/D16	IN	279	PE15/HIFD06/TxD0/D22	OUT
308	PE07/HIFRS	IN	278	PE14/HIFD05/-/D21	OUT
307	PE06/HIFWR/SIOFSYNC0/-	IN	277	PE13/HIFD04/-/D20	OUT
306	PE05/HIFRD	IN	276	PE12/HIFD03/-/D19	<b>OUT</b>
305	PE04/HIFINT/TXD_SIO0/-	IN	275	PE11/HIFD02/-/D18	OUT
304	PE03/HIFMD	IN	274	PE10/HIFD01/-/D17	OUT

**Table 21.3 External pins and Boundary Scan Register Bits** 





















Note: \* Control means a low active signal.

The corresponding pin is driven with an OUT value when the Control is driven low.



# **21.3.4 ID Register (SDID)**

SDID is a 32-bit read-only register in which SDIDH and SDIDL are connected. Each register is a 16-bit that can be read by the CPU.

To read this register by the H-UDI side, the contents can be read via the TDO pin when the IDCODE command is set and the TAP state is Shift-DR. Writing is disabled.





# **21.4 Operation**

## **21.4.1 TAP Controller**

Figure 21.2 shows the internal states of the TAP controller. State transitions basically conform to the JTAG standard.



**Figure 21.2 TAP Controller State Transitions** 

Note: The transition condition is the TMS value at the rising edge of the TCK signal. The TDI value is sampled at the rising edge of the TCK signal and is shifted at the falling edge of the TCK signal. For details on change timing of the TDO value, see section 21.4.3, TDO Output Timing. The TDO pin is high impedance, except in the shift-DR and shift-IR states. A transition to the Test-Logic-Reset state is made asynchronously with TCK by driving the TRST signal 0.

#### **21.4.2 Reset Configuration**



#### **Table 21.4 Reset Configuration**

Notes: 1. Selects to normal mode or ASE mode.  $\overline{\text{ASEMDO}}$  = high: normal mode  $\overline{ASEMDO}$  = low: ASE mode

> 2. In ASE mode, the reset hold state is entered by driving the  $\overline{\text{RES}}$  and  $\overline{\text{TRST}}$  pins low for the given time. In this state, the CPU does not start up, even if the RES pin is driven high. After that, when the  $\overline{\text{TRST}}$  pin is driven high, H-UDI operation is enabled, but the CPU does not start up. The reset hold state is canceled by the following: another RES assert (power-on reset) or TRST reassert.

## **21.4.3 TDO Output Timing**

The timing of data output from the TDO differs according to the command type set in SDIR. The timing changes at the TCK falling edge when JTAG commands (EXTEST, CLAMP, HIGHZ, SAMPLE/PRELOAD, IDCODE, and BYPASS) are set. This is a timing of the JTAG standard. When the H-UDI commands (H-UDI reset negate, H-UDI reset assert, and H-UDI interrupt) are set, the TDO signal is output at the TCK rising edge earlier than the JTAG standard by a half cycle.





**Figure 21.3 H-UDI Data Transfer Timing** 

## **21.4.4 H-UDI Reset**

An H-UDI reset is generated by setting the H-UDI reset assert command in SDIR. An H-UDI reset is of the same kind as a power-on reset. An H-UDI reset is released by inputting the H-UDI reset negate command. The required time between the H-UDI reset assert command and H-UDI reset negate command is the same as time for keeping the RESETP pin low to apply a power-on reset.





## **21.4.5 H-UDI Interrupt**

The H-UDI interrupt function generates an interrupt by setting an H-UDI command in SDIR. An H-UDI interrupt is an interrupt of general exceptions, resulting in a branch to an address based on the VBR value plus offset, and with return by the RTE instruction. This interrupt request has a fixed priority level of 15.

RENESAS

H-UDI interrupts are accepted in sleep mode, but not in standby mode.

# **21.5 Boundary Scan**

A command can be set in SDIR by the H-UDI to place the H-UDI pins in boundary scan mode stipulated by JTAG.

## **21.5.1 Supported Instructions**

This LSI supports the three mandatory instructions defined in the JTAG standard (BYPASS, SAMPLE/PRELOAD, and EXTEST) and three option instructions (IDCODE, CLAMP, and HIGHZ).

**BYPASS:** The BYPASS instruction is a mandatory instruction that operates the bypass register. This instruction shortens the shift path to speed up serial data transfer involving other chips on the printed circuit board. While this instruction is executing, the test circuit has no effect on the system circuits. The upper four bits of the instruction code are 1111.

**SAMPLE/PRELOAD:** The SAMPLE/PRELOAD instruction inputs data from this LSI's internal circuitry to the boundary scan register, outputs data from the scan path, and loads data onto the scan path. While this instruction is executed, signals input to this LSI pins are transmitted directly to the internal circuitry, and internal circuit outputs are directly output externally from the output pins. This LSI's system circuits are not affected by execution of this instruction. The upper four bits of the instruction code are 0100.

In a SAMPLE operation, a snapshot of a value to be transferred from an input pin to the internal circuitry, or a value to be transferred from the internal circuitry to an output pin, is latched into the boundary scan register and read from the scan path. Snapshot latching is performed in synchronization with the rising edge of the TCK signal in the Capture-DR state. Snapshot latching does not affect normal operation of this LSI.

In a PRELOAD operation, an initial value is set in the parallel output latch of the boundary scan register from the scan path prior to the EXTEST instruction. Without a PRELOAD operation, when the EXTEST instruction was executed an undefined value would be output from the output pin until completion of the initial scan sequence (transfer to the output latch) (with the EXTEST instruction, the parallel output latch value is constantly output to the output pin).

**EXTEST:** This instruction is provided to test external circuitry when this LSI is mounted on a printed circuit board. When this instruction is executed, output pins are used to output test data (previously set by the SAMPLE/PRELOAD instruction) from the boundary scan register to the printed circuit board, and input pins are used to latch test results into the boundary scan register from the printed circuit board. If testing is carried out by using the EXTEST instruction N times, the Nth test data is scanned-in when test data (N-1) is scanned out.



Data loaded into the output pin boundary scan register in the Capture-DR state is not used for external circuit testing (it is replaced by a shift operation).

The upper four bits of the instruction code are 0000.

**IDCODE:** A command can be set in SDIR by the H-UDI pins to place the H-UDI pins in the IDCODE mode stipulated by JTAG. When the H-UDI is initialized (TRST is asserted or TAP is in the Test-Logic-Reset state), the IDCODE mode is entered.

**CLAMP, HIGHZ:** A command can be set in SDIR by the H-UDI pins to place the H-UDI pins in the CLAMP or HIGHZ mode stipulated by JTAG.

## **21.5.2 Points for Attention**

- Boundary scan mode does not cover clock-related system signals (EXTAL, XTAL, CKIO, and CK\_PHY), E10A-related signals (RES and ASEMD), and H-UDI-related signals (TCK, TDI, TDO, TMS, and TRST).
- When the EXTEST, CLAMP, and HIGHZ commands are set, fix the RES pin low.
- When a boundary scan test for other than BYPASS and IDCODE is carried out, fix the ASEMD pin high.

# **21.6 Usage Notes**

- An H-UDI command, once set, will not be modified as long as another command is not reissued from the H-UDI. If the same command is given continuously, the command must be set after a command (BYPASS, etc.) that does not affect LSI operations is once set.
- Because LSI operations are suspended in standby mode, H-UDI commands are not accepted. To hold the state of the TAP before and after standby mode, the TCK signal must be high during standby mode transition.
- The H-UDI is used for emulator connection. Therefore, H-UDI functions cannot be used when using an emulator.



# Section 22 Ethernet Physical Layer Transceiver (PHY)

This LSI has an on-chip PHY module.

# **22.1 Features**

- Fully-integrated IEEE 802.3/802.3u compliant 10/100Mbps Ethernet PHY
- PHY clock  $= 25$  MHz, 3.3 V Analog power supply.
- Integrated DSP with adaptive-equalizer and Baseline Wander (BLW) correction High immunity to crosstalk
- Link-configuration automatically determined by Auto-negotiation / parallel detection; manual configuration also available
- Low power consumption
- Half- and Full-duplex capable for both 10 and 100 Mbps links
- Automatic Polarity Correction in 10Base-T
- Extended cable length option in 10Base-T
- MII interface to the CPU core of this LSI.
- Serial Management Interface (SMI)
- Link, Activity, Duplex and Speed LED outputs







**Figure 22.1 The Block Diagram around PHY Module** 

# **22.2 Pin Configuration**

PHY module has below pins.

## **Table 22.1 Pin Configuration**







# **22.3 Top Level Functional Architecture**

Functionally, this PHY module can be divided into the following sections:

- 100Base-TX transmit and receive
- 10Base-T transmit and receive
- MII interface to the on-chip EtherC of this LSI
- Auto-negotiation to automatically determine the best speed and duplex possible
- Management Control to read status registers and write control register.



**Figure 22.2 Architectural Overview** 



# **22.4 PHY Management Control**

The Management Control module includes 2 blocks:

- Serial Management Interface (SMI)
- Management Registers Set

# **22.4.1 Serial Management Interface (SMI)**

The Serial Management Interface is used to control this PHY core and obtain its status. This interface supports registers 0 through 6 as required by Clause 22 of the IEEE802.3 standard. Nonsupported registers (7 to 15) will be read as hexadecimal "FFFF".

At the system level there are 2 signals, MDIO and MDC where MDIO is bi-directional open-drain and MDC is the clock. In the core there is no notion of bi-directional signals so the MDIO signal is implemented as 3 signals: CO\_MDIO\_DIR, CO\_MDO and CO\_MDI. The relationship among these signals is made clear in figure 22.3.



**Figure 22.3 How to Derive MDIO Signal from Core Signals** 

The CO MDC signal is an a-periodic clock provided by the station management controller (SMC), part of the EtherC. The CO\_MDI signal receives serial data (commands) from the controller SMC. The CO\_MDO sends serial data (status) to the SMC.

The minimum time between edges of the CO\_MDC is 160 ns. There is no maximum time between edges. The minimum cycle time (time between two consecutive rising or two consecutive falling edges) is 400 ns. These modest timing requirements allow this interface to be easily driven by the CPU.



The data on the CO\_MDO and CO\_MDI lines is latched on the rising edge of the CO\_MDC. The frame structure and timing of the data is shown in figure 22.4 and figure 22.5.



**Figure 22.4 MDIO Timing and Frame Structure (READ Cycle)** 



**Figure 22.5 MDIO Timing and Frame Structure (WRITE Cycle)** 

Shown below is an example of coding for MDC cycles implemented by software loops.

Note: CO\_MDIO\_DIR in figures 22.4 and 22.5 above has a reverse polarity in relation to the MMD bit in the PIR register.



```
/* SMI register read */
unsigned short ether_reg_read( unsigned short reg_addr )
{ 
     unsigned short data;
      phy_preamble();
     phy_reg_set( reg_addr, PHY_READ ); 
    phy_t_a_20();
     phy_reg_read( &data ); 
      mii_idle(); 
     return( data ); 
} 
/* SMI register write */
void ether_reg_write( unsigned short reg_addr, unsigned short data ) 
{ 
      phy_preamble(); 
      phy_reg_set( reg_addr, PHY_WRITE ); 
    phy_ta_10();
     phy_reg_write( data ); 
     mii_idle(); 
} 
/* Subroutines */
void phy_preamble( void ) 
{ 
      long i; 
     i = 32;while(i > 0)
      { 
           mii_write_1(); 
          \underline{\textbf{i}}--\textbf{j} }
```
}

```
void phy_reg_set( unsigned short reg_addr, long option )
{ 
     long i; 
    unsigned short data;
    data = 0;data = (PHY_ST \ll 14); /* ST code */
     if( option == PHY_READ ) 
      { 
         data | = (PHY\_READ \ll 12); /* OP code(RD) */
      } 
      else 
      { 
         data | = (PHY_MRITE \ll 12); /* OP code(WT) */
      } 
    data | = (PHY\rule{0pt}{0pt} << 7); /* PHY Address */
    data | = (reg\_addr \ll 2); /* Reg Address */
     i = 14;
     while( i > 0 )
      { 
           if( (data & 0x8000) == 0 ) 
           { 
                  mii_write_0(); 
           } 
           else 
           { 
                 mii_write_1(); 
           } 
         data \leq 1;
          i--; } 
}
```

```
#define QuatA 6 // =25cyc/4 (Please define to keep, "MDC cycle > 400ns")
void phy_reg_read( unsigned short *data ) 
{ 
     long i; 
     long j; 
    unsigned short reg_data;
    reg\_data = 0;i = 16; //Preceding TA cycle set PIR 0x00000000
    while( i > 0 )
      { 
         for (j=1; j<=QuatA; j++) REG_PIR = 0x000000000;for (j=1; j<=QuatA;j++) REG_PIR = 0x00000001;
          reg_data <<= 1; 
          reg_data |= (REG_PIR & 0x00000008) >> 3; /* MDI read*/ 
         for (j=1; j<=QuatA; j++) REG_PIR = 0x00000001;for (j=1; j<=QuatA; j++) REG_PIR = 0x000000000;i--; } 
     *data = reg_data; 
} 
void phy_reg_write( unsigned short data )
{ 
     long i; 
    i = 16;while( i > 0 )
      { 
          if( (data & 0x8000) == 0 ) 
\{ mii_write_0();
```


```
 } 
           else 
           { 
                   mii_write_1(); 
           } 
          i--;data \leq= 1;
      } 
} 
void phy_ta_z0( void )
{ 
  mii_idle(); 
  mii_idle(); 
} 
void phy_ta_10( void )
{ 
    mii_write_1(); 
    mii_write_0(); 
} 
/* Output 1 */
void mii_write_1( void ) 
{ 
  int j; 
  unsigned short pre_data;
```


```
 pre_data = REG_PIR&0x00000006; /* MDO,MMD */
  for (j=1; j<=Quata; j++) REG_PIR = 0x00000000 | pre_data; //line 1
 for (j=1; j<=QuatA;j++) REG_PIR = 0x00000001 | pre_data; //line 2
 for (j=1; j<=QuatA; j++) REG_PIR = 0x00000007; //line 3
 for (j=1; j<=Quata; j++) REG_PIR = 0x00000006; //line 4
} 
/* Output 0 */ 
void mii_write_0( void ) 
{ 
   int j; 
   unsigned short pre_data; 
  pre_data = REG_PIR&0x00000006; /* MDO,MMD */
 for (j=1; j<=QuatA;j++) REG_PIR = 0x00000000 | pre_data;
 for (j=1; j<=QuatA;j++) REG_PIR = 0x00000001 | pre_data;
 for (j=1; j<=Quata; j++) REG_PIR = 0x00000003;for (j=1; j<=Quata; j++) REG_PIR = 0x00000002;} 
/* Idle cycle */ 
void mii_idle( void ) 
{ 
   int j; 
   unsigned short pre_data; 
  pre_data = REG_PIR&0x00000006; /* MDO,MMD */
  for (j=1; j<=QuatA;j++) REG_PIR = 0x00000000 | pre_data;
 for (j=1; j<=QuatA;j++) REG_PIR = 0x00000001 | pre_data;
 for (j=1; j<=Quata; j++) REG_PIR = 0x00000001;for (j=1; j<=Quata; j++) REG_PIR = 0x000000000;}
```






## **22.4.2 SMI Register Mapping**



The following registers are supported (register numbers are in decimal):

• SMI Register Format

The mode key is as follows:

 $RW = read/write$ ,  $SC = self clearing$ ,  $WO = write only$ ,  $RO = read only$ 

LH = latch high, clear on read of register

 $LL =$  latch low, clear on read of register

NASR = Not Affected by Software Reset

 $(n,m)$  = register n, bit m





# • Register 0 (Basic Control)







• Register 2 (PHY Identifier 1)




• Register 3 (PHY Identifier 2)

• Register 4 (Auto Negotiation Advertisement)









# • Register 5 (Auto Negotiation Link Partner Ability)





• Register 6 (Auto Negotiation Expansion)



# **22.5 100Base-TX Transmit**

The data path of the 100Base-TX is shown in figure 22.6. Each major block is explained below.



**Figure 22.6 100Base-TX Data Path** 

# **(1) 100M Transmit Data across the MII**

The MAC controller drives the transmit data onto the CO\_MII\_TXD bus and asserts the internal signal (CO\_TX\_EN) to indicate valid data. The data is latched by the PHY's MII block on the rising edge of CO\_TX\_CLK. The data is in the form of 4-bit wide 25MHz data.

# **(2) 4B/5B Encoding**

The transmit data passes from the MII block to the 4B/5B encoder. This block encodes the data from 4-bit nibbles to 5-bit symbols (known as "code-groups") according to table 22.2. Each 4-bit data-nibble is mapped to 16 of the 32 possible code-groups. The remaining 16 code-groups are either used for control information or are not valid.

The first 16 code-groups are referred to by the hexadecimal values of their corresponding data nibbles, 0 through F. The remaining code-groups are given letter designations with slashes on either side. For example, an IDLE code-group is /I/, a transmit error code-group is /H/, etc.



# **Table 22.2 4B/5B Code Table**





# **(3) Scrambling**

Repeated data patterns (especially the IDLE code-group) can have power spectral densities with large narrow-band peaks. Scrambling the data helps eliminate these peaks and spread the signal power more uniformly over the entire channel bandwidth. This uniform spectral density is required by FCC regulations to prevent excessive EMI from being radiated by the physical routing.

The seed for the scrambler is generated from the PHY address. The scrambler also performs the Parallel In Serial Out conversion (PISO) of the data.

# **(4) NRZI and MLT3 Encoding**

The scrambler block passes the 5-bit wide parallel data to the NRZI converter where it becomes a serial 125MHz NRZI data stream. The NRZI is encoded to MLT-3. MLT3 is a tri-level code where a change in the logic level represents a code bit "1" and the logic output remaining at the same level represents a code bit "0".

#### **(5) 100M Transmit Driver**

The MLT3 data is then passed to the analog transmitter, which launches the differential MLT-3 signal, on outputs TXP and TXM, to the twisted pair media via a 1:1 ratio isolation transformer. The 10Base-T and 100Base-TX signals pass through the same transformer so that common "magnetics" can be used for both. The transmitter drives into the 100 ohm impedance of the CAT-5 cable. Cable termination and impedance matching require external components.



## **(6) 100M Phase Lock Loop (PLL)**

The 100M PLL locks onto reference clock and generates the 125MHz clock used to drive the 125 MHz logic and the 100Base-Tx Transmitter.

# **22.6 100Base-TX Receive**



**Figure 22.7 Receive Data Path** 

The receive data path is shown in figure 22.7. Detailed descriptions are given below.

# **(1) 100M Receive Input**

The MLT-3 from the cable is fed into the Core PHY (on inputs RXP and RXM) via a 1:1 ratio transformer. The ADC samples the incoming differential signal at a rate of 125M samples per second. Using a 64-level quantizer it generates 6 digital bits to represent each sample. The DSP adjusts the gain of the ADC according to the observed signal levels such that the full dynamic range of the ADC can be used.

## **(2) Equalizer, Baseline Wander Correction and Clock and Data Recovery**

The 6 bits from the ADC are fed into the DSP block. The equalizer in the DSP section compensates for phase and amplitude distortion caused by the physical channel consisting of magnetics, connectors, and CAT- 5 cable. The equalizer can restore the signal for any goodquality CAT-5 cable between 1m and 150m.

If the DC content of the signal is such that the low-frequency components fall below the low frequency pole of the isolation transformer, then the droop characteristics of the transformer will become significant and Baseline Wander (BLW) on the received signal will result. To prevent corruption of the received data, the Core PHY corrects for BLW and can receive the ANSI X3.263-1995 FDDI TP-PMD defined "killer packet" with no bit errors.

The 100M PLL generates multiple phases of the 125MHz clock. A multiplexer, controlled by the timing unit of the DSP, selects the optimum phase for sampling the data. This is used as the received recovered clock. This clock is used to extract the serial data from the received signal.

### **(3) NRZI and MLT-3 Decoding**

The DSP generates the MLT-3 recovered levels that are fed to the MLT-3 converter. The MLT-3 is then converted to an NRZI data stream.

#### **(4) Descrambling**

The descrambler performs an inverse function to the scrambler in the transmitter and also performs the Serial In Parallel Out (SIPO) conversion of the data.

During reception of IDLE (/I/) symbols. the descrambler synchronizes its descrambler key to the incoming stream. Once synchronization is achieved, the descrambler locks on this key and is able to descramble incoming data.

Special logic in the descrambler ensures synchronization with the remote PHY by searching for IDLE symbols within a window of 4000 bytes. This window ensures that a maximum packet size of 1514 bytes, allowed by the IEEE 802.3 standard, can be received with no interference.

If no IDLE-symbols are detected within this time-period, receive operation is aborted and the descrambler re-starts the synchronization process.



## **(5) Alignment**

The de-scrambled signal is then aligned into 5-bit code-groups by recognizing the /J/K/ Start-of-Stream Delimiter (SSD) pair at the start of a packet. Once the code-word alignment is determined, it is stored and utilized until the next start of frame.

## **(6) 5B/4B Decoding**

The 5-bit code-groups are translated into 4-bit data nibbles according to the 4B/5B table. The translated data is presented on the CO\_MII\_RXD[3:0] signal lines. The SSD, /J/K/, is translated to "0101 0101" as the first 2 nibbles of the MAC preamble. Reception of the SSD causes the PHY to assert the CO\_RX\_DV signal, indicating that valid data is available on the CO\_MII\_RXD bus. Successive valid code-groups are translated to data nibbles. Reception of either the End of Stream Delimiter (ESD) consisting of the /T/R/ symbols, or at least two /I/ symbols causes the PHY to deassert carrier sense and CO\_RX\_DV.

These symbols are not translated into data.

### **(7) Receive Data Valid Signal**

The Receive Data Valid signal (CO\_RX\_DV) indicates that recovered and decoded nibbles are being presented on the CO\_MII\_RXD[3:0] outputs synchronous to CO\_RX\_CLK. CO\_RX\_DV becomes active after the /J/K/ delimiter has been recognized and CO\_MII\_RXD is aligned to nibble boundaries. It remains active until either the /T/R/ delimiter is recognized or link test indicates failure, etc.

CO\_RX\_DV is asserted when the first nibble of translated  $J/K/$  is ready for transfer over the Media Independent Interface (MII).



**Figure 22.8 Relationship between Received Data and Some MII Signals** 



### **(8) Receiver Errors**

During a frame, unexpected code-groups are considered receive errors. Expected code groups are the DATA set (0 through F), and the /T/R/ (ESD) symbol pair. When a receive error occurs, the CO\_RX\_ER signal is asserted and arbitrary data is driven onto the CO\_MII\_RXD lines. Should an error be detected during the time that the /J/K/ delimiter is being decoded (bad SSD error), CO\_RX\_ER is asserted true and the value '1110' is driven onto the CO\_MII\_RXD lines. Note that the Valid Data signal is not yet asserted when the bad SSD error occurs.

# **(9) 100M Receive Data across the MII**

The 4-bit data nibbles are sent to the MII block. These data nibbles are clocked to the controller at a rate of 25MHz. The controller samples the data on the rising edge of CO\_RX\_CLK. CO\_RX\_CLK is the 25MHz output clock for the MII bus. It is recovered from the received data to clock the CO\_MII\_RXD bus. If there is no received signal, it is derived from the system reference clock (CO\_CLKIN).

When tracking the received data, CO\_RX\_CLK has a maximum jitter of 0.8ns (provided that the jitter of the input clock, CO\_CLKIN, is below 100ps).

# **22.7 10Base-T Transmit**

Data to be transmitted comes from the MAC layer controller. The 10Base-T transmitter receives 4-bit nibbles from the MII at a rate of 2.5MHz and converts them to a 10Mbps serial data stream. The data stream is then Manchester-encoded and sent to the analog transmitter which drives a signal onto the twisted pair via the external magnetics.

The 10M transmitter uses the following blocks:

- MII (digital)
- TX 10M (digital)
- 10M Transmitter (analog)
- 10M PLL (analog)

# **(1) 10M Transmit Data across the MII**

The MAC controller (EtherC) drives the transmit data onto the CO\_MII\_TXD BUS. When the controller (EtherC) has driven CO\_TX\_EN high to indicate valid data, the data is latched by the MII block on the rising edge of CO\_TX\_CLK. The data is in the form of 4-bit wide 2.5 MHz data.

In order to comply with legacy 10Base-T MAC/Controllers, in Half-duplex mode the PHY loops back the transmitted data, on the receive path. This does not confuse the MAC/Controller since the CO\_COL signal is not asserted during this time. The PHY also support the SQE (Heart beat) signal.

### **(2) Manchester Encoding**

The 4-bit wide data is sent to the TX10M block. The nibbles are converted to a 10Mbps serial NRZI data stream. The 10M PLL locks onto the external clock or internal oscillator and produces a 20MHz clock. This is used to Manchester encode the NRZ data stream. When no data is being transmitted (CO\_TX\_EN is low, the TX10M block outputs Normal Link Pulses (NLPs) to maintain communications with the remote link partner.



**Figure 22.9 Manchester Encoded Output** 

# **(3) 10M Transmit Drivers**

The Manchester encoded data is sent to the analog transmitter where it is shaped and filtered before being driven out as a differential signal across the TXP and TXM outputs.



# **22.8 10Base-T Receive**

The 10Base-T receiver gets the Manchester- encoded analog signal from the cable via the magnetics. It recovers the receive clock from the signal and uses this clock to recover the NRZI data stream. This 10M serial data is converted to 4-bit data nibbles which are passed to the controller (EtherC) across the MII at a rate of 2.5 MHz.

This 10M receiver uses the following blocks:

- Filter and SQUELCH (analog)
- 10M PLL (analog)
- RX 10M (digital)
- MII (digital)

### **(1) 10M Receive Input and Squelch**

The Manchester signal from the cable is fed into the core PHY (on inputs RXP and RXM) via 1:1 ratio magnetics. It is first filtered to reduce any out-of-band noise. It then passes through a SQUELCH circuit. The SQUELCH is a set of amplitude and timing comparators that normally reject differential voltage levels below 300mV and detect and recognize differential voltages above 585mV.

#### **(2) Manchester Decoding**

The output of the SQUELCH goes to the RX10M block where it is validated as Manchester encoded data. The polarity of the signal is also checked. If the polarity is reversed (local RXP is connected to RXM of the remote partner and vice versa), then this is identified and corrected. The 10M PLL is locked onto the received Manchester signal and from this, generates the received 20MHz clock. Using this clock, the Manchester encoded data is extracted and converted to a 10MHz NRZI data stream. It is then converted from serial to 4-bit wide parallel data.

The RX10M block also detects valid 10Base-T IDLE signals, Normal Link Pulses (NLPs), to maintain the link.

#### **(3) 10M Receive Data across the MII**

The 4 bit data nibbles are sent to the MII block. These data nibbles are valid on the rising edge of the 2.5 MHz CO\_RX\_CLK.

### **(4) Jabber detection**

Jabber is a condition in which a station transmits for a period of time longer than the maximum permissible packet length, usually due to a fault condition, that results in holding the CO\_TX\_EN input for a long period. Special logic is used to detect the jabber state and abort the transmission to the line, within 45ms. Once CO\_TX\_EN is deasserted, the logic resets the jabber condition.

Bit 1.1 indicates that a jabber condition was detected.

# **22.9 MAC Interface**

The MII (Media Independent Interface) block is responsible for the communication with the controller (EtherC). Special sets of hand-shake signals are used to indicate that valid received/transmitted data is present on the 4 bit receive/transmit bus.

# **(1) The MII includes 16 interface signals:**

- transmit data: CO\_MII\_TXD[3:0]
- transmit strobe: CO\_TX\_EN
- transmit: CO\_TX\_CLK
- transmit error: CO\_TX\_ER
- receive data: CO\_MII\_RXD[3:0]
- receive strobe: CO\_RX\_DV
- receive clock: CO\_RX\_CLK
- receive error: CO\_RX\_ER
- collision indication: CO\_COL
- carrier sense: CO\_CRS

On the transmit path, the PHY drives the transmit clock, CO\_TX\_CLK, to the controller (EtherC). The controller (EtherC) synchronizes the transmit data to the rising edge of CO\_TX\_CLK. The controller (EtherC) drives CO\_TX\_EN high to indicate valid transmit data. The controller (EtherC) drives CO\_TX\_ER high when a transmit error is detected.

On the receive path, the PHY drives both the receive data, CO\_RXD, and the CO\_RX\_CLK signal. The controller (EtherC) clocks in the receive data on the rising edge of CO\_RX\_CLK when the PHY drives CO\_RX\_DV high. The PHY drives CO\_RX\_ER high when a receive error is detected.



### **(2) Auto-negotiation**

The purpose of the Auto-negotiation function is to automatically configure the PHY to the optimum link parameters based on the capabilities of its link partner. Auto-negotiation is a mechanism for exchanging configuration information between two link-partners and automatically selecting the highest performance mode of operation supported by both sides. Auto-negotiation is fully defined in clause 28 of the IEEE 802.3 specification.

Once auto-negotiation has completed, information about the resolved link can be passed back to the controller (EtherC) via the Serial Management Interface (SMI). The results of the negotiation process are reflected in the Link Partner Ability Register (Register 5).

The auto-negotiation protocol is a purely physical layer activity and proceeds independently of the MAC controller (EtherC).

The advertised capabilities of the PHY are stored in register 4 of the SMI registers. The default advertised by the core PHY is determined by user-defined on-chip signal options. (i.e. the configuration of PHY-IF)

The following blocks are activated during an Auto-negotiation session:

- Auto-negotiation (digital)
- 100M ADC (analog)
- 100M PLL (analog)
- 100M equalizer/BLW/clock recovery (DSP)
- 10M SQUELCH (analog)
- 10M PLL (analog)
- 10M Transmitter (analog)

When enabled, auto-negotiation is started by the occurrence of one of the following events:

- Module reset (co\_resetb of PHY-IF)
- PHY power on reset
- Software reset
- Power-down reset
- Link status down
- Setting register 0, bit 9 high (auto-negotiation restart)

On detection of one of these events, the PHY begins auto-negotiation by transmitting bursts of Fast Link Pulses (FLP). These are bursts of link pulses from the 10M transmitter. They are shaped as Normal Link Pulses and can pass uncorrupted down CAT-3 or CAT-5 cable. A Fast Link Pulse Burst consists of up to 33 pulses. The 17 odd-numbered pulses, which are always present, frame the FLP burst. The 16 even-numbered pulses, which may be present or absent, contain the data word being transmitted. Presence of a data pulse represents a "1", while absence represents a "0".

The data transmitted by an FLP burst is known as a "Link Code Word." These are defined fully in IEEE 802.3 clause 28. In summary, the Core PHY advertises 802.3 compliance in its selector field (the first 5 bits of the Link Code Word). It advertises its technology ability according to the bits set in register 4 of the SMI registers.

There are 4 possible matches of the technology abilities. In the order of priority these are:

- 100M Full Duplex (Highest priority)
- 100M Half Duplex
- 10M Full Duplex
- 10M Half Duplex

If the full capabilities of the core PHY are advertised (100M, Full Duplex), and if the link partner is capable of 10M and 100M, then auto-negotiation selects 100M as the highest performance mode. If the link partner is capable of Half and Full duplex modes, then auto-negotiation selects Full Duplex as the highest performance operation.

Once a capability match has been determined, the link code words are repeated with the acknowledge bit set. Any difference in the main content of the link code words at this time will cause auto-negotiation to re-start. Auto-negotiation will also re-start if not all of the required FLP bursts are received.

The capabilities advertised during auto-negotiation by the core PHY are initially determined the co st mode[2:0] bits (PHYIFCR in the PHY-IF) latched after Module reset or PHY power on reset completes. This bit can also be used to disable auto-negotiation on power-up.

Writing register 4 bits [8:5] allows software control of the capabilities advertised by the core PHY. Writing register 4 does not automatically re-start auto-negotiation. Register 0, bit 9 must be set before the new abilities will be advertised. Auto-negotiation can also be disabled via software by clearing register 0, bit 12.

The PHY module does not support the Next Page capability.



# **(3) Parallel Detection**

If the PHY module is connected to a device lacking the ability to auto-negotiate (i.e. no FLPs are detected), it is able to determine the speed of the link based on either 100M MLT-3 symbols or 10M Normal Link Pulses. In this case the link is presumed to be Half Duplex per the IEEE standard. This ability is known as "Parallel Detection. This feature ensures interoperability with legacy link partners. If a link is formed via parallel detection, then bit 0 in register 6 is cleared to indicate that the Link Partner is not capable of auto-negotiation. The controller (EtherC) has access to this information via the management interface (SMI). If a fault occurs during parallel detection, bit 4 of register 6 is set.

Register 5 is used to store the Link Partner Ability information, which is coded in the received FLPs. If the Link Partner is not auto-negotiation capable, then register 5 is updated after completion of parallel detection to reflect the speed capability of the Link Partner.

# **(4) Re-starting Auto-negotiation**

Auto-negotiation can be re-started at any time by setting register 0, bit 9. Auto-negotiation will also re-start if the link is broken at any time. A broken link is caused by signal loss. This may occur because of a cable break, or because of an interruption in the signal transmitted by the Link Partner. Auto-negotiation resumes in an attempt to determine the new link configuration.

If the management entity re-starts Auto-negotiation by writing to bit 9 of the control register, the PHY module will respond by stopping all transmission/receiving operations. Once the break\_link\_timer is done, in the Auto-negotiation state-machine (approximately 1200ms) the autonegotiation will re-start. The Link Partner will have also dropped the link due to lack of a received signal, so it too will resume auto-negotiation detection is disabled.

# **(5) Auto-negotiation Disabling**

Auto-negotiation is disabled by setting the bit 12 in the register 0 to 0. The device forcibly reflects the information in the bit 13 (SPEED) and bit 8 (Duplex) in the register 0 to the operation speed. Information in the bit 13 (SPEED) and bit 8 (Duplex) in the register 0 is ignored while autonegotiation is enabled.



# **(6) Half-duplex and Full-duplex**

Half-duplex operation conforms to CSMA/CD (Carrier Sense Multiple Access/Collision Detect) protocol that deals with the network traffic and collision. In this mode, the carrier signal (CRS) supports either of transmit/receive operation. Receiving data during PHY transmission causes a collision.

In full-duplex mode, the PHY performs transmit and receive simultaneously. In this mode, the CRS supports only receive. The CSMA/CD protocol is not applied and the collision detection is disabled.

# **22.10 Miscellaneous Functions**

# **(1) Carrier Sense**

The carrier sense is output on CRS (to EtherC). CRS is a signal defined by the MII specification in the IEEE 802.3u standard. The PHY asserts CRS based only on receive activity whenever the PHY is either in repeater mode or full-duplex mode. Otherwise the PHY asserts CRS based on either transmit or receive activity.

The carrier sense logic uses the encoded, unscrambled data to determine carrier activity status. It activates carrier sense with the detection of 2 non-contiguous zeros within any 10 bit span. Carrier sense terminates if a span of 10 consecutive ones is detected before a /J/K/ Start-of Stream Delimiter pair. If an SSD pair is detected, carrier sense is asserted until either /T/R/ End-of-Stream Delimiter pair or a pair of IDLE symbols is detected. Carrier is negated after the /T/ symbol or the first IDLE. If /T/ is not followed by /R/, then carrier is maintained. Carrier is treated similarly for IDLE followed by some non-IDLE symbol.

# **(2) Collision Detect**

A collision is the occurrence of simultaneous transmit and receive operations. The CO\_COL output is asserted to indicate that a collision has been detected. CO\_COL remains active for the duration of the collision. CO\_COL is changed asynchronously to both CO\_RX\_CLK and TX\_CLK. The CO\_COL output becomes inactive during full duplex mode.

CO\_COL may be tested by setting register 0, bit 7 high. This enables the collision test. CO\_COL will be asserted within 512 bit times of CO\_TX\_EN rising and will be de-asserted within 4 bit times of CO\_TX\_EN falling.

In 10M mode, CO\_COL pulses for approximately 10 bit times (1us), 2us after each transmitted packet (de-assertion of CO\_TX\_EN). This is the Signal Quality Error (SQE) signal and indicates that the transmission was successful.



### **(3) Isolate Mode**

The ordinary external PHY LSI has a ability to make PHY data paths electrically isolated from the MII by setting register 0, bit 10 to a logic one.

But this PHY core is on-chip type so that this function is not supported.

# **(4) Link integrity Test**

This PHY performs the link integrity test as outlined in the IEEE 802.3u (Clause 24-15) Link Monitor state diagram. The link status is multiplexed with the 10Mbps link status to form the reportable link status bit in Serial Management Register 1, and is driven to LINK LED.

The DSP indicates a valid MLT-3 waveform present on the RXP and RXM signals as defined by the ANSI X3.263 TP-PMD standard, to the Link Monitor state-machine, using internal signal called DATA\_VALID. When DATA\_VALID is asserted the control logic moves into a Link-Ready state, and waits for an enable from the Auto Negotiation block. When received, the Link-Up state is entered, and the Transmit and Receive logic blocks become active. Should Auto Negotiation be disabled, the link integrity logic moves immediately to the Link-Up state, when the DATA\_VALID is asserted.

Note that to allow the line to stabilize, the link integrity logic will wait a minimum of 330 msec from the time DATA\_VALID is asserted until the Link-Ready state is entered. Should the DATA\_VALID input be negated at any time, this logic will immediately negate the Link signal and enter the Link-Down state.

When the 10/100 digital block is in 10Base-T mode, the link status is from the 10Base-T receiver logic.

#### **(5) Power-Down modes**

There is a power-down modes for the core:

• Power-Down

This power-down is controlled by register 0, bit 11. In this mode the entire PHY, except the management interface, is powered-down and stays in that condition as long as bit 0.11 is HIGH. When bit 0.11 is cleared, the PHY powers up and is automatically reset.



#### **(6) Reset**

The core PHY has 4 reset sources:

Module reset (co\_resetb):

It is connected to the co\_resetb of PHYIFCR, and to the internal POR signal.

If the co\_resetb is asserted(write "0"), it should be held "0" for at least 100 us to ensure that the core is properly reset.

• The Power-On-Reset (POR):

POR(Power-On-Reset) signal, which is driven out of the core through the co\_pwruprst of PHYIFSR, is asserted for approximately 16 ms after the first time that power is supplied to the chip.

• Software (SW) reset: (Do not use with this product.)

Activated by writing register 0, bit 15 high. This signal is self- clearing. After the registerwrite, internal logic extends the reset by 256µs to allow PLL-stabilization before releasing the logic from reset.

The IEEE 802.3u standard, clause 22 (22.2.4.1.1) states that the reset process should be completed within 0.5s from the setting of this bit.

• Power-Down reset:

Automatically activated when the PHY comes out of power-down mode. The internal powerdown reset is extended by 256µs after exiting the power-down mode to allow the PLLs to stabilize before the logic is released from reset.

These 4 reset sources are Module reset(Low active) and none Module reset(PHY power on reset, software reset, power down reset(High active) combined together in the digital block to create the internal "general reset", SYSRST, which is an asynchronous reset and is active HIGH. This SYSRST directly drives the PCS, DSP and MII blocks. It is also input to the Central Bias block in order to generate a short reset for the PLLs.

The SMI mechanism and registers are reset only by the Module reset, PHY power-on reset and Software reset. During Power-Down, the SMI registers are not reset. Note that some SMI register bits are not cleared by Software reset - these are marked "NASR" in the register tables.

For the first 16us after coming out of reset, the MII will run at 2.5 MHz. After that it will switch to 25 MHz if auto-negotiation is enabled.



# **(7) LED Description**

The PHY provides four LED signals. These provide a convenient means to determine the mode of operation of the core. All LED signals are active low.

• The CRS LED :

Its output is driven low when CRS is active (high). When CRS becomes inactive, the Activity LED output is extended by 128 ms.

The Link LED<sup>.</sup>

Its output is driven low whenever the PHY detects a valid link. The use of the 10Mbps or 100Mbps link test status is determined by the condition of the internally determined speed selection.

• The Speed LED:

Its output is driven low when the operating speed is 100Mbit/s or during Auto-negotiation. This LED will go inactive when the operating speed is 10Mbit/s.

• The Full-Duplex LED

Its output is driven low when the link is operating in Full-Duplex mode.

# **(8) Loopback Operation**

The 10/100 digital has an independent loop-back mode: Internal loopback.

Internal loopback

The internal loopback mode is enabled by setting bit register 0 bit 14 to logic one. In this mode, the scrambled transmit data (output of the scrambler) is looped into the receive logic (input of the descrambler). The CO\_COL signal will be inactive in this mode, unless collision test (bit 0.7) is active.

In this mode, during transmission (CO\_TX\_EN is HIGH), nothing is transmitted to the line and the transmitters are powered down.

# **22.11 Internal I/O Signals**

The I/O signals interface the logic of the core PHY to other modules on this LSI. The input signals can either be connected to other modules on the chip so that they can be connected to pins and driven externally, or they can be tied high or low inside the chip to set the behavior of the core PHY.

The following abbreviations are used:

- I: Input. Digital TTL levels.
- O: Output. Digital TTL levels.
- AI: Input. Analog levels.
- AO: Output. Analog levels.
- AI/O: Input or Output. Analog levels.



• MII signals





• Management signals

#### General signals



# **22.12 Signals Relevant to PHY-IF**

This PHY core has a part set up by the PHY-IF module.

#### **(1) PHY address**

The PHY address initialized by PHYIFADDR of PHY-IF, is same as the one that the ordinary external PHY LSI has. It gives each PHY a unique address. This address is latched into an internal register during Module reset and PHY power on reset. Originally, it enables a function to manage each PHY via the unique address in a multi-PHY application.

About this PHY module, you can not connect multiple PHYs to the MII interface within the LSI. But PHY address is also used to seed the scrambler, so that please accord the configuration of PHYIFADDRR and the PHY address on the management interface.

#### **(2) Operation mode**

The co\_st\_mode of the PHYIFCR of PHY-IF controls the configuration of 10/100 digital block.





#### Section 22 Ethernet Physical Layer Transceiver (PHY)

# **22.13 Usage Notes**

#### **(1) Input clock to PHY module**

The initial clock to PHY module is internal clock, mck  $(=ick/4)$ , but it does work only when it is 25MHz, which is acceptable to PHY module.

It corresponds to power down mode. For example, even in the application which doesn't use the on-chip PHY module, you have to set up the clock to the on-chip PHY so that it could be low power consumption mode with power down mode.

#### **(2) Treatment of Pins When PHY Power Supply is Not Used**

Even when the on-chip PHY is not used, supply power to the analog power supply pins for the PHY (Vcc1A, Vcc2A, and Vcc3A) and connect the analog ground pins for the PHY (Vss1A and Vss2A) to the ground. Pull up the CK-PHY pin to VccQ through a resistor or pull down the CK-PHY pin to VssQ through a register. Connect pins TxP, TxM, RxP, and RxM to the PHY analog ground. Connect the EXERS1 pin to the PHY analog power supply without going through a resistor. Do not connect anything to the TSTBUSA pin.



# **(3) Software Reset of the PHY**

The software reset of the on-chip PHY of this LSI has a defect in characteristics, which can prevent correct resetting of the PHY in some cases. Because of this, the PHY should be reset by a module reset, which is generated by setting the PHYIFCR register (in the PHY-IF module).

- Note: 1. Software reset refers to the reset which is executed by bit 15 of register 0 (basic control) described in section 22.4.2, SMI Register Mapping.
	- 2. Module reset refers to the reset which is executed by bit 14 of PHYIFCR (PHY-IF control register) described in section 23.2, Register Descriptions, in section 23, PHY Interface (PHY-IF).

# **(4) Waveform Adjustment**

The Ethernet PHY module of this LSI has test registers for adjustment of differential output waveforms. Using these test registers in their initial values produces no problem, but their specifications are shown below to facilitate printed circuit board design by the customer.

# **(a) Adjustment of Tx100 Waveform Output**

The on-chip PHY module of this LSI has the following adjustment registers as SIM registers, which allow waveform adjustment in the Tx100 operation. These registers have been designed so that they are not accidentally written. To change their values, follow the example procedure shown in "How to Use" that is described later.

- Register 20: Register for changing modes
- Register 23: Register for waveform adjustment (The register numbers are decimal)
- Meanings of the value written to register 23











• How to Use (Example)

Write to the SIM registers in the following sequence.



Note: The setting of this register is initialized during the auto-negotiation process or when the PHY module is reset (including a system reset of the LSI). Accordingly, when waveform adjustment is to be performed by this register, the above steps must be carried out every time the register is initialized.



# **(b) Adjustment Register for Tx10 Waveform Output**

Note: This register has little effect. The following descriptions of the register are only for your reference.

The adjustment register for Tx10 waveform output has DnTAMP ( $n = 1, 0$ ) bits to adjust the amplitude of waveforms and  $DnTCMP$  ( $n = 1, 0$ ) bits to adjust the slope of waveforms. The number of the register is 23 (decimal). When the value of writing of the step 8 in the adjustment register for Tx100 waveform output, described in (a), is H'4418 instead of H'4416, the value of writing of the step 7 is written as the setting value for the adjustment register for Tx10 waveform output. As described in the table below, the values written in bit15 and bit14 in the adjustment register for Tx10 waveform output are used as the setting values for  $DnTAMP (n = 1, 0)$  bits, while the values written in bit13 and bit12 are used as the setting values for DnTCMP ( $n = 1, 0$ ) bits. However, based our testing, the adjustment of the amplitude by  $DnTAMP (n = 1, 0)$  bits effects only in several millivolts.



### • Adjustment register for Tx10 waveform output

#### • How to Use (Example)

Write to the SIM registers in the following sequence.



Note:  $*$  To make the LSI enter the mode for setting the waveform adjustment, the Tx100 mode must be selected, instead of the Tx10 mode.

 The setting of the waveform adjustment is initialized during the auto-negotiation process or when the PHY module is reset (including a system reset of the LSI).

#### **(c) Detailed Descriptions**

The detailed descriptions of the functions of the adjustment registers for Tx100 waveform output are given below.

1. External Specification for Waveform Generation

Compliance tests include the items of the Rise Time (+/-ve) and Fall Time (+/-ve) in the "Tx100". The specified values are from 3 ns to 5 ns, respectively.

Therefore, the on-chip PHY module of this LSI is designed to transfer from 0 V to 1 V in 4 ns.



2. Mechanism of Waveform Generation

Waveforms are generated in two ways; divided in time and voltage.

For an example of divisions in time and voltage, the case of a transfer from 0 V to 1 V in 4 ns is shown below.



Time ranges

In this case, four-divided time ranges are generated on internal clocks, at first. Rise times are controlled as the divided numbers are controlled.

Total transition time is controlled as each timing in each time range is shifted on the DnSL bits in the adjustment registers.

Each slope in each time range is set on the DnCMP bits.

• Voltage levels

The voltage levels are also divided in four. The levels are modified at once as the maximum amplitude, the standard, is controlled on the DnA bits.



- 3. Control Method with Adjustment Registers for Tx100 Waveform Output
- Description of the bits of the adjustment registers for Tx100 waveform output The figure below shows the adjustment of the rising waveform from 0 V to 1 V, with the symbols;

Vout: Maximum amplitude (target in manufacturing is 1 V)

Tr: Transition time (target in manufacturing is 4 ns)





• Targets in manufacturing

The table below shows the targets in manufacturing. Each target can be adjusted with the adjustment registers.



• Adjustment effects

The amplitude and the transition time (the slope) are controlled independently, as shown above.

The slope is controlled on the DnSL bits and DnCMP bits together. However, since it is difficult to express the generated analog waveforms quantitatively, the waveforms must be ensured on the actual boards.

# **(d) Other Control Methods**

The methods, shown below for your reference, may have some bad effects or disadvantages. Therefore, if the methods will be used, it is necessary to confirm the advantage and disadvantage sufficiently.



- 1. Common Amplitude Adjustment Method in Tx10 and Tx100
	- Advantage:

As a common amplitude adjustment method in Tx10 and Tx100, there is a method of modifying the resistances of the resistors R1 and R2 in figure 22.10. The amplitudes in Tx10 and Tx100 have correlations with the resistances of both the resistors R1 and R2. Increasing the resistances increases the amplitudes in both Tx10 and Tx100, while decreasing the resistances decreases the amplitudes.

Disadvantage:

Unfavorable outcomes may often appear in harmonic content testings.

- 2. Amplitude Adjustment Method in Tx10
	- Advantage:

The amplitudes in Tx10 depend on VccnA (meaning PVCC in the example of connection above;  $n = 1$  to 3). Increasing VccnA increases the amplitudes, while decreasing VccnA decreases the amplitudes.

The amplitudes in Tx100 also depend on VccnA, though, less than in Tx100. Therefore, the amplitudes in Tx10 can be adjusted with modifying VccnA, with no influence on the results in Tx100.

Disadvantage:

However, since VccQ and VccnA are connected with diode inside this LSI, the permanent potential difference in them may damage the LSI's reliability. Therefore, the method has the disadvantage that VccQ must be adjusted simultaneously.



# **22.14 Guidelines for Layout**

### **22.14.1 General Guidelines**

The guidelines for four-layer boards are shown below.

### **(1) Configuration of Board Layers**

- Layer 1: Top layer (component side), which is a signal layer
- Layer 2: Ground layer
- Layer 3: Power layer
- Layer 4: Bottom layer (solder side), which is a signal layer

# **(2) Impedance Control**

Ideally, impedance control should satisfy the following.

- Single ended traces: 51 ohm  $\pm 10\%$
- Differential pairs: 99 ohm  $\pm 10\%$
- No restrictions on the impedance of short power/grand traces

#### **(3) Vias**

Vias are a source of impedance mismatches and distorted waveforms on transmission lines, which can cause problems of signal integrity (noise) and EMI issues. For differential signals and fast signal traces, avoid using vias on the signal lines whenever possible. If vias are used on such signal traces, ensure that they do not create problems by simulation or other means.

# **(4) Notes on Routing**

Stubs (branching) cause signal reflections, so they should be 12.7 mm (0.5 inch) or shorter for critical nets.

Stagger is a bad source of crosstalk, so all the signal traces around the PHY should be 25.4 mm (1 inch) or shorter.



#### **(5) Terminations**

To reduce signal reflections caused by impedance mismatches, provide damper or terminating resistance at the end-points of signal nets. Damper resistance should be placed close to the signal source, while terminating resistance should be placed at the farthest end-points of their nets. The distance from the signal source or farthest end-point must be shorter than 12.7 mm (0.5 inch).

# **22.14.2 Guidelines for Layout**

Since the signals of the PHY are analog signals with high frequencies and small amplitudes, they are susceptible to digital noise. So, routing and placement must be done with extra care.

An example of connection with a pulse transformer (RJ45) is shown in figure 22.10. The codes such as C1 and R2 in the following explanation are the part numbers indicated in figure 22.10.

#### **(1) Example of Connection with a Pulse Transformer (RJ45)**



**Figure 22.10 Example of Connection with a Pulse Transformer (RJ45)** 

# **(2) Sample Placement**

- 1. The pulse transformer should be placed close to the PHY-related pins of this LSI.
- 2. Components should be placed so that the signal traces of differential pairs, TxP/TxM and RxP/RxM, do not cross each other.
- 3. R4 and R5, which are terminating resistors, should be placed close to this LSI.
- 4. R1 and R2 should be placed close to the pulse transformer (RJ45).
- 5. R3 and C4, which form a filter, should be placed close to the pulse transformer (RJ45).
- 6. C4 of the center tap should be placed close to the pulse transformer (RJ45).
- 7. Do not place any components on the bottom side.

# **(3) Ground Planes**

Layer 2 is divided into logic ground plane and frame ground plane.

The logic ground is the combination of digital ground and analog ground. The frame ground is connected to the system ground and the shielding of the RJ45 socket so that it is grounded. Beware that this ground plane cuts impact the routing on adjacent signal layers.

Signal traces of L1 and L4 should not run across the cuts in the ground plane to avoid impedance mismatches and EMI problems. Minimize the frame ground area so as to make the logic ground as large and solid as possible. Connect the logic ground and frame ground by a ferrite bead or thick signal trace to provide a DC path. For safety, exclude the area near the leads of the RJ45 from the ground area.

# **(4) Common Power Plane**

Layer 3 consists of multiple power planes of Vcc and Vcc for PLL1 and PLL2, which supply 1.8 V, and VccQ and VccnA ( $n = 1$  to 3), which supply 3.3 V. VccnA is made up of an area of analog power for the RJ45 (connector-type pulse transformer) and an area of analog power for this LSI.

# **(5) Sample Routing**

In the above example, the ground layer is simply divided into two planes while the power layer is divided into more planes. Therefore, the top layer (component side) is superior to the bottom layer (solder side) in terms of signal integrity. If possible, all the critical signals of the PHY, differential signal pairs for example, should be wired in the top layer without any vias.

Another important thing to be noted about differential signal pairs is that the pair of traces of a pair must be strictly equal in length to minimize duty cycle distortion and common mode radiation.
#### **(6) Clock Layout**

In addition to the clock input for the CPU, an external clock for the PHY (CKPHY) can also be input to this LSI.

Analog power supply and analog signals should be placed far away from the oscillator, resonator, and digital devices that produce much noise. Clock signal lines should be wired in a layer higher than the ground layer (the top layer (component side) in this example). In addition, clock traces should be kept as far away from other traces as possible. The minimum spacing is three times of the trace width.





# Section 23 PHY Interface (PHY-IF)

This is an interface for operation of the on-chip PHY on this LSI.

# **23.1 Features**

- Selectable operation to enable the on-chip PHY or to disable (= utilizing an external PHY LSI) by pin function controller of ports.
- Below settings for the on-chip PHY are available.

The module reset

Selectable operation clock of the PHY module, the internal clock or the exclusive external clock for PHY.

But the clock of the on-chip PHY module has 25 MHz, fixed frequency.



Figure 23.1 shows the block diagram of PHY-IF.







# **23.2 Register Descriptions**

PHY-IF has below registers. Refer to section 24, List of Registers, about the addresses and the status under each operating condition.

- PHY-IF control register (PHYIFCR)
- PHY-IF SMI register 2 (PHYIFSMIR2)
- PHY-IF SMI register 3 (PHYIFSMIR3)
- PHY-IF address register (PHYIFADDRR)
- PHY-IF status register (PHYIFSR)

## **23.2.1 PHY-IF Control Register (PHYIFCR)**

PHYIFCR is a 16-bit readable/writeable register, which sets the operation mode of the on-chip PHY module. The changed bit values except co\_resetb are taken by the module reset of the onchip PHY with co\_resetb.

PHYIFCR is initialized by power-on-reset. It is also initialized as H'C000 in the standby mode.







#### **23.2.2 PHY-IF SMI Register 2 (PHYIFSMIR2)**

PHYIFSMIR2 is a 16-bit readable/writeable register, which sets the initial value of SMI register 2 in the case of the module reset the on-chip PHY module.

The changes of this register are taken by the on-chip PHY module reset with co\_resetb.

PHYIFSMIR2 is initialized by power-on-reset. It is also initialized as H'0000 in the standby mode.



#### **23.2.3 PHY-IF SMI Register 3 (PHYIFSMIR3)**

PHYIFSMIR3 is a 16-bit readable/writeable register, which sets the initial value of SMI register 3 in the case of the module reset the on-chip PHY module.

The changes of this register are taken by the on-chip PHY module reset with co\_resetb.

PHYIFSMIR2 is initialized by power-on-reset. It is also initialized as H'0000 in the standby mode.



#### **23.2.4 PHY-IF Address Register (PHYIFADDRR)**

PHYIFADDRR is a 16-bit readable/writeable register, which sets the PHY address of the on-chip PHY module.

The changes of this register are taken by the on-chip PHY module reset with co-resetb.

PHYIFADDRR is initialized by power-on-reset. It is also initialized as H'0000 in the standby mode.





#### **23.2.5 PHY-IF status Register (PHYIFSR)**

PHYIFSR is a 16-bit read-only register that shows the status of the on-chip PHY module.

PHYIFSR is initialized by power-on-reset.





# **23.3 PHY-IF Operation**

PHY-IF is basically for initializing the on-chop PHY module.

Following the procedures described in the following sections, please set up the on-chip PHY module with the MII interface like as for the external PHY LSI. The PHY module itself goes to power down mode with the initial values of co\_st\_mode of PHYIFCR after power-on-reset of the whole LSI at power-up.

## **23.3.1 The Procedures of Setting Up the On-Chip PHY**

Please set up with below procedures.

1. Release of module stop

First of all, release the module stop (MSTP20 of STBCR4), if PHY-IF is in module stop mode.

2. Power Up Reset

Check the release of power up reset mode, shown in the co\_pwruprst-bit of PHYIFSR with value "0".

3. Activation of the on-chip PHY module

To activate the on-chip PHY module, set the pin function registers of Port C as something but EtherC function, that is, I/O ports and LED outputs of the on-chip PHY.

- $\bullet$  PCCRH2 = H'0000
- $\bullet$  PCCRL1 = H'0000
- $\bullet$  PCCRL2 = H'FF00

In this case, the LNKSTA input pin of the EtherC is deselected. As the link output of the onchip PHY and link input of the EtherC are connected in this LSI, the link signal change interrupt can be generated in the same way as the external PHY LSI is used.

4. Set up of the clock

In the case of utilizing the internal clock from CPG, you have to set up the MCLKCR during the reset period of the on-chip PHY. Set the input clock of the PHY module as 25 MHz by adjusting the FRQCR and MCLKCR.

Do this set up before module reset of the on-chip PHY.



5. The reset of the on-chip PHY

Before you reset the on-chip PHY module, please set the register sets of PHY-IF parts as you need, except PHYIFCR. After that, set the co\_resetb of PHYIFCR as zero, to make the on-chip PHY reset state.

At this moment, you should set the other bits of PHYIFCR, which corresponds to the operating mode of the on-chip PHY. Please adjust the waiting time with software-loop, etc., so that you can keep the reset period is over 100 µs.

6. Release of the reset of the on-chip PHY.

Set only the co\_resetb of PHYIFCR as "1", for releasing the reset state of the on-chip PHY. After releasing the reset, adjust the waiting time with software loops, etc. as over 20 ms for propagation of reset signal within the PHY.

7. Set up the on-chip PHY module with the MII management frame.

The procedures after this step are set up by the MII management frame like an external PHY LSI on the market.

Please refer the section of PHY module about the each settings of it.

## **23.3.2 The Procedures of Set Up the External PHY LSI**

In the case of utilizing the external PHY LSI, select the EtherC function of the pin function controllers and then set up the internal registers of the PHY LSI with the MII management frame.

1. Activation of the external PHY LSI.

Select the EtherC functions with pin function controller.

- $\bullet$  PCCRH2 = H'0155
- $\bullet$  PCCRL1 = H'5555
- PCCRL2 =  $H'5555$
- 2. Set up the external PHY LSI with the MII management frame.

Following procedures are set up by the MII management frame.

About the each settings of the PHY LSI that you utilize, please refer the documents of it.



# Section 24 List of Registers

The register list gives information on the on-chip I/O register addresses, how the register bits are configured, and the register states in each operating mode. The information is given as shown below.

- 1. Register addresses (address order)
- Registers are listed from the lower allocation addresses.
- Reserved addresses are indicated by  $\frac{1}{\sqrt{2}}$  in the register name column. Do not access the reserved addresses.
- When registers consist of 16 or 32 bits, the addresses of the MSBs are given.
- Registers are classified according to functional modules.
- The numbers of Access Cycles are given.
- 2. Register bits
- Bit configurations of the registers are listed in the same order as the register addresses.
- Reserved bits are indicated by  $\frac{1}{\sqrt{1-\frac{1}{n}}}$  in the bit name column.
- Space in the bit name field indicates that the entire register is allocated to either the counter or data.
- For the registers of 16 or 32 bits, the MSB is listed first.
- 3. Register states in each operating mode
- Register states are listed in the same order as the register addresses.
- The register states shown here are for the basic operating modes. If there is a specific reset for an on-chip peripheral module, refer to the section on that on-chip peripheral module.



# **24.1 Register Addresses (Address Order)**

Entries under Access size indicates numbers of bits.

The number of access cycles indicate the number of cycles of the given reference clock. B, W, and L indicate values for 8-, 16-, and 32-bit accesses, respectively.

Note: Access to undefined or reserved addresses is prohibited. Since operation or continued operation is not guaranteed when these registers are accessed, do not attempt such access.























Note: \* The numbers of access cycles are eight bits when reading and 16 bits when writing.



Section 24 List of Registers

## **24.2 Register Bits**

Register addresses and bit names of the on-chip peripheral modules are described below.

Each line covers eight bits, and 16-bit and 32-bit registers are shown as 2 or 4 lines, respectively.
































































# **24.3 Register States in Each Processing State**

























Notes: 1. Some bits are not initialized.

- 2. Not initialized by a power-on reset caused by the WDT.
- 3. This module does not enter the module standby mode.
- 4. Initialization by applying the PHY power supply, not by a reset through power-on reset pin.

# Section 25 Electrical Characteristics

### **25.1 Absolute Maximum Ratings**

Table 25.1 shows the absolute maximum ratings.





Caution: Permanent damage to the LSI may result if absolute maximum ratings are exceeded.



## **25.2 Power-On and Power-Off Order**

- Order of turning on 1.8-V system power (Vcc, Vcc (PLL1), and Vcc (PLL2)) and 3.3-V system power (VccQ, Vcc1A, Vcc2A, and Vcc3A)
	- First turn on the 3.3-V system power, then turn on the 1.8-V system power within 1 ms. This time should be as short as possible. The system design must ensure that the states of pins or undefined period of an internal state do not cause erroneous system operation.
	- Until voltage is applied to all power supplies and a low level is input to the RES pin, internal circuits remain unsettled, and so pin states are also undefined. The system design must ensure that these undefined states do not cause erroneous system operation. Waveforms at power-on are shown in the following figure.



### **Table 25.2 Recommended Timing at Power-On**



Note: \* The values shown in table 25.2 are recommended values, so they represent guidelines rather than strict requirements.

The time over which the internal state is undefined means the time taken to reach Vcc (min.).

The pin states become settled when VccQ and VccnA  $(n = 1 to 3)$  reached the VccQ (min.). The timing when a power-on reset  $(RES)$  is normally accepted is after Vcc reaches Vcc (min.) and oscillation becomes stable (when using the on-chip oscillator).

Ensure that the time over which the internal state is undefined is less than or equal to 100 ms.

- Power-off order
	- In the reverse order of power-on, first turn off the 1.8-V system power, then turn off the 3.3-V system power within 10 ms. This time should be as short as possible. The system design must ensure that the states of pins or undefined period of an internal state do not cause erroneous system operation. In some systems, Vcc may exceed 3.3-V system power (Vcc > 3.3-V system power) temporarily, on the falling edge. Even in this case, the inverted potential difference must be 0.3 V or less.
	- Pin states are undefined while only the 1.8-V system power is turned off. The system design must ensure that these undefined states do not cause erroneous system operation.



#### **Table 25.3 Recommended Timing in Power-Off**



Note: \* The table shown above is recommended values, so they represent guidelines rather than strict requirements.



# **25.3 DC Characteristics**

Tables 25.4 and 25.5 show the DC characteristics.

### **Table 25.4 DC Characteristics (1)**

Conditions: For Ta, see the operating temperatures given in appendix B, Product Code Lineup.



### **Table 25.4 DC Characteristics (2)**

Conditions: For Ta, see the operating temperatures given in appendix B, Product Code Lineup.



s pins must be connected to the  $\rm v_{\rm cc}$  and  $\rm v_{\rm ss}.$ 

2. Current consumption values are for  $V_{\text{H}}$  min. =  $V_{\text{cc}}Q - 0.5$  V and  $V_{\text{L}}$  max. = 0.5 V with all output pins unloaded.



### **Table 25.5 Permissible Output Currents**

Conditions:  $V_{cc}Q = 3.0$  V to 3.6 V,  $V_{cc} = 1.71$  V to 1.89 V; for Ta, see the operating temperatures given in appendix B, Product Code Lineup.



Caution: To protect the LSI's reliability, do not exceed the output current values in table 25.5.

### **25.4 AC Characteristics**

Signals input to this LSI are basically handled as signals synchronized with the clock. Unless otherwise noted, setup and hold times for individual signals must be followed.

#### **Table 25.6 Maximum Operating Frequency**

Conditions:  $V_{C}Q = 3.0 V$  to 3.6 V,  $V_{C} = 1.71 V$  to 1.89 V; for Ta, see the operating temperatures given in appendix B, Product Code Lineup.



### **25.4.1 Clock Timing**

### **Table 25.7 Clock Timing**

Conditions:  $V_{cc}Q = 3.0 V$  to 3.6 V,  $V_{cc} = 1.71 V$  to 1.89 V; for Ta, see the operating temperatures given in appendix B, Product Code Lineup; External bus operating frequency (Max.) =  $62.5$  MHz







Notes: 1. Error margin means frequency tolerance (reference value). Recommending under 100 ps of peak to peak jitter.

2.  $t_{\text{box}}$  indicates the period of the external bus clock (B $\phi$ ).







**Figure 25.2 CKIO Clock Output Timing and CK\_PHY Clock Input Timing** 



**Figure 25.3 Oscillation Settling Timing after Power-On** 



**Figure 25.4 Oscillation Settling Timing after Standby Mode (By Reset)** 



**Figure 25.5 Oscillation Settling Timing after Standby Mode (By NMI or IRQ)** 





**Figure 25.6 PLL Synchronize Settling Timing By Reset or NMI** 



### **25.4.2 Control Signal Timing**

### **Table 25.8 Control Signal Timing**

Conditions:  $V_{cc}Q = 3.0 V$  to 3.6 V,  $V_{cc} = 1.71 V$  to 1.89 V; for Ta, see the operating temperatures given in appendix B, Product Code Lineup.



Notes: 1. The RES, NMI, and IRQ7 to IRQ0 signals are asynchronous signals. When the setup time is satisfied, a signal change is detected at the rising edge of the clock signal. When the setup time is not satisfied, a signal change may be delayed to the next rising edge.

2. In standby mode,  $t_{RESW} = t_{OSC2}$  (10 ms). When changing the clock multiplication,  $t_{RESW} = t_{PL1}$  $(100 \,\mu s)$ .

3.  $t_{\text{box}}$  indicates the period of the external bus clock (B $\phi$ ).



**Figure 25.7 Reset Input Timing** 









**Figure 25.9 Pin Drive Timing in Standby Mode** 



### **25.4.3 AC Bus Timing**

### **Table 25.9 Bus Timing**

Conditions: Clock mode =  $1/2/5/6$ ,  $V_{cc}Q = 3.0 V$  to 3.6 V,  $V_{cc} = 1.71 V$  to 1.89 V; for Ta, see the operating temperatures given in appendix B, Product Code Lineup.

<b>Item</b>	Symbol Min.		Max.	Unit	<b>Reference Figures</b>
Address delay time 1	$t_{AD1}$	1	14	ns	Figures 25.10 to 25.36
Address setup time	$t_{\rm As}$	3		ns	Figures 25.10 to 25.13
Address hold time	$t_{\text{\tiny AH}}$	3		ns	Figures 25.10 to 25.13
BS delay time	$\textnormal{t}_{\textnormal{\tiny{BSD}}}$		14	ns	Figures 25.10 to 25.29 and 25.33 to 25.36
CS delay time 1	$\mathfrak{t}_{\text{cSD1}}$	1	14	ns	Figures 25.10 to 25.36
Read write delay time	$\mathfrak{t}_{\text{\tiny{RWD1}}}$	1	14	ns	Figures 25.10 to 25.36
Read strobe time	$\rm t_{\rm asp}$	$1/2 \times t_{\text{bcyc}}$	$1/2 \times t_{\text{heve}} + 13$ ns		Figures 25.10 to 25.15, 25.33, and 25.34
Read data setup time 1	$\mathfrak{t}_{\text{\tiny RDS1}}$	$1/2 \times t_{\text{bcyc}} +$ 10		ns	Figures 25.10 to 25.15 and 25.33 to 25.36
Read data setup time 2	$\mathfrak{t}_{\text{\tiny{RDS2}}}$	10		ns	Figures 25.16 to 25.19, Figures 25.24 to 25.26
Read data hold time 1	$t_{\sf RDH1}$	0		ns	Figures 25.10 to 25.15 and 25.33 to 25.36
Read data hold time 2	$t_{\scriptscriptstyle\mathrm{RDH2}}$	$\overline{2}$		ns	Figures 25.16 to 25.19 and 25.24 to 25.26
Write enable delay time 1	$t_{\text{wED1}}$	$1/2 \times t_{\text{bcyc}}$	$1/2 \times t_{\text{bcyc}} + 10$ ns		Figures 25.10 to 25.14, 25.33, and 25.34
Write enable delay time 2	$t_{\rm wED2}$		13	ns	<b>Figure 25.15</b>
Write data delay time 1	$\mathfrak{t}_{\text{wDD1}}$		18	ns	Figures 25.10 to 25.15 and 25.33 to 25.36
Write data delay time 2	$t_{\tiny \textsf{WDD2}}$		14	ns	Figures 25.20 to 25.23 and 25.27 to 25.29
Write data hold time 1	$t_{\scriptscriptstyle{\sf WDH1}}$	$\overline{c}$		ns	Figures 25.10 to 25.15 and 25.33 to 25.36







Note:  $*$  The AC timing specification of  $\overline{WAIT}$  is as follows.

Input setup time  $+$  hold time of WAIT

 $= 11$  [ns] + 10 [ns] = 21 [ns]

As the frequency, 47.62 [MHz]

 Therefore, when the bus clock is 47.62 MHz or more, at least either setup time or hold time cannot be satisfied during 1-bus clock. The following notes should be confirmed.

• When the hardware-wait function is used synchronously

The bus clock frequency must be low enough to satisfy the AC specification above.

• When the hardware-wait function is used asynchronously

 To ensure the setup time until the start of the input assertion of WAIT, insert appropriate number of the software wait after the T1 state. Then, even if the AC specification above cannot be satisfied, the accesses can be executed correctly.



### **25.4.4 Basic Timing**



**Figure 25.10 Basic Bus Timing: No Wait Cycle** 





**Figure 25.11 Basic Bus Timing: One Software Wait Cycle** 



**Figure 25.12 Basic Bus Timing: One External Wait Cycle** 





**Figure 25.13 Basic Bus Timing: One Software Wait Cycle, External Wait Enabled (WM Bit = 0), No Idle Cycle** 



**Figure 25.14 Byte Control SRAM Timing: SW = 1 Cycle, HW = 1 Cycle, One Asynchronous External Wait Cycle, CSnWCR.BAS = 0 (UB-/LB-Controlled Write Cycle)** 





**Figure 25.15 Byte Control SRAM Timing: SW = 1 Cycle, HW = 1 Cycle, One Asynchronous External Wait Cycle, CSnWCR.BAS = 1 (WE-Controlled Write Cycle)** 



#### **25.4.5 Synchronous DRAM Timing**

**Figure 25.16 Synchronous DRAM Single Read Bus Cycle (Auto-Precharge, CAS Latency = 2, WTRCD = 0 Cycle, WTRP = 0 Cycle)** 



**Figure 25.17 Synchronous DRAM Single Read Bus Cycle (Auto-Precharge, CAS Latency = 2, WTRCD = 1 Cycle, WTRP = 1 Cycle)** 







**Figure 25.19 Synchronous DRAM Burst Read Bus Cycle (Single Read** × **4) (Auto-Precharge, CAS Latency = 2, WTRCD = 1 Cycle, WTRP = 0 Cycle)**






**Figure 25.21 Synchronous DRAM Single Write Bus Cycle (Auto-Precharge, WTRCD = 2 Cycles, TRWL = 1 Cycle)** 



**Figure 25.22 Synchronous DRAM Burst Write Bus Cycle (Single Write** × **4) (Auto-Precharge, WTRCD = 0 Cycle, TRWL = 1 Cycle)** 



**Figure 25.23 Synchronous DRAM Burst Write Bus Cycle (Single Write** × **4) (Auto-Precharge, WTRCD = 1 Cycle, TRWL = 1 Cycle)** 



**Figure 25.24 Synchronous DRAM Burst Read Bus Cycle (Single Read** × **4) (Bank Active Mode: ACT + READ Commands, CAS Latency = 2, WTRCD = 0 Cycle)** 



**Figure 25.25 Synchronous DRAM Burst Read Bus Cycle (Single Read** × **4) (Bank Active Mode: READ Command, Same Row Address, CAS Latency = 2, WTRCD = 0 Cycle)** 



**Figure 25.26 Synchronous DRAM Burst Read Bus Cycle (Single Read** × **4) (Bank Active Mode: PRE + ACT + READ Commands, Different Row Addresses, CAS Latency = 2, WTRCD = 0 Cycle)** 



**Figure 25.27 Synchronous DRAM Burst Write Bus Cycle (Single Write** × **4) (Bank Active Mode: ACT + WRITE Commands, WTRCD = 0 Cycle, TRWL = 0 Cycle)** 



**Figure 25.28 Synchronous DRAM Burst Write Bus Cycle (Single Write** × **4) (Bank Active Mode: WRITE Command, Same Row Address, WTRCD = 0 Cycle, TRWL = 0 Cycle)** 



**Figure 25.29 Synchronous DRAM Burst Write Bus Cycle (Single Write** × **4) (Bank Active Mode: PRE + ACT + WRITE Commands, Different Row Addresses, WTRCD = 0 Cycle, TRWL = 0 Cycle)** 



**Figure 25.30 Synchronous DRAM Auto-Refreshing Timing (WTRP = 1 Cycle, WTRC = 3 Cycles)** 



**Figure 25.31 Synchronous DRAM Self-Refreshing Timing (WTRP = 1 Cycle)** 



**Figure 25.32 Synchronous DRAM Mode Register Write Timing (WTRP = 1 Cycle)** 

# **25.4.6 PCMCIA Timing**



**Figure 25.33 PCMCIA Memory Card Interface Bus Timing** 



**Figure 25.34 PCMCIA Memory Card Interface Bus Timing (TED = 2.5 Cycles, TEH = 1.5 Cycles, One Software Wait Cycle, One External Wait Cycle)** 







**Figure 25.35 PCMCIA I/O Card Interface Bus Timing** 





**Figure 25.36 PCMCIA I/O Card Interface Bus Timing (TED = 2.5 Cycles, TEH = 1.5 Cycles, One Software Wait Cycle, One External Wait Cycle)** 



# **25.4.7 DMAC Signal Timing**

## **Table 25.10 DMAC Signal Timing**

Conditions:  $V_{cc}Q = 3.0$  V to 3.6 V,  $V_{cc} = 1.71$  V to 1.89 V; for Ta, see the operating temperatures given in appendix B, Product Code Lineup.









**Figure 25.38 TENDn, DACKn Output Timing** 



## **25.4.8 SCIF Timing**

#### **Table 25.11 SCIF Timing**

Conditions:  $V_{cc}Q = 3.0 V$  to 3.6 V,  $V_{cc} = 1.71 V$  to 1.89 V; for Ta, see the operating temperatures given in appendix B, Product Code Lineup.



Note: \*  $_{\sf poyc}$  indicates the period of the peripheral module clock (P $\upphi$ ).



**Figure 25.39 SCK Input Clock Timing** 





**Figure 25.40 SCI Input/Output Timing in Clocked Synchronous Mode** 

#### **25.4.9 SIOF Module Signal Timing**

#### **Table 25.12 SCIF Timing**

Conditions:  $V_{cc}Q = 3.0 V$  to 3.6 V,  $V_{cc} = 1.71 V$  to 1.89 V; for Ta, see the operating temperatures given in appendix B, Product Code Lineup.





Note: \*  $_{\sf poyc}$  indicates the period of the peripheral module clock (P $\upphi$ ).



**Figure 25.41 SIOMCLK Input Timing** 



**Figure 25.42 SIOF Transmit/Receive Timing (Master Mode 1/Falling Edge Sampling)** 











**Figure 25.45 SIOF Transmit/Receive Timing (Master Mode 2/Rising Edge Sampling)** 





# **25.4.10 Port Timing**

### **Table 25.13 Port Timing**

Conditions:  $V_{cc}Q = 3.0$  V to 3.6 V,  $V_{cc} = 1.71$  V to 1.89 V; for Ta, see the operating temperatures given in appendix B, Product Code Lineup.





**Figure 25.47 I/O Port Timing** 

## **25.4.11 HIF Timing**

#### **Table 25.14 HIF Timing**

Conditions:  $V_{cr}Q = 3.0 V$  to 3.6 V,  $V_{cr} = 1.71 V$  to 1.89 V; for Ta, see the operating temperatures given in appendix B, Product Code Lineup.



Notes: 1.  $t_{\text{poyc}}$  indicates the period of the peripheral module clock (P $\phi$ ).

- 2.  $t_{\text{Hifas}}$  is given from the start of the time over which both the  $\overline{\text{HIFCS}}$  and  $\overline{\text{HIFRD}}$  (or HIFWR) signals are low levels.
- 3.  $t_{\text{HIEAH}}$  is given from the end of the time over which both the  $\overline{\text{HIFCS}}$  and  $\overline{\text{HIFRD}}$  (or HIFWR) signals are low levels.
- 4.  $t_{HIPWRI}$  is given as the time over which both the  $\overline{HIFCS}$  and  $\overline{HIFRD}$  signals are low levels.
- 5.  $t_{\text{HIEWM}}$  is given as the time over which both the  $\overline{\text{HIFCS}}$  and  $\overline{\text{HIFWR}}$  signals are low levels.
- 6. When reading the register specified by bits REG5 to REG0 after writing to the HIF index register (HIFIDX),  $t_{\text{HIFWRWH}}$  (min.) = 2  $\times$   $t_{\text{poyc}}$  + 5 ns.



**Figure 25.48 HIF Access Timing** 







**Figure 25.50 HIFRDY and HIF Pin Enable/Disable Timing** 



# **25.4.12 EtherC Timing**

Note: These characteristics are valid in the case of utilizing the external PHY LSI. For example, "MDIO output" means that the MDIO input/output function is selected as the function of the pin PC16/MDIO, and the pin is used as the MDIO output pin of the on-chip EtherC.

#### **Table 25.15 EtherC Timing**

Conditions:  $V_{cc}Q = 3.0$  V to 3.6 V,  $V_{cc} = 1.71$  V to 1.89 V; for Ta, see the operating temperatures given in appendix B, Product Code Lineup.





**Figure 25.51 MII Transmission Timing (Normal Operation)** 



**Figure 25.52 MII Transmission Timing (Collision Occurred)** 





**Figure 25.53 MII Reception Timing (Normal Operation)** 



**Figure 25.54 MII Reception Timing (Error Occurred)** 



**Figure 25.55 MDIO Input Timing** 



**Figure 25.56 MDIO Output Timing** 



**Figure 25.57 WOL Output Timing** 





#### **25.4.13 H-UDI Related Pin Timing**

#### **Table 25.16 H-UDI Related Pin Timing**

Conditions:  $V_{cc}Q = 3.0 V$  to 3.6 V,  $V_{cc} = 1.71 V$  to 1.89 V; for Ta, see the operating temperatures given in appendix B, Product Code Lineup.



Note:  $*$  t<sub>bcyc</sub> indicates the period of the external bus clock (B $\phi$ ).











**Figure 25.61 H-UDI Data Transmission Timing** 

#### **25.4.14 AC Characteristic Test Conditions**

- I/O signal reference level:  $V_{cc}Q/2$  ( $V_{cc}Q = 3.0$  V to 3.6 V,  $V_{cc} = 1.71$  V to 1.89 V)
- Input pulse level:  $V_{ss}$  to  $V_{cc}Q$  (RES, NMI, IRQ7 to IRQ0, MD5, MD3 to MD0, ASEMD, TESTMD, HIFMD, TRST, and EXTAL),  $V_{ss}$  to 3.0 V (other pins)
- Input rising and falling times: 1 ns



**Figure 25.62 Output Load Circuit** 



# **25.5 Physical Layer Ttransceiver (PHY) Characteristics (Reference Values)**

Table 25.17 shows the characteristics of the physical layer transceiver (PHY).

# **Table 25.17 PHY Characteristics**

Conditions:  $V_{\text{cc}} 1A = V_{\text{cc}} 2A = V_{\text{cc}} 3A = 3.3 \text{ V}$ ; for Ta, see the operating temperatures given in appendix B, Product Code Lineup.





# Appendix

# **A. Port States in Each Pin State**

## **Table A.1 Port States in Each Pin State**














[Legend]

: This pin function is not selected as an initial state.

- I: Input
- O: Output
- IO: Input/output
- H: High level output
- L: Low level output



- Z: High-impedance
- P: Input or output depending on the register setting
- Notes: 1. Depends on the clock mode (setting of pins MD2 to MD0).
	- 2. Depends on the HIZCNT bit in CMNCR.
	- 3. High-impedance when  $HIFEBL = low$
	- 4. Depends on the HIZMEM bit in CMNCR.
	- 5. Depends on the HIZCNT bit in CMNCR or the CKOEN bit in FRQCR.
	- 6. This pin becomes output state only when reading data from the H-UDI and retains highimpedance state when the pin is not output state.
	- 7. In all pins having the weak keeper circuit, even with the "Z" (meaning high-impedance) description, each weak keeper circuit is always operating. For details on the weak keeper circuit, see section 19.6, Usage Notes.



#### **B. Product Code Lineup**





#### **C. Package Dimensions**



**Figure C.1 Package Dimensions (BP-176)** 

Appendix



## Main Revisions and Additions in this Edition











[Workaround]















![](_page_840_Picture_1.jpeg)

![](_page_841_Picture_104.jpeg)

![](_page_842_Picture_103.jpeg)

![](_page_842_Picture_1.jpeg)

![](_page_843_Picture_161.jpeg)

RENESAS

![](_page_844_Picture_108.jpeg)

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#### **Item Page Revision (See Manual for Details)**

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#### **Renesas 32-Bit RISC Microcomputer Hardware Manual SH7619 Group**

![](_page_856_Picture_35.jpeg)

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